

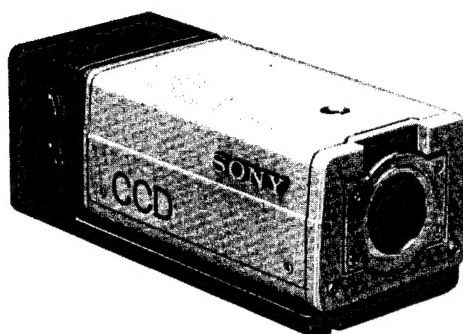
COLOR VIDEO CAMERA
AUTO IRIS LENS

DXC-101/102

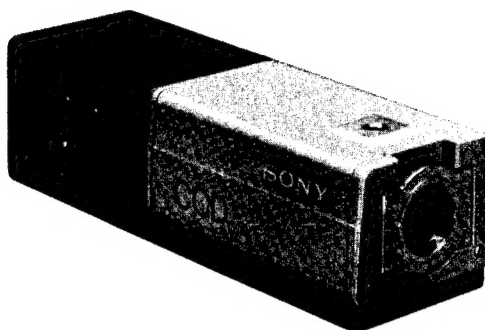
VCL-08Y/16Y

Revised-1

DXC-101



DXC-102



SONY
SERVICE MANUAL

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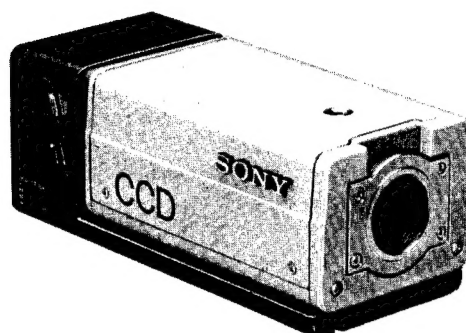
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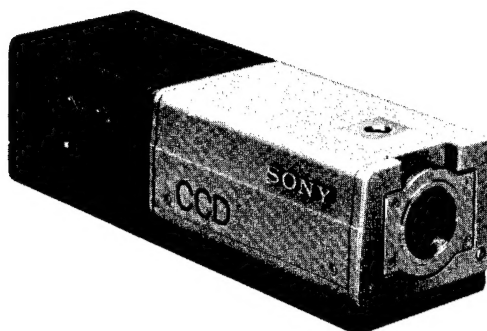
COLOR VIDEO CAMERA HEAD

DXC-101/102

DXC-101



DXC-102



SONY
SERVICE MANUAL

SPECIFICATIONS

Pickup device Interline-transfer CCD, 1-chip
 Picture elements 500 × 582 (horizontal/vertical)
 Sensing area 8.8 mm × 6.6 mm
 (equivalent to 2/3-inch pickup tube)
 Lens mount C mount
 Signal system EIA standards, NTSC color system
 Scanning system 525 lines, 2:1 interlace, 30 frames/sec.

Scanning frequency
 Horizontal: 15.734 kHz
 Vertical: 59.94 Hz

Sync system
 DXC-101: Internal
 DXC-102: Internal
 External with the VBS or BS signal
 Resolution Horizontal: 320 lines
 Vertical: 350 lines

Minimum illumination 30 lux (F1.4 at +12 dB gain setup)
 Sensitivity 2,000 lux, F4.0 (3,200°K)
 Gain selection AUTO, 0dB, 6dB or 12dB
 Video output 1.0 V (p-p), sync negative, 75 ohms,
 unbalanced

Video signal-to-noise ratio
 More than 48 dB
 (Gamma: OFF, Detail: OFF)

Input/output connectors
 DXC-101: VIDEO OUT: BNC type
 LENS: 4-pin connector
 DC IN: 12-pin connector
 DXC-102: DC IN/VIDEO OUT: BNC type
 LENS: 4-pin
 REMOTE: BNC type
 GEN LOCK IN: BNC type

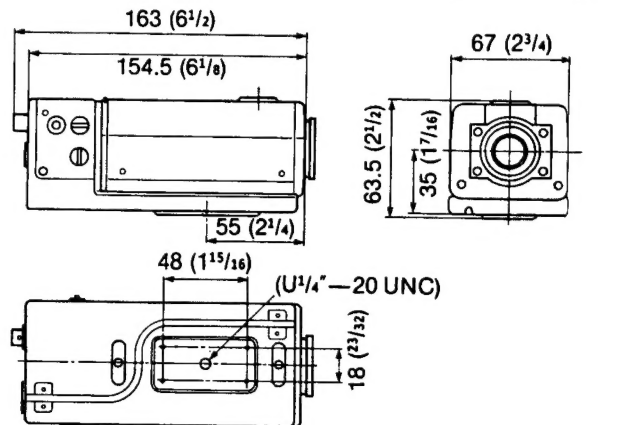
Power requirements
 DXC-101: 10.5 to 16.0 V DC
 DXC-102: 25 to 28 V DC

Power consumption
 DXC-101: 4.2 W
 DXC-102: 7.6 W
 Operating temperature 0°C to 40°C (32°F to 104°F)
 Storage temperature -40°C to +60°C (-40°F to +140°F)
 Operating humidity Less than 70 %
 Storage humidity Less than 90 %
 Vibration resistance Less than 7 G (11 to 200 Hz)
 Shock resistance Less than 70 G

Weight
 DXC-101: Approx. 550 g (1 lb 3 oz)
 DXC-102: Approx. 800 g (1 lb 12 oz)

Dimensions

[DXC-101]



[DXC-102]

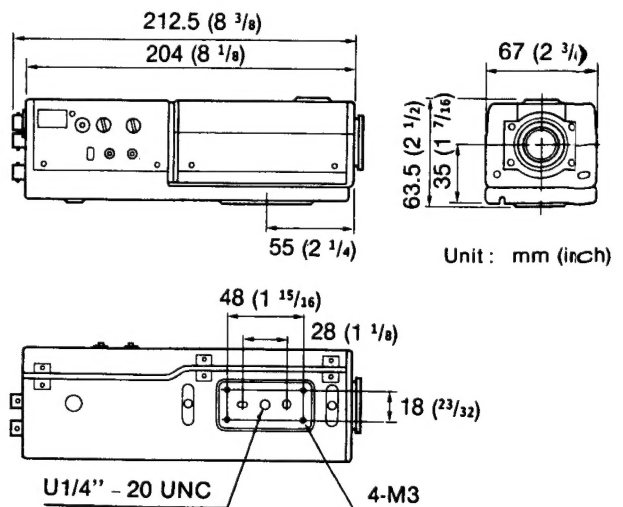


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SECTION 1 GENERAL DESCRIPTION

1-1. DXC-101/101P GENERAL DESCRIPTION

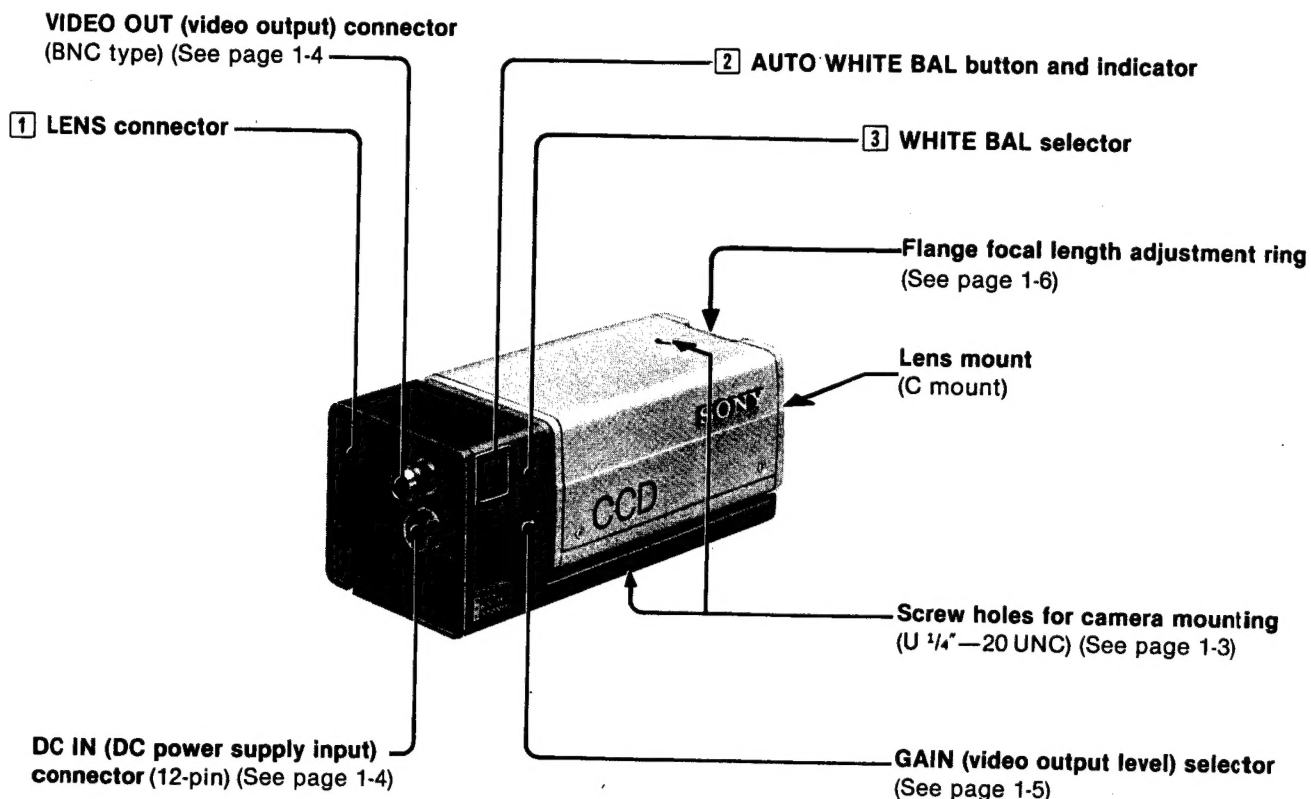
1-1-1. GENERAL FEATURES

The DXC-101/101P color video camera, designed for monitoring and surveillance, features a 1-chip CCD (Charge Coupled Device) which affords small size, light weight, and low power consumption. This CCD improves highlight after-images and color reproduction, eliminates highlight burn-in and picture distortion, and resists vibration and shock.

The camera lens mount is a C mount. Auto iris lenses such as the VCL-08Y and the VCL-16Y (optional) are available.

To use this camera for monitoring, connect a video monitor and the CMA-D1/D1CE camera adaptor (optional) to the camera. The camera can be installed on a wall or ceiling with a mounting bracket.

1-1-2. LOCATION AND FUNCTION OF PARTS



1 LENS connector (4-pin)

This connector is used when the VCL-08Y or VCL-16Y auto iris lens is used, to control the iris of the lens automatically.

2 AUTO WHITE BAL (automatic white balance adjustment) button and indicator (green)

Press this button to adjust the white balance automatically.

When the adjustment is completed, the indicator lights up for a few seconds.

3 WHITE BAL (white balance adjustment) selector

AUTO: Set to AUTO to adjust the white balance automatically.

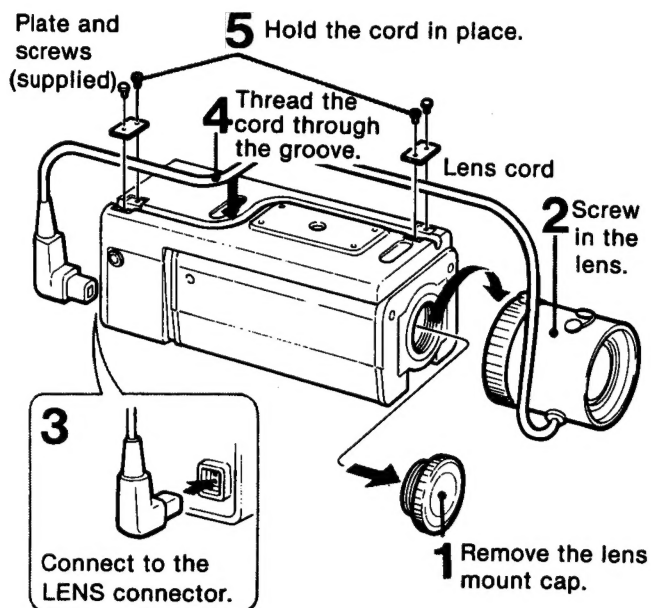
1, 2 or 3: Set to 1, 2 or 3 to adjust the white balance to one of the factory-preset values.

For details, refer to "WHITE BALANCE ADJUSTMENT" on page 1-5.

1-1-3. INSTALLATION

•LENS MOUNTING

Mount the lens according to the following procedure from 1 to 5.



To change the lens mounting position, refer to the instruction manual of the lens.

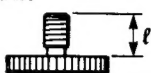
•CAMERA INSTALLATION

To install the camera on a wall or ceiling, use a screw which matches the screw hole in the camera ($U\frac{1}{4}$ " — 20 UNC), and attach the camera to a support or to a mounting bracket with the screw.

Be sure to use the screw specified below.

ISO standard: $\ell = 4.5 \text{ mm} \pm 0.2 \text{ mm}$

ASA standard: $\ell = 0.197 \text{ inches}$

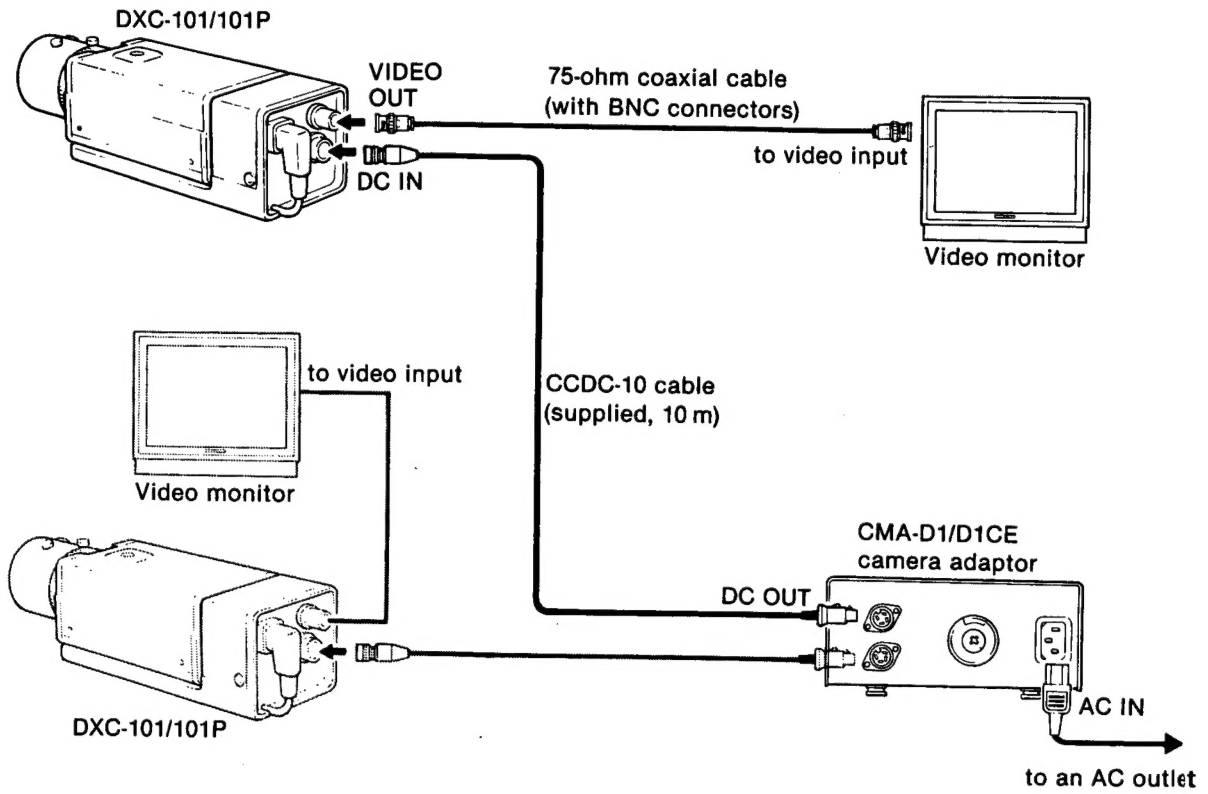


Caution on installation

Do not install the camera in a place as follows:

- Extremely hot or cold places (operating temperature: 0°C to 40°C or 32°F to 104°F).
- Where it is exposed to rain, high humidity or dust.
- Where it is subjected to very high vibration.
- Place near a TV or radio station which radiates high power radio waves.

1-1-4. CONNECTIONS



1-1-5. OPERATION

1) PREPARATION

- Check that all the units are connected properly.
- Set the POWER switch of the CMA-D1/D1CE to ON to turn on the camera.
- Turn on the video monitor, and adjust its controls properly.
- Set the GAIN selector of the camera to 0 dB.
- Illuminate the object properly.
- When a manual iris control lens is used, adjust the iris depending on the lighting conditions.

2) WHITE BALANCE ADJUSTMENT (for lifelike color reproduction)

There are two ways to adjust the white balance as described below.

To adjust the white balance to the factory-preset values
Select the position of the WHITE BAL selector depending on the lighting conditions.

Selector position	Label indication	Lighting conditions
1	3200°K (color temperature)	Iodine lamp, sunrise, sunset
2	INDOORS	Fluorescent light
3	OUTDOORS	Under a clear sky

For better color setup according to lighting conditions (Automatic white balance adjustment)

Perform the procedure described below.

- 1 Set the WHITE BAL selector to AUTO.
- 2 Shoot a white object (a white cloth or a white wall) with the camera so that the white object fills the screen.
- 3 Press the AUTO WHITE BAL button. When the automatic white balance adjustment is completed, the indicator lights up for a few seconds.

The white balance adjustment function may not operate in the following lighting conditions:

If the lighting is insufficient, the AUTO WHITE BAL indicator will not light up. This signifies that the white balance cannot be adjusted properly.

If the lighting is excessive, the AUTO WHITE BAL indicator will light up, even if the white balance cannot be adjusted properly. In this case, the entire monitor screen turns greenish to indicate that the white balance adjustment cannot be made properly.

In both cases, try to adjust the white balance again as follows.

When an auto iris lens is used:

When the lighting is insufficient, the white balance cannot be adjusted properly. Increase the lighting and press the AUTO WHITE BAL button again.

When a manual iris lens is used:

When the lighting is insufficient or excessive, the white balance cannot be adjusted properly. When the lighting is insufficient, open the iris or increase the lighting; when the lighting is excessive, stop down the lens. Then press the AUTO WHITE BAL button again.

Memory of the automatic white balance adjustment value

In the DXC-101/101P, a built-in memory stores the adjusted white balance value. The memorized value will be retained for about 24 hours after the power is turned off without any further power supply to the camera or until the adjustment is made again.

3) VIDEO OUTPUT LEVEL SELECTION

The video output level can be adjusted with the GAIN selector.

AUTO: Set the selector to this position when the brightness of objects changes as in conditions outdoors. The video output level is automatically adjusted according to the brightness of the objects.

0 dB: The selector is usually set to this position.

6 or 12 dB: The video output level can be raised by 6 dB or by 12 dB depending on the position of the selector. When the lighting is insufficient and the picture observed on the monitor is too dim, set the selector to one of these positions.

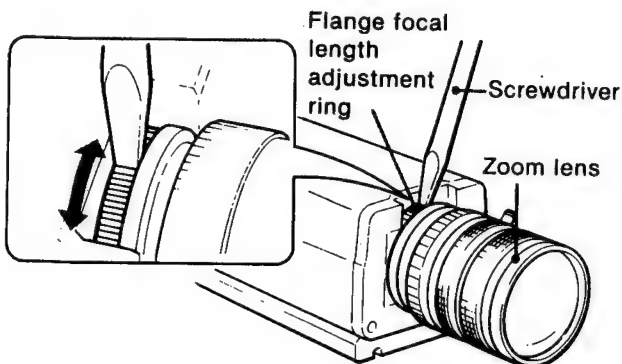
After these adjustments (white balance and video output level) are completed, shoot an object with the camera and observe the picture on the monitor screen. Then, adjust the lens focus. Once these adjustments have been completed, no further adjustments will be necessary provided that both the lighting and the distance to the object do not change. To monitor the picture again after the camera and other units have been turned off, just turn on the camera adaptor and the monitor.

1-1-6. FLANGE FOCAL LENGTH ADJUSTMENT

When a zoom lens is used with this camera, flange focal length adjustment may be required. The proper flange focal length adjustment insures that the object is in focus both at the wide-angle position and at the telephoto position when zooming. Once the flange focal length adjustment has been made, readjustment is not necessary as long as the lens stays mounted on the same camera.

Focus on an object with fine detail to adjust the flange focal length.

- 1 **When a manual iris lens is used, set the iris fully open.**
When an auto iris lens is used, illuminate an object so that the iris is fully open.
- 2 Point the camera at an object about 3 meters (10 feet) from the camera.
- 3 Set the zoom to the telephoto position.
- 4 Turn the focus ring to adjust the focus.
- 5 Set the zoom to the wide-angle position.
- 6 Turn the flange focal length adjustment ring of the camera until the same object is in focus. Do not turn the focus ring.

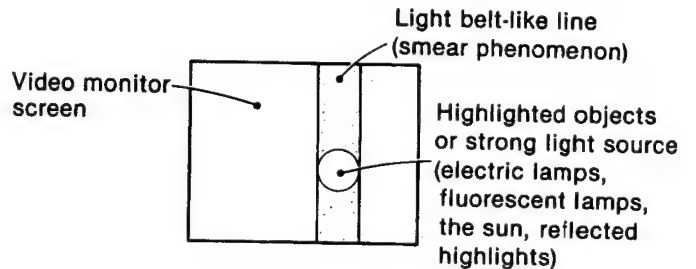


- 7 Repeat steps 3 to 6 until the object is in focus while the zoom is in both the telephoto position and the wide-angle position.

1-1-7. SPECIFIC EFFECTS CAUSED BY CCD

Smear in picture

This may appear when a highlighted object is shot.



Patterned noise in picture

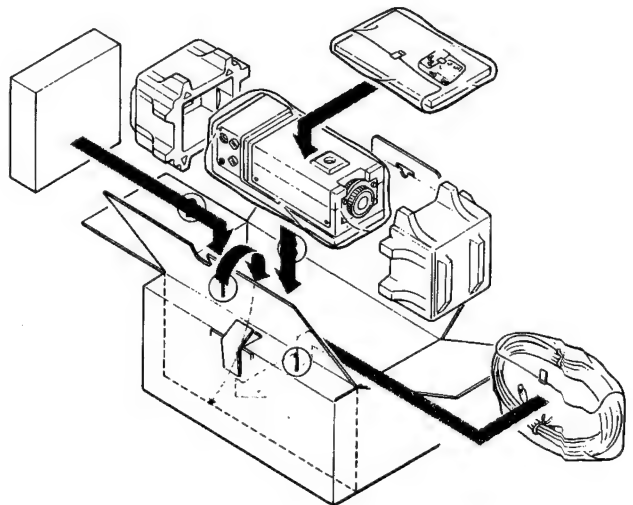
When the camera is used at a high temperature, a fixed patterned noise may appear on the entire screen of the monitor.

Gear-tooth effect in picture

When vertical stripes or straight lines are shot, they may look wavy.

1-1-8. REPACKING FOR SHIPMENT

The repacking procedure is subject to change. Refer to the packing instructions on the original carton, as well as those shown here.



1-2. DXC-102/102P GENERAL DESCRIPTION

1-2-1. OUTLINE

The DXC-102/102P color video camera, designed for monitoring and surveillance, features a 1-chip CCD (Charge Coupled Device) which allows the camera to be small and lightweight and have a low power consumption. This CCD reduces highlight after-images, eliminates highlight burn-in and picture distortion, improves color reproduction, and resists vibration and shock.

The camera lens mount is a C mount.

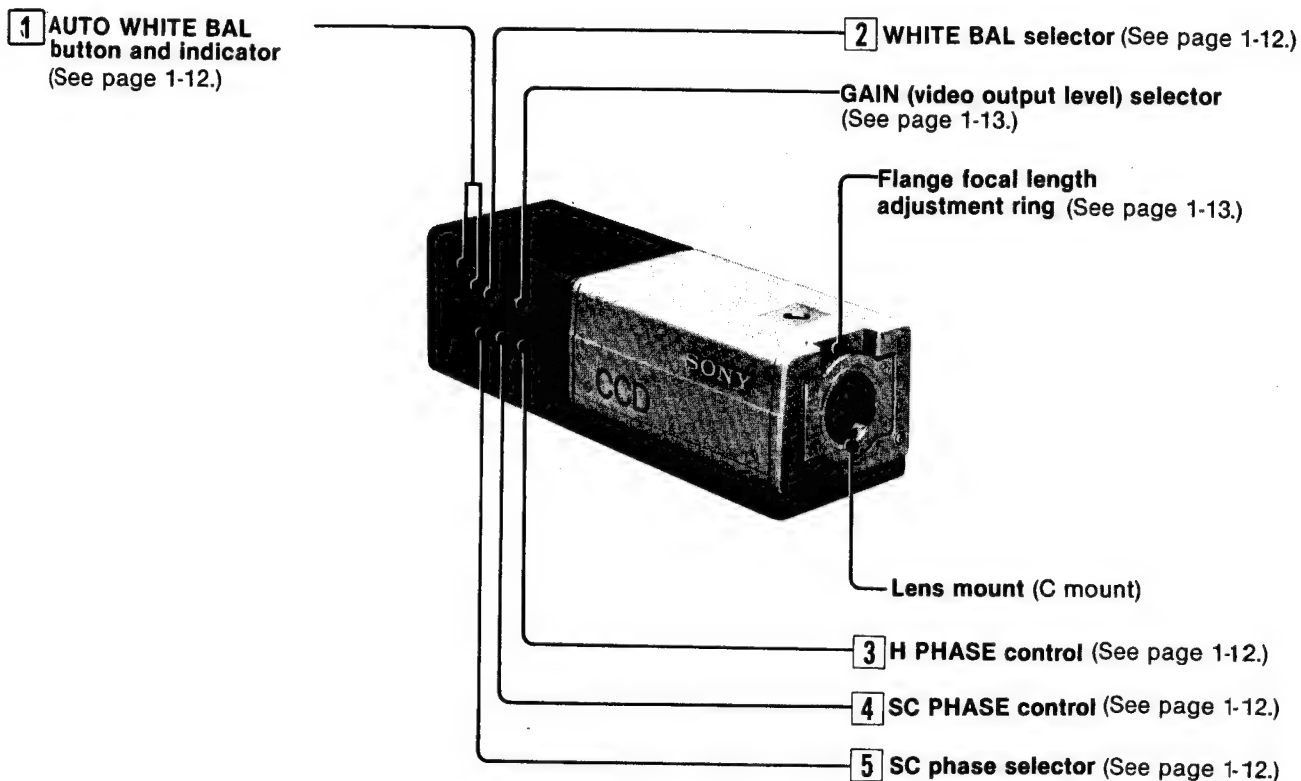
Auto iris lenses such as the VCL-08Y and the VCL-16Y (optional) are available from your authorized Sony dealer.

To use this camera for monitoring, connect a video monitor and a CMA-10/10CE camera adaptor (optional) to the camera.

The camera can be synchronized to a reference signal (VBS or BS) supplied to the camera.

The camera can be installed on a wall or ceiling with a mounting bracket.

1-2-2. LOCATION AND FUNCTION OF CONTROLS



1 AUTO WHITE BAL (automatic white balance) button and indicator (green)

When the WHITE BAL selector is set to AUTO, press this button to adjust the white balance automatically. When the adjustment is completed, the indicator lights up for a few seconds.

2 WHITE BAL (white balance adjustment) selector

AUTO: Set to AUTO to adjust the white balance automatically.

1, 2 or 3: Set to 1, 2 or 3 to adjust the white balance to one of the factory-preset values.

3 H (horizontal) PHASE control

When two or more cameras are used, turn this control with a small screwdriver to adjust the H phase difference between the gen-lock input and video output signals.

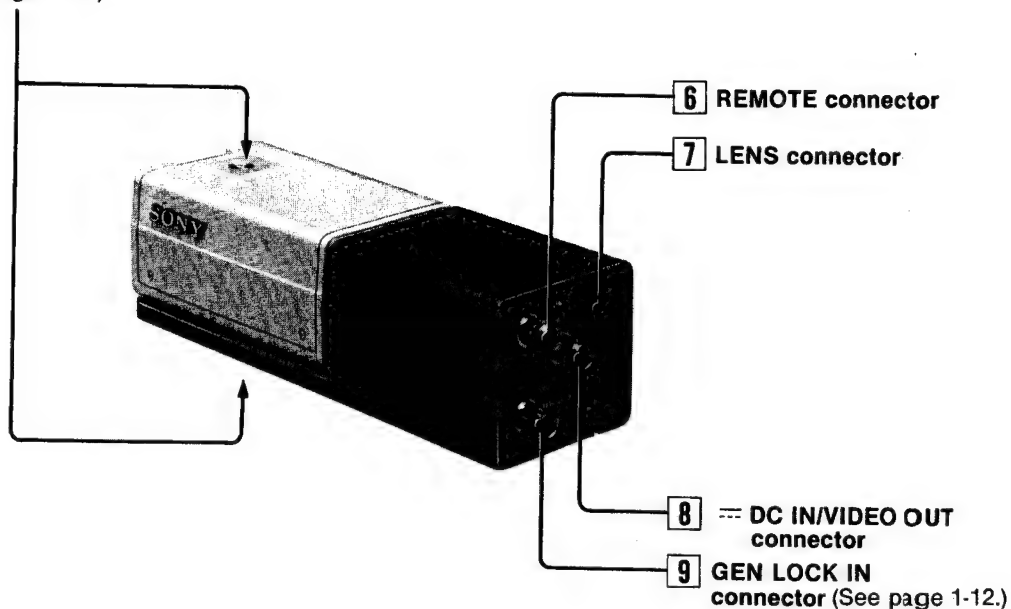
4 SC (subcarrier) PHASE control

When two or more cameras are used, this control is used for fine adjustment of the subcarrier phase after making the rough adjustment with the SC phase selector **5**.

5 SC (subcarrier) phase selector

When two or more cameras are used, set this selector so that the SC phase difference between the gen-lock input and video output signals to 0° or 180°

Screw holes for camera mounting
(U 1/4" —20 UNC) (See page 1-10.)



6 REMOTE (remote control) connector (BNC type)

Connect to the REMOTE connector of a CMA-10/10CE camera AC adaptor (optional), so that the white balance and the pedestal level can be adjusted by the camera AC adaptor. For details on the pedestal level adjustment, refer to the CMA-10/10CE's instruction manual.

Notes

- When the camera's REMOTE connector is connected to the CMA-10/10CE's REMOTE connector, the white balance adjustment cannot be made by the camera.
- If you wish to cancel the white balance control by the camera AC adaptor and to adjust the white balance by the camera, first turn off the camera AC adaptor, then, disconnect the cable connecting the REMOTE connectors.

If the connecting cable is disconnected with the camera AC adaptor powered, the camera's white balance adjustment function will be inoperative. In this case, first turn off the camera AC adaptor, and after a few seconds, turn on the adaptor once again, so that the adjustment function will be operative.

7 LENS connector (4-pin)

Connect the lens connector plug of the VCL-08Y or VCL-16Y auto iris lens (optional) here. For details about the lens, refer to the lens' instruction manual.

8 ==DC IN (input) / VIDEO OUT (output) connector (BNC type)

Connect the ==DC OUT/VIDEO IN connector of the CMA-10/10CE camera AC adaptor (optional) here. Through a single coaxial cable, the power is supplied to the camera and the video output signals from the camera are transmitted to the camera AC adaptor.

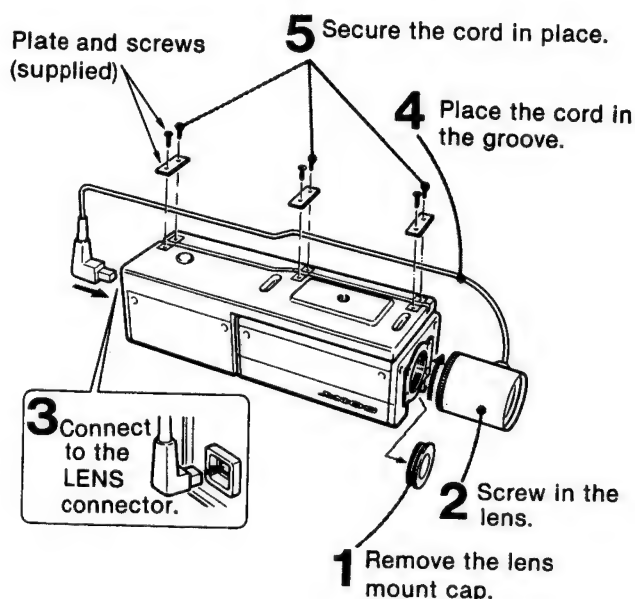
9 GEN LOCK IN (input) connector (BNC type)

Connect the gen-lock input signal (VBS or BS) for synchronization. No connection is necessary when only one camera is used.

1-2-3. INSTALLATION

•LENS ATTACHMENT

Mount the lens following Steps 1 to 5 in order.



To change the position of the mounted lens, refer to the lens' instruction manual.

•CAMERA INSTALLATION

To install the camera on a wall or ceiling, attach the camera to a support or to a mounting bracket by using a screw which matches the screw holes in the camera (U 1/4"–20 UNC).

Be sure to use the screw specified below.

ISO standard: $\ell = 4.5 \text{ mm} \pm 0.2 \text{ mm}$

ASA standard: $\ell = 0.197 \text{ inches}$



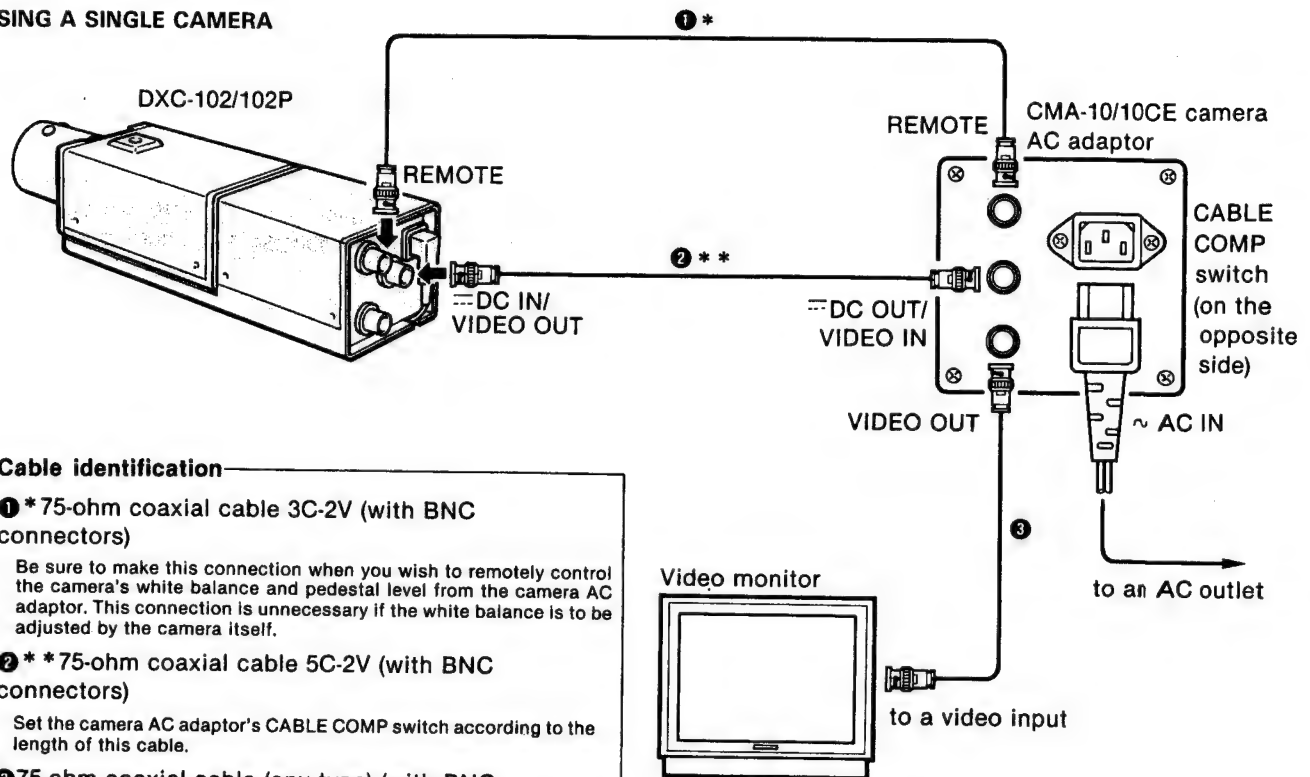
Caution on installation

Do not install the camera in:

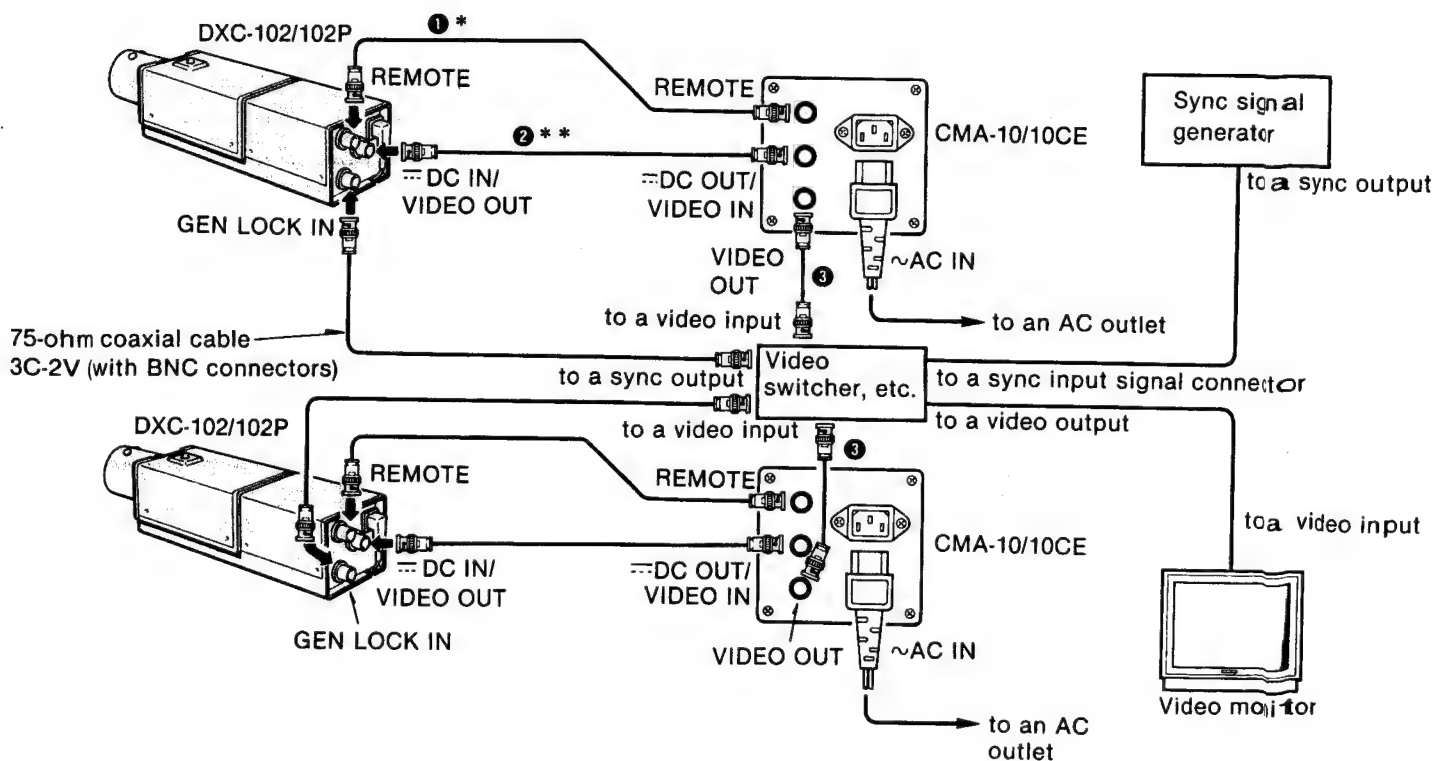
- An extremely hot or cold location. (Operating temperature: 0°C to 40°C or 32°F to 104°F)
- A location exposed to rain, high humidity or dust.
- A location subject to strong vibrations. (Resistance to vibration: 7G. Resistance to shock: 70G)
- A location near TV or radio station which radiates strong signals.

1-2-4. CONNECTIONS

•USING A SINGLE CAMERA



•USING TWO OR MORE CAMERAS



Use of the GEN LOCK IN connector

When two or more cameras are to be used in connection with a video switcher, a special-effects generator or a similar equipment, etc., and each camera picture selected by the switcher is to be observed on the same video monitor, supply each camera with the same reference signal to obtain the same picture tone. Connect a sync signal generator to the GEN LOCK IN connector to supply a reference signal (VBS or BS) to each camera, so that all the cameras are synchronized to this signal.

Adjustment of the picture tone for two or more cameras

When two or more cameras are used in connection with a video switcher, a special-effects generator or a similar equipment, supply each camera with a reference signal and adjust each camera to obtain the same picture tone. Adjust the SC (subcarrier) phase and the H (horizontal) phase following the procedure described below.

Subcarrier phase adjustment

Adjust the subcarrier phase roughly with the SC phase selector, then, make the fine adjustment using the SC PHASE control. A vectorscope will allow you to make the adjustment more easily.

Horizontal phase adjustment

Adjust the horizontal phase with the H PHASE control. A waveform monitor or an oscilloscope will allow you to make the adjustment more easily.

1-2-5. OPERATION

1) PREPARATION

- Check that all the units are connected properly.
- Set the POWER switch of the CMA-10/10CE to ON to turn on the camera.
- Turn on the video monitor, and adjust its controls properly.
- Set the camera's GAIN selector to 0 dB.
- Illuminate the subject properly.
- If a manual iris control lens is used, adjust the iris depending on the lighting conditions.

2) WHITE BALANCE ADJUSTMENT (for lifelike color reproduction)

There are two ways to adjust the white balance :

To adjust the white balance to the values preset at the factory

Select the position of the WHITE BAL selector depending on the lighting conditions.

Selector position	Label indication	Lighting conditions
1	3200°K (color temperature)	Iodine lamp, sunrise, sunset
2	INDOORS	Fluorescent light
3	OUTDOORS	Under a clear sky

Automatic white balance adjustment

(For the best possible color tone given under the lighting conditions)

- 1 Set the WHITE BAL selector to AUTO.
- 2 Shoot a white object (a white cloth or a white wall) with the camera so that the white object fills the screen.
- 3 Press the AUTO WHITE BAL button. When the automatic white balance adjustment is completed, the indicator lights up for a few seconds.

The white balance adjustment function may not operate in the following lighting conditions:

If the lighting is insufficient, the AUTO WHITE BAL indicator will not light up. This signifies that the white balance cannot be adjusted properly.

If the lighting is excessive, the AUTO WHITE BAL indicator will light up, even if the white balance cannot be adjusted properly. In this case, the entire monitor screen turns greenish to indicate that the white balance adjustment cannot be made properly.

In both cases, try to adjust the white balance again as follows.

When an auto iris lens is used :

If the lighting is insufficient, increase the lighting and press the AUTO WHITE BAL button again.

When a manual iris lens is used :

If the lighting is insufficient, open the iris or increase the lighting ; if the lighting is excessive, stop down the lens. Then press the AUTO WHITE BAL button again.

Memory of the automatic white balance adjustment value

In the DXC-102/102P, a built-in memory stores the adjusted white balance value. The memorized value will be retained for about 24 hours after the power is turned off without any further power supply to the camera or until the adjustment is made again.

3) VIDEO OUTPUT LEVEL SELECTION

The video output level can be adjusted with the GAIN selector.

AUTO: Set the selector to this position when the lighting conditions are subject to change, as in conditions outdoors. The video output level is automatically adjusted according to the lighting conditions.

0 dB: Generally, set the selector to this position.

6 or 12 dB: The video output level is raised by 6 dB or by 12 dB depending on the position of the selector. When the lighting is insufficient and the picture observed on the monitor is too dim, set the selector to one of these positions.

After the white balance and video output level adjustments have been completed, shoot an object with the camera and observe the picture on the monitor screen. Then focus the lens.

Once these adjustments have been completed, no further adjustments will be necessary unless the lighting conditions and the distance to the object change. To monitor the picture again after the camera and other units have been turned off, just turn on the equipments.

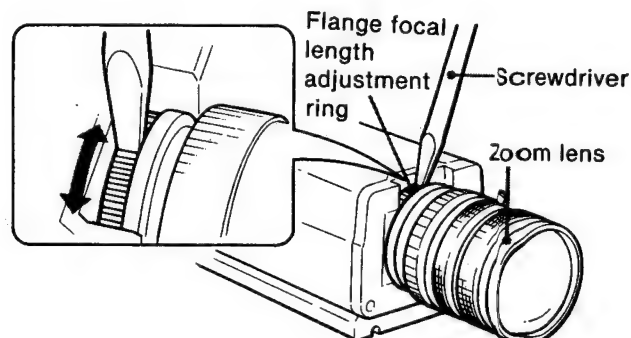
1-2-6. FRANGE FOCAL LENGTH ADJUSTMENT

When a zoom lens is used with this camera, flange focal length adjustment ensures that the object is in focus both at the wide-angle position and at the telephoto position when zooming. Once the flange focal length adjustment has been made, readjustment is unnecessary as long as the lens stays mounted on the same camera.

Focus on an object with fine detail to adjust the flange focal length.

Procedure

- 1 When a manual iris lens is used, set the iris fully open.
When an auto iris lens is used, illuminate an object so that the iris is fully open.
- 2 Point the camera at an object about 3 meters (10 feet) from the camera.
- 3 Set the zoom to the telephoto position.
- 4 Turn the focus ring to adjust the focus.
- 5 Set the zoom to the wide-angle position.
- 6 Turn the flange focal length adjustment ring of the camera until the same object is in focus. Do not turn the focus ring.

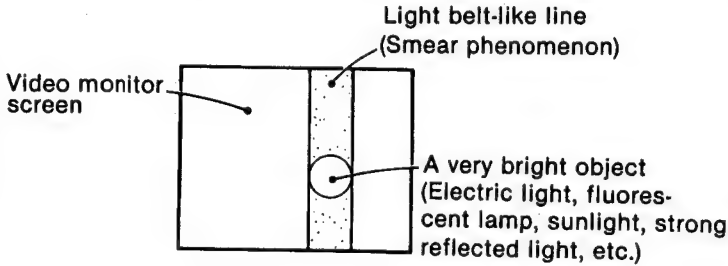


- 7 Repeat Steps 3 to 6 until the object is in focus while the zoom is in both the telephoto position and the wide-angle position.

1-2-7. SPECIAL CHARACTERISTICS OF A CCD

Smear phenomenon

A smear may appear when a very bright object is shot.



Patterned noise

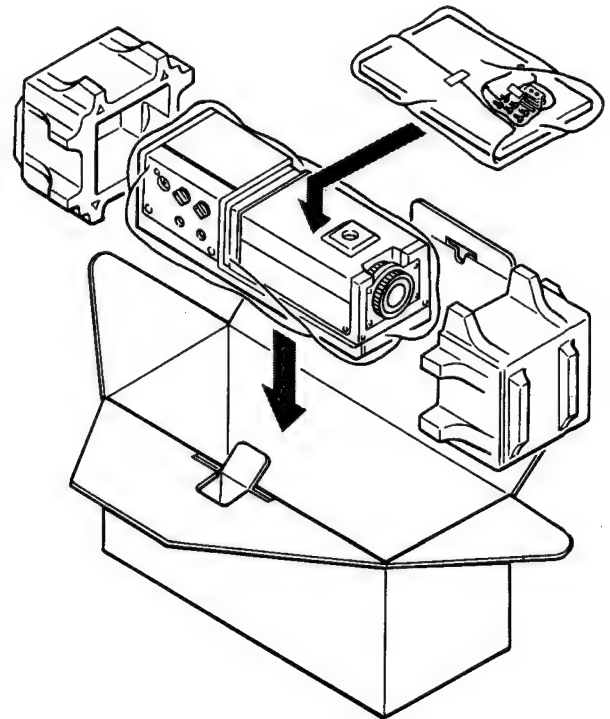
This may appear uniformly over the entire monitor screen when the camera is operated at a high temperature.

Wavy picture

This may appear when fine stripes, straight lines, etc. are shot. The image monitored on the screen may appear wavy.

1-2-8. REPACKING FOR SHIPMENT

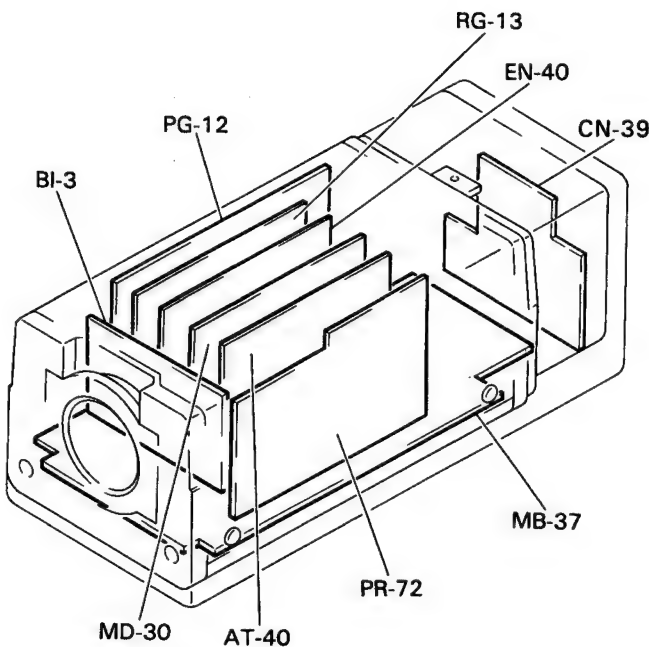
The repacking procedure is subject to change. Refer to the packing instructions on the original carton, as well as those shown here.



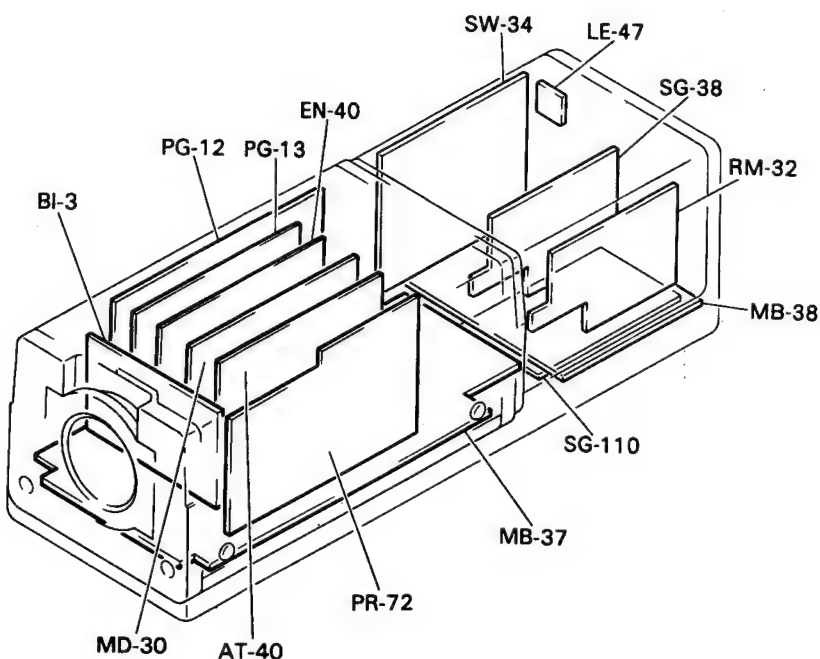
SECTION 2
SERVICE INFORMATION

2-1. BOARD LAYOUT

DXC-101/101P



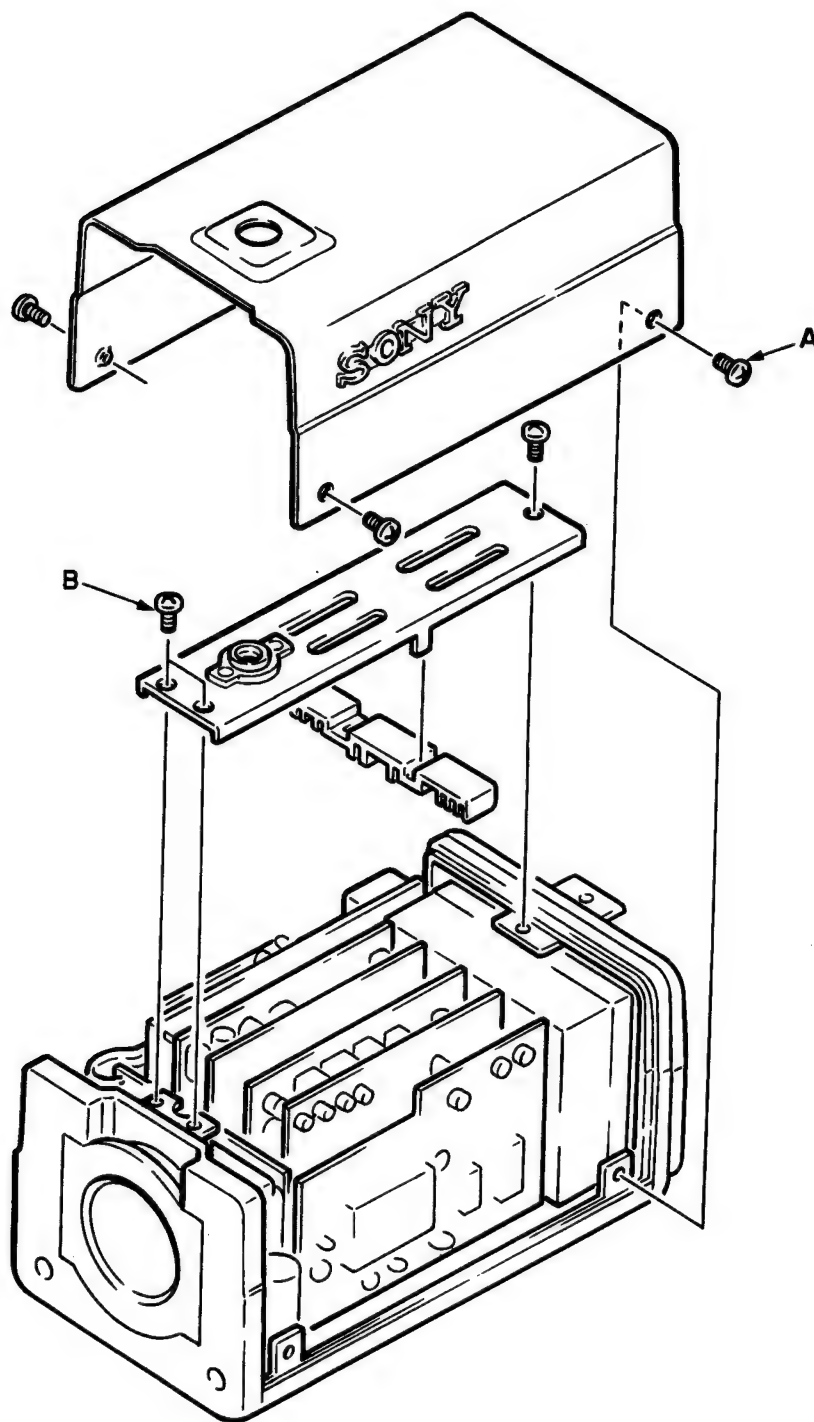
DXC-102/102P



2-2. REMOVAL OF CABINET

Remove the four screws A (PRECISION +P2x3) and remove the camera cover.

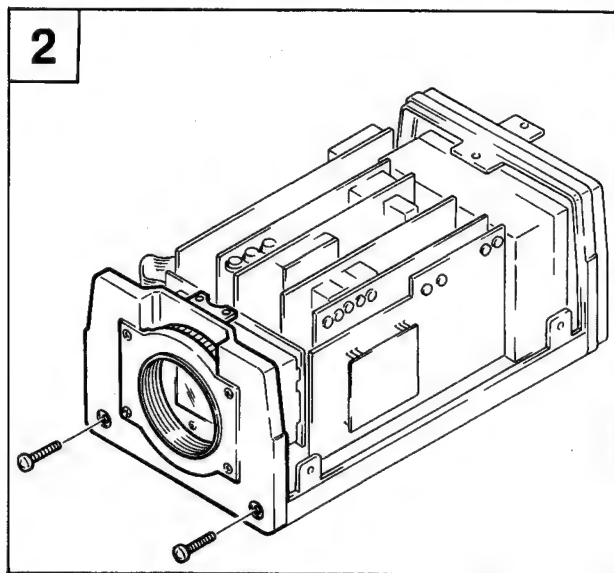
Remove the three screws B (PRECISION +P2x3) which hold the SPAN ASSY and remove the SPAN ASSY and board holder.



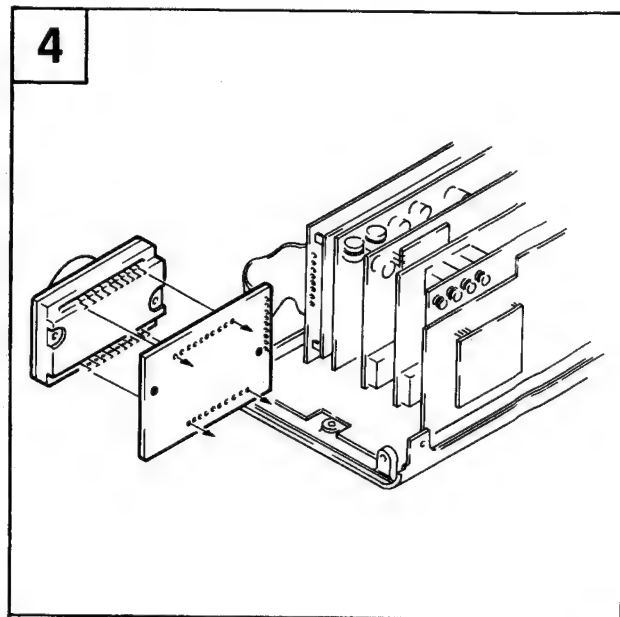
2-3. REPLACEMENT OF MAIN PARTS

2-3-1. REPLACEMENT OF CCD ASSY

1. Remove the cabinet referring to 2-2. REMOVAL OF CABINET.
2. Remove the two screws which hold the front panel.

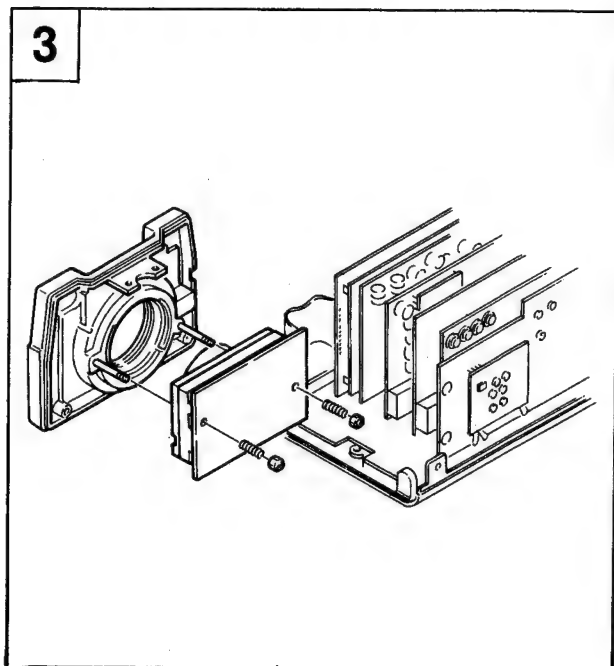


4. Remove pins 1 - 20 of IC on the BI-3 board by using a desoldering tool.

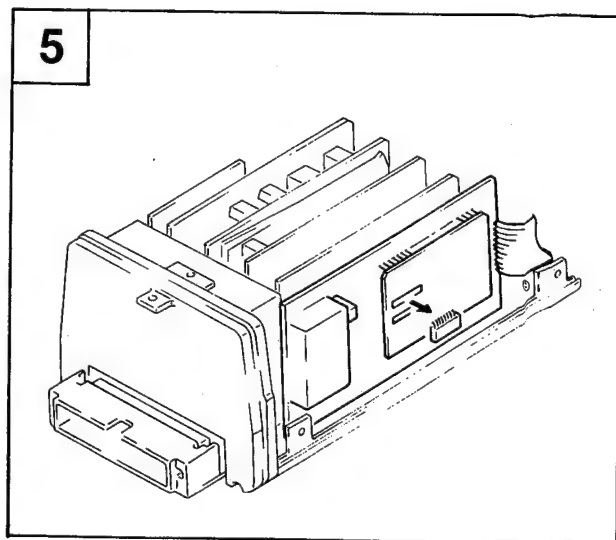


3. Remove the hexagonal screw shown in the figure below.

When the board is pulled in the direction shown by the arrow, the CCD ASSY can be removed from the front panel.



5. When the CCD ASSY is replaced, be sure to replace the ROM IC with a new one attached to a CCD ASSY for repair. Take out the ROM IC (MB7052) of the IC on the PG-12 board. Place "solderwick" on the pins of the ROM IC and apply a soldering iron on it sufficiently so that it will absorb solder. To prevent the pattern from peeling off, do not pull it with tweezers or pliers.



6. Install a new CCD ASSY in opposite procedures of the disassembly. When the ROM IC is installed, use a soldering iron with temperature controller in order to prevent damage to the CCD.

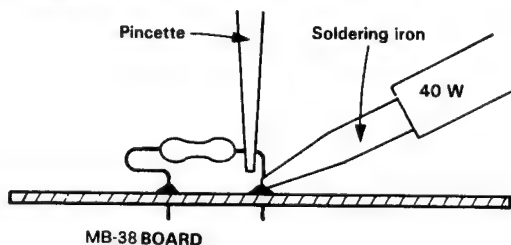
Place a new ROM IC on the home position and solder legs of the ROM IC one by one.

1. Apply a soldering iron on a leg for 7 - 10 seconds to heat up the leg and board.
2. After soldering, keep applying the solder iron for 4 - 5 seconds.

2-3-2. CAUTION OF FUSE REPLACEMENT

Applying too much heat may burn out fuses used in the camera module and the GENLOCK unit. In case the fuse is replaced. Cut the lead of the fuse so that rather long lead wire remained with the fuse. Then hold the lead by a metal pincette, and solder the fuse quickly as shown below.

Please avoid any mechanical stress to the fuse when you bent the leads.



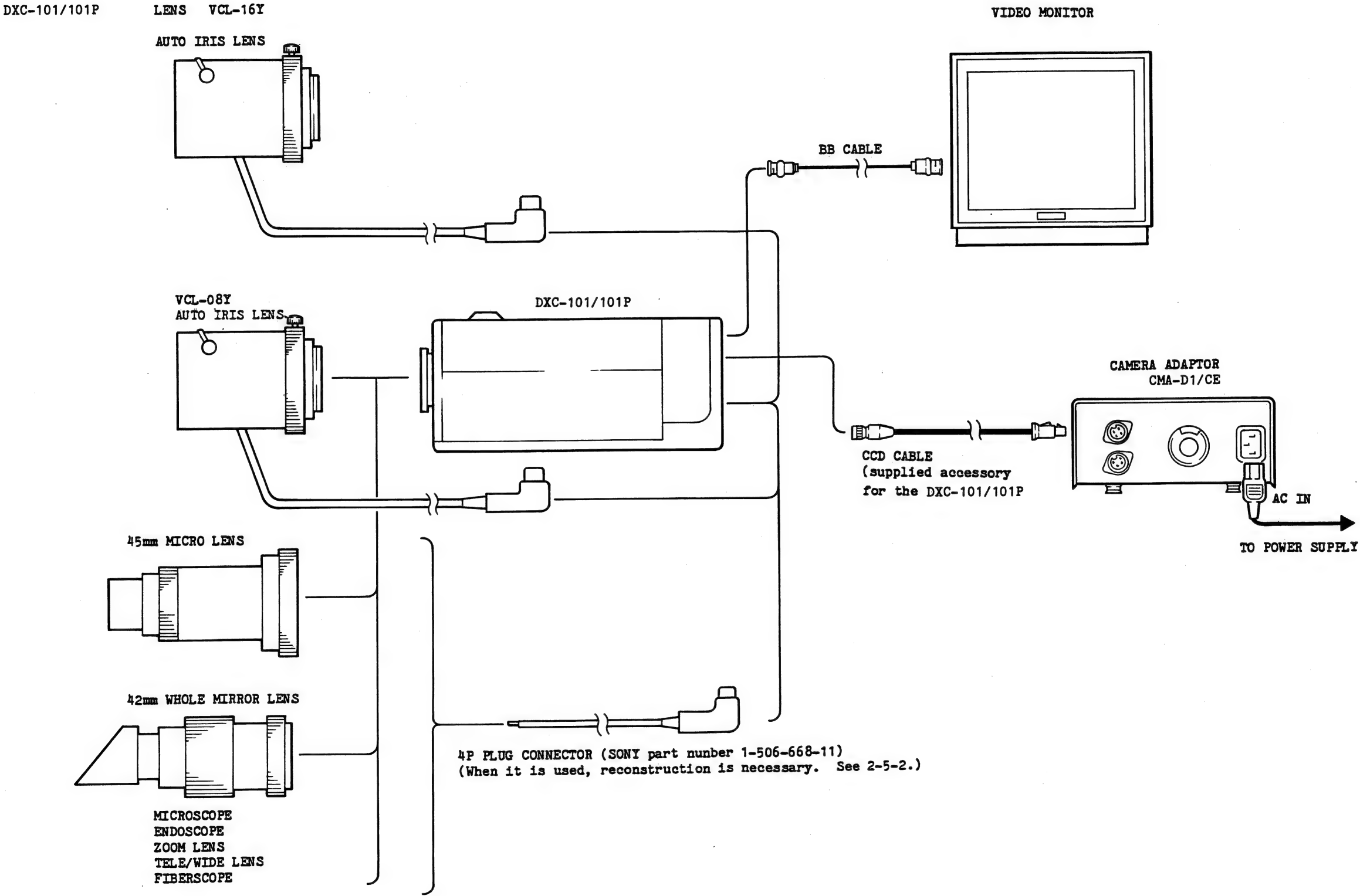
2-4. COMPATIBLE CONNECTORS AND CABLES

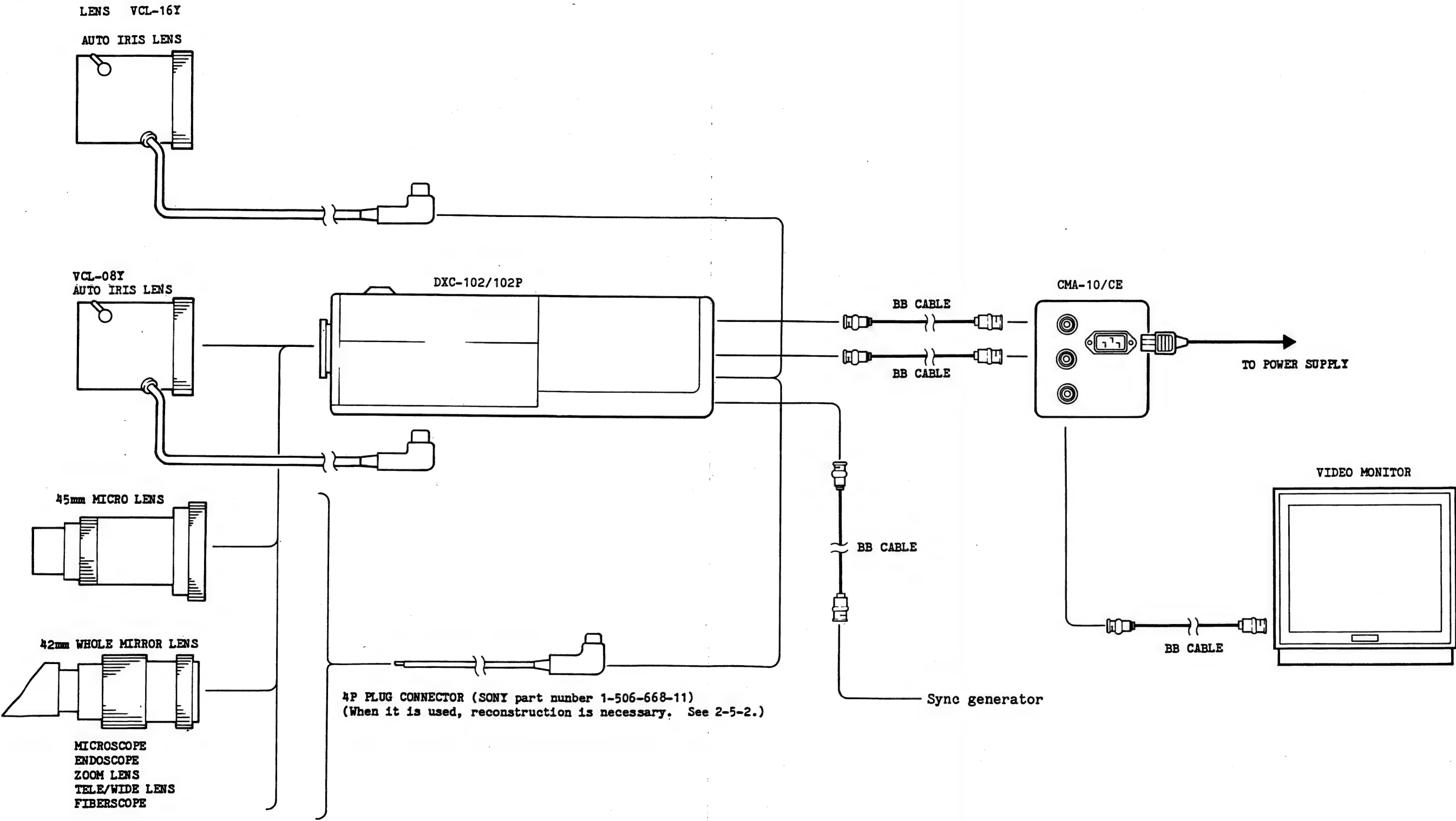
Attach the following connectors or equivalents to the ends of the cables to be connected on the connector panel during at installation or maintenance service.

DXC-102/102P function names	Connector names and part numbers of the connectors on the ends of the connection cables
VIDEO OUT, BNC REMOTE IN, BNC GENLOCK IN, BNC	BNC 1-508-898-00 B B CABLE (optional)
LENS 4P, FEMALE	LENS CONNECTOR 1-506-668-11 (When a lens, except for VCL-08Y or VCL-16Y is installed, modification is necessary. See 2-5-2.) CABLE with CONNECTOR 1-558-489-11

DXC-101/101P function names	Connector names and part numbers of the connectors on the ends of the connection cables
DC IN 4P, MALE	DIN(4P) PLUG 1-560-246-11 ROUND CONNECTOR, FEMALE (12P) 1-562-356-00 CCDC-10 1-557-668-12 (supplied accessory for DXC-101)
LENS 4P, FEMALE	LENS CONNECTOR 1-506-668-11 (When a lens, except for VCL-08Y or VCL-16Y is installed, modification is necessary. See 2-5-2.) CABLE with CONNECTOR 1-558-489-11
VIDEO OUT, BNC	BNC 1-508-898-00 B B CABLE (optional)

2-5. CONNECTION
 2-5-1. SYSTEM BLOCK DIAGRAM

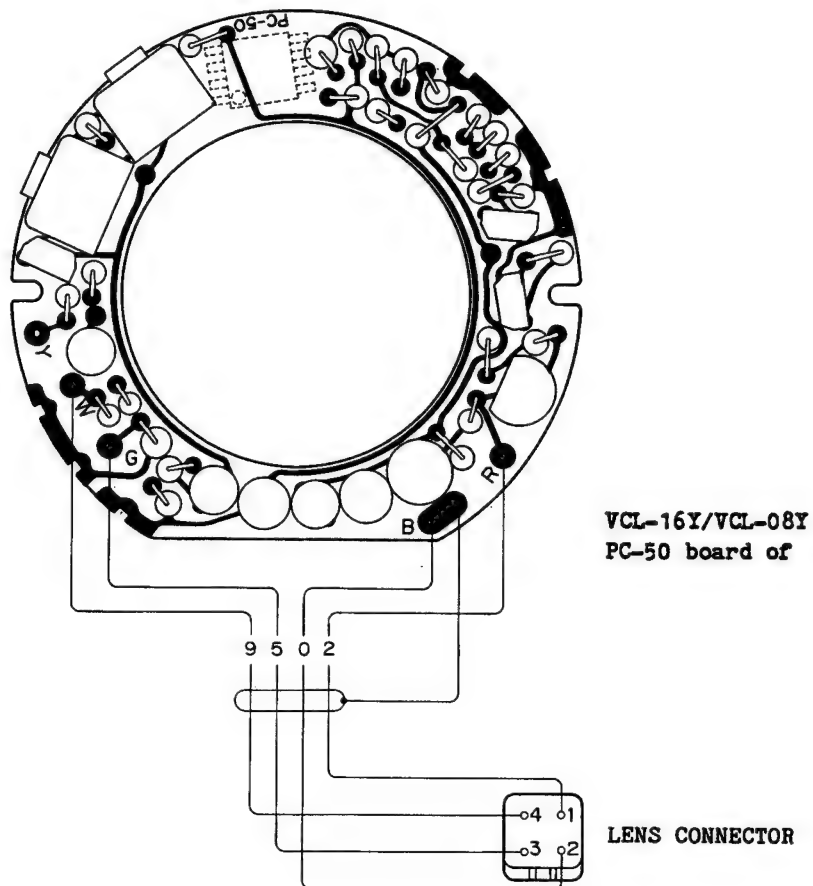




2-5-2. MODIFICATION OF LENS CONNECTOR, EXCEPT FOR VCL-16Y OR VCL-08Y

When another lens is used, connect the lens connector to the lens cable referring to the cable wiring diagram shown below.

VCL-16Y/VCL-08Y LENS (CABLE WIRING DIAGRAM)



CONNECTOR INPUT/OUTPUT SIGNAL

PIN No.	WIRING COLOR CODE	SIGNAL NAME	CONNECTED TERMINAL
1	2	+12V IN	+12V IN Terminal on a board in anoter lens.
2	0	GND	GND IN Terminal on a board in anoter lens.
3	5	REMOTE IN/OUT	REMOTE IN/OUT Terminal on a board in anoter lens.
4	9	VS IN	VS IN Terminal on a board in anoter lens.

2-6. INFORMATION ON MAINTENANCE SERVICE

2-6-1. NOTES ON REPAIR PARTS

- 1) Printed Components in bold-face type on the spare parts list are normally stocked for replacement purposes. The remaining parts are not normally stocked for routine service work. Orders for parts not shown in bold-face type will be processed, but allow for additional delivery time.
- 2) Components identified by shading marked with on the exploded view and spare parts list are critical to safe operation. Replace these components with Sony parts whose part numbers appear in the manual or service bulletins and service manual supplements published by Sony.
- 3) Replacement parts that are supplied from the Sony Parts Center can sometimes have a different shape and external appearance than what are actually used in equipment. This is due to "accommodating the improved parts and/or engineering changes" or "standardization of genuine parts".

2-6-2. HANDLING OF ROM IC ATTACHED TO A CCD ASSY

When the following components are replaced, be sure to replace a ROM of hybrid IC on the PG-12 board.

- 1) When the CCD ASSY is replaced.
Replace the ROM with a new one attached to a CCD ASSY for repair.
(See 2-3. REPLACEMENT OF MAIN PARTS)
- 2) When the PG-12 board is replaced.
Move the ROM of hybrid IC to a new PG-12 board.

2-6-3. PRECAUTIONS

Avoid operating and storing the camera in the following locations.

- Extremely hot or cold places (The operating temperature is from 0°C to +40°C.)
- Places subject to humidity or excessive dust
- Places subject to strong vibration
- Places near an antenna which transmits a strong electromagnetic wave.

Avoid covering the camera with a cloth or similar items while an operation to prevent raising the temperature in the camera because it is being badly ventilated.

Note on transporting

Do not discard the carton. It affords maximum protection whenever the camera is transported by track, ship, or plane. Repack it as it was originally packed.

Note on cleaning

Clean the cabinet or panel with a dry soft cloth or soft cloth lightly moistened with mild detergent solution.

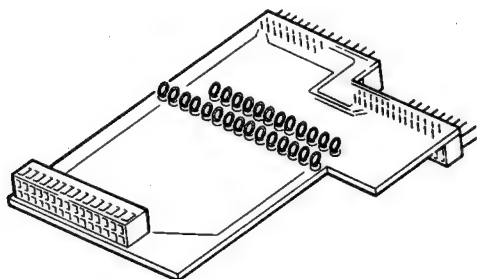
Do not use solvents such as alcohol, benzine, thinner, or insecticide as the finish may be damaged.

2-6-4. Caution when replacing the CCD image sensor

1. To prevent the static electricity shock
The CCD image sensor is easily destroyed by the static electricity.
When handling this device, prevent the static electricity shock as follows.
 - a) Work with bare hands or wearing non-electrified gloves, and wearing non-electrified clothes so as to prevent the static electricity.
 - b) Install an earth board or an earth wire on a floor, a table and a door in a workshop so as to discharge the static electricity.
 - c) Earth tools such as a screw drives, long nose pliers, a tweezer and a soldering iron.
 - d) Earth a worker by wearing an earth band.
 - e) The CCD image sensor is recommended to be discharged by spraying ionized air.
2. Window Glass
When dusts or soils stick to the surface of the glass, black spots appear in the picture. Keep the window glass clean.
 - a) Wipe off dusts and soils with soft cloth or cleaning paper which contains a little organic solution such as alcohol, and spray ionized air.
 - b) Just before use, peel off a protection tape which has been stuck to the glass at the factory after performing "1. To prevent the static electricity shock". Don't use the stripped tape again.

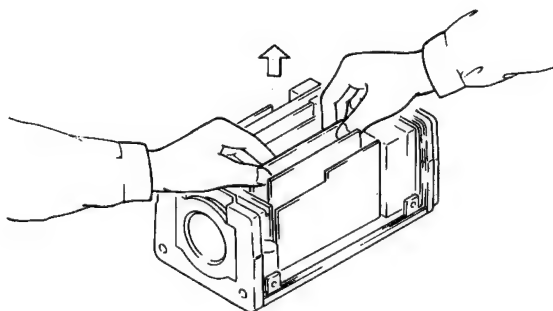
2-7. SERVICE JIG

Extension board : EX-97 (J-6028-450-A)
It is used for the alignment of the MD-30 and EN-40 boards. If two extension boards are prepared, the MD-30 and EN-40 boards can be aligned correctly at the same time.



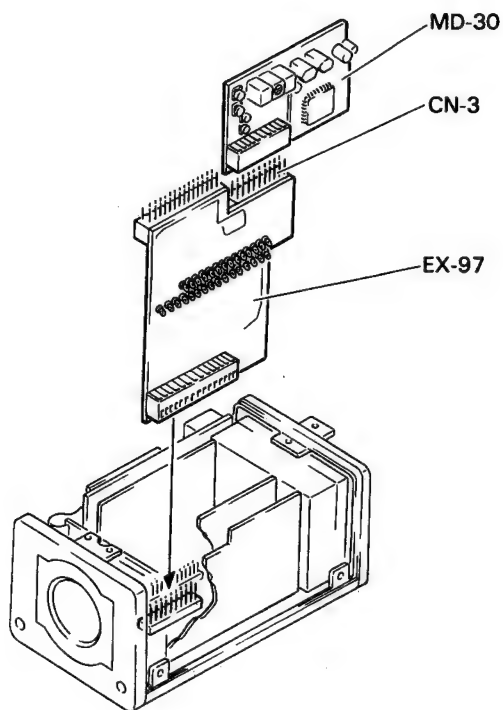
[INSTALLATION OF EXTENSION BOARD EX-97]

1. Remove the cabinet referring to 2-2. REMOVAL OF CABINET.
2. Hold the ends of the board and pull up MD-30, EN-40 boards as shown in the figure.

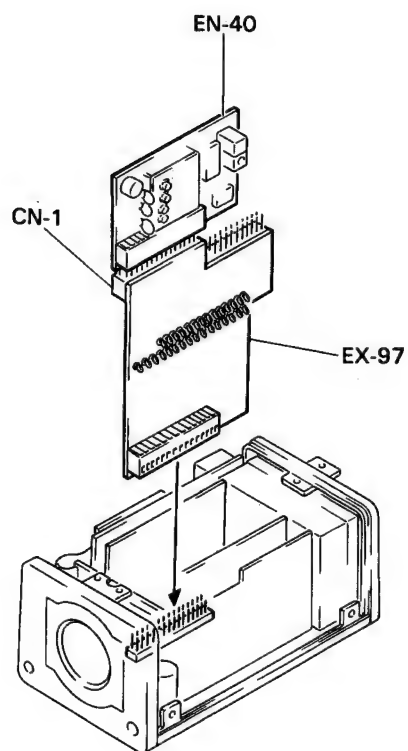


3. Insert the EX-97 board.

Insert CN1 on the MD-30 board to CN3 on the EX-97 board.



Insert CN1 on the EN-40 board to CN1 on the EX-97 board.



SECTION 3 THEORY OF OPERATION

3-1. Operation principle of the CCD

A CCD (Charge Coupled Device) consists of MOS (Metal-Oxide-Silicon) capacitors arranged in a regular array. It basically performs three functions connected with handling electrical charges.

1. Photoelectric conversion (photo sensor)

Incident light generates electrical charges on the MOS capacitors, with the quantity of charge being proportional to the brightness.

2. Accumulation of electrical charges

When a voltage is applied to the electrodes of the CCD, an electrical potential well is formed in the silicon layer. The electrical charge is accumulated in this well.

3. Transmission of electrical charge

When a high voltage is applied to the electrodes, a deeper well is formed; when a low voltage is applied, a shallower well is formed. In the CCD, this property is used to transmit electrical charge. When a high voltage is applied to the electrodes, a deep electric potential well is formed, and electrical charge flows in from neighboring wells. When this is repeated over and over among the regularly arranged electrodes, the electrical charge is transferred from one MOS capacitor to another.

This is the principle of CCD electrical charge transmission.

3-2. Mechanism of CCD electrical charge transmission

The DXC-101/102 camera uses a 4-phase drive method CCD in practice. For simplicity, a 2-phase drive method CCD is explained below.

Figure 1 shows an example of the changes which can occur in potential wells in successive time intervals.

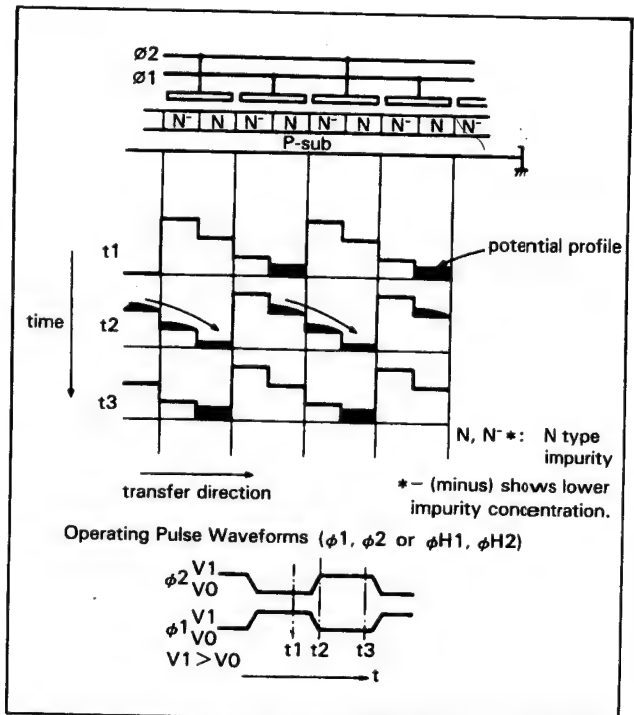
At t_1 , the electrode voltages are $\phi_1 > \phi_2$, so the potential wells are deeper toward the electrode at the higher voltage ϕ_1 .

Electrical charge accumulates in these deep wells. At t_2 , the clock voltages ϕ_1 and ϕ_2 are reversed; now the wells toward the electrode at voltage ϕ_2 are deeper while those toward the electrode at voltage ϕ_1 are shallower. Since the wells toward the electrode at ϕ_2 are deeper than those toward the electrode at ϕ_1 , the signal charge flows toward the deeper wells toward the electrode at voltage ϕ_2 . At t_3 , the electrode voltages have not changed since t_2 , so the signal charge flows into the wells toward the electrode at ϕ_2 , and one transmission of electrical charge is completed. This action is repeated over and over to execute the horizontal and vertical transmissions.

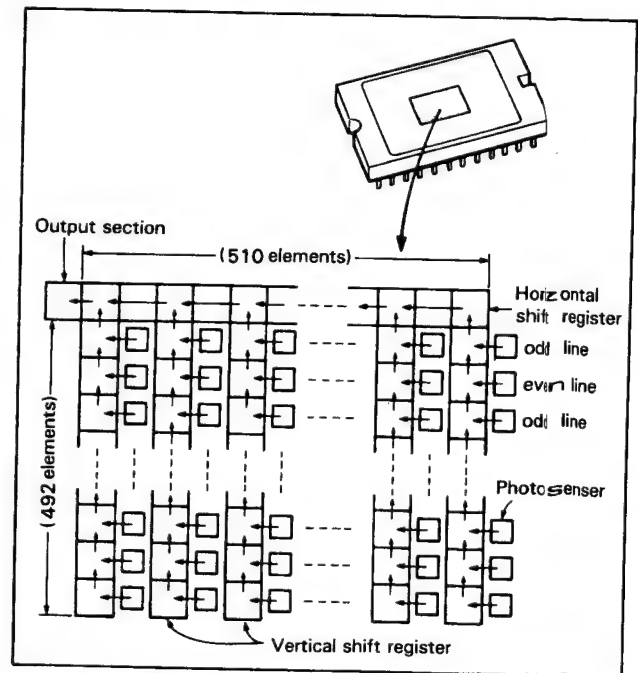
3-3. The interline-transfer organization of the CCD image sensors

The DXC-101/102 CCD video camera module adopts an interline-transfer organization in which precisely aligned photosensors and vertical Transmission section are arrayed interlinearly and a horizontal shift register links up with the vertical Transmission section. Light variations are sensed by the photosensors, which generate electronic

charges proportional to the light intensity. The generated charges are fed into the vertical shift registers all at once. The charges are then transferred from the vertical Transmission section to the horizontal shift registers successively and finally reach the output amplifier to be read out successively.



[Fig. 1] The interline-transfer organization of the CCD image sensors



[Fig. 2] Two Phase CCD Charge Transfer

3-4. BI-3 board

Light which comes through the camera lens strikes the CCD chip surface of IC1 on the BI-3 board. The surface of the CCD chip contains a number of photo sensors. The photo sensors are arranged in a 510 (horizontal) X 492 (vertical) array, so that there are a total of 250,920. Incident light is converted to an electrical signal with the amplitude (electric charge analog amount) at the photosensor section in proportion to the brightness of the light. The converted electric charge is read out by the transfer section from the photosensor, and is transferred in sequence and fed to the output section.

The transfer section is subdivided into horizontal and vertical transfer sections.

Figure 2, in the figure below, there are 510 vertical transfer sections, while there is only one horizontal transfer section, across the top. Each converted electric charge is transferred to the transmission element (vertical transmission element) immediately to the left of it.

The electric charge on each vertical transfer section are transferred in sequence, from the bottom to the top of the screen, at a frequency determined by the vertical transfer clock f_v . At the top there is the horizontal transfer section.

The horizontal transfer section sends electrical signals to the output section at a rate of 455 f_h .

The capacitor in the output section converts the electrical charge to a voltage signal; it is then output from the IC1, passed through the buffer Q1 and sent to MB-37 board.

3-5. MB-37 board

The signal from the BI-3 board output by the CCD chip is separated into two signal paths. The signal of one path is sampled by the sample and hold pulse (SHP), the signal of the other path is sampled by two different sample and hold pulses (SHD and SHP), and these signals are converted into video signals. The output signal of a CCD chip used as an image photo sensor includes inherent noise, and these sample and hold circuits remove most of this noise.

The SAMPLE and HOLD circuits and DC-DC converter are on this board.

If an element of the CCD chip is defective, its output is not sampled, but is replaced by the last sampled signal.

Each signal then goes to the differential amplifier, and the output signal goes to the PR-72 board.

The externally supplied DC from the CN-39 board is converted into four different DC voltages by the DC-DC converter: +20 V, +8.5 V, +5 V, and -5 V. These voltages are supplied to each board.

3-6. PR-72 board

The video signal processing circuits are on this board.

The processing circuits convert the output signal of the CCD chip into several control signals and into gamma-corrected G and R/B signals.

The signal from the MB-37 board output by the CCD chip is gain controlled by the gain control signals (AGC CONT, G1, and G2), then this gain-controlled signal is separated into two signal paths. The signal of one path is not processed on this board, but goes directly to the AT-40 board as the IRIS DET signal, which is the controlled lens iris data.

The signal of the other path is automatically gain controlled in the AGC circuit, then it is separated into two signal paths. Here, the signal of one path goes directly to the AT-40 board as the AGC DET signal, which is the controlled auto gain data. The signal of the other path, which is to be used as the video signal, is separated into G and R/B signals.

These G and R/B signals are mixed, then the mixed signal is applied to the color mixing correction, white balance control, and clamping circuits. This signal is separated into two paths. The signal of one path goes directly to the AT-40 board as the G DET signal, which is the controlled G signal data. The signal of the other path is applied to the blanking mixer, pedestal adder, gamma correction circuit, and white clip circuit; then it goes to the MD-30 board as the G γ signal.

The white balance for each R or B signal is respectively performed by the R or B attenuator control signal from the MB-37 board. Each signal is clamped, off-set controlled, then switched line-by-line by the multiplexer so that the R and B signals are alternately output as a sequential signal. This signal is separated into two signal paths. The signal of one path goes directly to the AT-40 board as the R/B DET signal, which is the controlled R/B signal data. The signal of the other path is applied to the blanking mixer, pedestal adder, gamma correction circuit, and white clip circuit; then it goes to the MD-30 board as the R/B γ signal.

3-7. MD-30 board

The KNEE control circuits for the G and R/B signals are on this board. The 1H delay line circuits, which delay the signals by 1H or 2H, and the matrix circuits for the Y, Y-I, Y-R-Y, and B-Y signals are also on this board.

The G γ signal from the PR-72 board is applied to the knee clipper and the clamping circuits, then it is separated into two signal paths. The signal of one path is directly output as the original G signal, and the signal of the other path is delayed by the 1H delay line. This delayed signal is clamped, gain controlled, then separated into two signal paths. Here, the signal of one path is directly output as the 1H delayed G signal, and the signal of the other path is again delayed by the same 1H delay line. This 2H delayed signal is clamped, gain controlled, then output as the 2H delayed G signal. As described here, the G1 signal is delayed to produce the following three signals, which have different timings: 0H delayed (G0), 1H delayed (G1), and 2H delayed (G2) signals.

The R/B signal from the PR-72 board is also processed in the same way to produce 0H delayed (R0/B0), 1H delayed (R1/B1), and 2H delayed (R2/B2) signals.

Then, the G0 and R0/B0 signals, the G1 and R1/B1 signals, and the G2 and R2/B2 signals are applied to the subtractors to output the G0-R0/B0, G1-R1/B1, and G2-R2/B2 signals.

The G0 and G1 signals, and the R0/B0 and R1/B1 signals are applied to the Y_H matrix circuits and mixed to be two signals. These two signals are mixed to be the Y_H signal.

The undesired sampling noise in the Y_H signal is filtered by the low-pass filter, then the filtered signal goes to the EN-40 board.

Both the G1-R1/B1 signal and the mixed signal of the G0-R0/B0 and G2-R2/B2 signals are applied to the multiplexer, and the R and B signals are switched line-by-line with the ID signal to output the G-R and G-B signals. Each of these signals is separated into two signal paths. Each signal of one separated path is applied to the chroma matrix circuits to output the R-Y and B-Y signals. These signals are gain controlled, then go to the EN-40 board. Each signal of the other separated path is applied to the Y_L matrix circuit with the G1 signal to be one signal. This signal is mixed with a signal resulting from a mixture of the G0, G1, and G2 signals and the aperture correction in the vertical direction. The signal processed here is compared with the Y_H signal, then goes to the EN-40 board as the Y_L signal.

3-8. EN-40 board

The encoders are on this board.

The R-Y and B-Y signals from the MD-30 board are clamped modulated by the balanced modulators, then mixed to become the chrominance signal. After passing through the burst signal adder, this signal is applied to the chroma balanced mixer.

The Y_H signal from the MD-30 board is clamped, then delayed by 150 ns. After this, aperture correction is performed. This signal is then mixed with the clamped Y_L - Y_H signal from the MD-30 board. Next, the signal is applied to the gain controller, blanking cleaner, setup circuit, and white clip circuit; then it is separated into two signal paths. The signal of one path is mixed with the chrominance signal in the chroma balanced mixer, previously described. For this signal, the undesired Y signal components are filtered by the band-pass filter. After this, blanking mixing is performed with the HD signal, and this signal is mixed with the signal of the other path.

This mixed signal is separated into two signal paths. The signal of one path is clamped, then goes to the MB-37 board as the video output signal (VBS). A sync signal is added to the signal of the other path, then this signal also goes to MB-37 board as the VS (B/W) signal.

3-9. CN-39 board

The power-on reset circuit, auto white balance trigger signal generator, and auto white balance indicator signal generator are on this board.

The power-on reset circuit operates when power is supplied. This circuit prevents mal-operations of the auto white balance trigger signal generator and the auto white balance indicator signal generator caused by insufficient voltage supplied to the ICs or by noise when the power is switched on.

When manual white balance is performed, this power-on reset circuit is controlled by the WB1 and WB2 signals. Therefore, in this case too, this circuit prevents mal-operations of the auto white balance trigger signal generator and the auto white balance indicator signal generator.

The auto white balance drive signal, which is HIGH when the auto white balance button on the side of the camera unit is pressed, is applied to the auto white balance trigger signal generator. The output signal of this auto white balance trigger signal generator operates as a trigger signal to the auto white balance circuit. When the auto white balance adjustment is completed and the white balance becomes the specified value, the indicator control signal, which is used to indicate OK for the white balance completion, is fed from the AT-40 board. This signal is applied to the auto white balance indicator signal generator. The output signal of the auto white balance indicator signal generator controls and switches the auto white balance LED indicator on the side of the camera unit. The drive signals (GAIN1 and GAIN2) from the gain switch on the side of the camera unit go directly to the PR-72 board. The VBS and VS (B/W) signals go directly to the VIDEO OUT connector and to the LENS connector on the back of the camera unit respectively.

3-10. PG-12 board

The sync signal generator (IC1) and the pulse generator (IC2) which is necessary to drive the CCD chip are on this board.

In the IC1 circuit, the VCO control signal from the RG-13 board is used as a clock signal to generate the following signals:

BLKG: Horizontal and vertical blanking signals

SYNC: Horizontal and vertical sync signals (composite sync)

CK: 910 kHz clock pulse

HD and VD: Horizontal and vertical drive pulses

BF: Horizontal and vertical burst flag

O/E: $f_v/2$ pulse for detection of Odd/Even fields

These CK, O/E, and HD pulses generated by IC1 and the VCO control signal from the RG-13 board are applied to IC2 to generate the following signals:

H1 and H2: Horizontal shift register drive pulses
These two signals having different phases are used to drive the horizontal shift register of the CCD chip to transfer the electric charges stored in the horizontal shift register.

V1 to V4: Vertical shift register drive pulses
These four signals having different phases are used to drive the vertical shift registers of the CCD chip to transfer the electric charges stored in the vertical shift registers.

PG: Precharge gate control pulse
The precharge gate is the gate of the output section connected to the horizontal shift register of the CCD chip. This gate is controlled by this pulse to convert a transferred electric charge into a voltage.

SHP and SHD: These pulses are the sample and hold pulses to gate the output signal of the CCD chip.

H BLKG: This pulse is used to hold the horizontal flyback period of the output signal of the CCD chip.

VAA: This pulse is used to hold the vertical flyback period of the output signal of the CCD chip.

SH1 and SH2: These are the sample and hold pulses for the 1H delay line (MD-30 board).

SP1 and SP2: These are the sample and hold pulses for chrominance separation (PR-72 board).

CLP1: This pulse is used to clamp the level of the optical black part of the output signal of the CCD chip.

CLP2 and CLP3: These are the 1H period clamp pulses.

ID: This is the identification signal for the R/B lines.

B line: H

R line: L

3-11. AT-40 board

The AGC control signal generator, auto white balance controller, and auto white balance indicator driver signal generator are on this board.

The G DET signal derived from the G signal and the R/B DET signal derived from the R/B signal, which are fed from the PR-72 board, are clamped and their amplitude is doubled. For each signal, the signal in a time period, which is the same as for 1/9 of one field picture (1/3 in horizontal and 1/3 in vertical directions), is blanked by the BLKG signal, then the pedestal is added. These signals are compared with each other and output as the R-G COMP and B-G COMP signals, which are applied to the auto white balance controller circuit.

When the auto white balance trigger signal is applied to the auto white balance controller circuit, the R-G COMP and B-G COMP signals control the voltages used to control the corresponding chrominance signal attenuators, and these signals are output to the PR-72 board as the R and B attenuator control signals.

The AGC DET signal from the PR-72 board, used to detect the auto gain, is clamped and its amplitude is amplified by 3.3 times. Then, this signal is applied to the blanking cleaner and the pedestal adder.

After this, the signal is applied to the weighting amplifier so that the highlighting at the top part of a picture is not detected, then it is applied to the mean value detector. This detected signal is amplified by the DC amplifier, then goes to the PR-72 board as the AGC control signal.

When the level of the auto white balance trigger signal becomes HIGH, auto white balance adjustment is performed. When this adjustment is completed and OK is indicated, the level of the auto white balance indicator driver signal switches from H to L, then goes to the MB-37 board.

3-12. RG-13 board

The 4fsc signal generator, VCO control signal generator, and +12 V voltage regulator are on this board. To select an external or internal 4fsc signal or to select an internal or external VCO control signal is controlled by the EXT/INT signal.

The DXC-101/102 camera unit does not have a gen-lock unit; therefore, the level of the EXT/INT signal is kept LOW to select internally generated signals only. Of the internally generated signals, the frequencies of the 28 MHz VCO control signal for the NTSC system and of the 28 MHz 4fsc signal for the PAL system are adjusted on the RV2/RG-13 board.

The 4fsc output signal goes to the EN-40 board, and the VCO control output signal goes to the PG-12 board.

The MB-37 board supplies +20 V to this +12 V voltage regulator. For this regulator, +5 V is used as a reference voltage to regulate the +12 V output. This output voltage is supplied to the MD-30 and PG-12 boards.

3-13. MB-38 board (DXC-102/P only)

The GENLOCK DRIVER circuit and EXT 4fsc oscillator circuit are on the MB-38 board.

VBS, CK, SYNC, and SC signals from the camera module are sent to the GENLOCK DRIVER circuit. Then, the SC COMP signal, which is the output signal of the MB-38 board, goes to the SG-110 board. This SC COMP signal is converted to a VCO control signal on the SG-110 board, then returned to the MB-38 board. This VCO control signal drives the EXT 4fsc oscillator, and the EXT 4fsc signal goes to the camera module.

3-14. SG-38 board (DXC-102/P only)

The GENLOCK DRIVER circuit is on the SG-38 board. When a composite video signal is sent to the GENLOCK IN connector (BNC), the external sync mode is selected and the level of the GEN EXT/INT signal from pin 9 of IC1 becomes HIGH. The composite video signal sent to the GENLOCK IN connector (BNC) is sync-separated in the sync separator circuit of IC2 to output EXT CHROMA and EXT SYNC signals. The EXT SYNC signal is directly input to IC1 to send to the GENLOCK DRIVER inside the IC. The undesired Y-signal components of the EXT CHROMA signal are removed by the low-pass filter, composed of L4 and C5, then the signal is sent to IC1 to be converted to an EXT SC signal by the band-pass filter inside the IC. This EXT SC signal is sent to the GENLOCK DRIVER inside the IC.

The INT SC signal from the camera module is phase-shifted and its duty cycle is set to 50% in IC4 to output two signals having opposite phases. IC3 selects one of these signals and the selected signal is sent to IC1. The PHASE SHIFTER in IC4 is controlled by the SC PHASE controller on the GENLOCK unit side and the phase selection of the signals in IC3 is controlled by the SC 0°/180° selector.

The following signals, output from IC1, go to the SYNC GENERATOR inside the camera module when the NTSC/PAL selector mode signal and CK signal from the camera module are sent to IC1 with the signals described before.

HR: H-reset signal

VR: V-reset signal

L ALT R: L ALT reset signal (PAL model only)

H COM: H-phase comparator signal

SC COM: SC phase comparator signal

GEN EXT/INT: Detection signal for EXT/INT sync mode

H: External sync

L: Internal sync

When a composite video signal is not sent to the GENLOCK IN connector (BNC), the internal sync mode is selected. In this case, the level of the GEN EXT/INT signal output from pin 9 of IC1 is LOW.

3-15. RM-32 board (DXC-102/P only)

A 4-bit microprocessor is on the RM-32 board. The VD signal from the camera module and the AUTO W/B IND signal from the SW-34 board are sent to the microprocessor, and the microprocessor outputs and inputs the signal as serial data to and from the REMOTE connector.

The AUTO W/B TRIG signal and PEDESTAL control signal from the microprocessor go to the SW-34 and MB-38 boards. This microprocessor also outputs the CCU IND and W/B control signals. The CCU IND signal is separated into two signal paths.

The signal of one path goes to the SW-34 board. The signal of other path and the W/B control signal are sent to the NOR gate with the control signal from the W/B switch on the GENLOCK unit side, then the output signal of this gate goes to the MB-38 board as the W/B control signal.

3-16. SW-34 board (DXC-102/P only)

The AUTO W/B IND and AUTO W/B TRIG signal generator circuits are on the SW-34 board.

The AUTO W/B IND drive signal from the RM-32 board and the AUTO W/B IND drive signal from the camera module are sent to the AUTO W/B IND signal generator circuit to output the AUTO W/B IND signal which controls the AUTO W/B indicator LED on the GENLOCK unit side.

The AUTO W/B TRIG drive signal from the RM-32 board and the TRIG signal controlled by the AUTO W/B button on the GENLOCK unit side are sent to the AUTO W/B TRIG signal generator circuit. The AUTO W/B TRIG signal, which is the output of this circuit, goes to the camera module via the MB-38 board.

The W/B control signal controlled with the W/B switch on the GENLOCK unit side controls the AUTO W/B IND and AUTO W/B TRIG signal generator circuits. It also goes to the RM-32 board.

The GAIN control signal controlled with the GAIN switch goes to the camera module via the MB-38 board. The signals controlled with the H PHASE controller, SC PHASE controller, and SC 0°/180° switch go to the SG-38 board.

3-17. SG-110 board (DXC-102/P only)

The DC adder circuit and VCO control signal generator circuit are on the SG-110 board.

The VBS signal from the MB-38 board is added to the DC of the DC IN/VIDEO OUT connector, then it is output from the DC IN/VIDEO OUT connector.

The DC from the DC IN/VIDEO connector is sent to the voltage regulator, then supplied to the MB-38 board as the REG +22 V.

The SC COMP signal from the MB-38 board is sent to the VCO control signal generator circuit. The undesired chroma signal components are removed by the low-pass filter of IC1, then it goes to the MB-38 board as the VCO control signal.

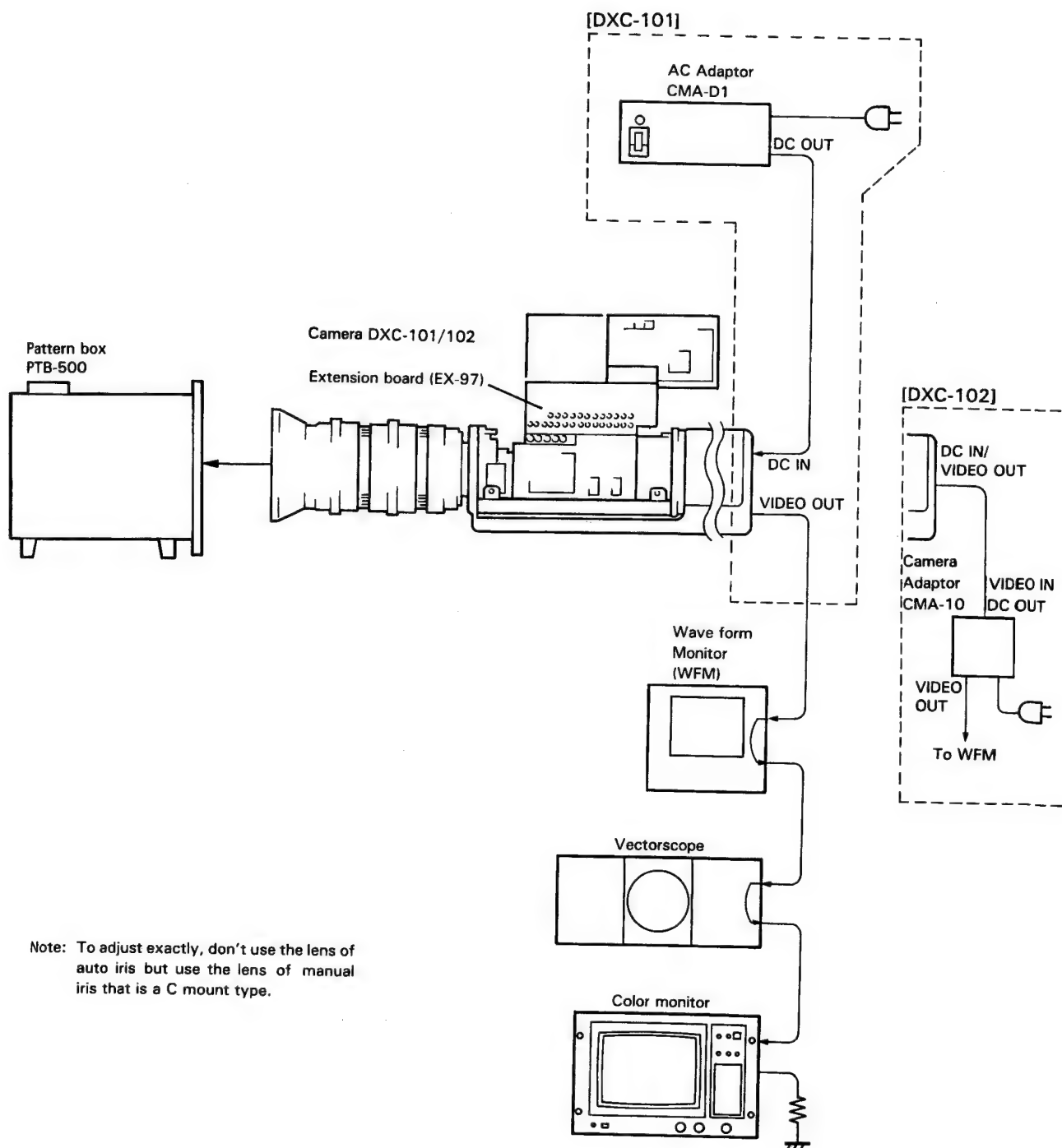
SECTION 4

ALIGNMENT

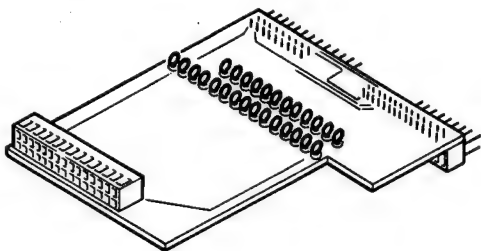
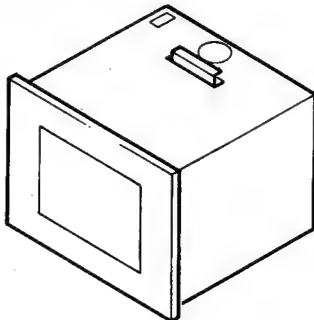
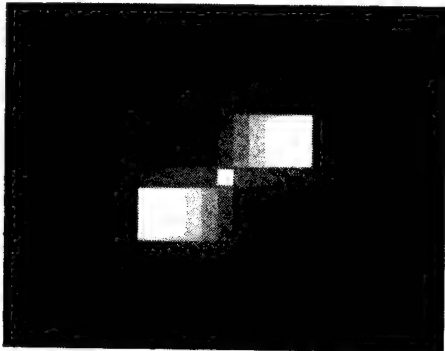
4-1. PREPARATION

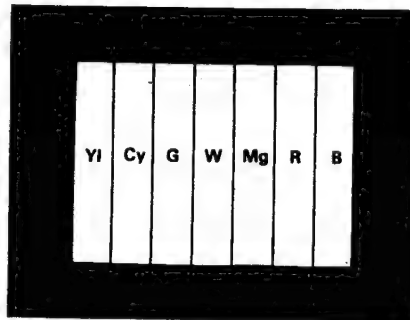
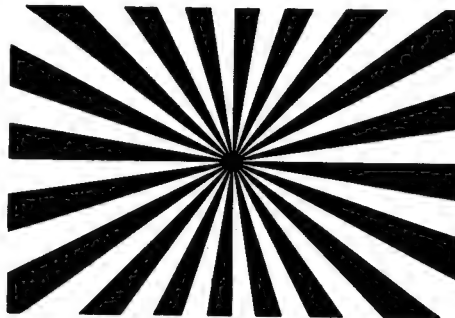
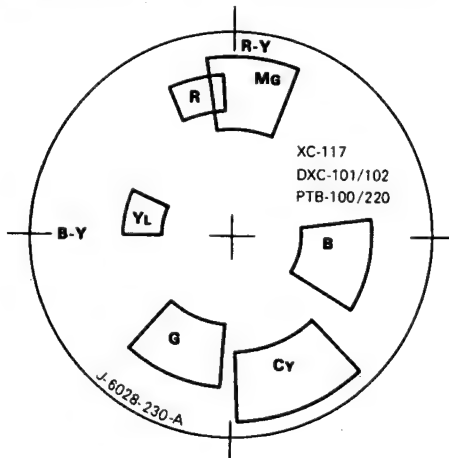
4-1-1. Connection for Adjustment

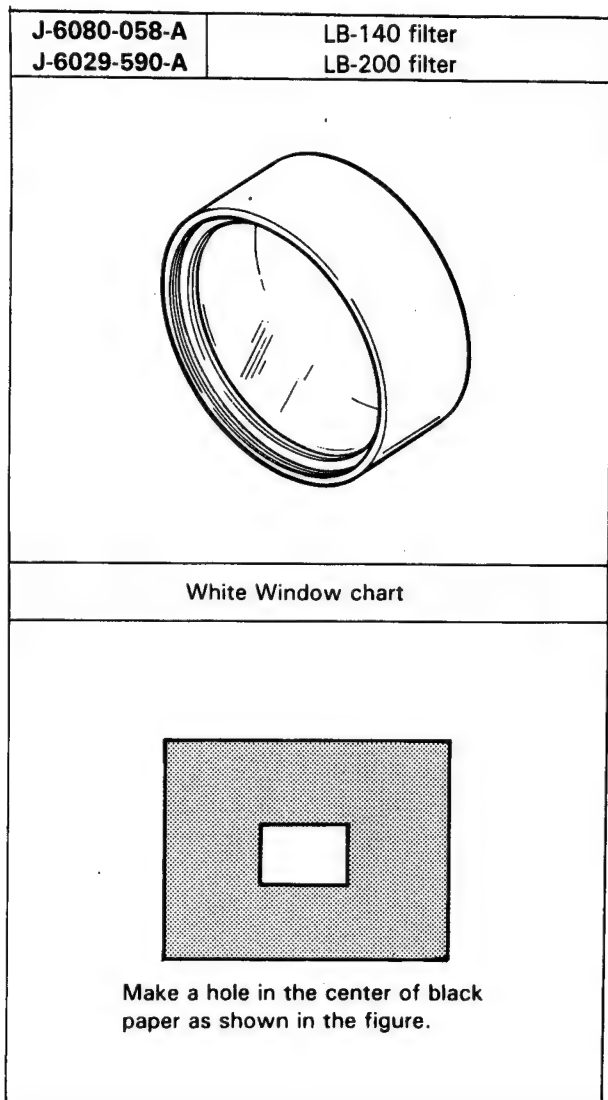
Revised-1 Change Information in SECTION 4		
Pattern box is changed to	PTB-500	from PTB-100.
Parts number of above	is changed to J-6029-140-A from J-6020-490-A.	
The filter is changed	to LB140	from C14.
The filter is changed	to LB200	from C20.



4-1-2. Adjustment Fixtures and Equipment

J-6028-450-A	Extension Board (EX-97)
<ul style="list-style-type: none"> For MD-30, EN-40 board adjustment 	
J-6029-140-A	Pattern Box PTB-500 (90 to 240 V)
<ul style="list-style-type: none"> Light source for test charts 	
J-6026-130-A	Grayscale Chart
<ul style="list-style-type: none"> For video level and gamma adjustment, etc. 	

J-6020-250-A	Color Bar Chart
<ul style="list-style-type: none"> For color adjustment. 	
J-6024-340-B	Siemens Star chart
<ul style="list-style-type: none"> For back focus adjustment 	
J-6028-230-A	Vectorscope Scale
 <p>XC-117 DXC-101/102 PTB-100/220</p>	



Commercial measuring equipment and fixture

- Dual Trace Oscilloscope
- Vectorscope
- Waveform Monitor (WFM)
- Frequency Counter
- Digital Voltmeter
- Color Monitor
- Lens (C mount and manual iris type)

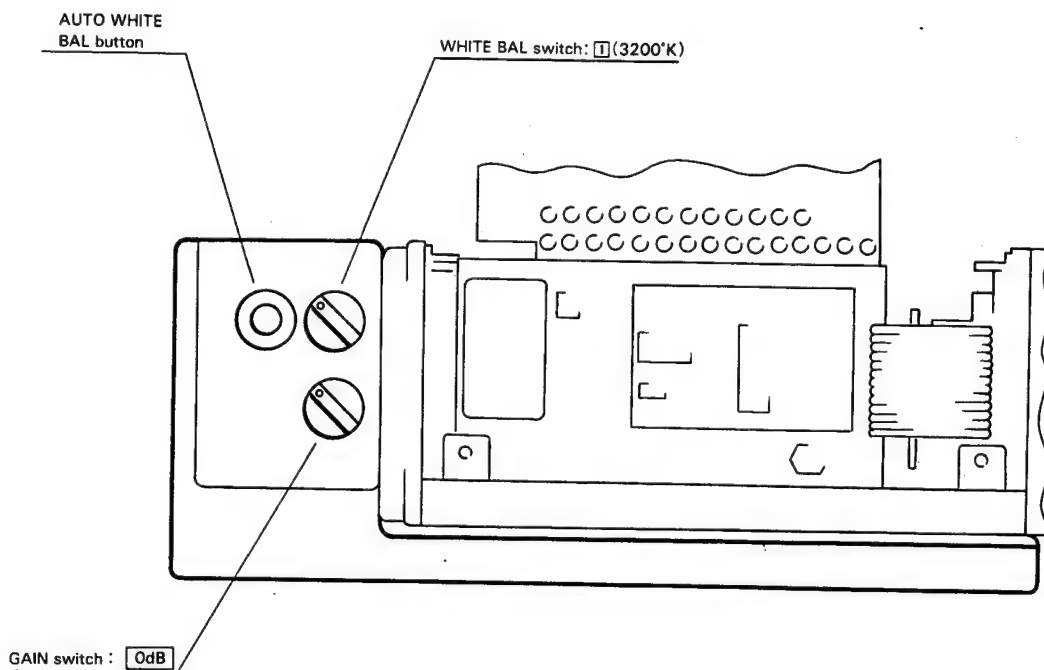
4-1-3 Switch Setting Position before Adjustment

Set the switches as follows:

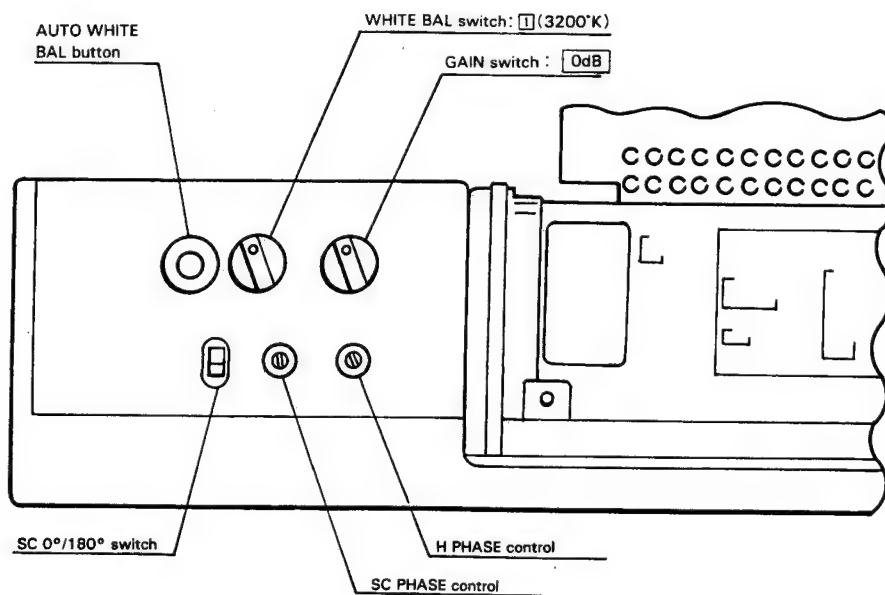
GAIN switch: "0dB"

WHITE BAL switch: "1" (3200°K)

[DXC-101]



[DXC-102]



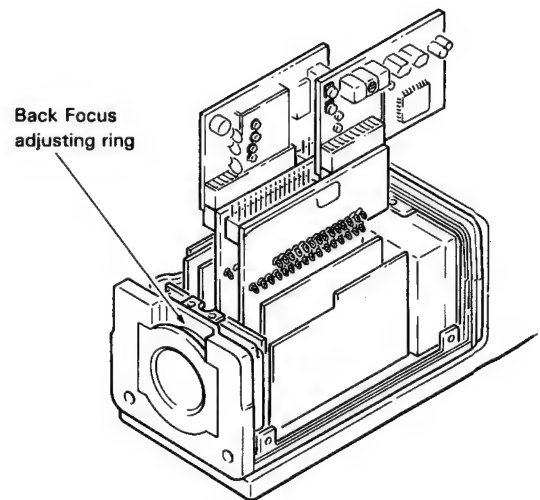
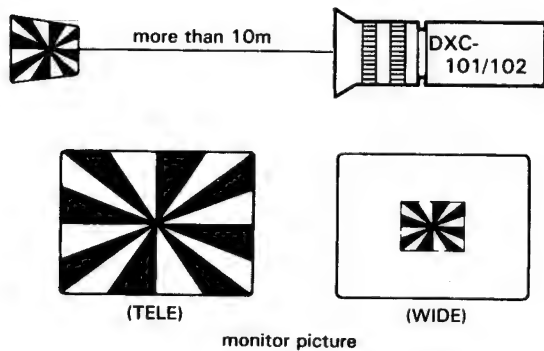
4-1-4. Mechanical Back Focus Adjustment

Subject: Siemens Star chart

Lens iris: Open

Adjust:

1. Set the zoom control at TELE so as to obtain the maximum multiplication factor. Optically focus the image so as to obtain the maximum resolution.
2. Set the zoom control at WIDE so as to obtain the minimum multiplication factor. Do not optically focus the image at this time.
Check whether the image is focused on the monitor while turning the zoom control from TELE to WIDE. If the image is not focused, properly set at back focus as follows.
3. When the zooming mechanism is set at WIDE, turn the back focus adjusting ring.
4. Repeat step 1 through 3 several times.



4-2. POWER SUPPLY SYSTEM

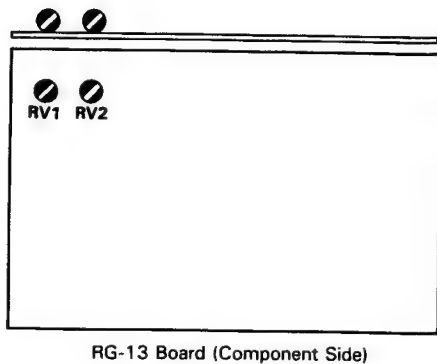
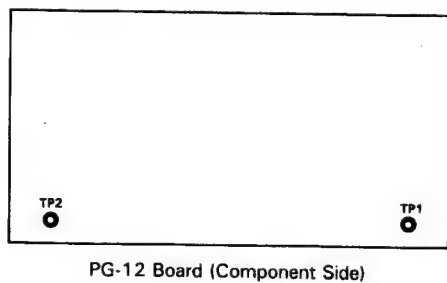
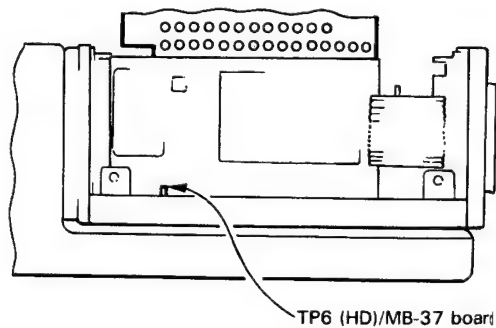
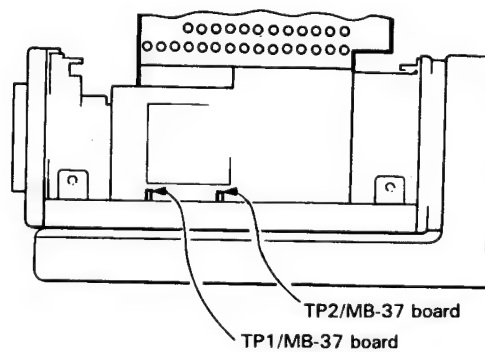
4-2-1. +12V Adjustment

Equipment: Digital voltmeter
 Test point: TP1 (GND: GND terminal/Extension board)/PG-12 board
 Adj. point: Ⓐ RV1/RG-13 board
 Spec.: $+12V \pm 0.1V$

4-3. SYNC SYSTEM

4-3-1. Sub-carrier Frequency Adjustment

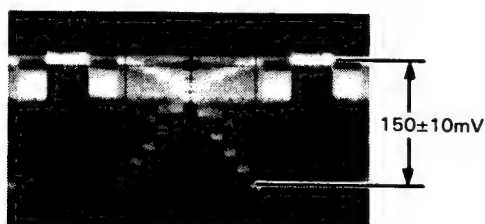
Equipment: Frequency counter
 Test point: TP2 (GND: GND terminal/Extension board)/PG-12 board
 Adj. point: Ⓐ RV2/RG-13 board
 Spec.: $3,579,545 \pm 5 \text{ Hz}$



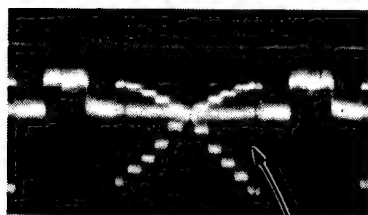
4-4. PROCESS SYSTEM

4-4-1. 0dB Video Level Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP4 (GND: TP10/PR-72)/PR-72 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: RV1/PR-72 board
 RV6/PR-72 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.

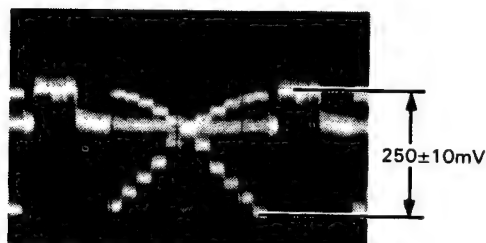


2. Adjust the RV6/PR-72 board so that the flicker of the video waveform at TP4/PR-72 board is minimum overall.



Flicker of the video waveform should be minimum overall.

3. Adjust the RV1/PR-72 board so that the video level at TP4/PR-72 board is 250 ± 10 mV.



Note: If it is unable to accomplish this adjustment, be sure to carry out step 4 through 6 as follows.

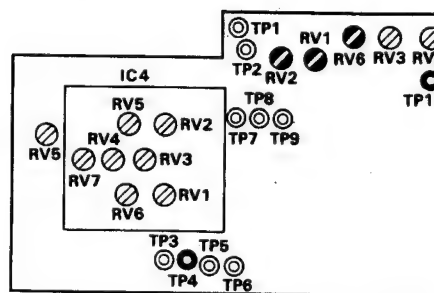
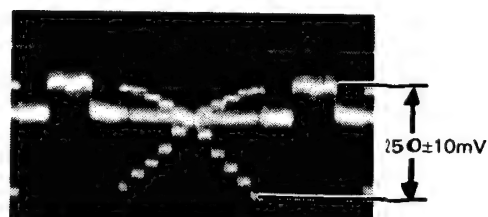
4. Preset the RV1/PR-72 board so that the video level at TP4/PR-72 board is maximum.



5. Adjust the RV2/PR-72 board so that the video level at TP4/PR-72 board is 350 ± 10 mV.



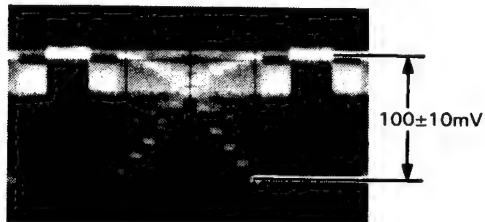
6. Adjust the RV1/PR-72 board so that the video level at TP4/PR-72 board is 250 ± 10 mV.



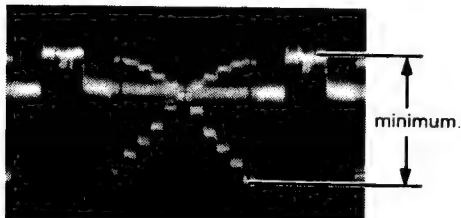
PR-72 Board (Component Side)

4-4-2. AGC Adjustment

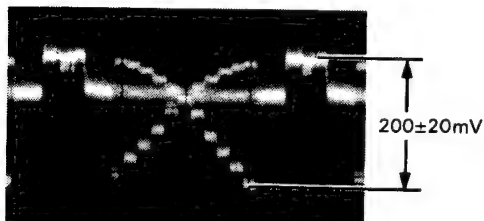
Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP4 (GND: TP10/PR-72)/PR-72 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: ⌚ RV1/AT-40 board
 ⌚ RV4/AT-40 board
 ⌚ RV1/PR-72 board
 ⌚ RV2/PR-72 board
 Preparation: Switch setting
 GAIN switch: "AUTO" position
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 100 ± 10 mV.



2. Turn the ⌚ RV1/AT-40 board counter-clockwise ⌚ so that the video level at TP4/PR-72 board is minimum.

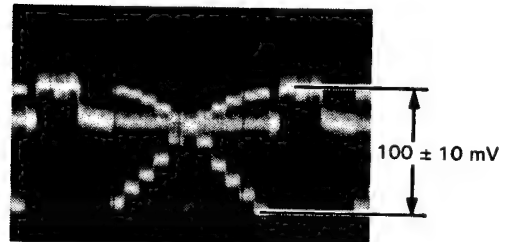


3. Adjust the ⌚ RV4/AT-40 board so that the video level at TP4/PR-72 board is 200 ± 20 mV.



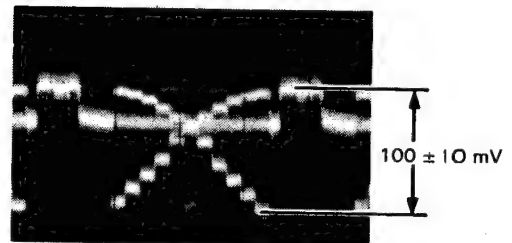
4. Set the GAIN switch at "12 dB".

5. Adjust the lens iris so that the video level at TP4/PR-72 board is 100 ± 10 mV.



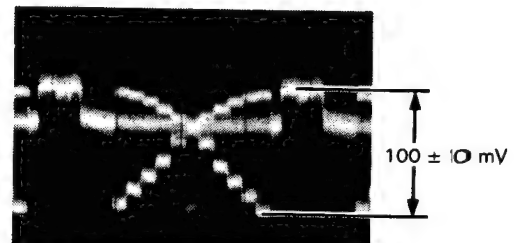
6. Set the GAIN switch at "AUTO".

7. Adjust the ⌚ RV2/PR-72 board so that the video level at TP4/PR-72 board is 100 ± 10 mV.



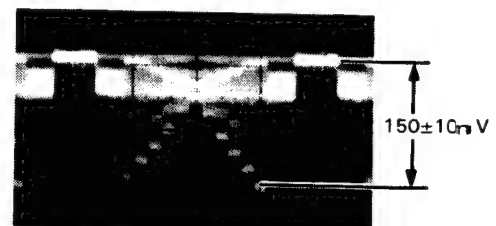
8. Set the GAIN switch at "12 dB".

9. Adjust the ⌚ RV1/PR-72 board so that the video level at TP4/PR-72 board is 100 ± 10 mV.

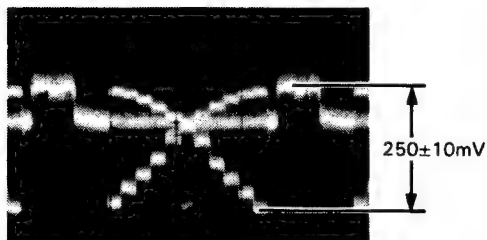


10. Set the GAIN switch at "AUTO".

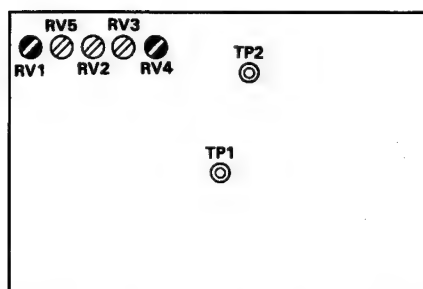
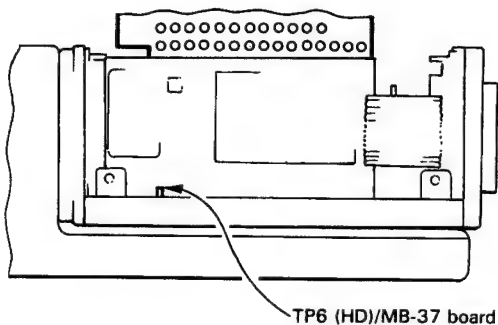
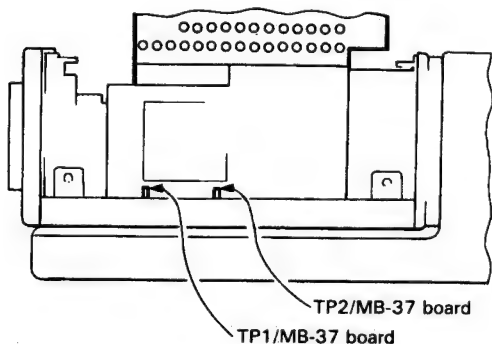
11. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



12. Adjust the RV1/AT-40 board so that the video level at TP4/PR-72 board is 250 ± 10 mV.



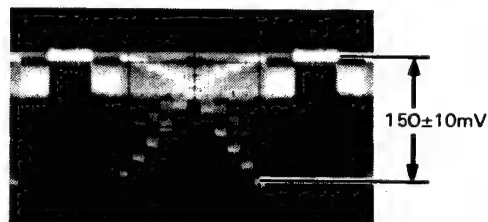
NOTE: When carrying out this adjustment, be sure to Set the GAIN switch to "0" and carry out 4-5-1. 0dB Video Level Adjustment.



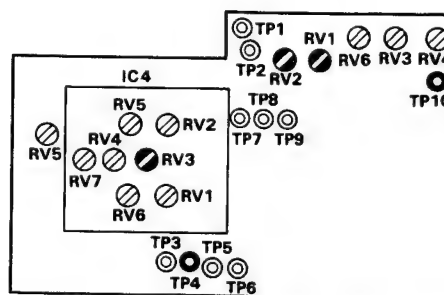
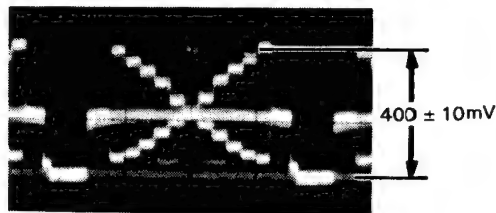
AT-40 Board (Component Side)

4-4-3. GAMMA Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 CN1-A4 pin (GND: GND terminal/Extension board)/MD-30 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC4- RV3/PR-72 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



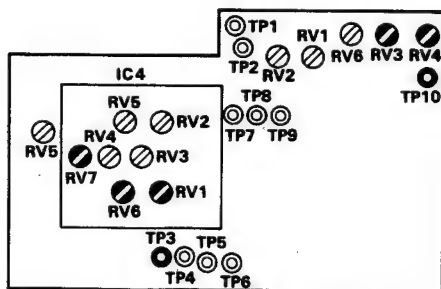
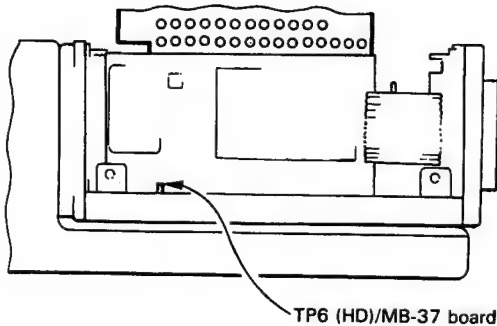
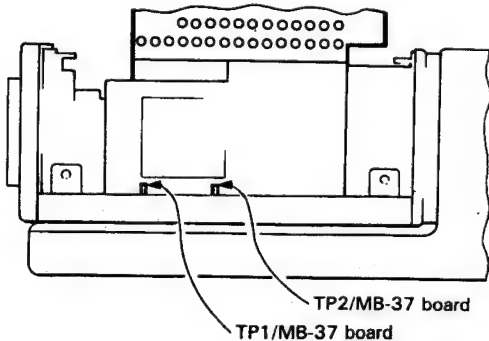
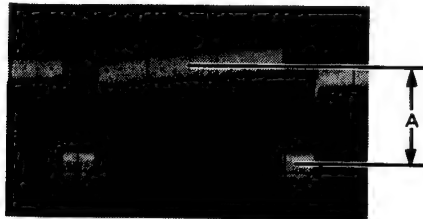
2. Adjust the IC4- RV3/PR-72 board so that the level "A" at CN1-A4 pin/MD-30 board is 400 ± 10 mV.



PR-72 Board (Component Side)

4-4-4. Pre-pedestal Adjustment

Lens: Closed "C"
 Equipment: Oscilloscope
 Test point: CN1-A4 pin (GND: GND terminal/Extension board)/MD-30 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC4- RV1/PR-72 board
 Spec: $A=50 \pm 4$ mV



PR-72 Board (Component Side)

4-4-5. R/B Gain Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP3 (GND: TP10/PR-72)/PR-72 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC4- RV6/PR-72 board
 IC4- RV7/PR-72 board
 Preparation: 1. Set the RV3, RV4/PR-72 board to mechanical center.

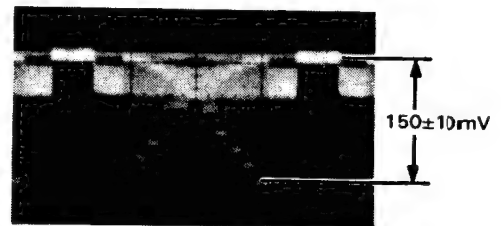
[Front View]



[Top View]



2. Switch setting
 WHITE BAL Switch: "3" position
3. Cover the LB140 filter in front of the lens.
- Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



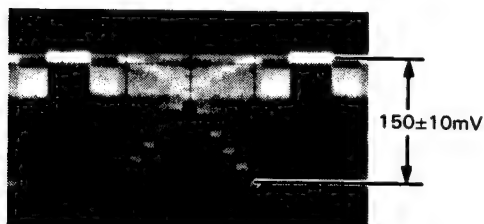
2. Adjust the IC4- RV6, RV7/PR-72 board so that the video level at TP3/PR-72 board is 250 ± 10 mV, and repeat this adjustment several times by turns.



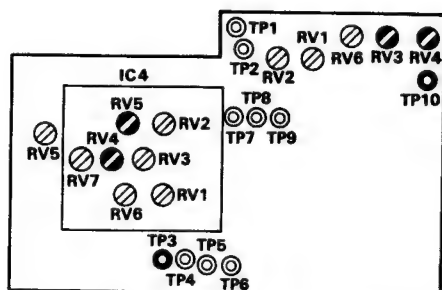
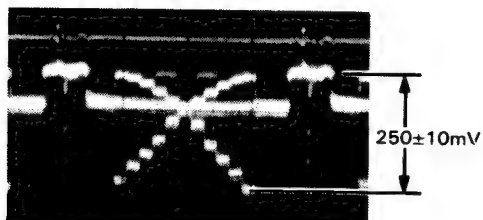
NOTE: After this adjustment, be sure to remove C14 filter attached the lens and return the WHITE BAL switch to "1".

4-4-6. 3200°K R/B Gain Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP3 (GND: TP10/PR-72)/PR-72 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: ⓪ RV3/PR-72 board
 ⓪ RV4/PR-72 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/PR-72 board is 150 ± 10 mV.



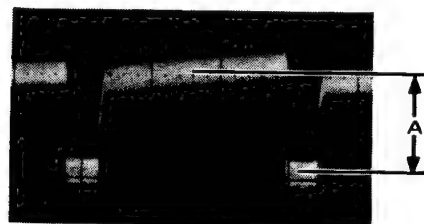
2. Adjust the ⓪ RV3, ⓪ RV4/PR-72 board so that the video level at TP3/PR-72 board is 250 ± 10 mV, and repeat this adjustment several times by turns.



PR-72 Board (Component Side)

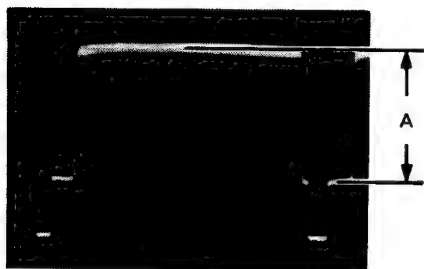
4-4-7. R/B Offset Adjustment

Lens: Closed "C"
 Equipment: Oscilloscope
 Test point: CN1-B4 pin (GND: GND terminal/Extension board)/MD-30 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC4- ⓪ RV4/PR-72 board
 IC4- ⓪ RV5/PR-72 board
 Spec: $A = 50 \pm 4$ mV

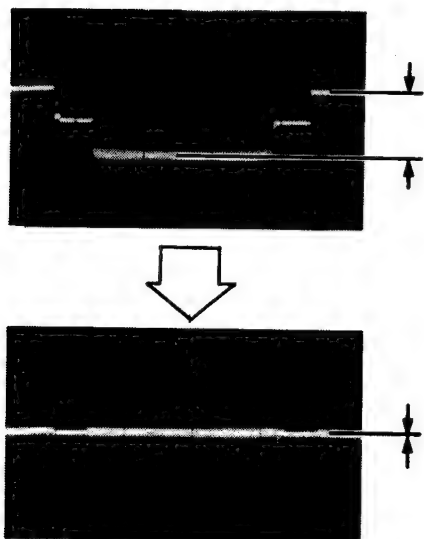


4-4-8. Auto White Balance Adjustment

Subject: White window chart
 Equipment: Waveform Monitor and Oscilloscope
 Adj. point: ⓪ RV2/AT-40 board
 ⓪ RV3/AT-40 board
 Preparation: 1. RESPONSE switch of WFM
 → "LUM" position
 2. Cover the LB200 filter in front of the lens.
 Adjust: 1. Test point: VIDEO OUT
 Adj. point: lens iris
 Spec.: $A = 50 \pm 5$ IRE.



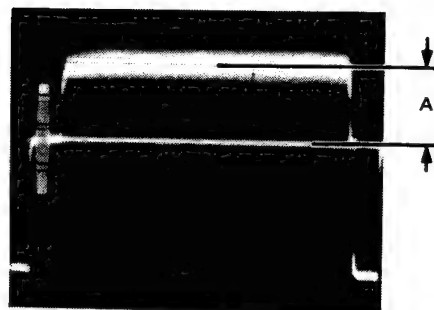
2. Set the WHITE BAL switch at "AUTO".
3. Equipment: Oscilloscope
 Test point: CH1 CN1-A4 pin/MD 30 board
 CH2 CN1-B4 pin/MD-30 board
 (Set the vertical deflections of CH1 CH2 at the same DC voltage range.)
 Mode: ADD mode (CH2 is "INVERT".)
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: ⓪ RV2/AT-40 board
 ⓪ RV3/AT-40 board
 Adjust: Adjust so that the waveform is flat, when the AUTO WHITE BAL button is pushed.



4. Repeat step3. several times.

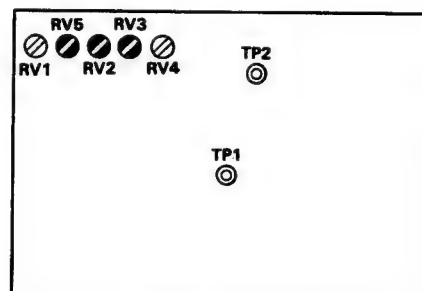
4-4-9. LOW LIGHT Adjustment

Subject: White Window chart
 Equipment: Waveform Monitor
 Test point: VIDEO OUT
 AUTO W/B Indication LED
 Adj. point: ⓪ RV5/AT-40 board
 Preparation: Set the WHITE BAL switch at "AUTO".
 Adjust: 1. Adj. point: lens iris
 Spec.: $A = 30 \pm 5$ IRE.



2. Adjust the ⓪ RV5/AT-40 board so that the AUTO W/B Indication LED does not illuminate in spite of pushing the AUTO W/B button.

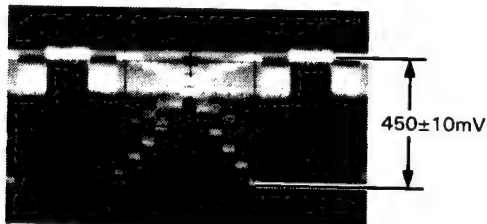
Note: After this adjustment, be sure to set the WHITE BAL switch at "1".



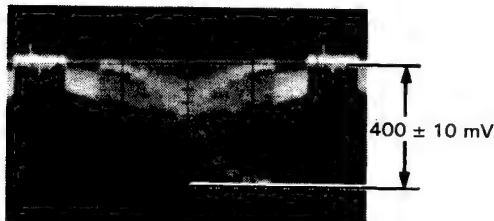
AT-40 Board (Component Side)

4-4-10. Video Clip Adjustment

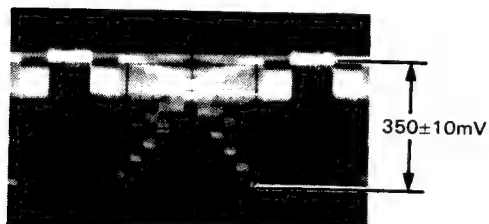
Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 IC4-26 pin (GND: TP10/PR-72)/PR-72 board
 TP7 (GND: TP10/PR-72)/PR-72 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: RV5/PR-72 board
 IC4- RV2/PR-72 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 450 ± 10 mV.



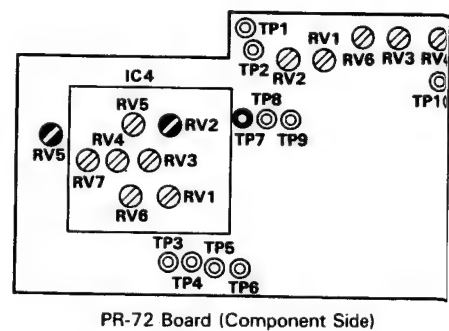
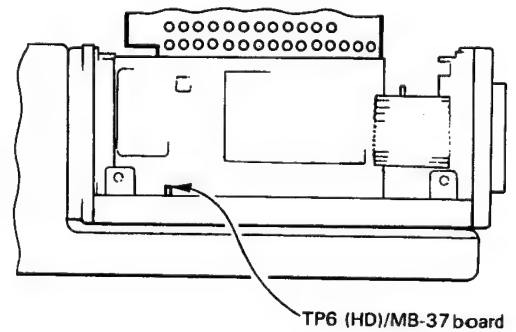
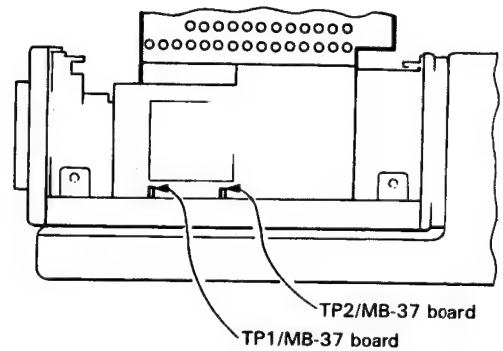
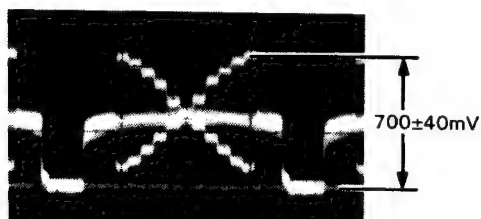
2. Adjust the RV5/PR-72 board so that the video level at IC4-26 pin/PR-72 board clips at 400 ± 10 mV.



3. Adjust the lens iris so that the video level at TP1/MB-37 board is 350 ± 10 mV.

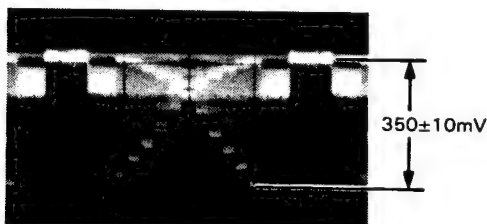


4. Adjust the IC4- RV2/PR-72 board so that the video level at TP7/PR-72 board is 700 ± 40 mV.

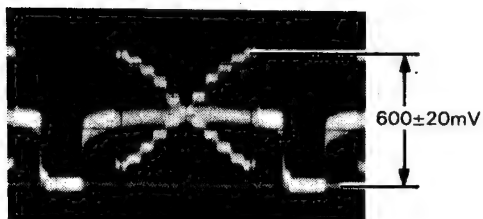


4-4-11. G KNEE Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP1 (GND: GND terminal/Extension board)/MD-30 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: RV1/MD-30 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 350 ± 10 mV.

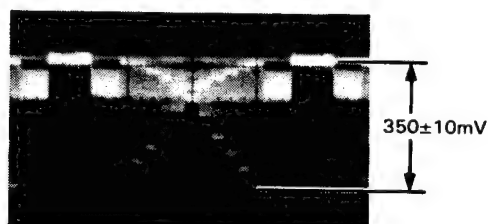


2. Adjust the RV1/MD-30 board so that the video level at TP1/MD-30 board is 600 ± 20 mV.

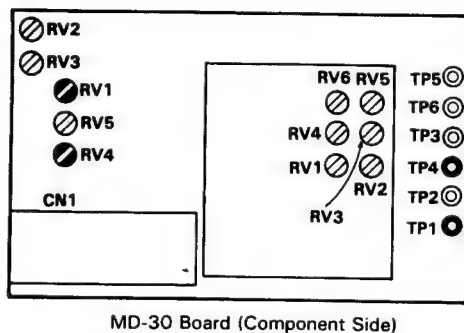
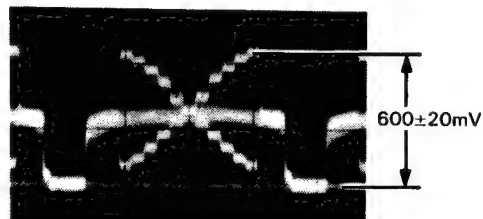


4-4-12. R/B KNEE Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 TP4 (GND: GND terminal/Extension board)/MD-30 board
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: RV4/MD-30 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 350 ± 10 mV.



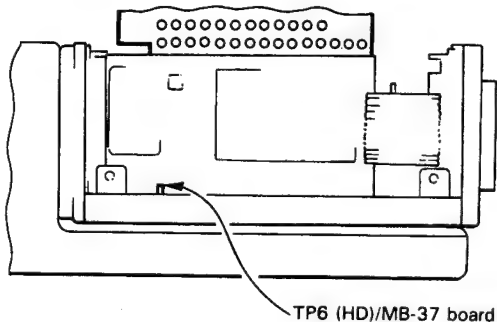
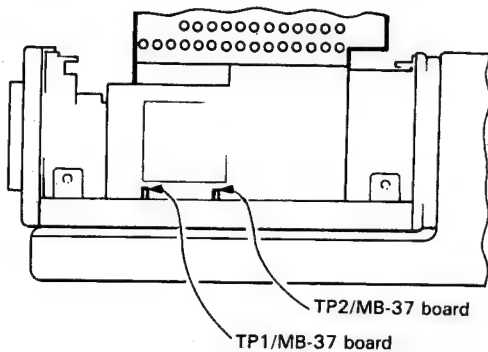
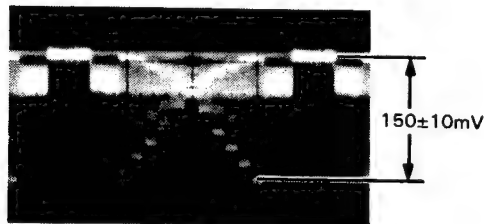
2. Adjust the RV4/MD-30 board so that the video level at TP4/MD-30 board is 600 ± 20 mV.



4-5. VIDEO OUT SYSTEM

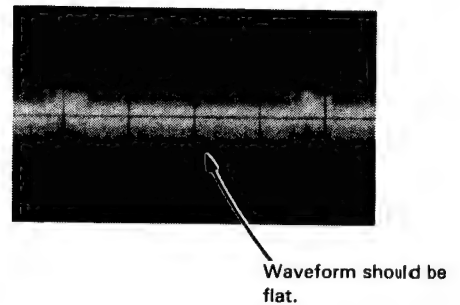
4-5-1. RB0/RB1/RB2 Adjustment

Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1/MB-37 board
 TP4/MD-30 board
 TP5/MD-30 board
 TP6/MD-30 board
 (GND: TP2/MB-37 or GND terminal/Extension board)
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC2- RV2/MD-30 board
 IC2- RV4/MD-30 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.

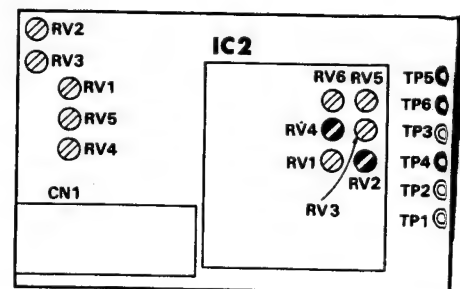
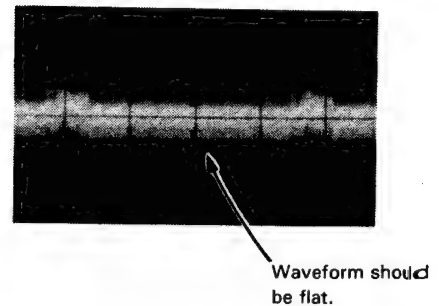


2. Test point: CH1 TP5/MD-30 Board
 CH2 TP4/MD-30 Board
 CH2: "INVERT"
 Mode: ADD mode
 DC range: 50 mV/Div (Set the vertical deflections of CH 1 and CH 2 at the same DC voltage range.)

3. Adjust the IC2- RV2/MD-30 board so that the waveform is flat.



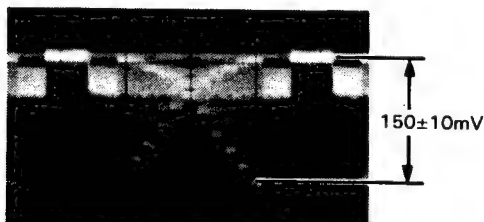
4. Test point: CH1 TP6/MD-30 board
 CH2 TP4/MD-30 board
 CH2: "INVERT"
 Mode: ADD mode
 5. Adjust the IC2- RV4/MD-30 board so that the waveform is flat.



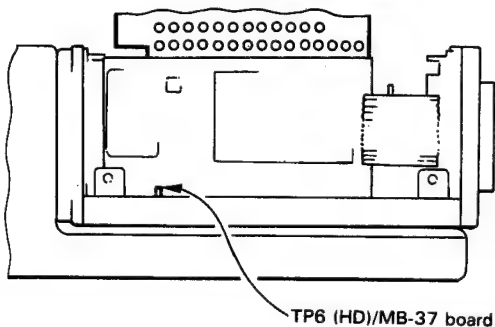
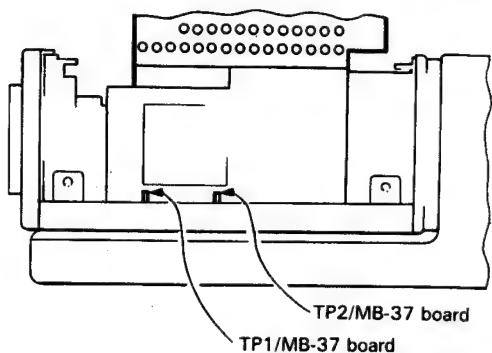
MD-30 Board (Component Side)

4-5-2. G0/G1/G2 Adjustment

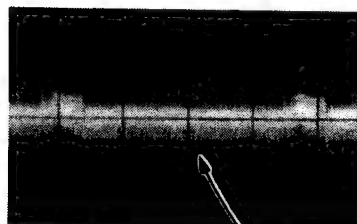
Subject: Grayscale chart
 Equipment: Oscilloscope
 Test point: TP1/MB-37 board
 TP1/MD-30 board
 TP2/MD-30 board
 TP3/MD-30 board
 (GND: TP10/PR-72 or GND terminal/Extension board)
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC2- RV1/MD-30 board
 IC2- RV3/MD-30 board
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



2. Test point: CH1 TP2/MD-30 board
 CH2 TP1/MD-30 board
 CH2: "INVERT"
 Mode: ADD mode
 DC range: 50 mV/Div (Set the vertical deflections of CH1 and CH2 at the same DC voltage range.)



3. Adjust the IC2- RV1/MD-30 board so that the waveform is flat.



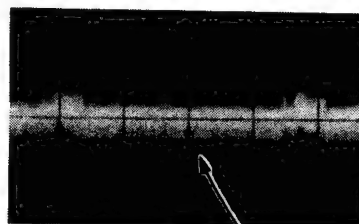
Waveform should be flat.

4. Test point: CH1 TP3/MD-30 board
 CH2 TP1/MD-30 board

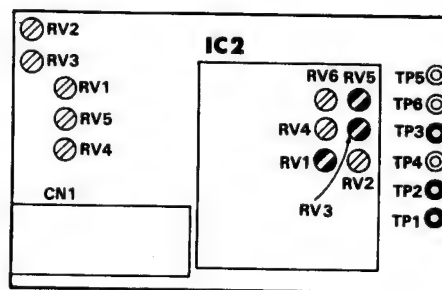
CH2: "INVERT"

Mode: ADD mode

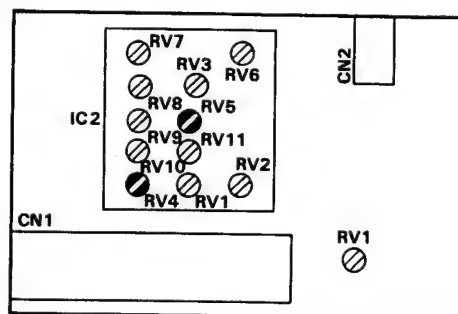
5. Adjust the IC2- RV3/MD-30 board so that the waveform is flat.



Waveform should be flat.



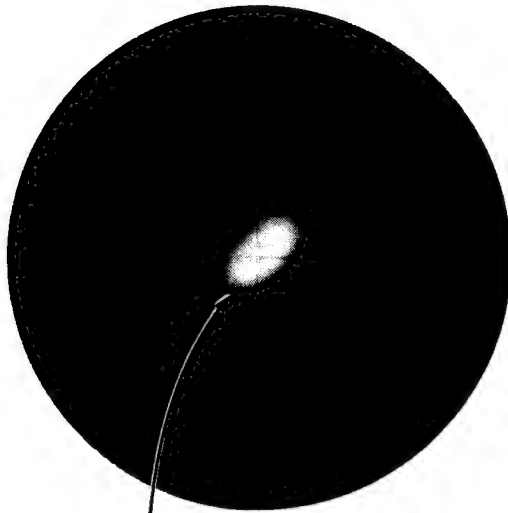
MD-30 Board (Component Side)



EN-40 Board (Component Side)

4-5-3. MPX DC Adjustment

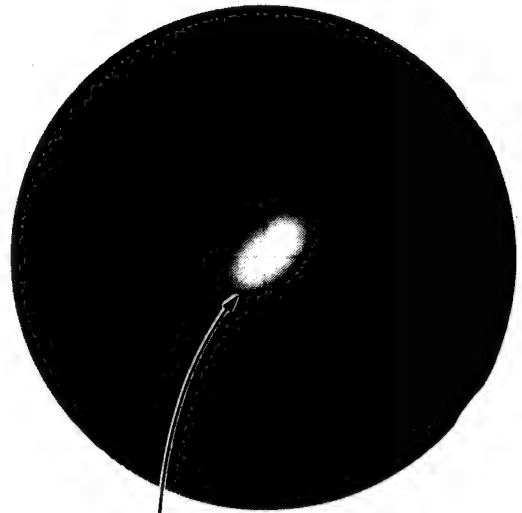
Lens iris: Closed "C"
Equipment: Vectorscope "MAX GAIN"
Adj. point: IC2- RV5/MD-30 board
Adjust: Adjust the IC2- RV5/MD-30 board so that the bright spot at vectorscope screen becomes one dot.



Bright spot should be one dot.

4-5-4. Carrier Balance Adjustment

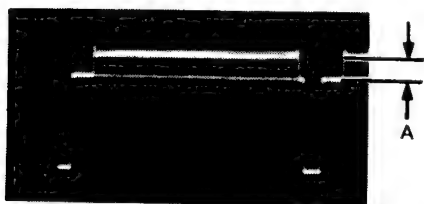
Lens iris: Closed "C"
Equipment: Vectorscope "MAX GAIN"
Adj. point: IC2- RV4/EN-40 board
IC2- RV5/EN-40 board
Adjust: Adjust the IC2- RV4, RV5/EN-40 board by turns several times till the bright spot is at the center of the vectorscope screen.



Bright spot should be at the center of the vectorscope screen.

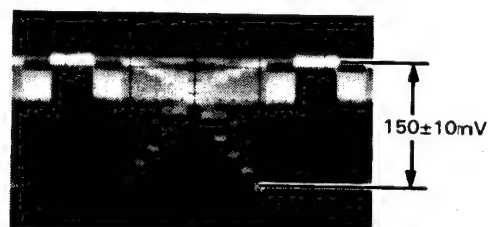
4-5-5. Pedestal Level Adjustment

Lens iris: Closed "C"
 Equipment: Waveform monitor
 Adj. point: IC2- RV8/EN-40 board
 Preparation: RESPONSE switch of Waveform monitor
 → "LUM" position
 Spec.: $A = 7.5 \pm 1$ IRE

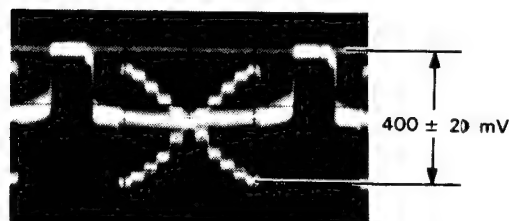


4-5-6. Y Level Adjustment

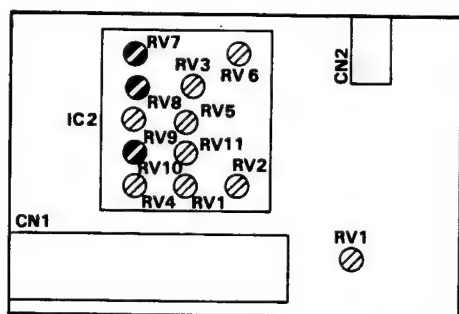
Subject: Grayscale chart
 Equipment: Oscilloscope and WFM
 Test point: TP1 (GND: TP2/MB-37)/MB-37 board
 IC2-24pin (GND: GND terminal/Extension board)/EN-40 board
 VIDEO OUT
 Trigger: TP6 (HD)/MB-37 board
 Adj. point: IC2- RV7/EN-40 board
 IC2- RV10/EN-40 board
 Preparation: RESPONSE switch of WFM
 → "LUM" position
 Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



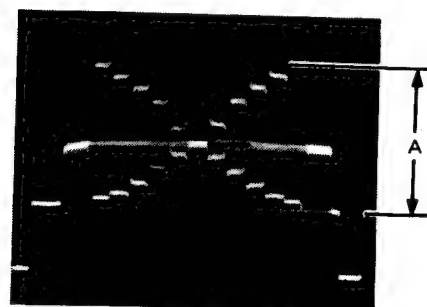
2. Adjust the IC2- RV7/EN-40 board so that the video level at IC2-24pin/EN-40 board is 400 ± 20 mV.



3. Test point: VIDEO OUT
 Adj. point: IC2- RV10/EN-40 board
 Spec.: $A = 100 \pm 5$ IRE

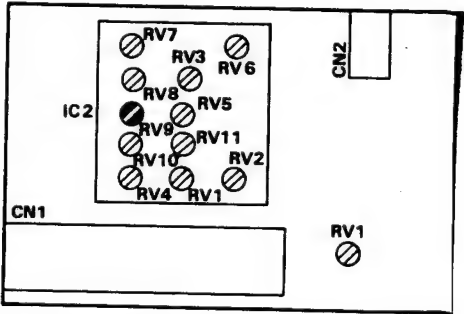
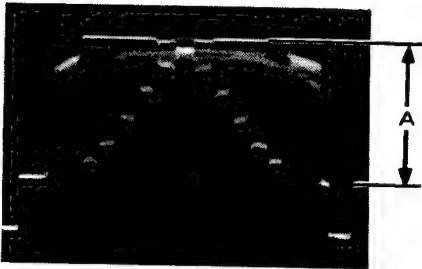
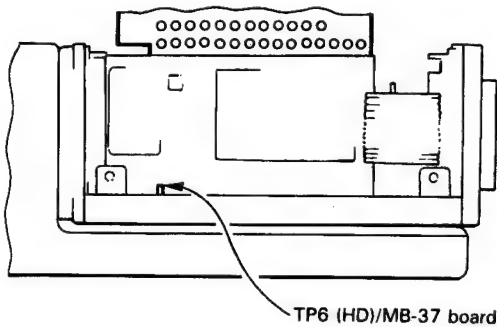
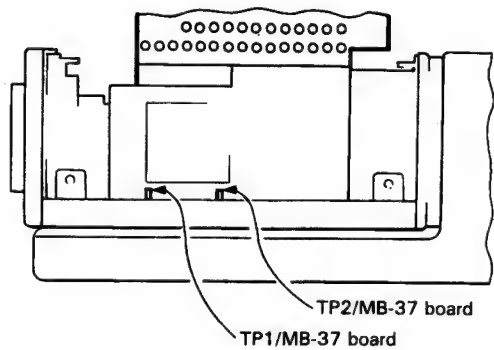


EN-40 Board (Component Side)



4-5-7. White Clip Adjustment

Subject: Grayscale chart
Lens iris: F2.0
Equipment: Waveform monitor (WFM)
Adj. point: IC2- RV9/EN-40 board
Adjust: Adjust the IC2- RV9/EN-40 board so that the video waveform clips at Specification.
Spec.: $A=120 \pm 10$ IRE



EN-40 Board (Component Side)

4-5-8. Color Vector Adjustment

Subject: Color Bar chart

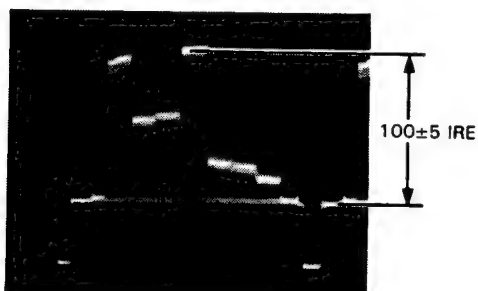
Equipment: WFM and Vectorscope

Adj. point: VIDEO OUT

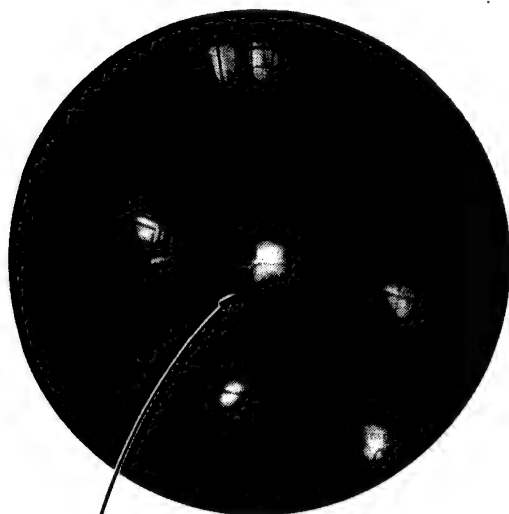
Preparation: RESPONSE switch of WFM

→ "LUM" position

Adjust: 1. Adjust the lens iris so that the VIDEO OUT level is 100 ± 5 IRE.



2. When the white balance is not adjusted, set the WHITE BAL switch at "AUTO" position, and push the AUTO WHITE BAL button.



White balance should be adjusted.

3. Adjust the following RVs by turns several times till the respective spots conform to the Spec.

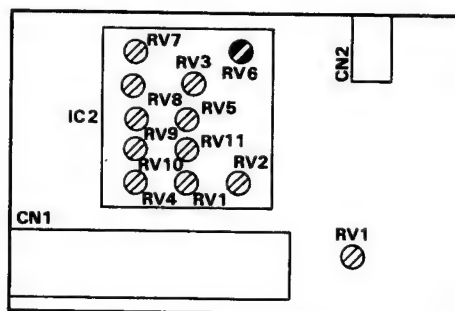
RV2/MD-30 board

RV3/MD-30 board

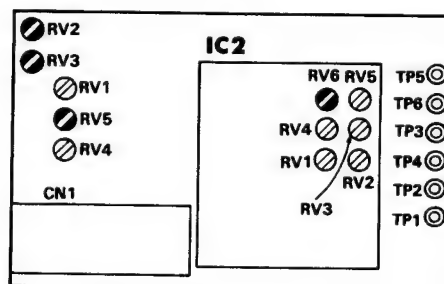
RV5/MD-30 board

IC2- RV6/EN-40 board

IC2- RV6/MD-30 board



EN-40 Board (Component Side)



MD-30 Board (Component Side)

4-5-9. Chroma Suppress Adjustment

Subject: Color Bar chart

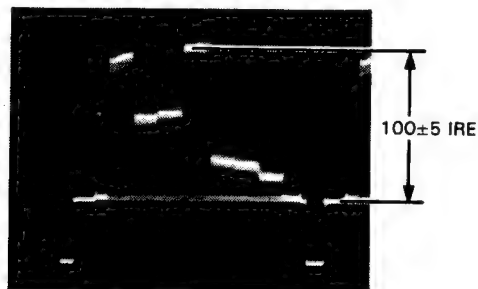
Equipment: WFM and Vectorscope

Test point: VIDEO OUT

Preparation: RESPONSE switch of WFM
→ "LUM" position

Adj. point: ⚙ RV1/EN-40 board

Adjust: 1. Adjust the lens iris so that the VIDEO
OUT level is 100 ± 5 IRE.

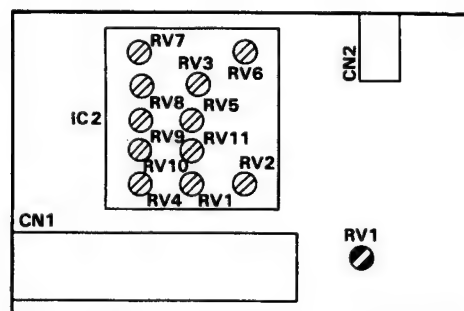


2. Set the GAIN switch at "6dB".
3. Adjust the ⚙ RV1/EN-40 board so that the white signal spot is at the center of the vectorscope screen.



White signal spot should be at the center of the vectorscope screen.

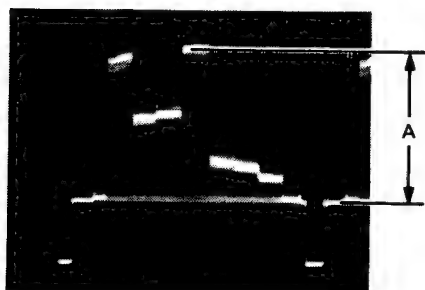
Note: After this adjustment, be sure to set the GAIN switch at "0dB".



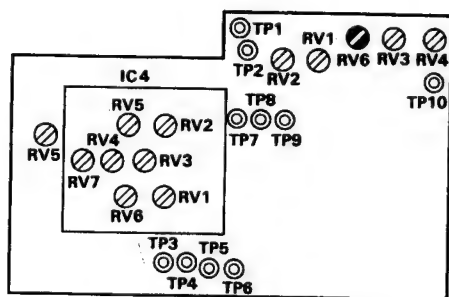
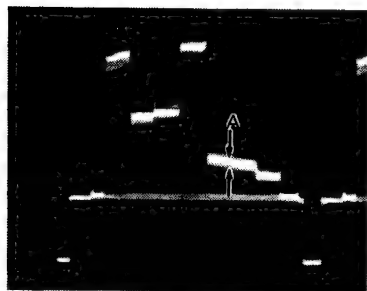
EN-40 Board (Component Side)

4-5-10. Mixed Color Correction Adjustment

Subject: Grayscale chart
 Equipment: WFM
 Test point: VIDEO OUT
 Adj. point: RV6/PR-72 board
 Preparation: RESPONSE switch of WFM
 → "LUM" position
 Adjust: 1. Adj. point: lens iris
 Spec.: $A = 700 \pm 10 \text{ mV}$



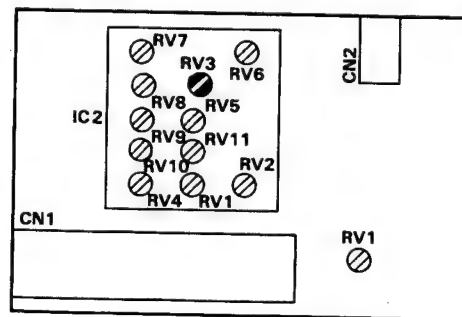
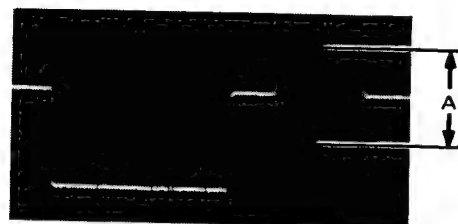
2. GAIN switch of WFM → MAX GAIN
3. Adjust the RV6/PR-72 board so that level "A" at WFM is less than 36mV.



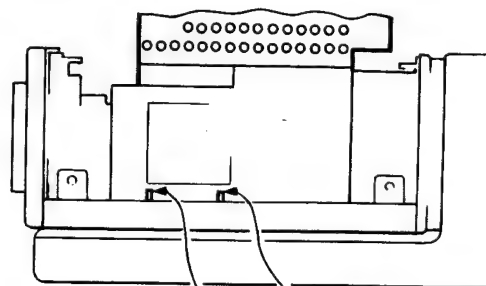
PR-72 Board (Component Side)

4-5-11. Bust Level Adjustment

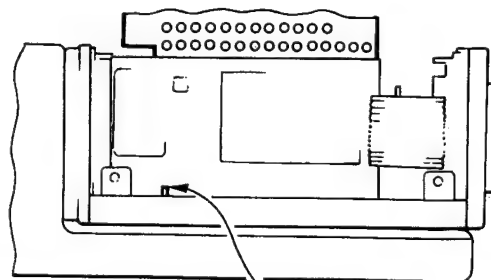
Equipment: Waveform monitor (WFM)
 Adj. point: IC2- RV3/EN-40 board
 Preparation: RESPONSE switch of WFM
 → "FLAT" position
 Spec.: $A = 300 \pm 15 \text{ mV}$



EN-40 Board (Component Side)



TP2/MB-37 board
 TP1/MB-37 board



TP6 (HD)/MB-37 board

4-5-12. Aperture Adjustment

NOTE: During this adjustment, make sure that the lens is just focused as the aperture level will vary with lens focus.

Subject: Grayscale chart

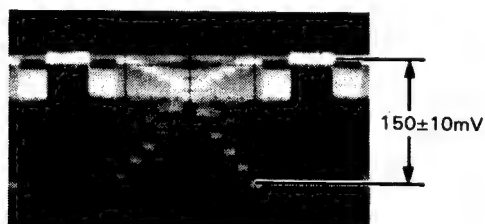
Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board
CN1-A4 pin (GND: GND terminal/Extension board)/EN-40 board

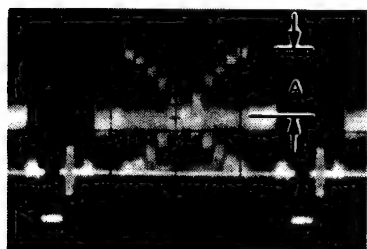
Trigger: TP6 (HD)/MB-37 board

Adj. point: IC2- ⚙ RV1/EN-40 board
IC2- ⚙ RV2/EN-40 board

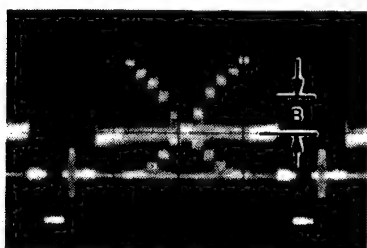
Adjust: 1. Adjust the lens iris so that video level at TP1/MB-37 board is 150 ± 10 mV.



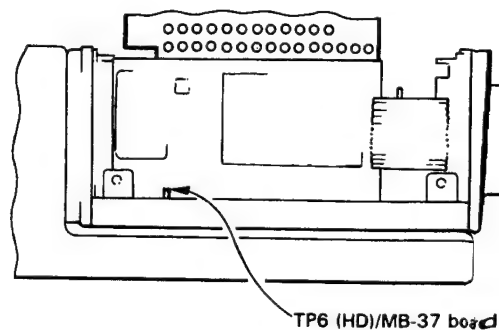
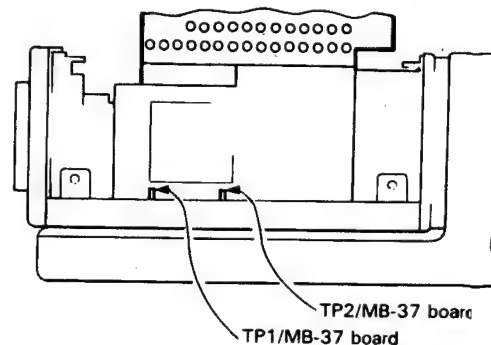
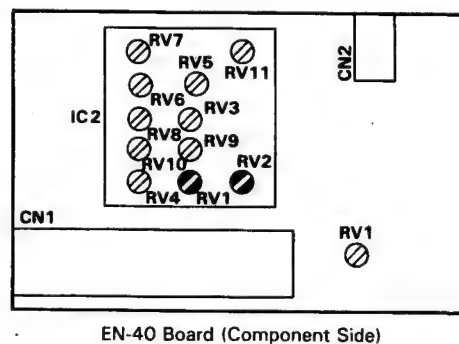
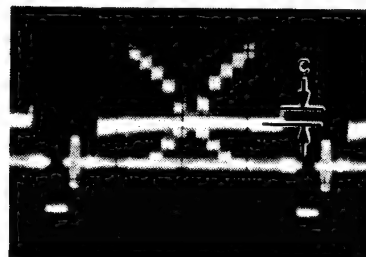
2. Preset the IC2- ⚙ RV1/EN-40 board so that the level "A" at CN1-A14 pin/EN-40 board is maximum.



3. Adjust the IC2- ⚙ RV2/EN-40 board so that the level "B" at CN1-A4 pin/EN-40 board is 200 ± 20 mV.



4. Adjust the IC2- ⚙ RV1/EN-40 board so that the level "C" at CN1-A4 pin/EN-40 board is 100 ± 20 mV.

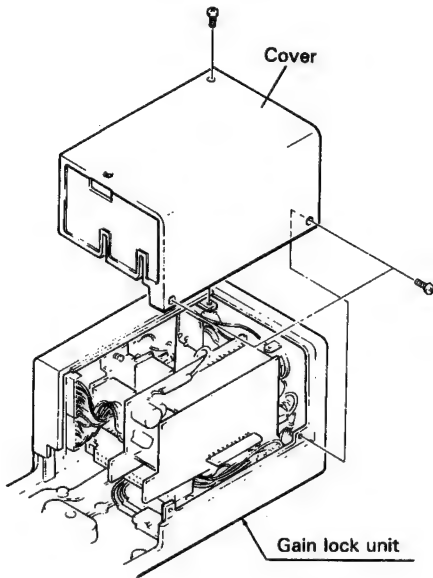


4-5-13. Video DC Level Adjustment (DXC-102 only)

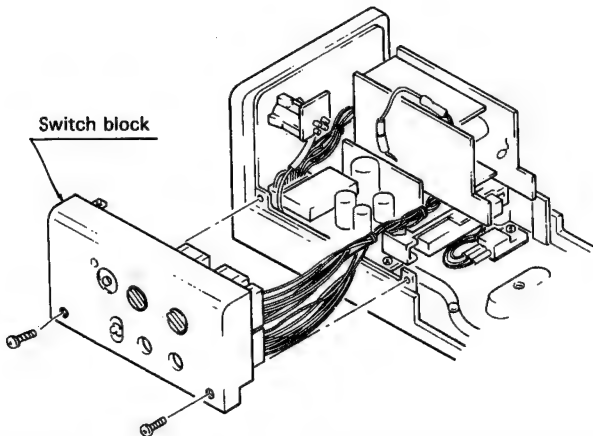
Preparations:

Disassemble the gain lock unit as follows:

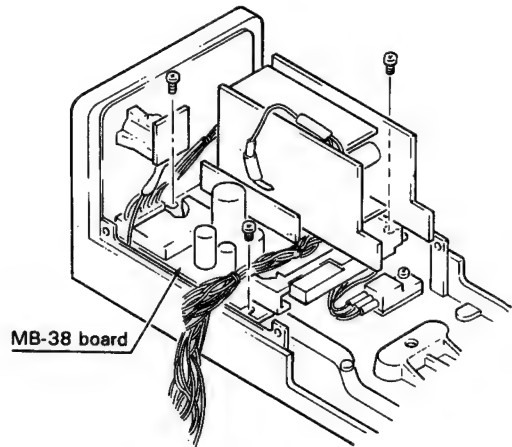
1. Remove the three camera unit fixing screws (one at the top and two at the bottom), then remove the camera unit from the gain lock unit.
2. Remove the three cover fixing screws from the gain lock unit, then remove the cover.



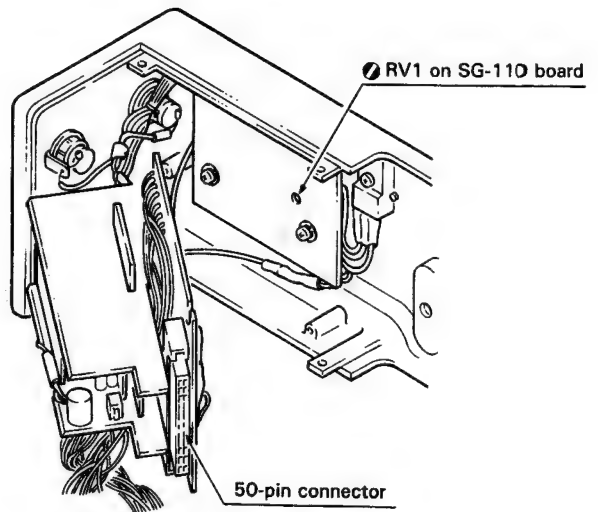
3. Remove the two switch block fixing screws, then remove the switch block. (Do not remove the connectors from the unit.)



4. Remove the three MB-38 board fixing screws, then remove the board. (Do not remove the connectors from the unit.)



5. Place the gain lock unit vertically as shown below:



Notes:

- Before adjustment, connect the 50-pin connector of the MB-38 board to its counterpart on the camera unit.
- To assemble the gain lock unit, follow the disassembly procedure in reverse order.

Lens: Close "C"

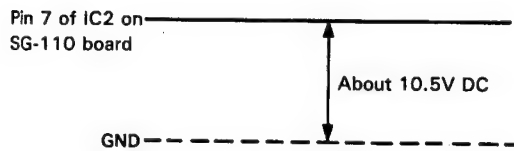
Equipment: Oscilloscope

Test points: Pin 7 of IC2 (chassis ground) on SG-110 board

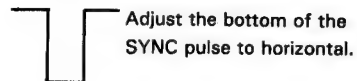
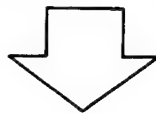
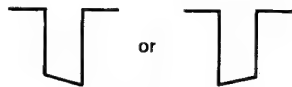
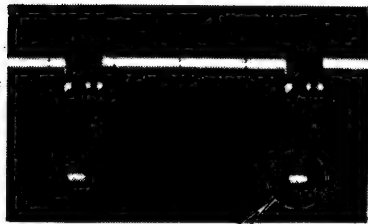
Pin 1 of CN1 (chassis ground) of SG-110 board

Adj. Point: RV1 on SG-110 PC board

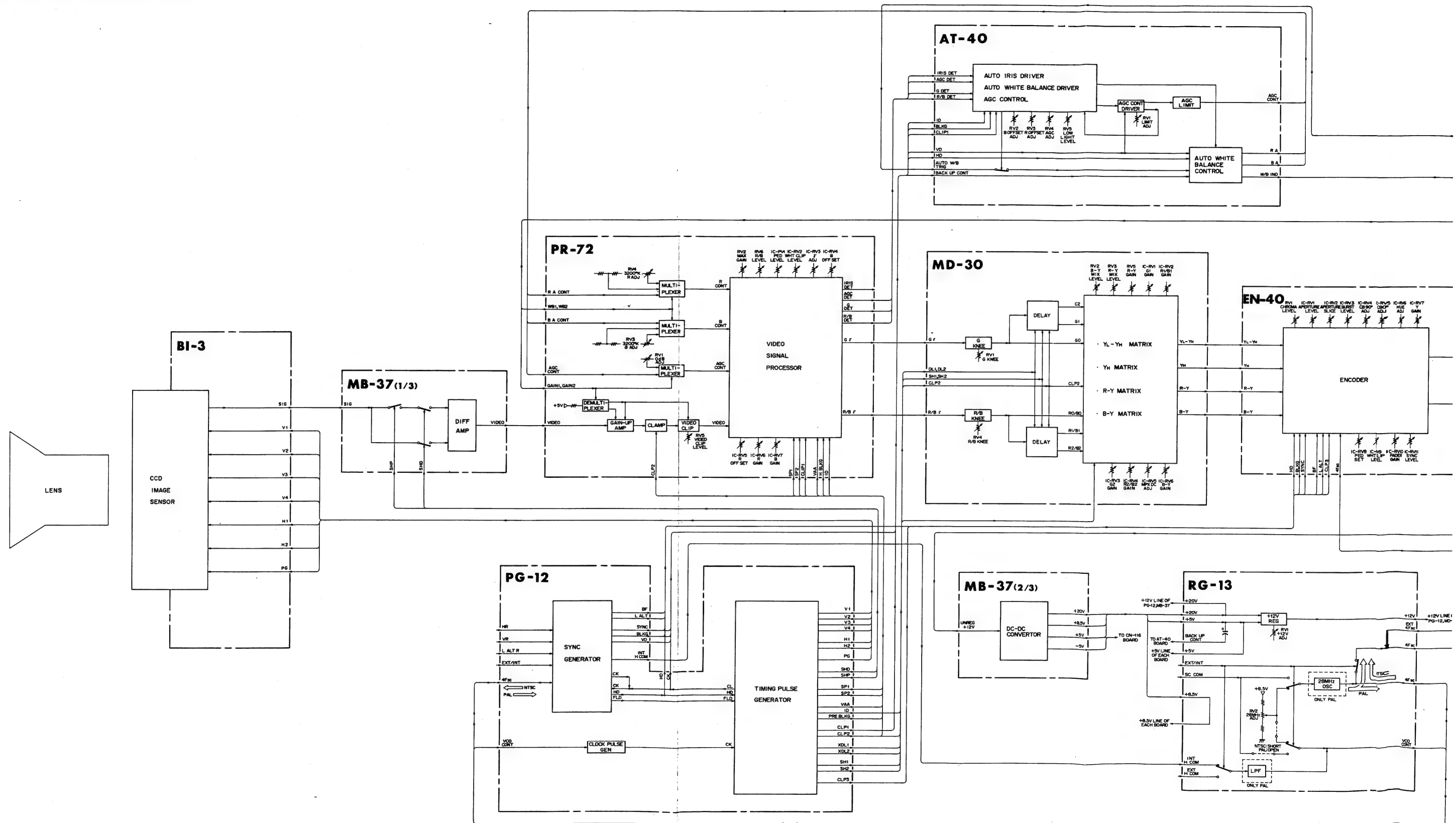
Adjust: Adjust RV1 on the SG-110 board so that pin 7 of IC2 on the SG-110 PC board is about 10.5V DC and the SYNC pulse bottom of the waveform at pin 1 of CN1 is horizontal.



Pin 1 of CN1 of SG-110 board

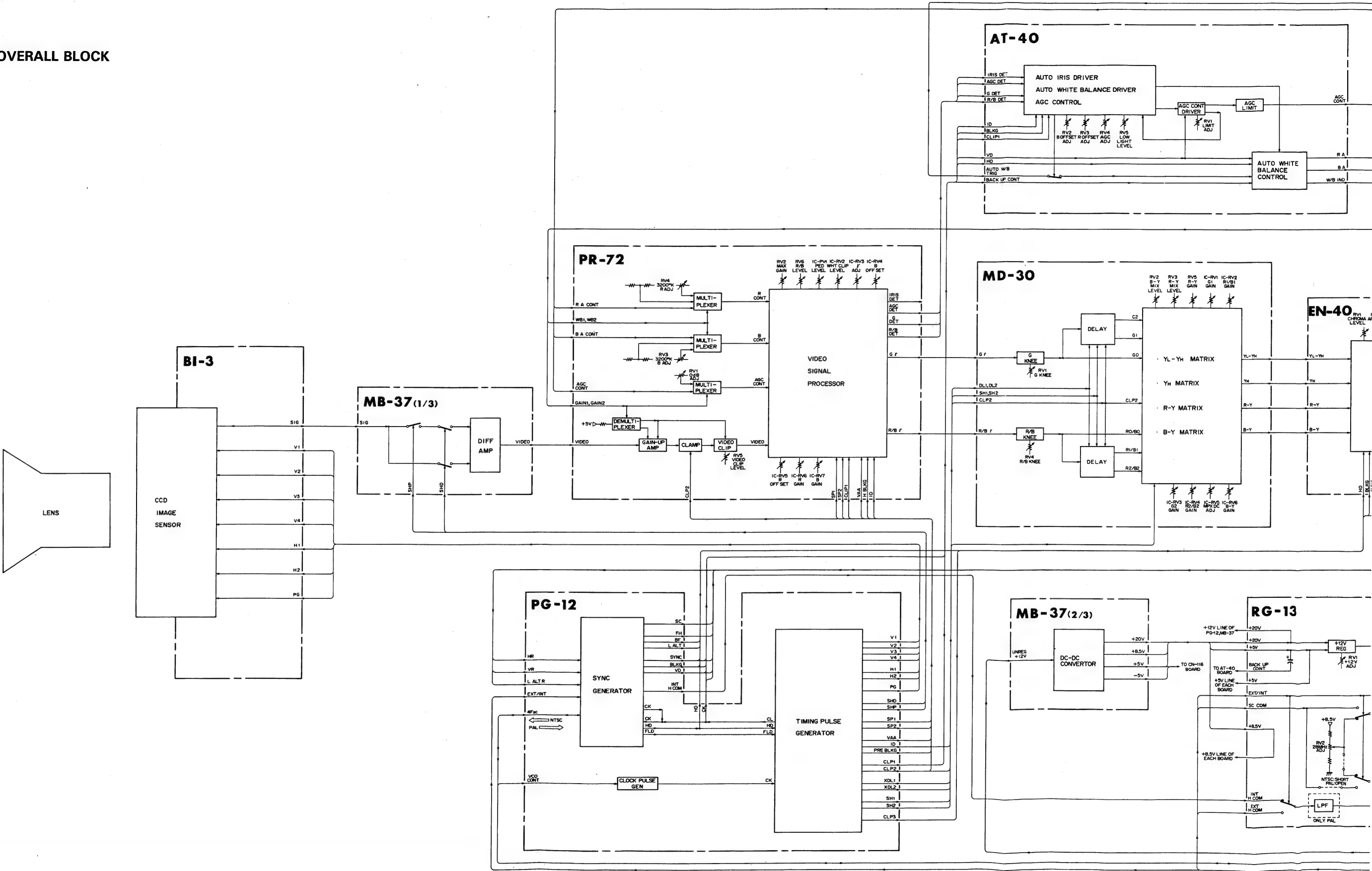


DXC-101/101P OVERALL BLOCK





DXC-102/102P OVERALL BLOCK

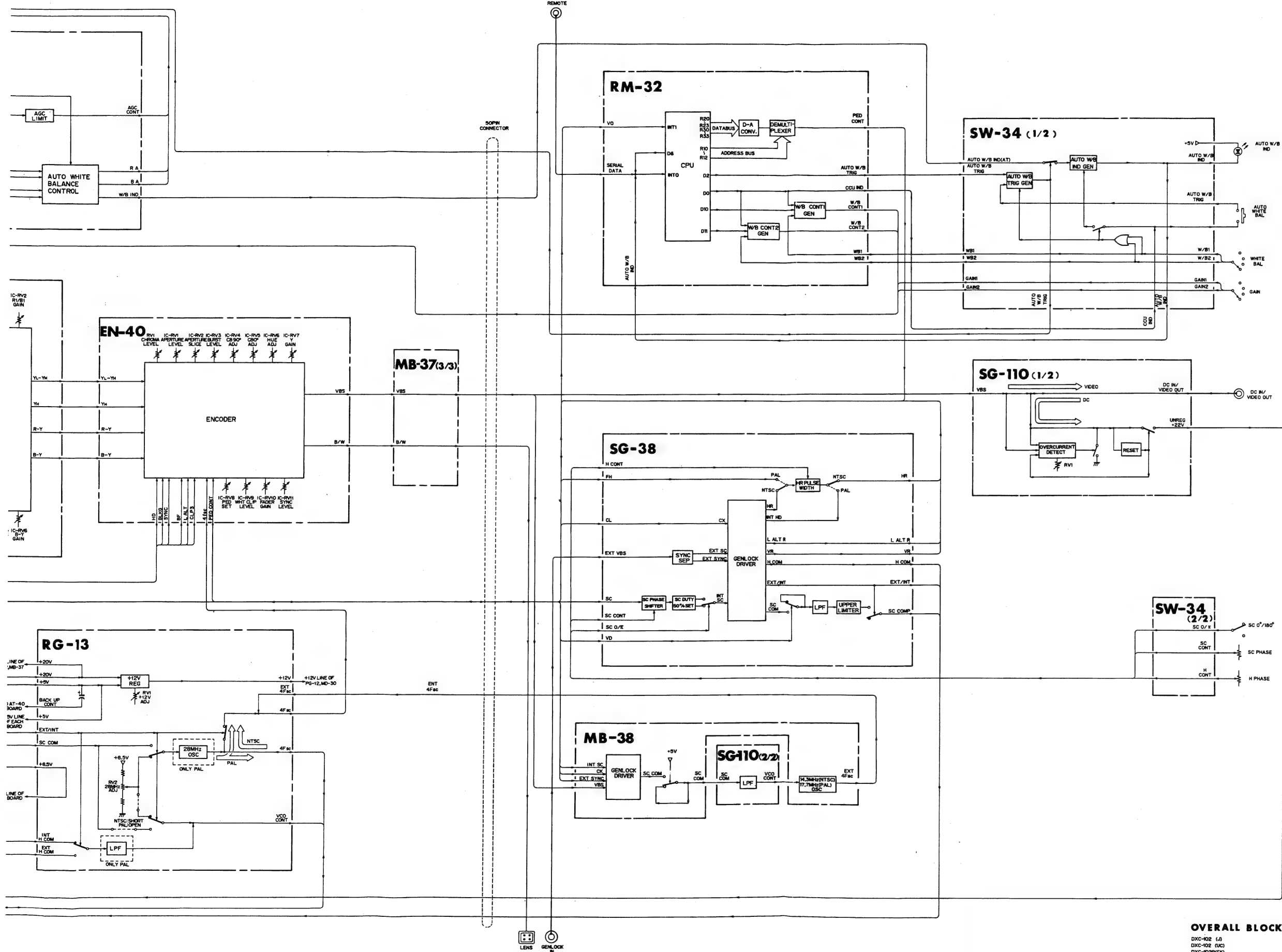


OA B/D

DXC-102/102P

DXC-102/102P

OA B/D

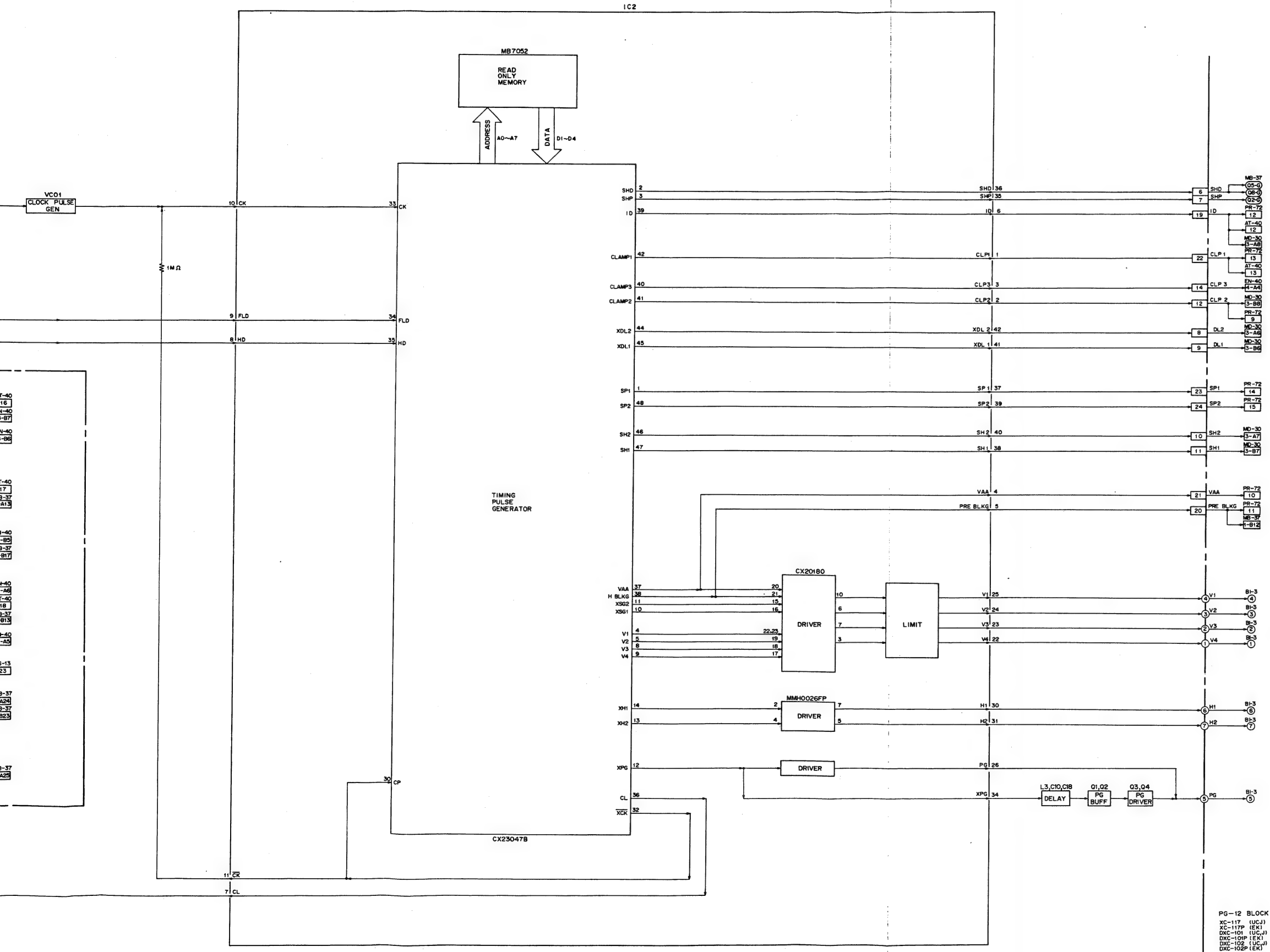


OVERALL BLOCK

DXC-102 (J)
DXC-102 (UC)
DXC-102P(EK)

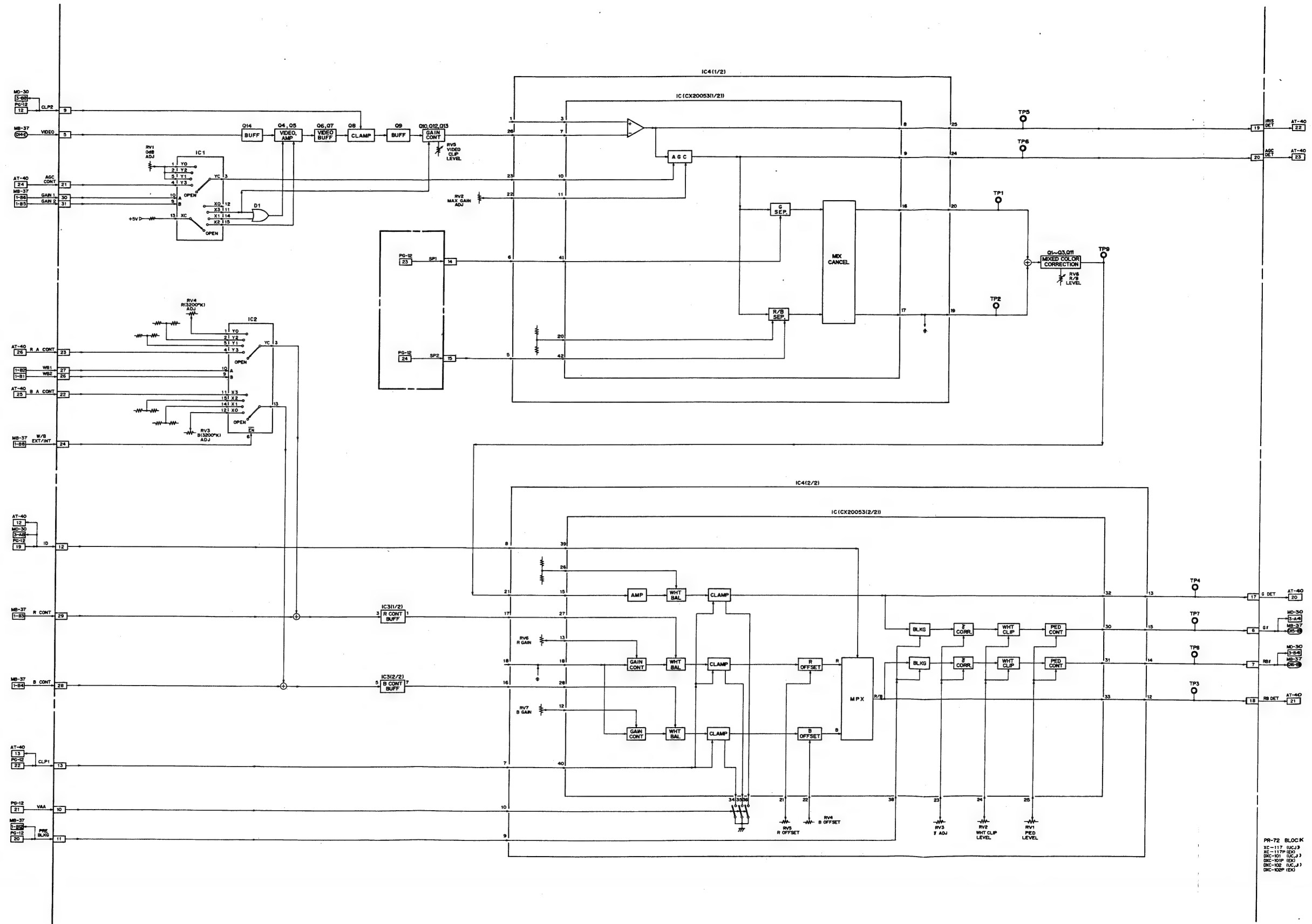
5-9

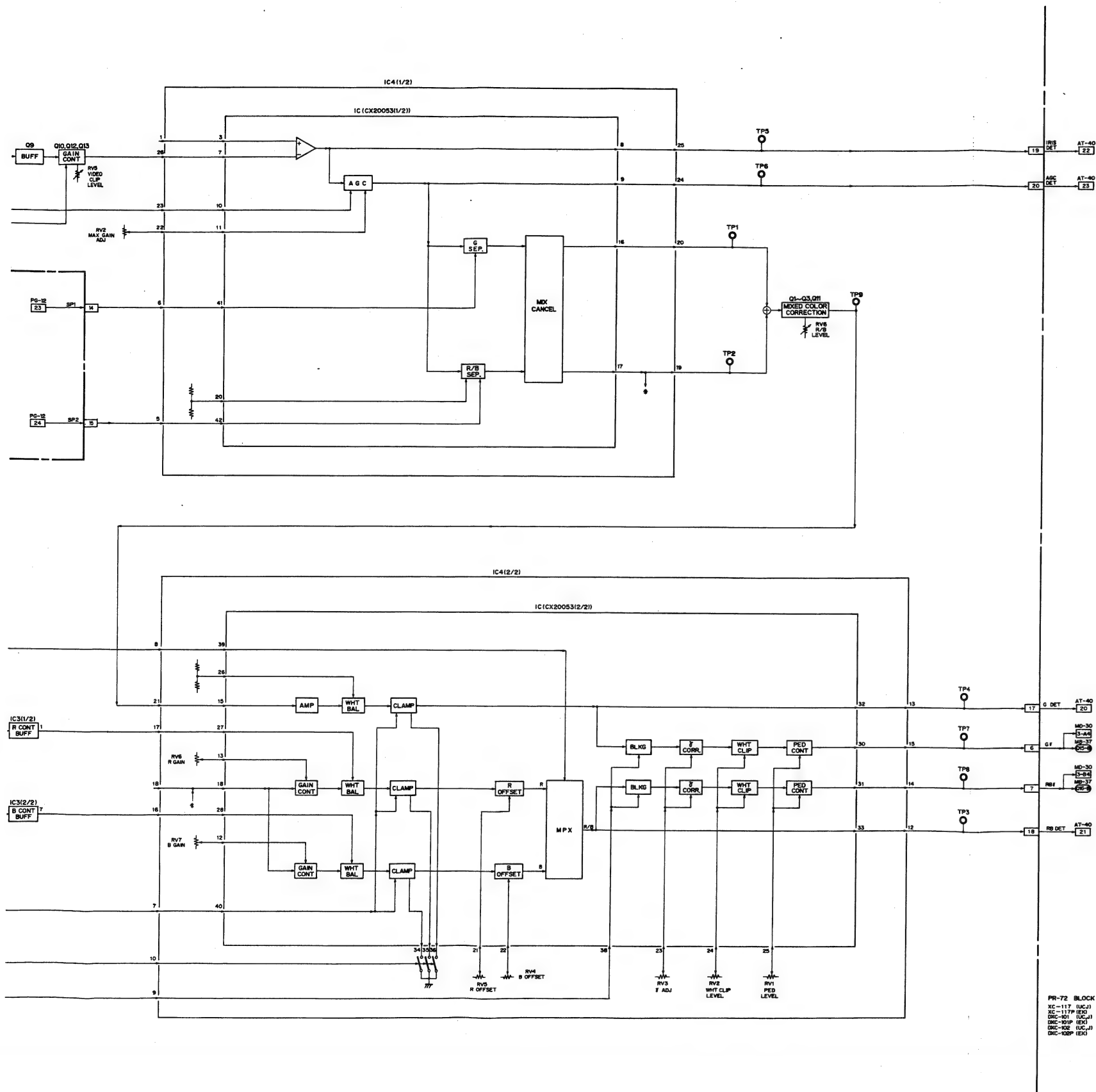


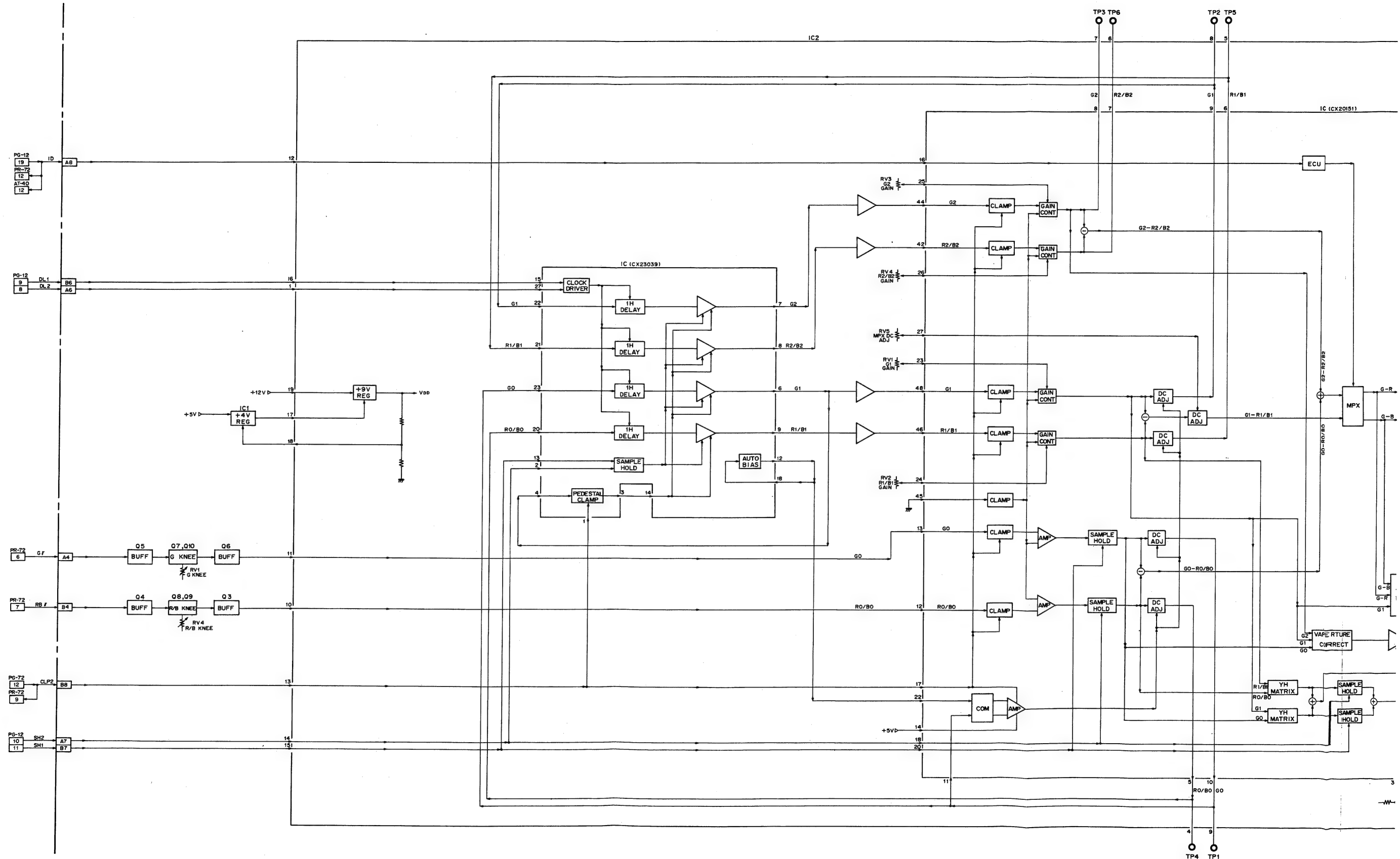


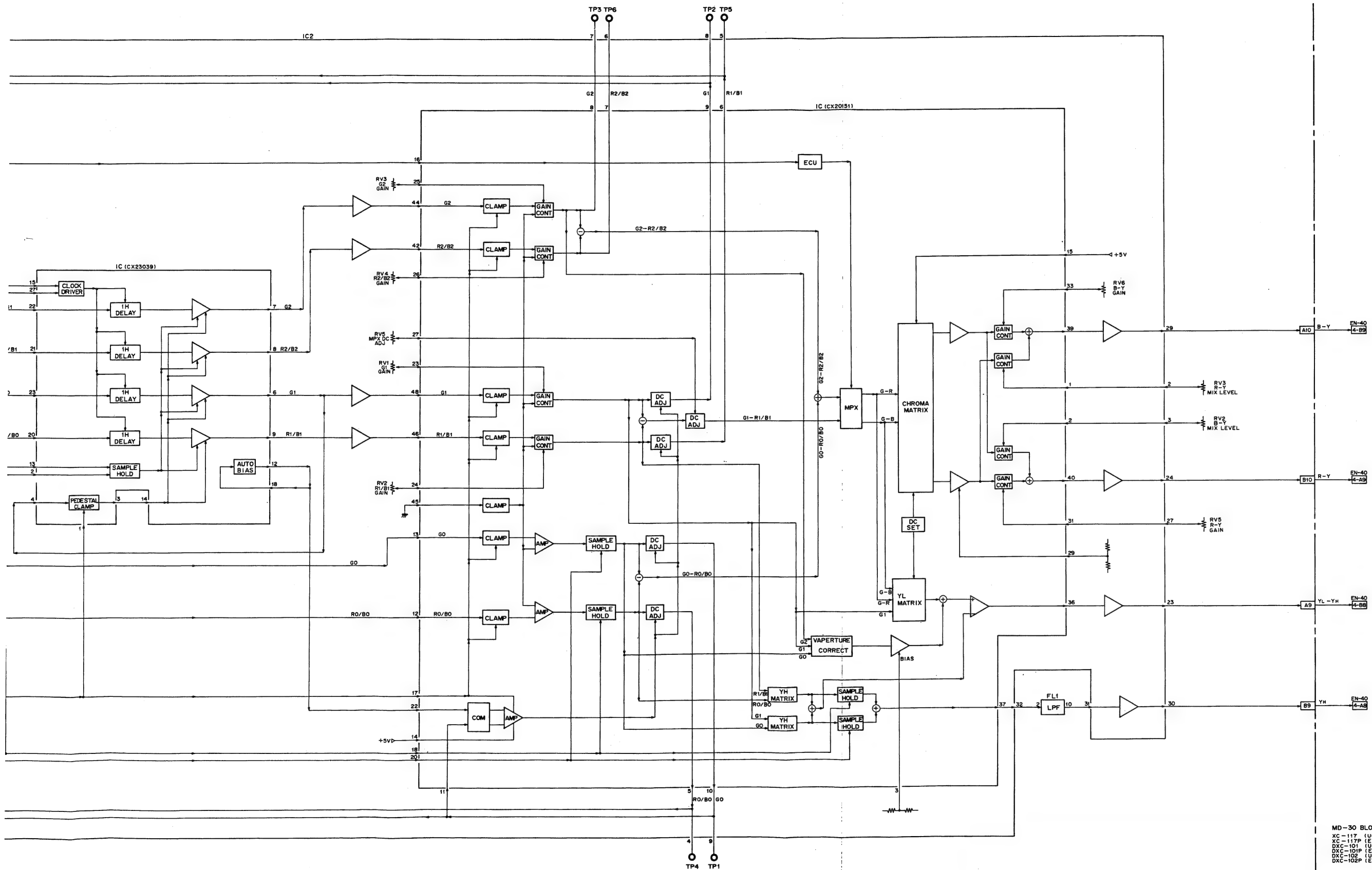
PG-12 BLOCK
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UCJ)
DXC-101P (EK)
DXC-102 (UCJ)
DXC-102P (EK)

PR-72 BLOCK

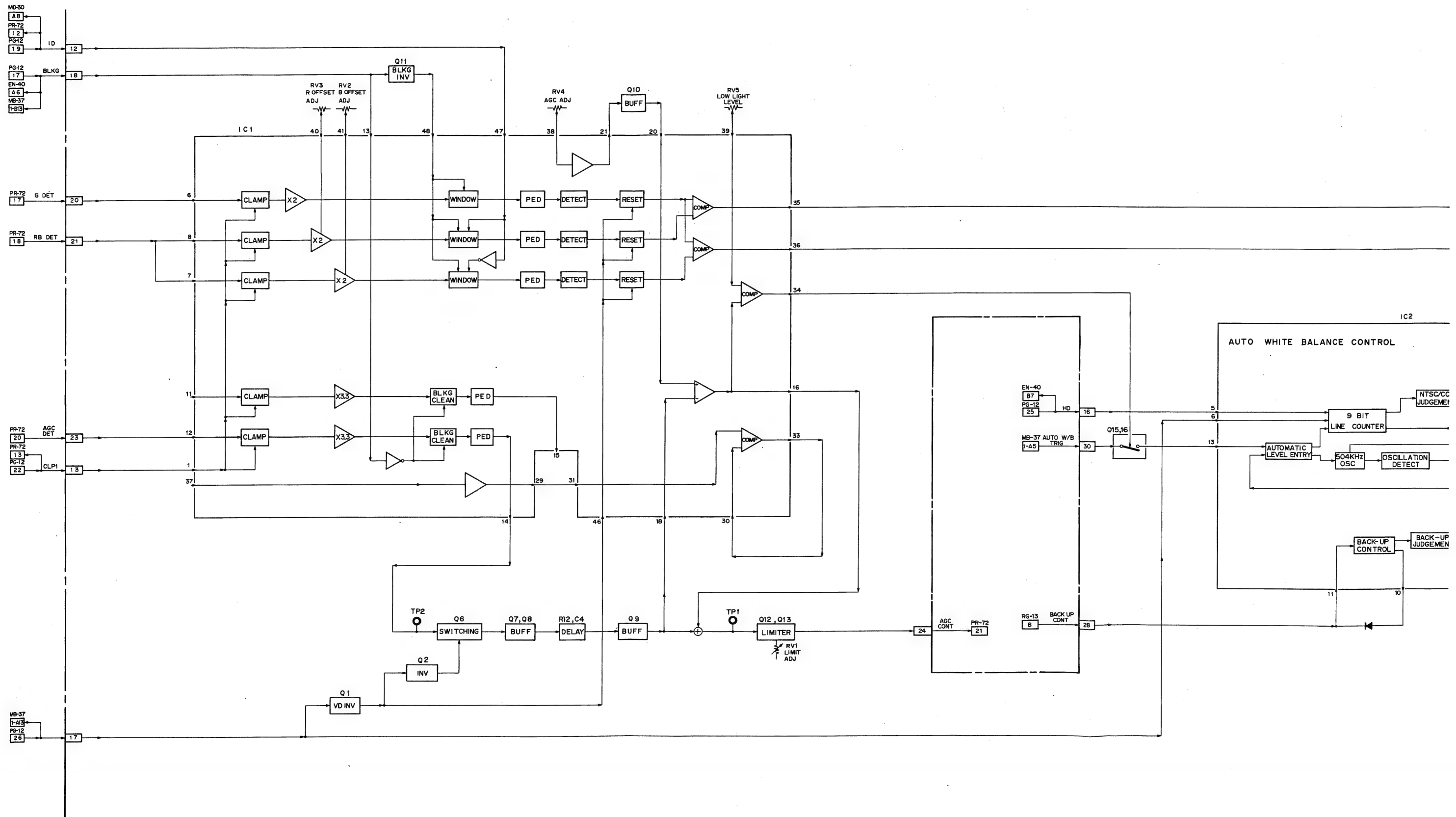


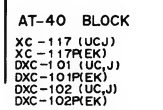


MD-30 BLOCK

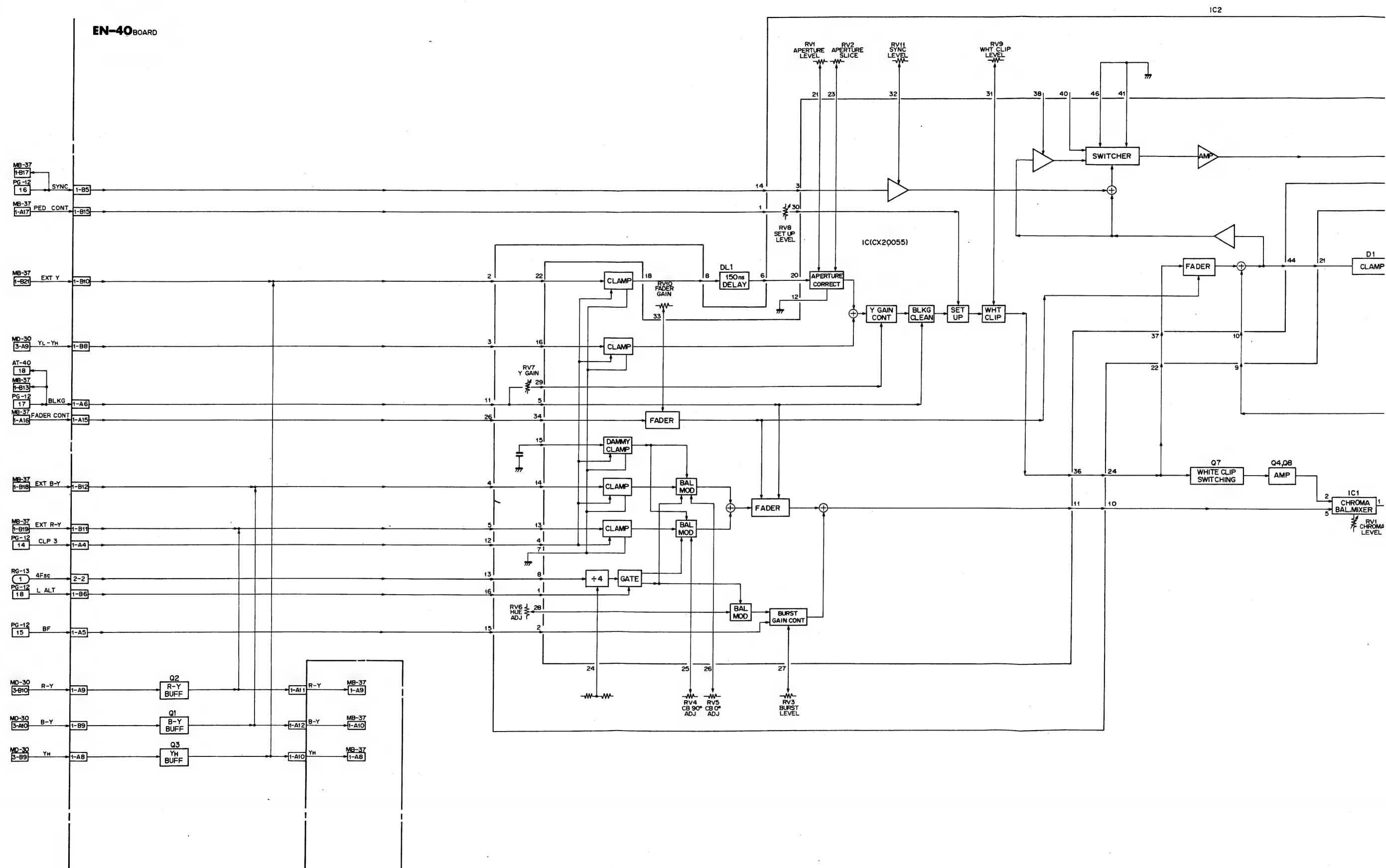


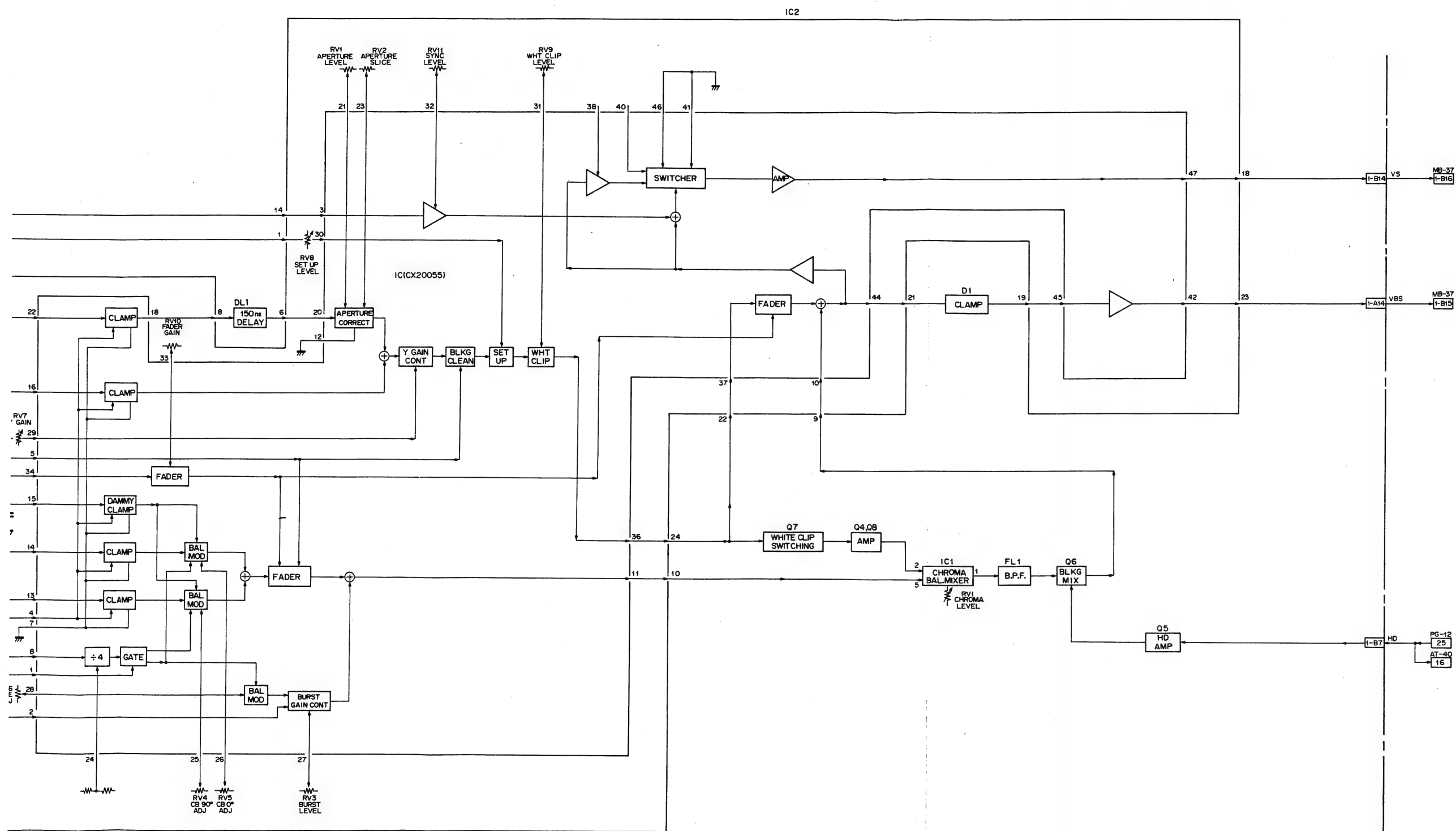
AT-40 BLOCK





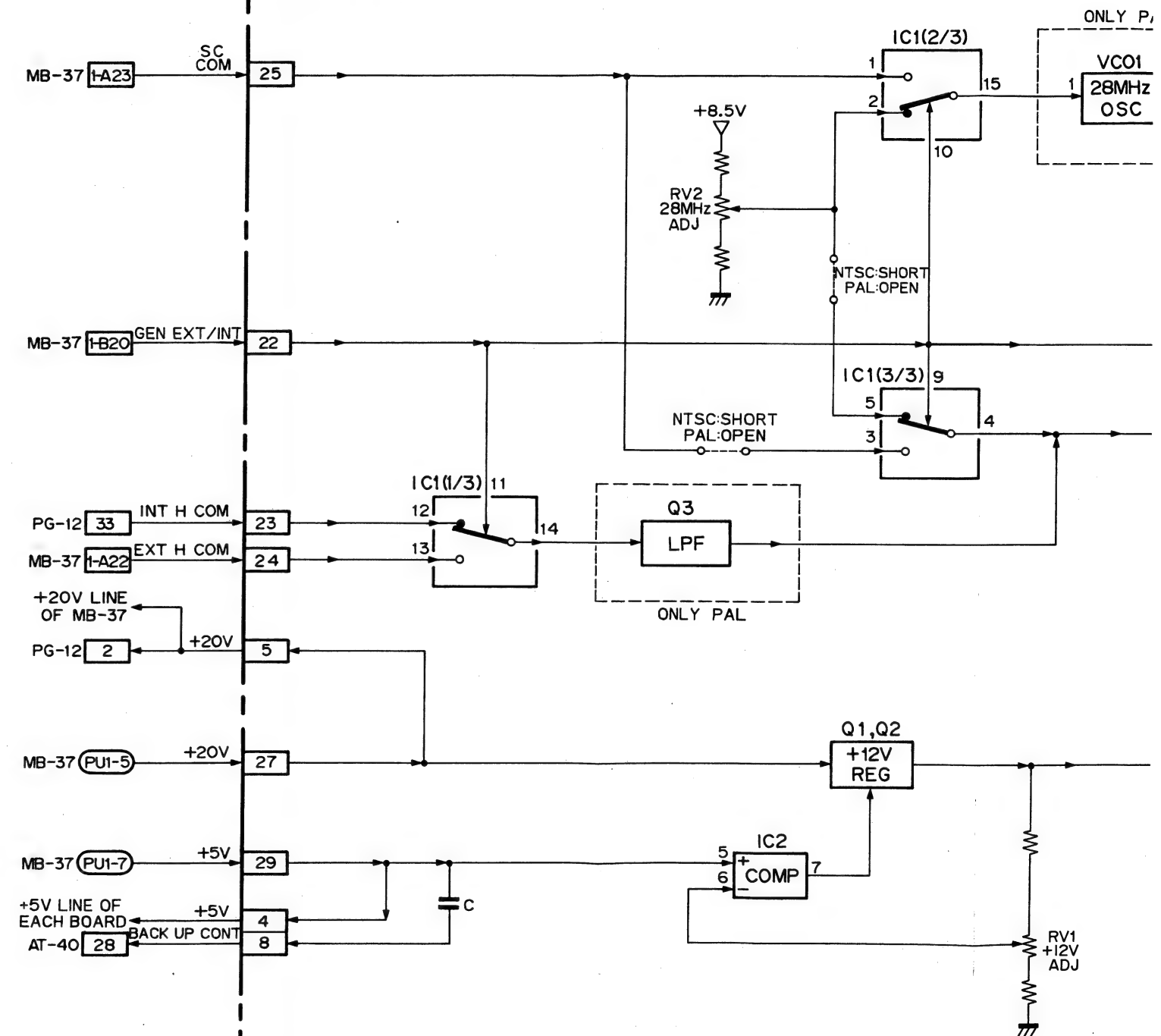
EN-40 BLOCK



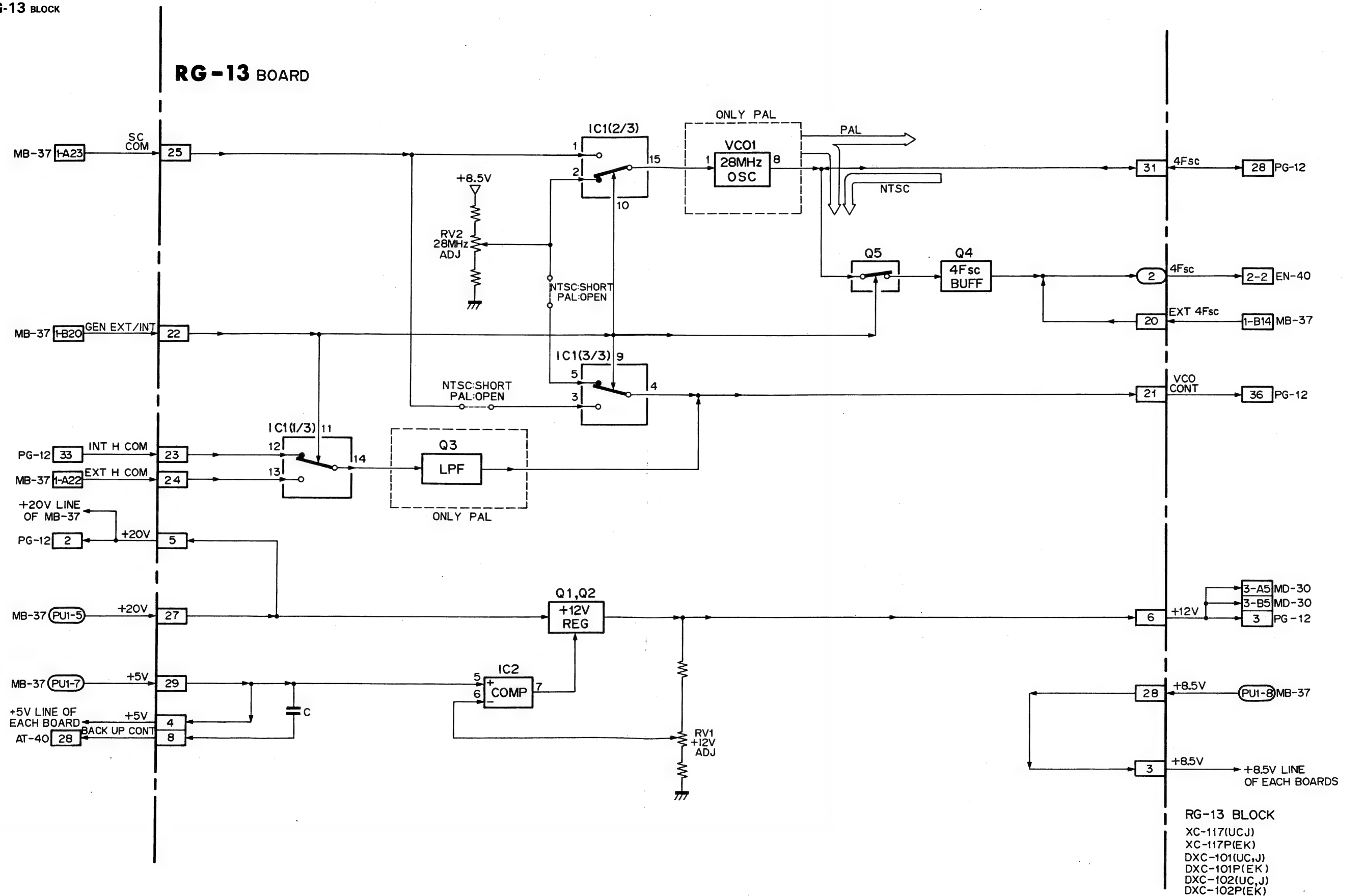


EN-40 BLOCK
 XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UCJ)
 DXC-101P (EK)
 DXC-102 (UCJ)
 DXC-102P (EK)

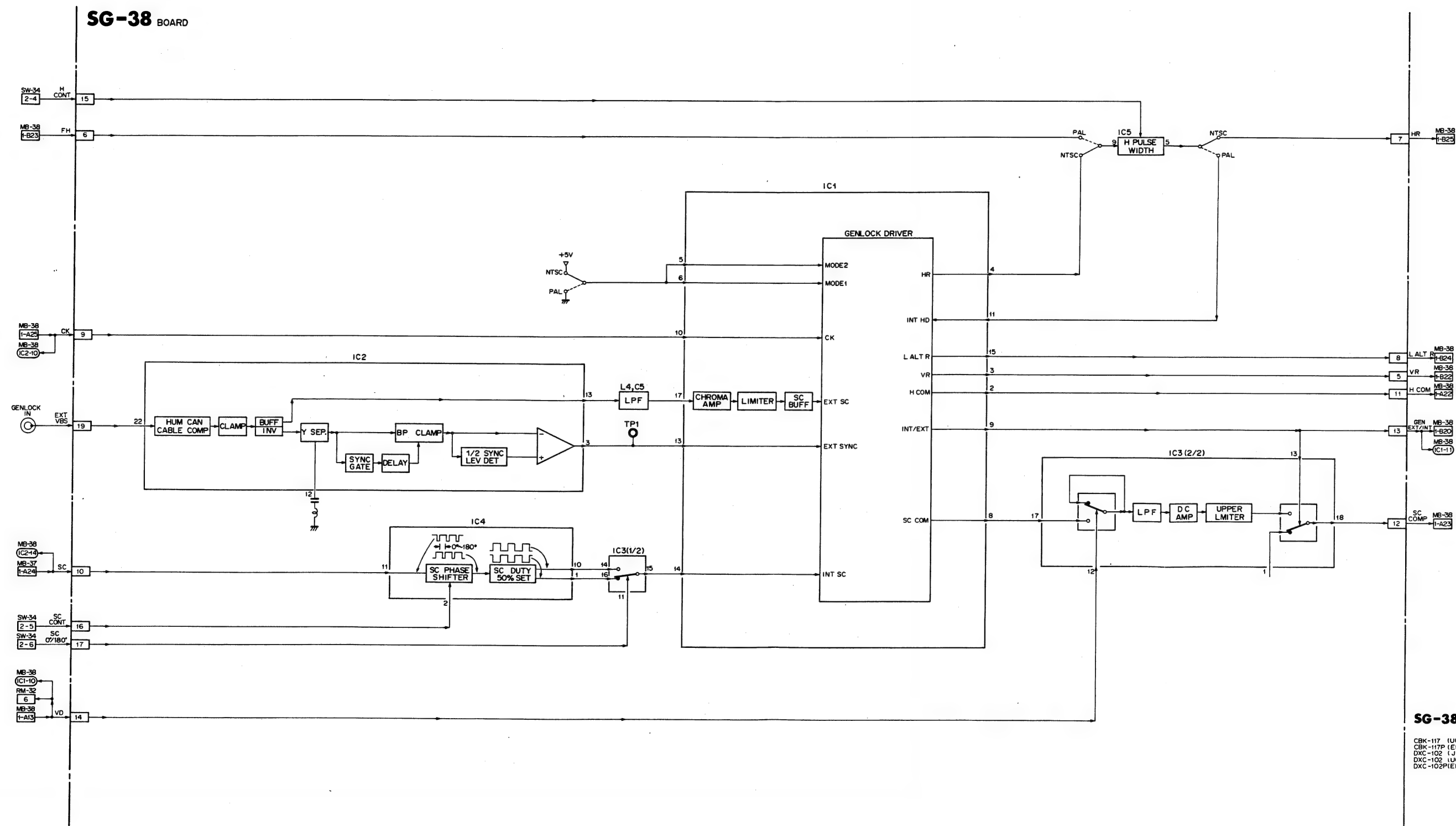
RG-13 BLOCK

RG-13 BOARD

RG-13 BLOCK



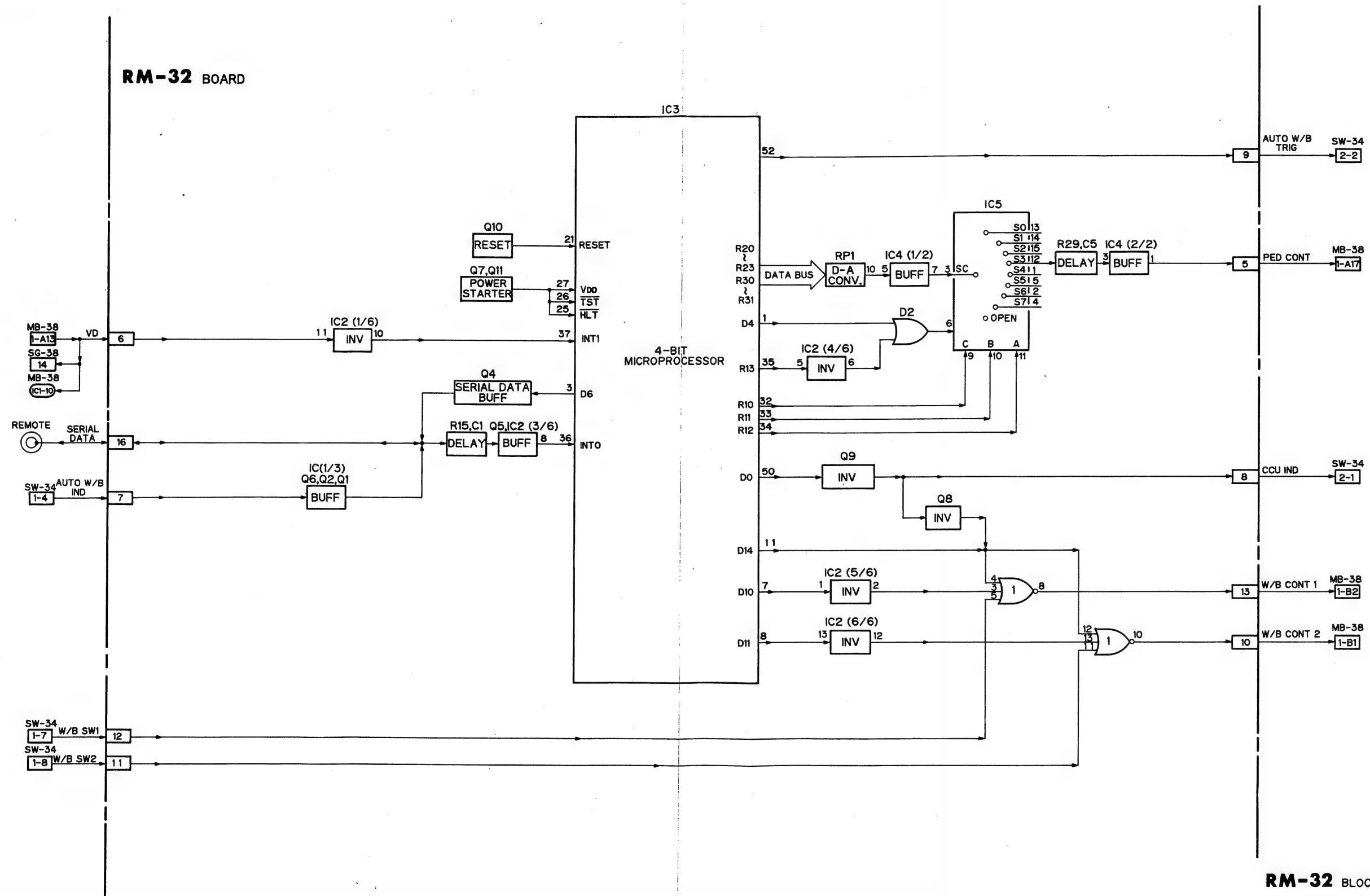
SG-38 BLOCK



SG-38 BLOCK

CBK-117 (UCJ)
 CBK-117P (EK)
 DXC-102 (J)
 DXC-102 (UC)
 DXC-102P(EK)

RM-32 BLOCK



RM-32 BLOCK

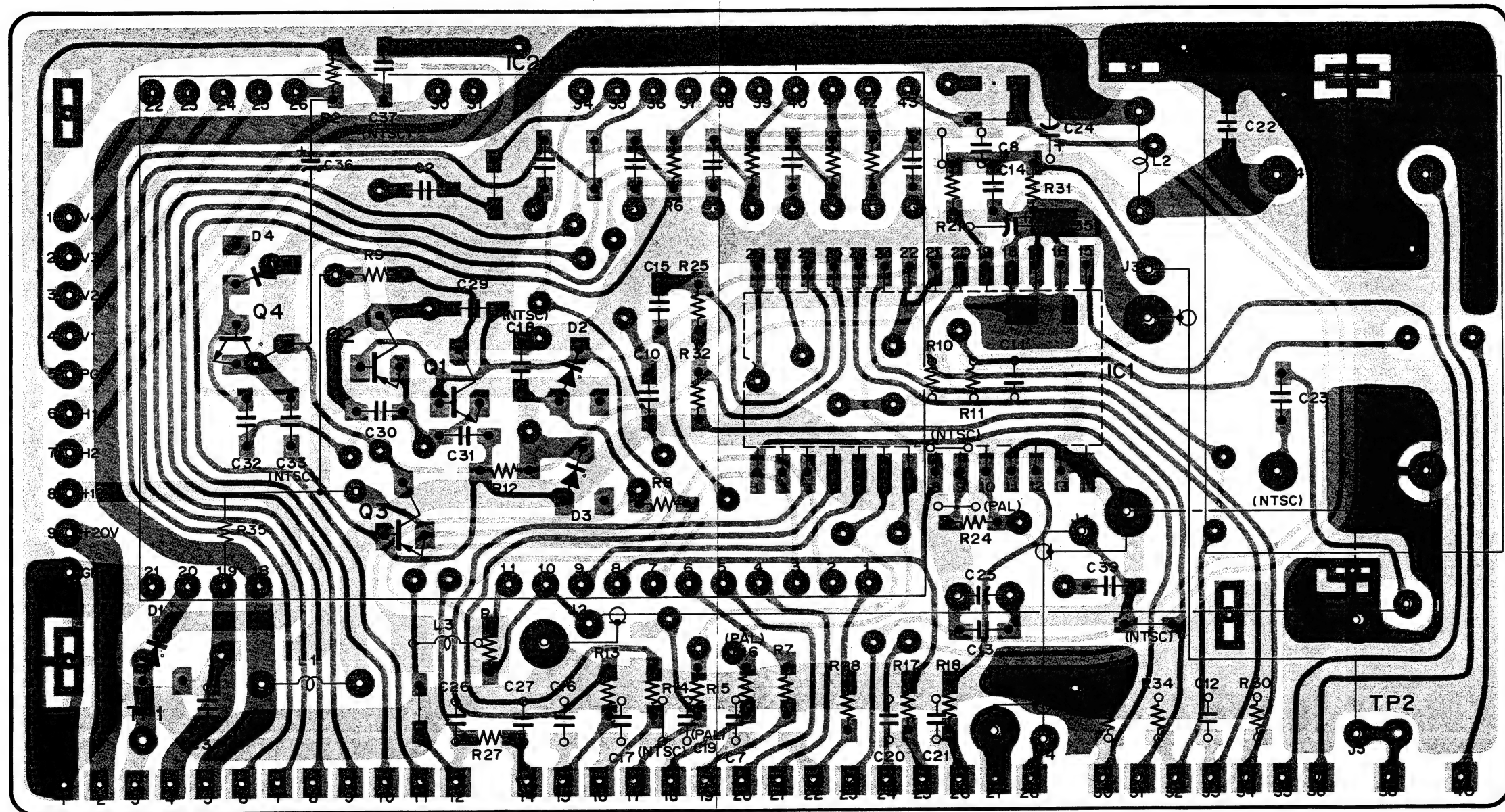
CBK-117 (UCJ)
 CBK-117P (EK)
 DXC-102 (J)
 DXC-102 (UC)
 DXC-102P (EK)

SECTION 6

SCHEMATIC AND MOUNTING DIAGRAM

PG-12 BOARD

SERIAL NO.
 DXC-101 (J) Up to 51290
 DXC-101 (UC) Up to 11180
 DXC-101P (EK) Up to 12080
 DXC-102 (J) Up to 10470
 DXC-102 (UC) Up to 10660
 DXC-102P (EK) Up to 11070



— SOLDERING SIDE —

PG-12 BOARD

1-617-210-11

XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC, J)
 DXC-101P (EK)
 DXC-102 (UC, J)
 DXC-102P (EK)

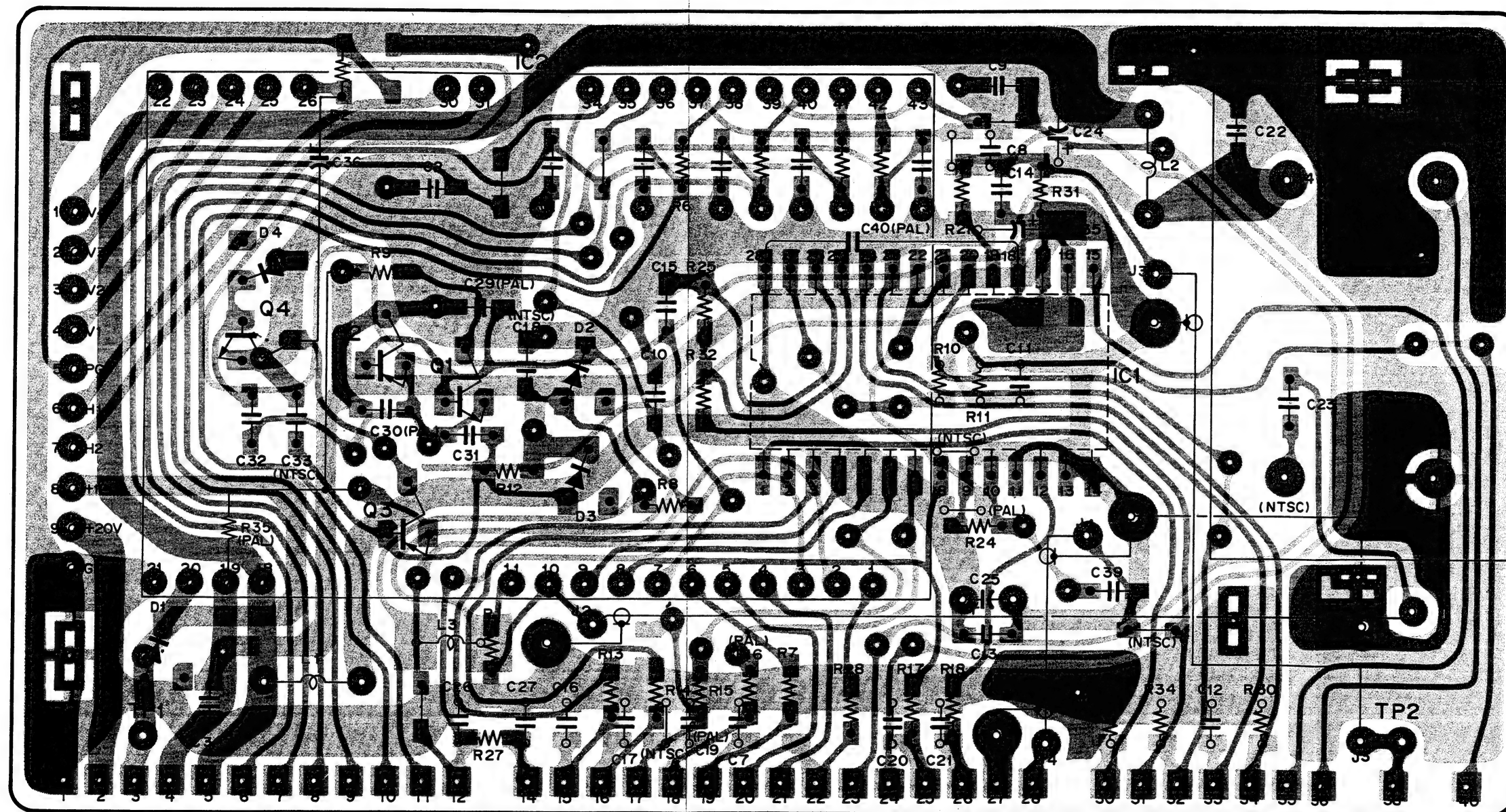
6-4(a)

DXC-101/102/101P/102P (J, UC, EK)

6-3(a)

PG-12 BOARD

SERIAL NO.
 DXC-101 (J) 51291 and higher
 DXC-101 (UC) 11181 and higher
 DXC-101P (EK) 12081 and higher
 DXC-102 (J) 10471 and higher
 DXC-102 (UC) 10661 and higher
 DXC-102P (EK) 11071 and higher



— SOLDERING SIDE —

PG-12 BOARD

1-617-210-12

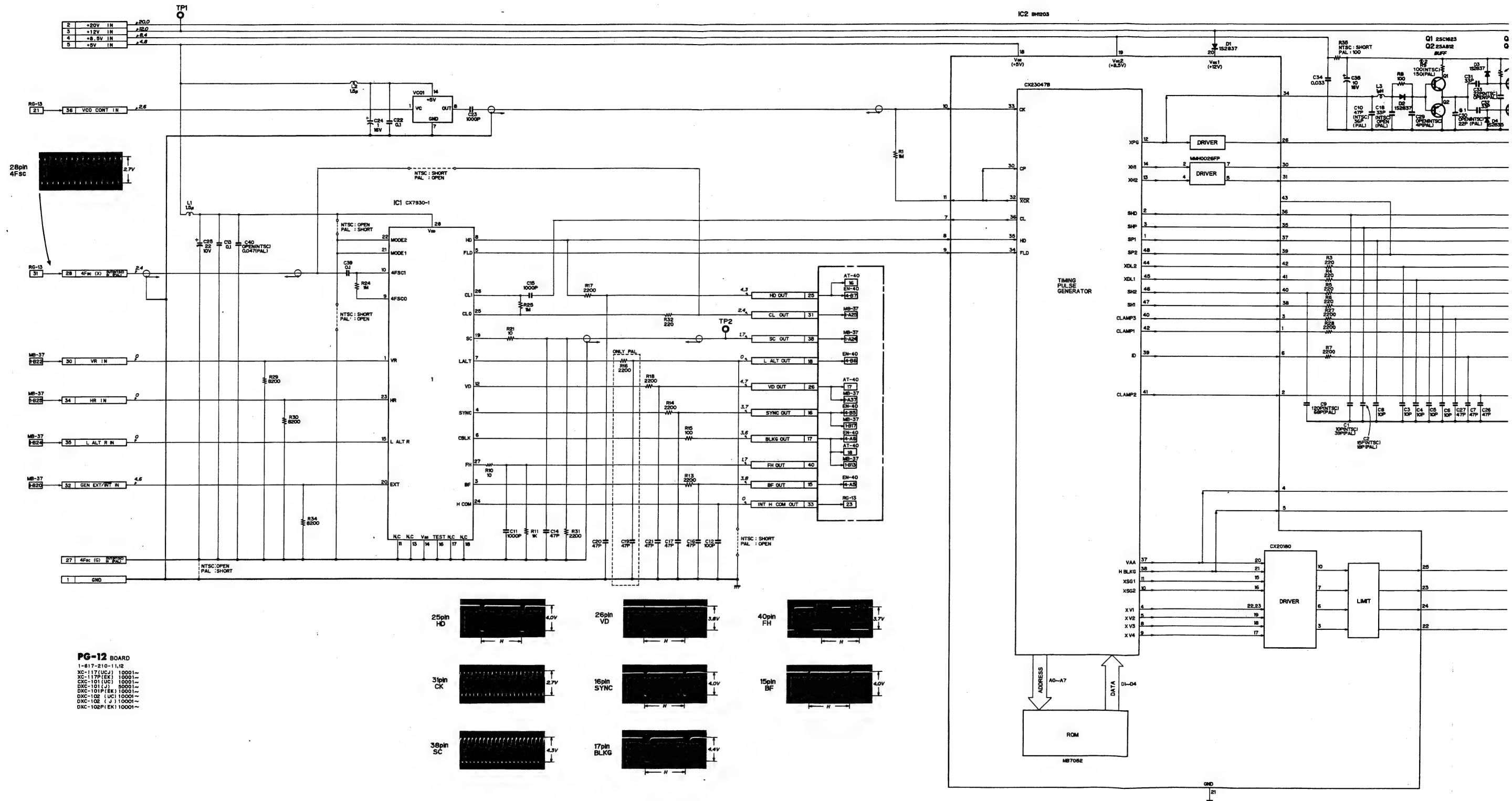
XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

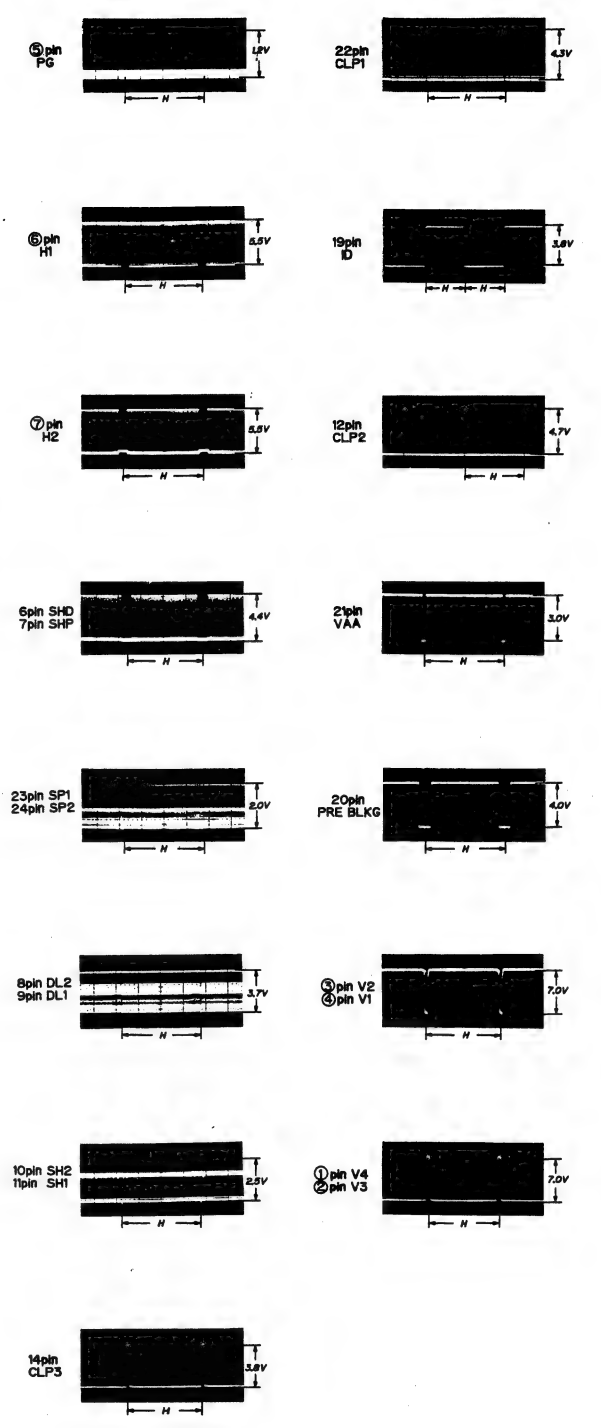
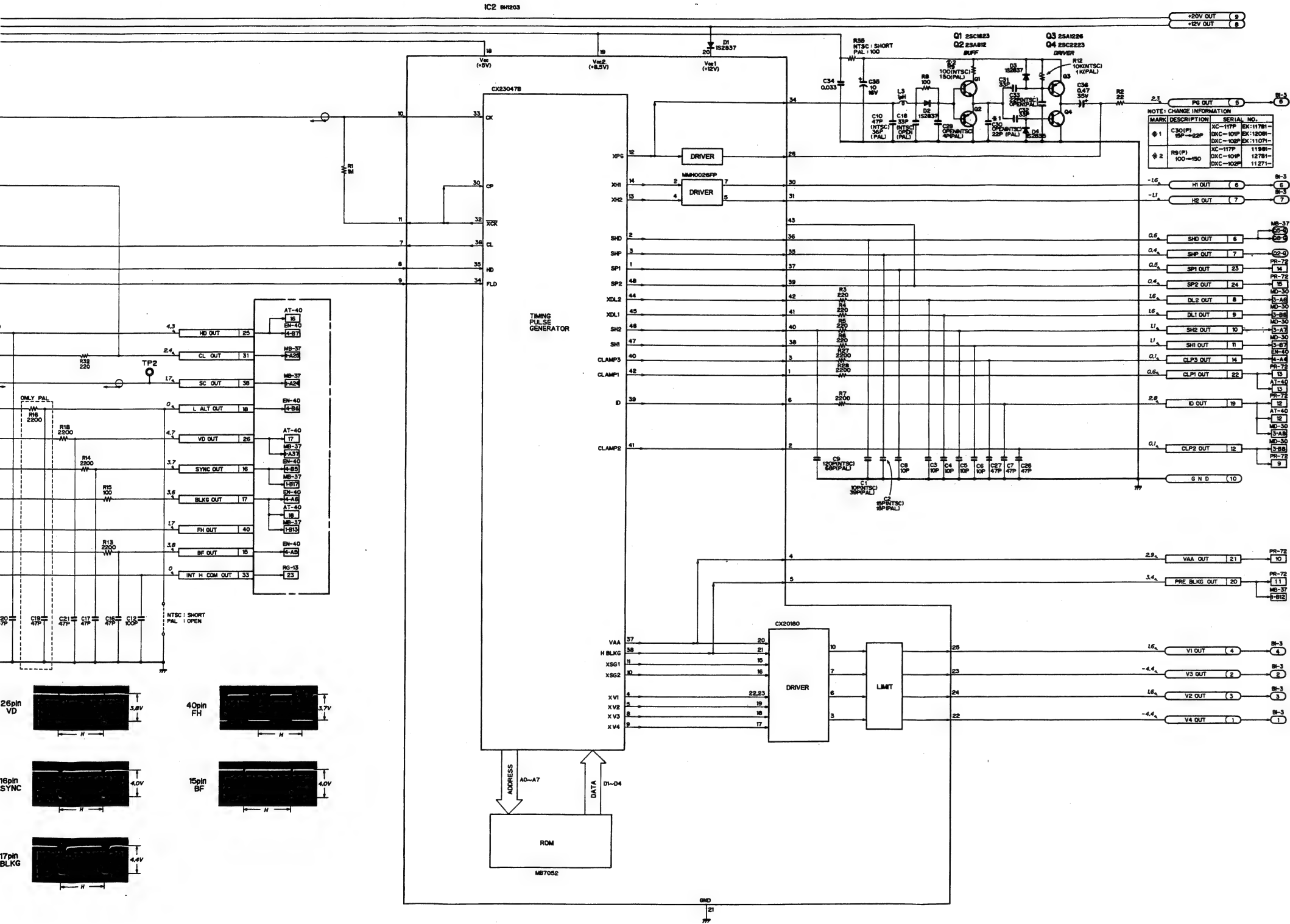
6-4(b)

DXC-101/102/101P/102P (J, UC, EK)

6-3(b)

PG-12 BOARD (SYNC AND TIMING PULSE GEN)



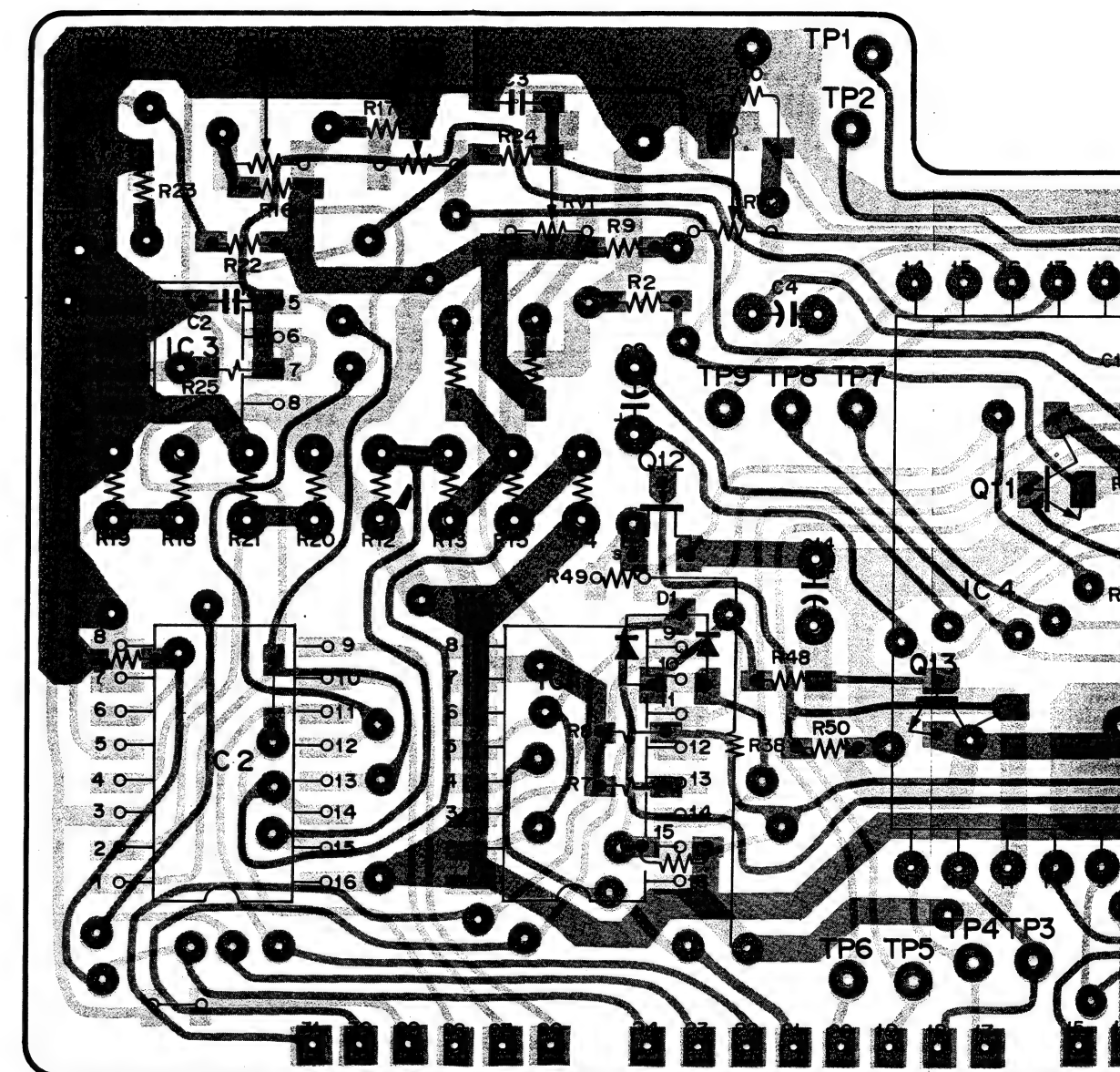


注意：
DC電圧はデジタル電圧計にて測定。

NOTE:
All voltage are mesured with a digital voltmeter (input resistance 10 MΩ).

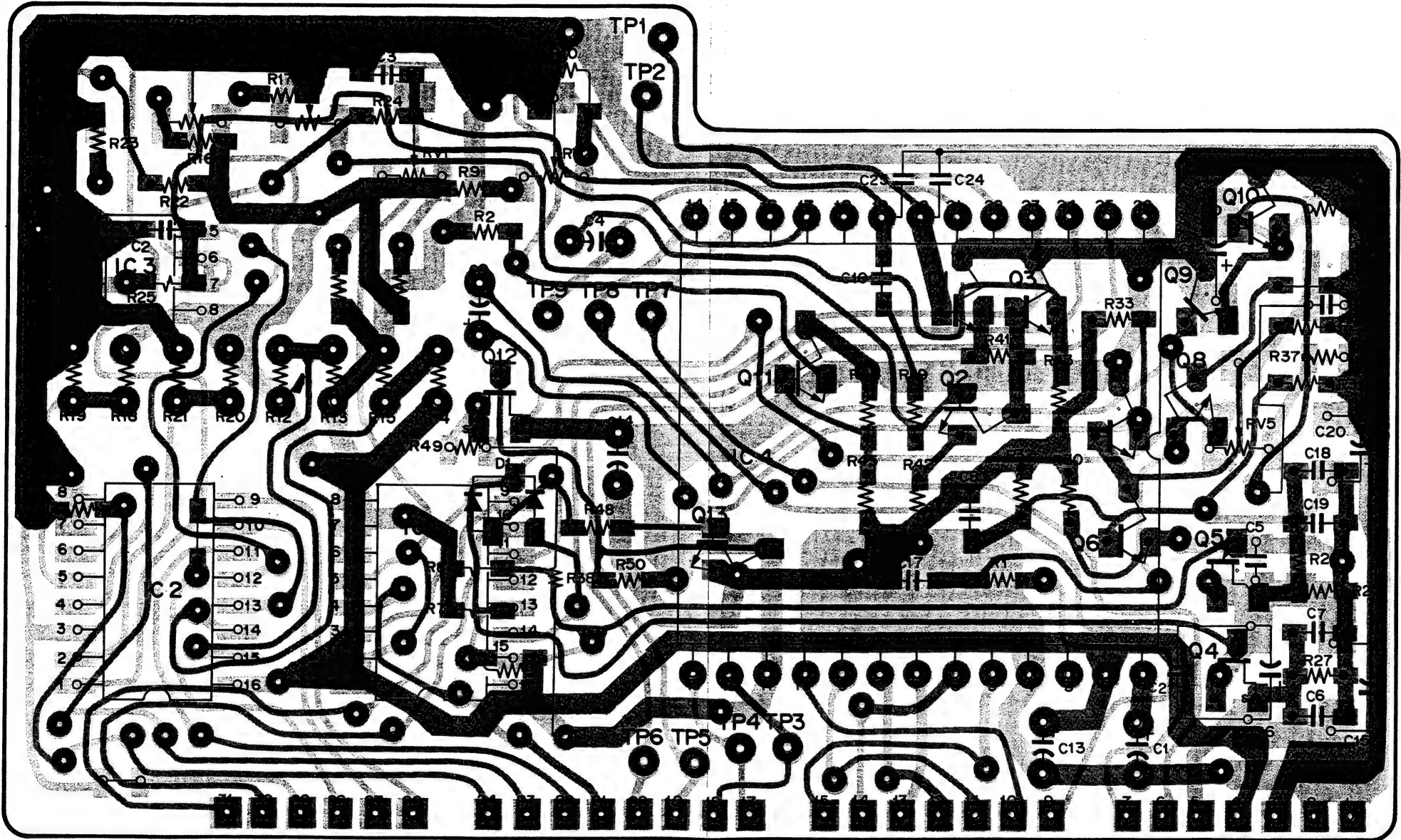
PR-72 BOARD

SERIAL NO.	
DXC-101 (J)	Up to 50430
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10260
DXC-102 (J)	Up to 10190
DXC-102 (UC)	Up to 10180
DXC-102P (EK)	Up to 10310



PR-72 BOARD

SERIAL NO.	
DXC-101 (J)	Up to 50430
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10260
DXC-102 (J)	Up to 10190
DXC-102 (UC)	Up to 10180
DXC-102P (EK)	Up to 10310



— SOLDERING SIDE —

PR-72 BOARD

1-617-214-11

- XC-117 (UCJ)
- XC-117P (EK)
- DXC-101 (UC, J)
- DXC-101P (EK)
- DXC-102 (UC, J)
- DXC-102P (EK)

PR-72

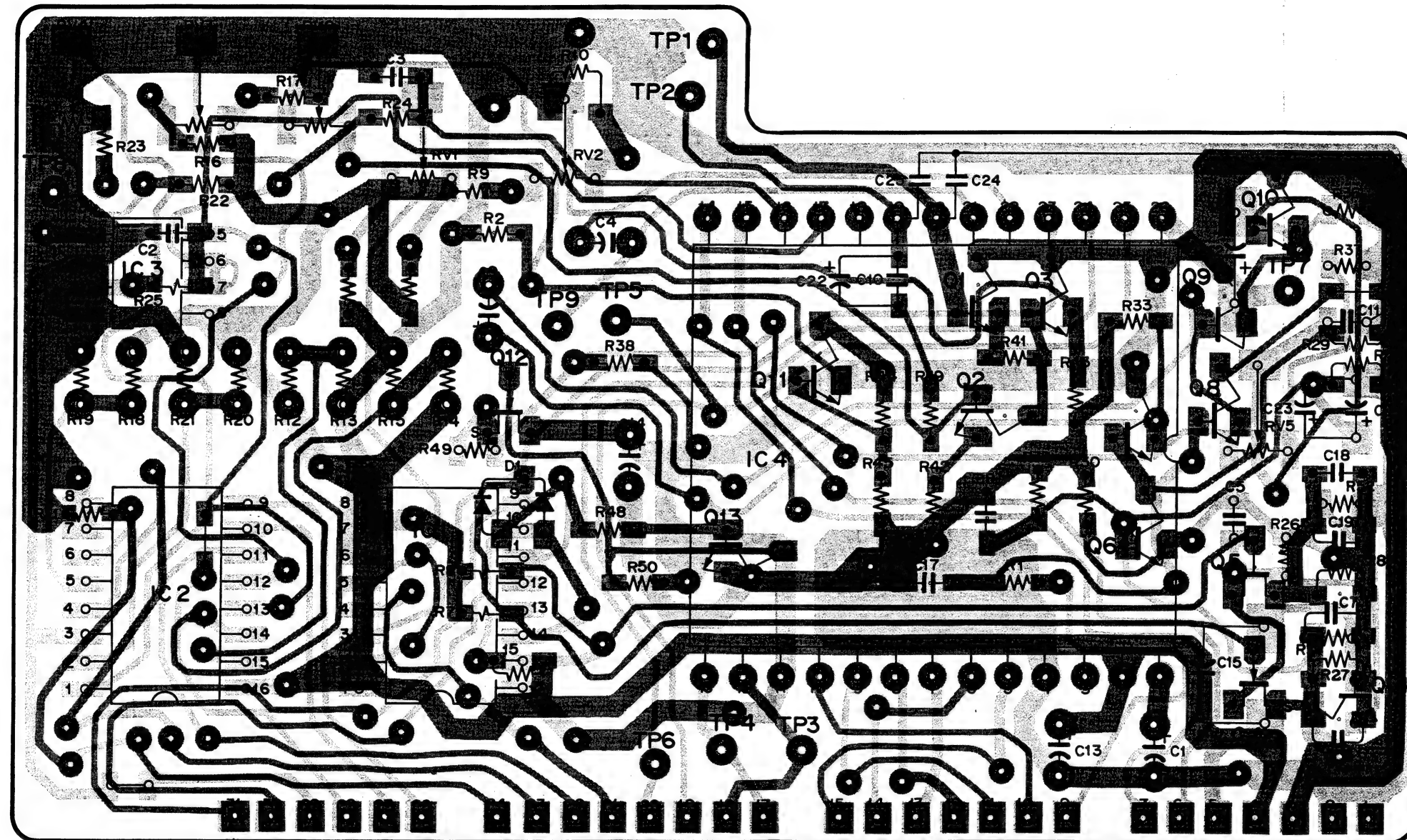
DXC-101/101P/102/102P

DXC-101/101P/102/102P

PR-72

PR-72 BOARD

SERIAL NO.
 DXC-101 (J) 50431 to 50790
 DXC-101 (UC) 10221 to 10830
 DXC-101P (EK) 10261 to 11080
 DXC-102 (J) 10191 to 10380
 DXC-102 (UC) 10181 to 10610
 DXC-102P (EK) 10311 to 10920



— SOLDERING SIDE —

PR-72 BOARD

1-617-214-12

XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC, J)
 DXC-101P (EK)
 DXC-102 (UC, J)
 DXC-102P (EK)

PR-72

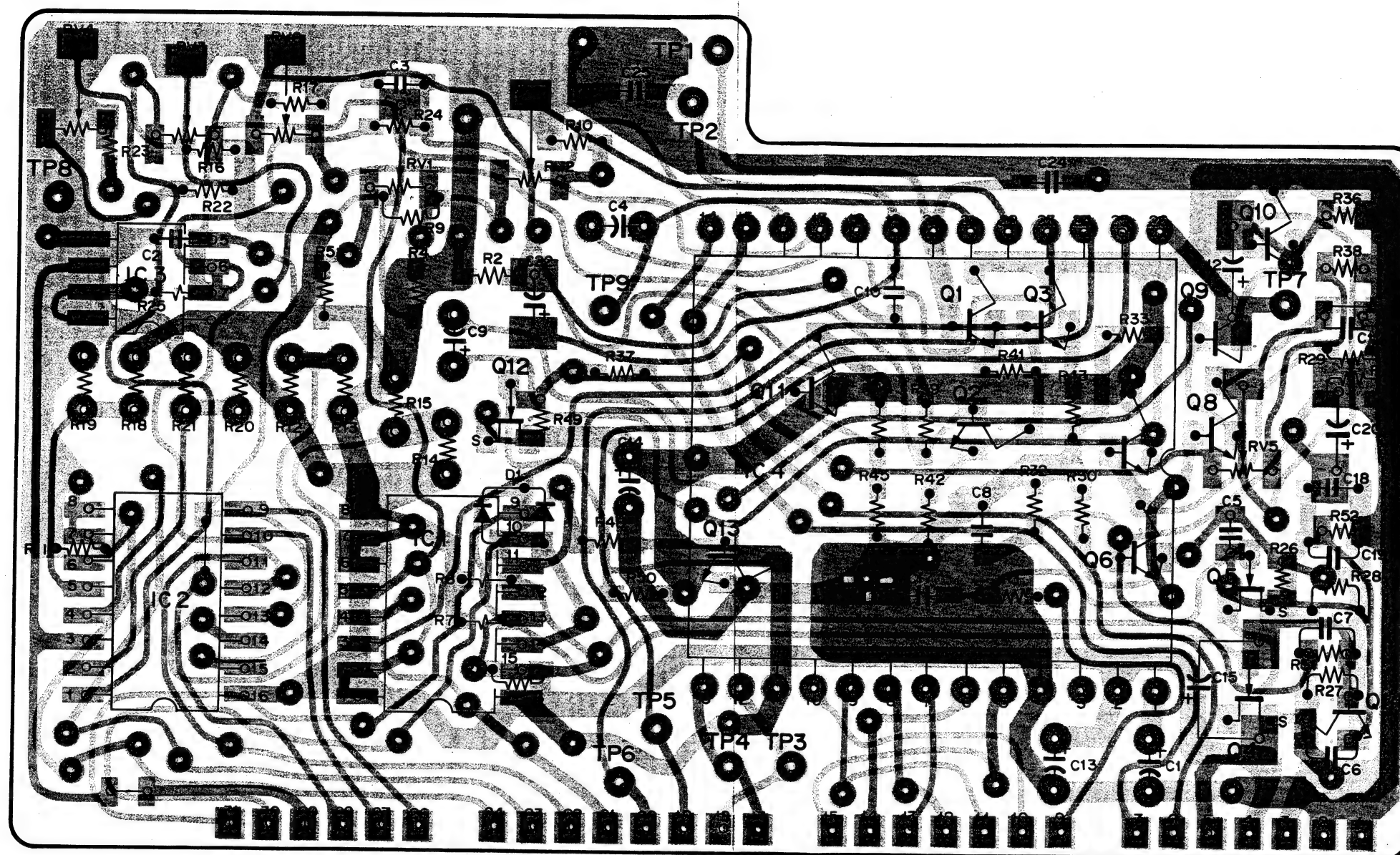
DXC-101/101P/102/102P

DXC-101/101P/102/102P

PR-72

PR-72 BOARD

SERIAL NO.
 DXC-101 (J) 50791 and higher
 DXC-101 (UC) 10831 and higher
 DXC-101P (EK) 11081 and higher
 DXC-102 (J) 10381 and higher
 DXC-102 (UC) 10611 and higher
 DXC-102P (EK) 10921 and higher

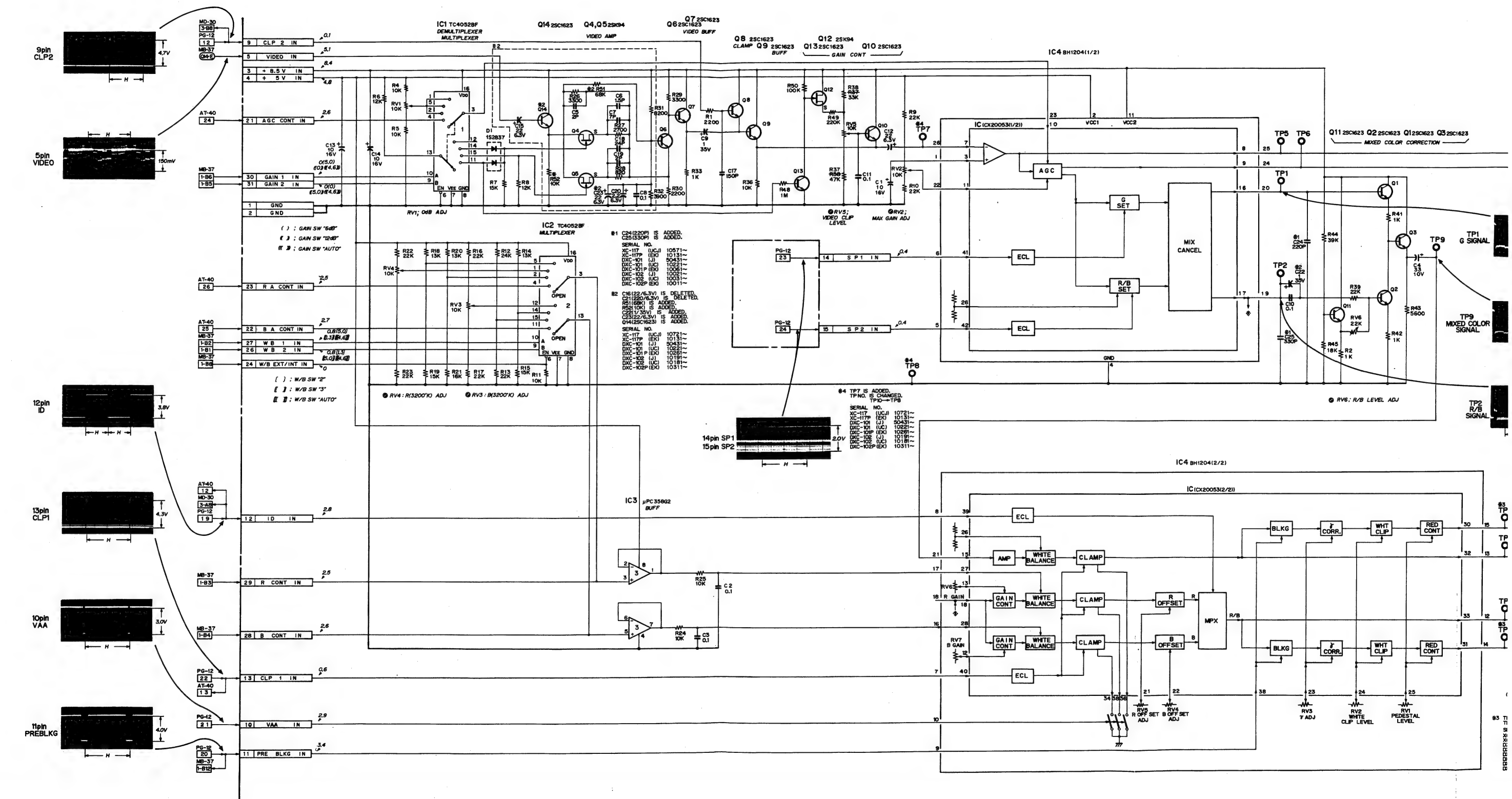


— SOLDERING SIDE —

PR-72 BOARD

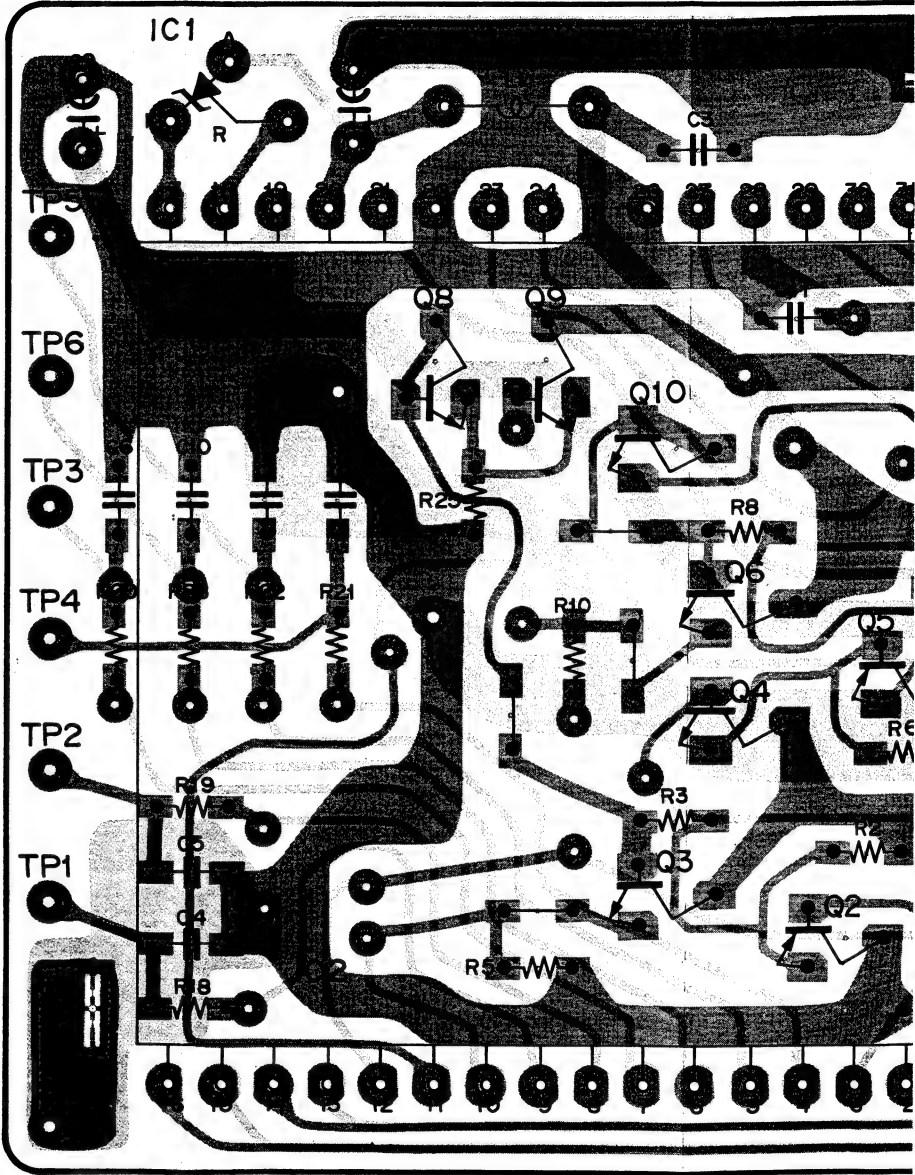
1-617-214-13

XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC, J)
 DXC-101P (EK)
 DXC-102 (UC, J)
 DXC-102P (EK)



MD-30 BOARD

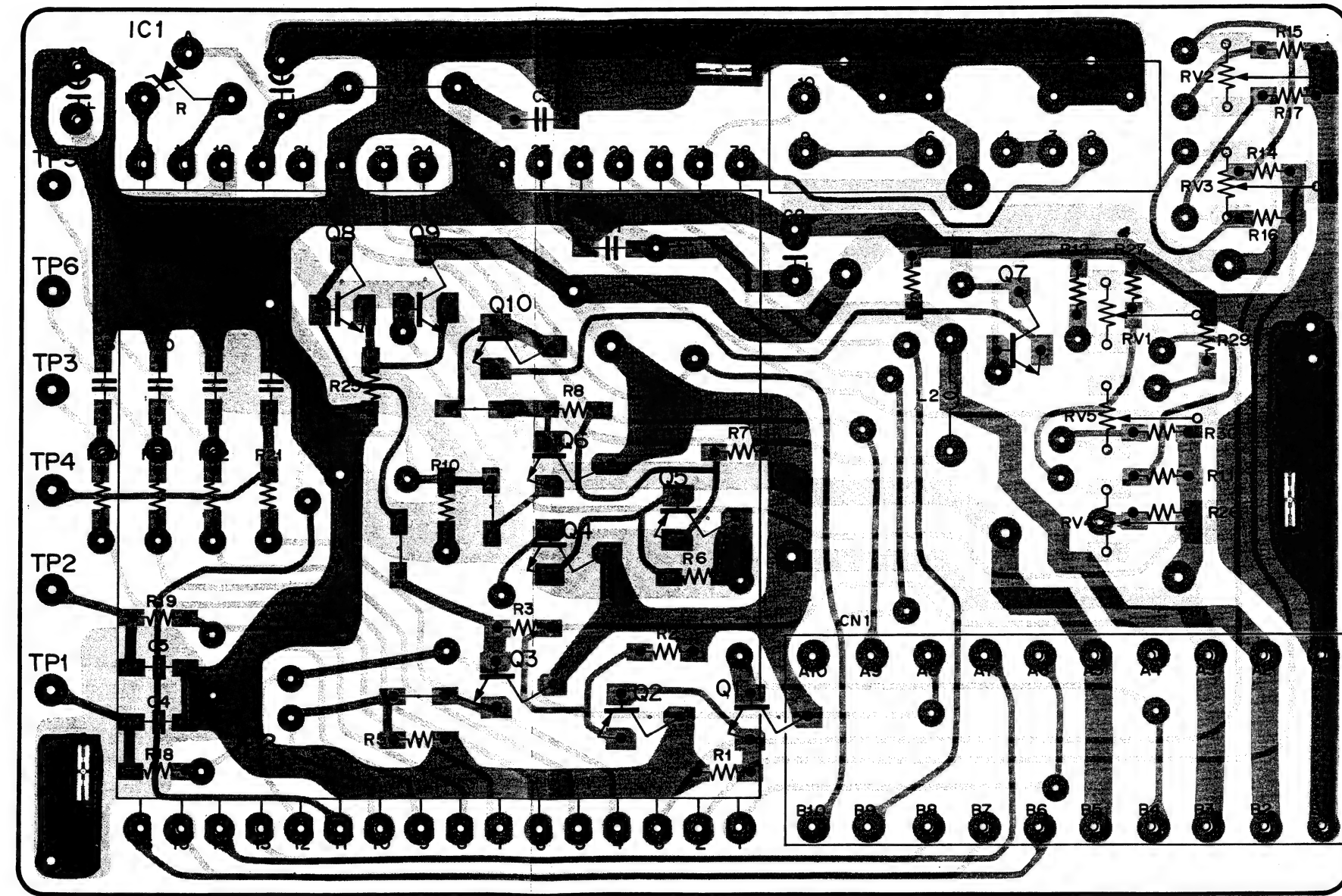
SERIAL NO.	
DXC-101 (J)	Up to 50180
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10060
DXC-102 (J)	Up to 10020
DXC-102 (UC)	Up to 10030
DXC-102P (EK)	Up to 10010



6-15(a)

MD-30 BOARD

SERIAL NO.	
DXC-101 (J)	Up to 50180
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10060
DXC-102 (J)	Up to 10020
DXC-102 (UC)	Up to 10030
DXC-102P (EK)	Up to 10010



—SOLDERING SIDE—
MD-30 BOARD
 1-617-212-11
 XC-117 (UC,J)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)

MD-30

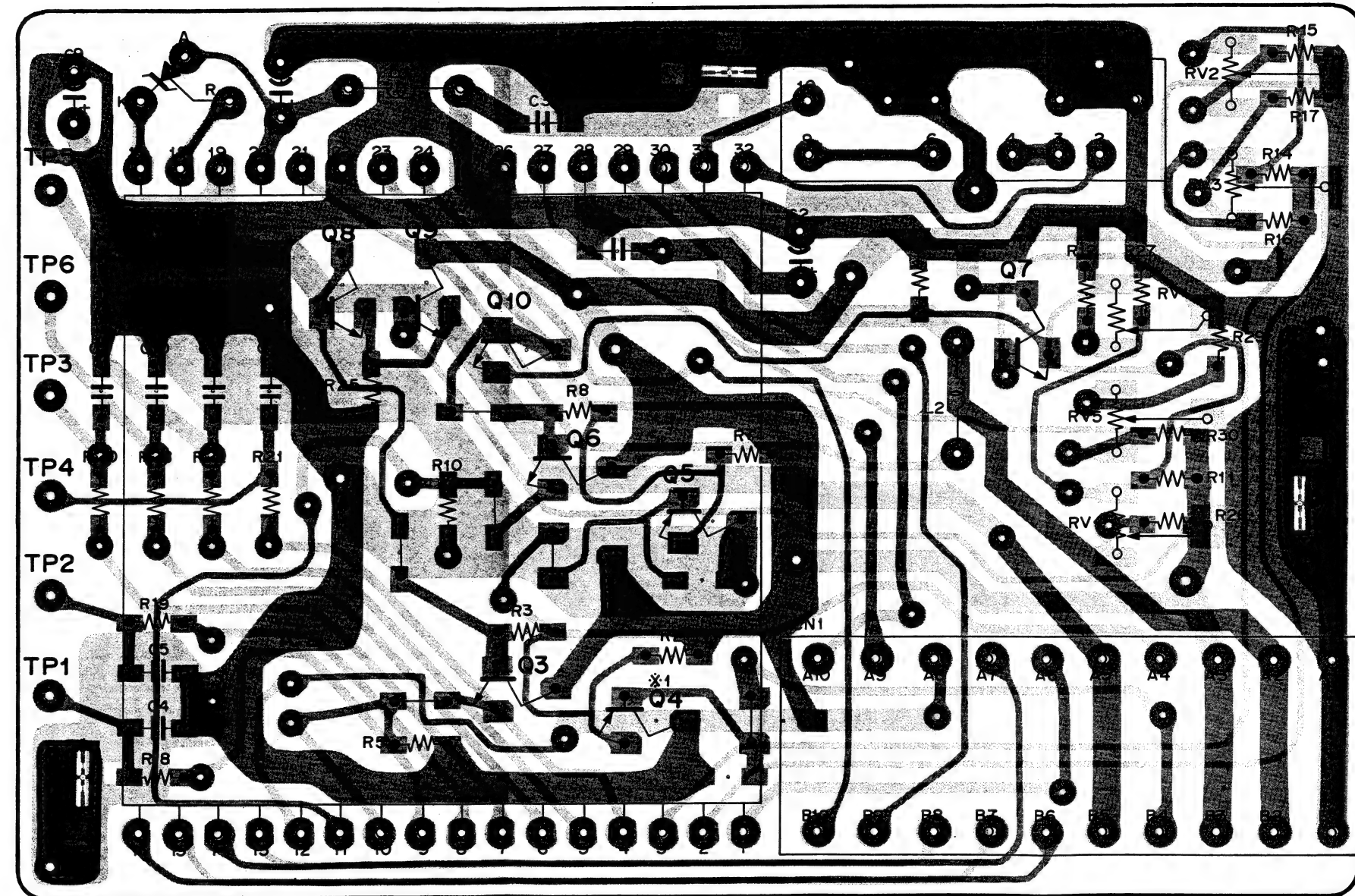
DXC-101/101P/102/102P

DXC-101/101P/102/102P

MD-30

MD-30 BOARD

SERIAL NO.	
DXC-101 (J)	50181 to 51290
DXC-101 (UC)	10221 to 11180
DXC-101P (EK)	10061 to 12080
DXC-102 (J)	10021 to 10470
DXC-102 (UC)	10031 to 10660
DXC-102P (EK)	10011 to 11070



*1 Q NO IS CHANGED

Q2 → Q4

SER. NO.

XC-117 (UCJ) 10721~

XC-117P (EK) 10131~

DXC-101 (J) 50431~

DXC-101 (UC) 10221~

DXC-101P(EK) 10261~

DXC-102 (J) 10191~

DXC-102 (UC) 10181~

DXC-102P(EK) 10311~

— SOLDERING SIDE —

MD-30 BOARD

1-617-212-12

XC-117 (UCJ)

XC-117P (EK)

DXC-101 (UC, J)

DXC-101P (EK)

DXC-102 (UC, J)

DXC-102P (EK)

MD-30

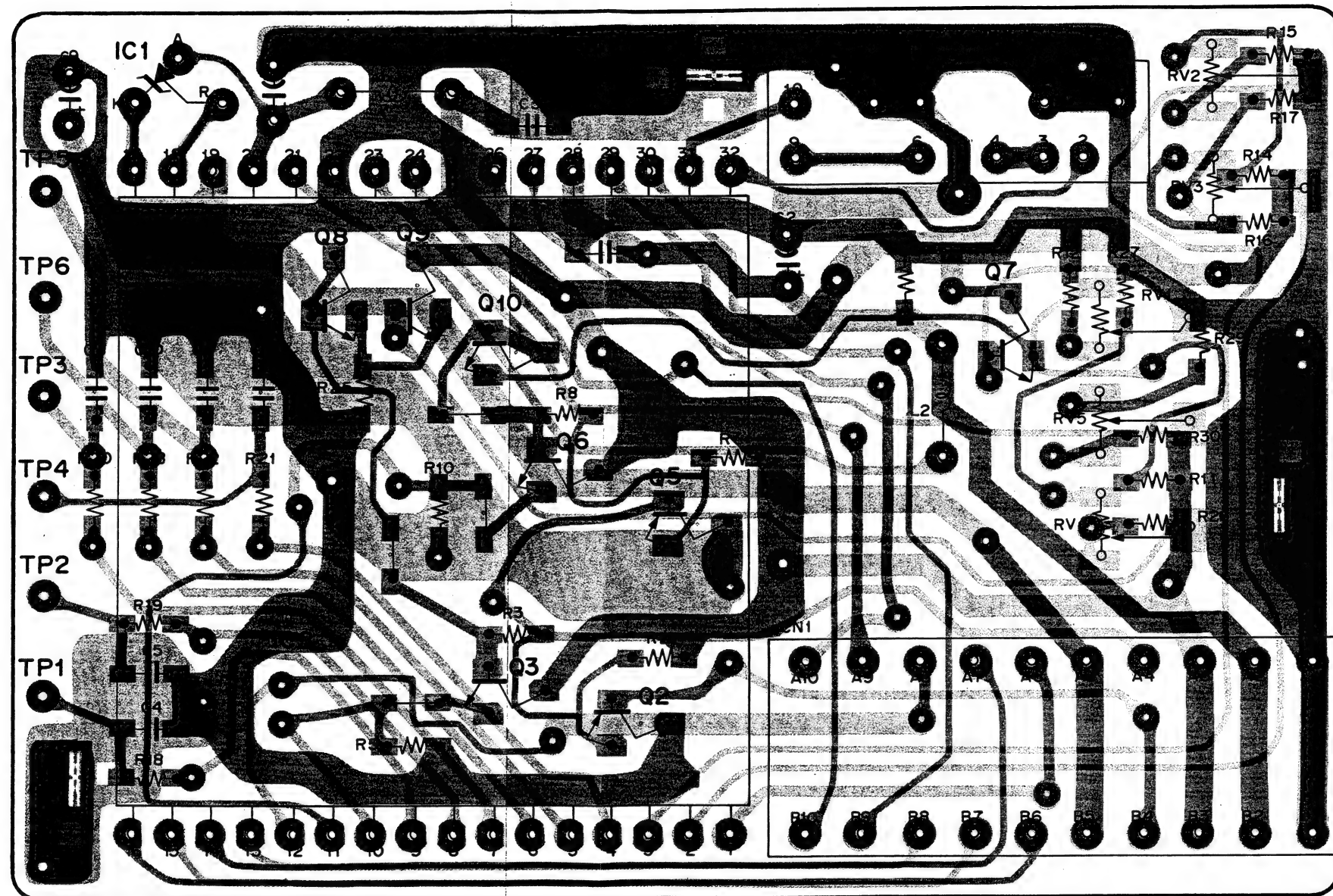
DXC-101/101P/102/102P

DXC-101/101P/102/102P

MD-30

MD-30 BOARD

SERIAL NO.
 DXC-101 (J) 51291 and higher
 DXC-101 (UC) 11181 and higher
 DXC-101P (EK) 12081 and higher
 DXC-102 (J) 10471 and higher
 DXC-102 (UC) 10661 and higher
 DXC-102P (EK) 11071 and higher



— SOLDERING SIDE —

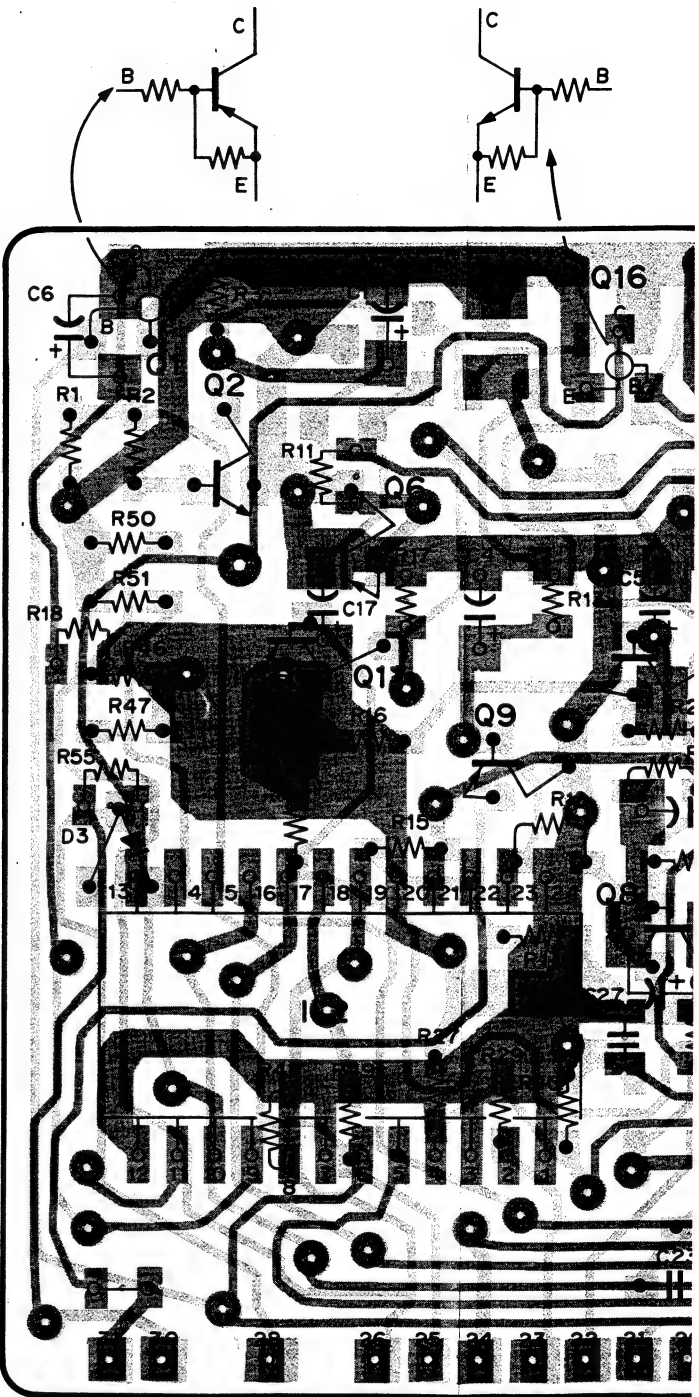
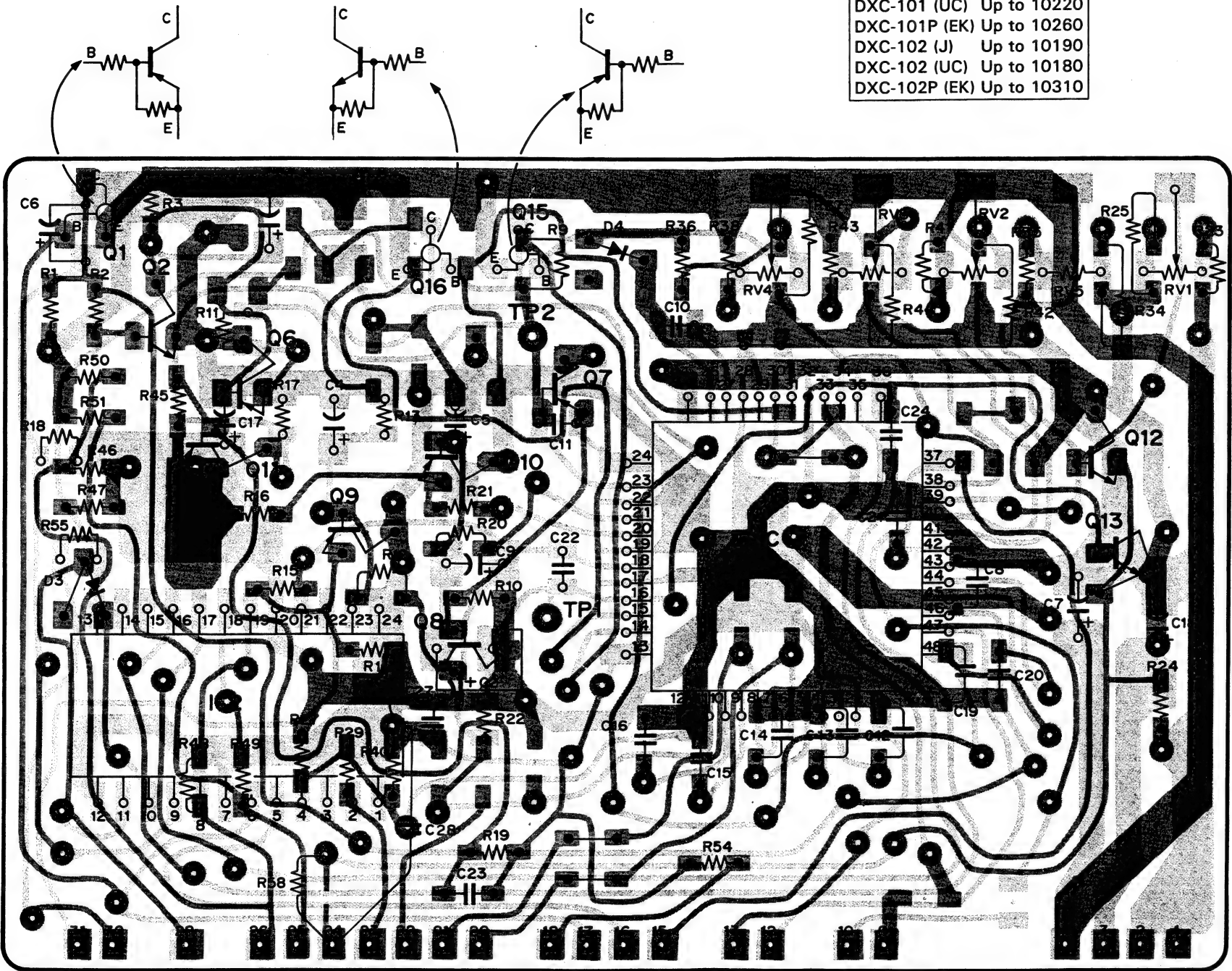
MD-30 BOARD

1-617-212-13

XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC, J)
 DXC-101P (EK)
 DXC-102 (UC, J)
 DXC-102P (EK)

AT-40 BOARD

SERIAL NO.
DXC-101 (J) Up to 50430
DXC-101 (UC) Up to 10220
DXC-101P (EK) Up to 10260
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310



-SOLDERING SIDE-

AT-40 BOARD

1-617-213-11
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

AT-40

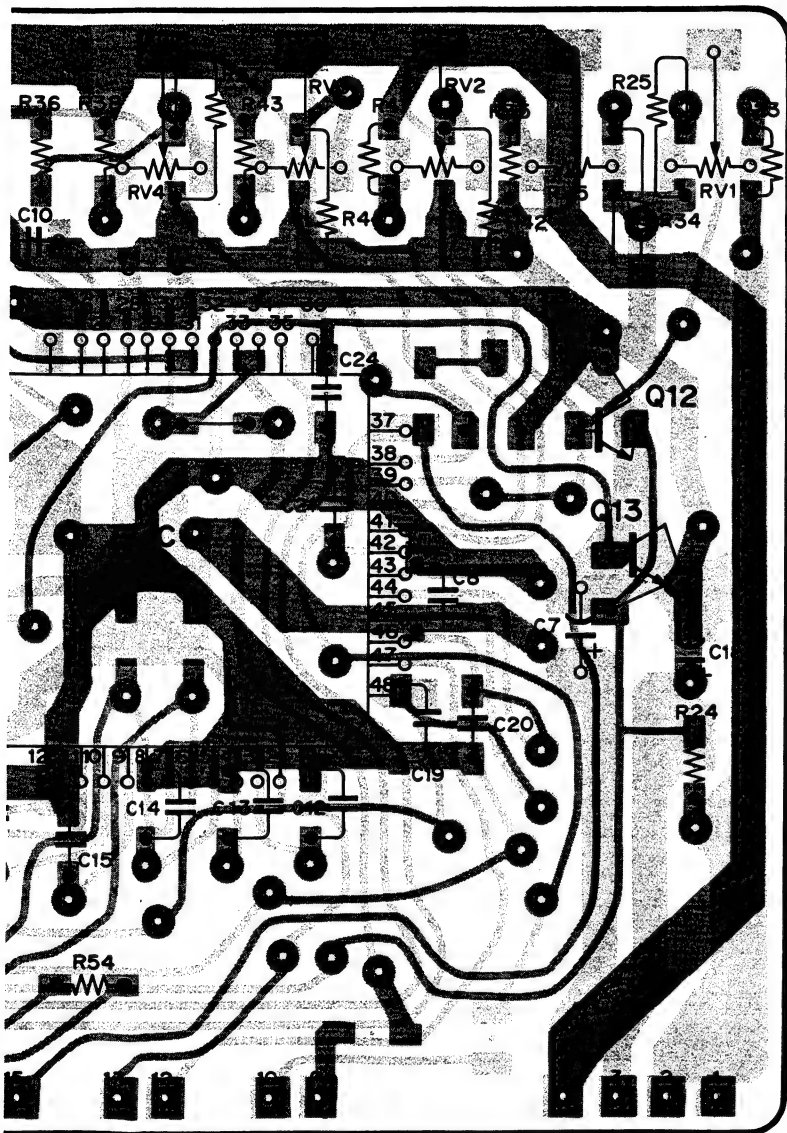
DXC-101/101P/102/102P

DXC-101/101P/102/102P

AT-40

SERIAL NO.
 DXC-101 (J) Up to 50430
 DXC-101 (UC) Up to 10220
 DXC-101P (EK) Up to 10260
 DXC-102 (J) Up to 10190
 DXC-102 (UC) Up to 10180
 DXC-102P (EK) Up to 10310

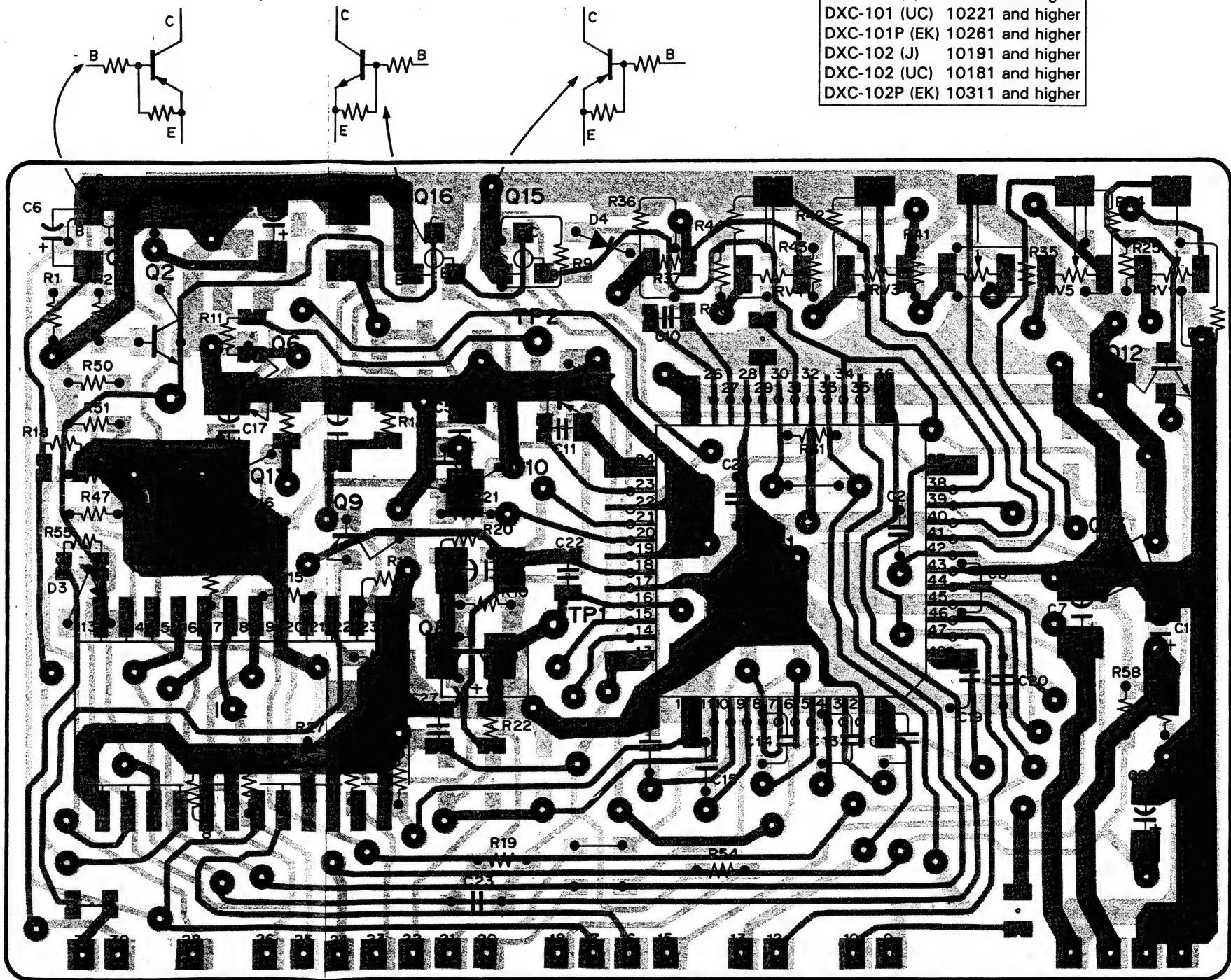
SERIAL NO.
 DXC-101 (J) 50431 and higher
 DXC-101 (UC) 10221 and higher
 DXC-101P (EK) 10261 and higher
 DXC-102 (J) 10191 and higher
 DXC-102 (UC) 10181 and higher
 DXC-102P (EK) 10311 and higher



—SOLDERING SIDE—

AT-40 BOARD

1-617-213-11
 XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

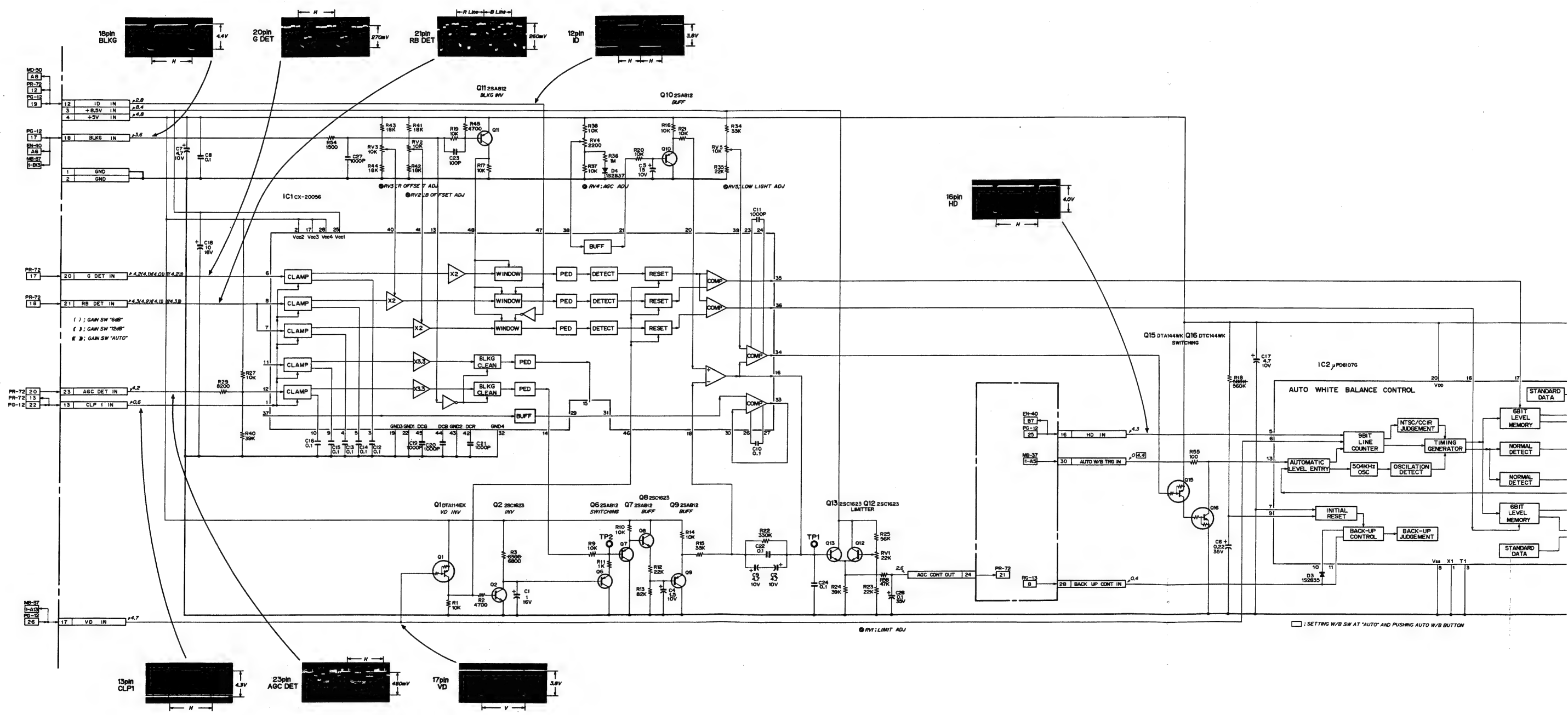


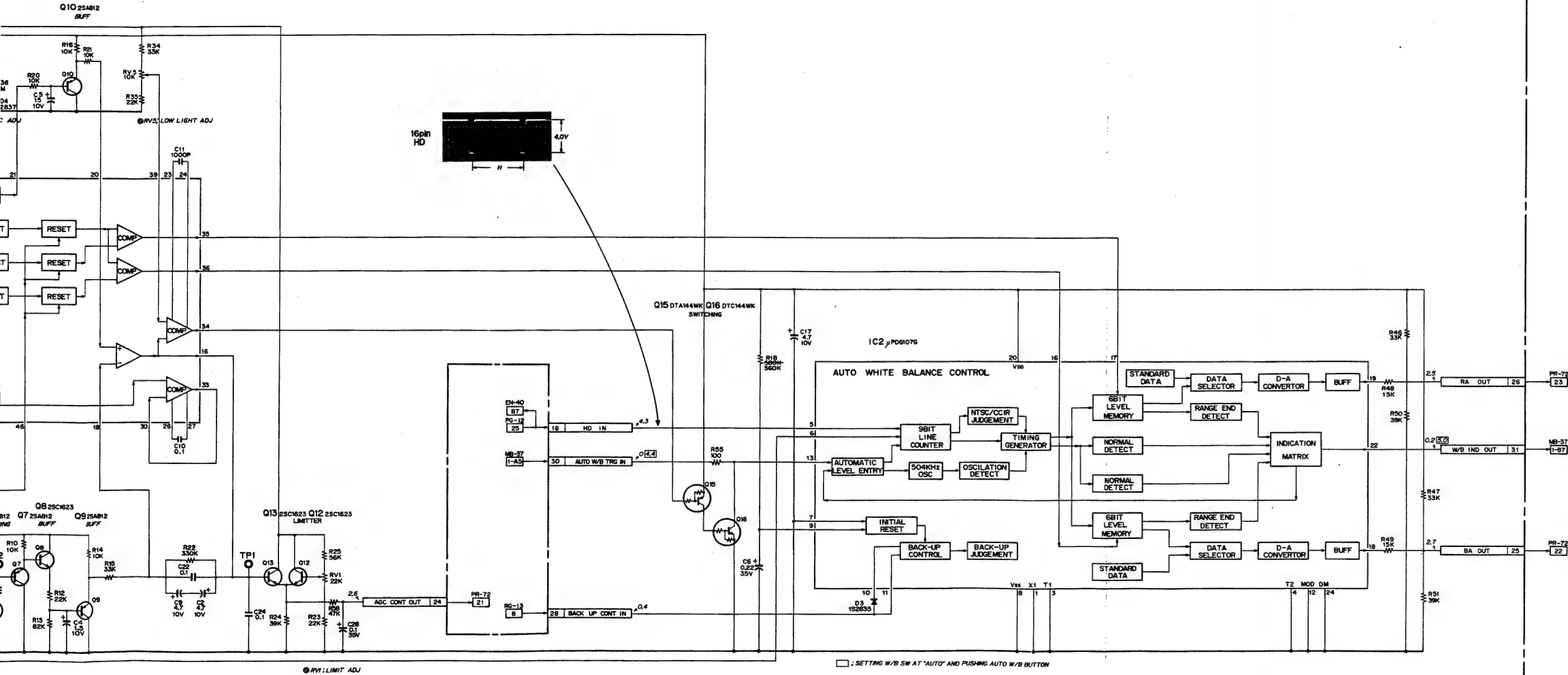
—SOLDERING SIDE—

AT-40 BOARD

1-617-213-12
 XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

AT-40 BOARD (AUTO CONTROL)



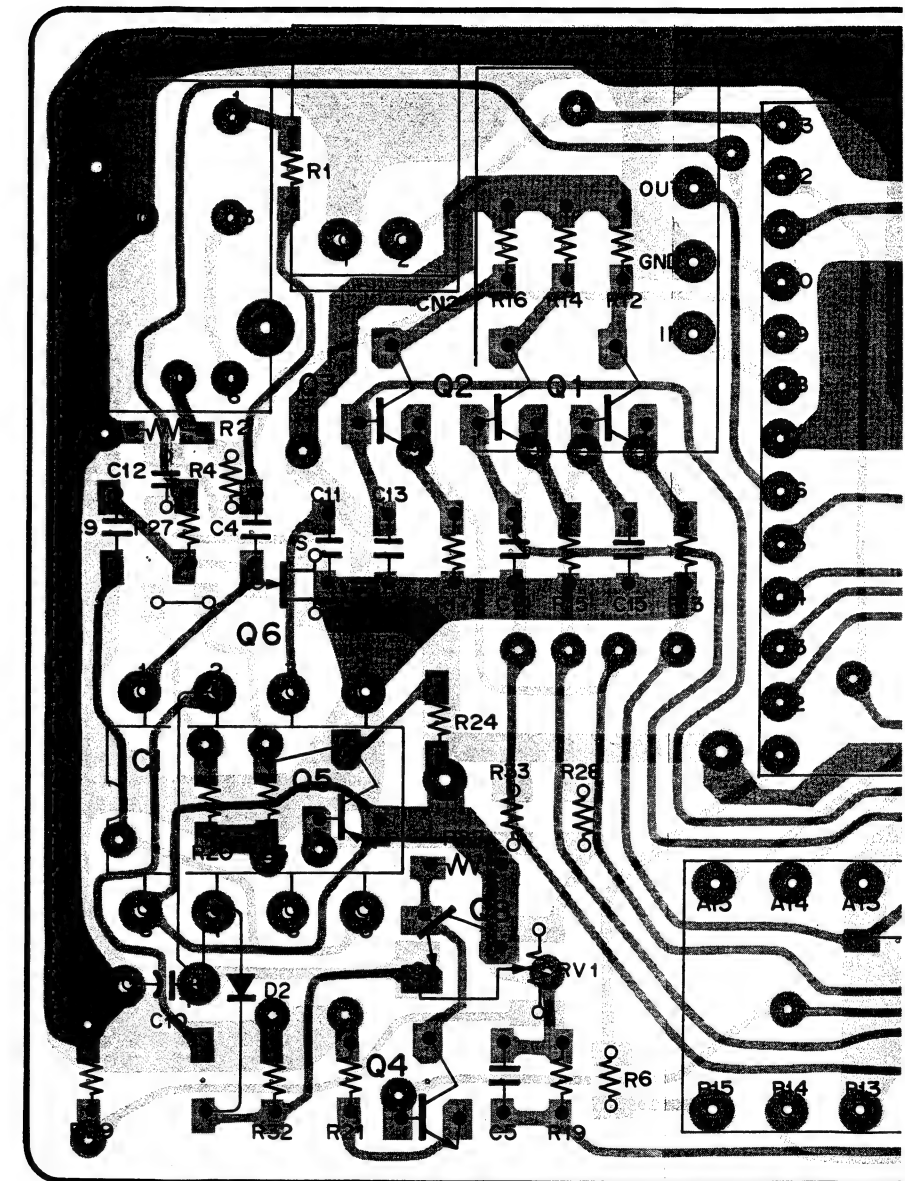


- 注意：
- DC電圧はデジタル電圧計による値。
 - 波形写真は下記条件で撮影。
 - MB-37基板、TP1にてカラーバーの白部分が150mVp-pになる様レンズアイリスをセットする。(F≒4、波形モニターで100IRE)
 - WHITE BALスイッチ→"1(3200°K)"位置
 - GAINスイッチ→"0dB"位置

- NOTE:
- All voltage are dc, measured with a digital voltmeter (input resistance 10 MΩ).
 - All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box.
 - Adjust lens iris so that a white level at TP1/MB-37 board is 150 mV. [F≒4, White level on the waveform monitor is 100 IRE (700 mV for PAL)]
 - Set camera WHITE BAL switch to "1 (3200° K)".
 - Set camera GAIN switch to "0 dB".

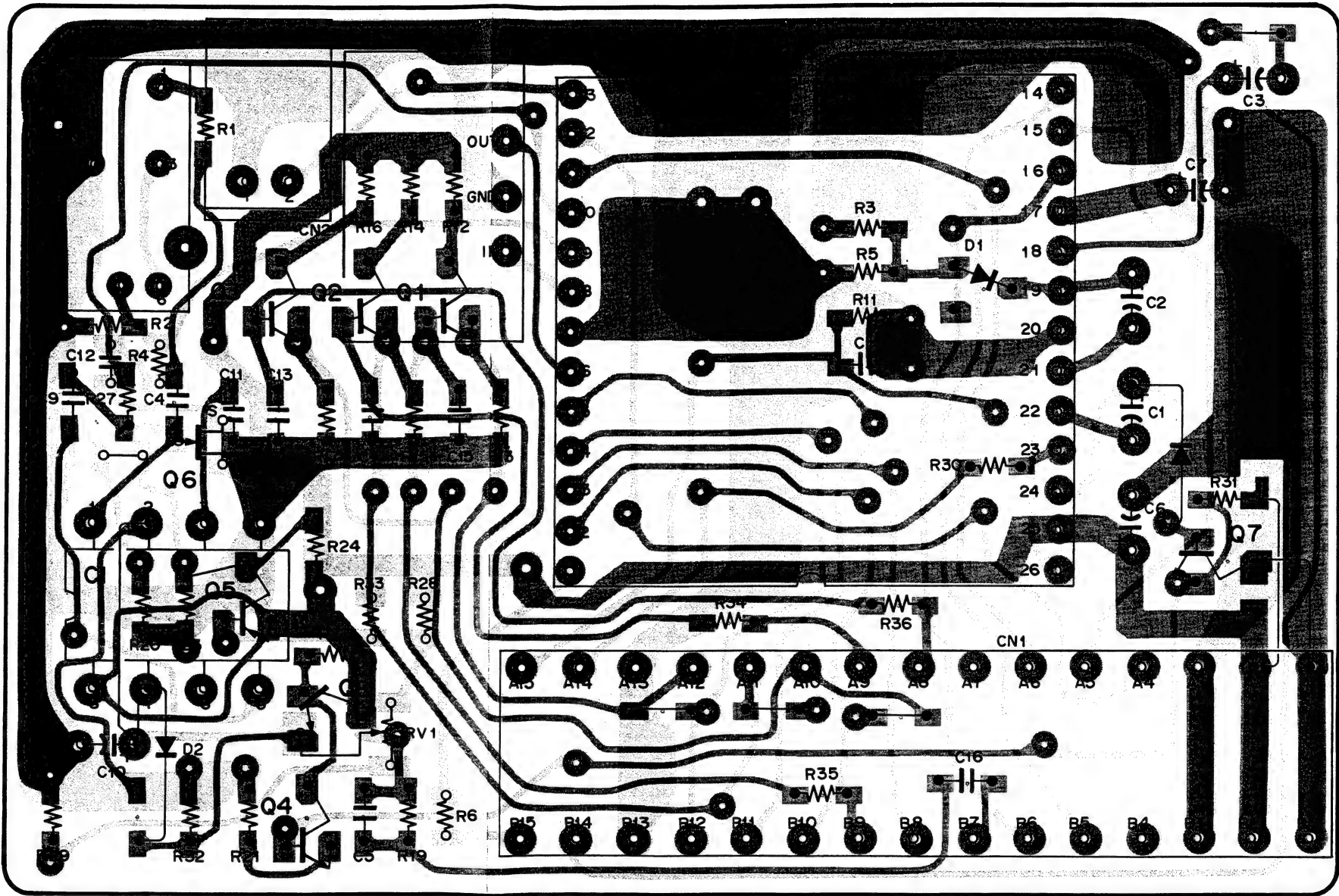
AT-40 BOARD
1-617-213-11,12
XC-117(U.C.J) 10001 ~
XC-117(P.E.K) 10001 ~
DXC-101(U.C) 10001 ~
DXC-101(J) 10001 ~
DXC-102(U.C) 10001 ~
DXC-102(J) 10001 ~
DXC-102(P.E.K) 10001 ~

SERIAL NO.	
DXC-101 (J)	Up to 50180
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10060
DXC-102 (J)	Up to 10020
DXC-102 (UC)	Up to 10030
DXC-102P (EK)	Up to 10010



EN-40 BOARD

SERIAL NO.	
DXC-101 (J)	Up to 50180
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10060
DXC-102 (J)	Up to 10020
DXC-102 (UC)	Up to 10030
DXC-102P (EK)	Up to 10010



-SOLDERING SIDE-

EN-40 BOARD

1-617-215-11

XC-117 (UCJ)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

EN-40

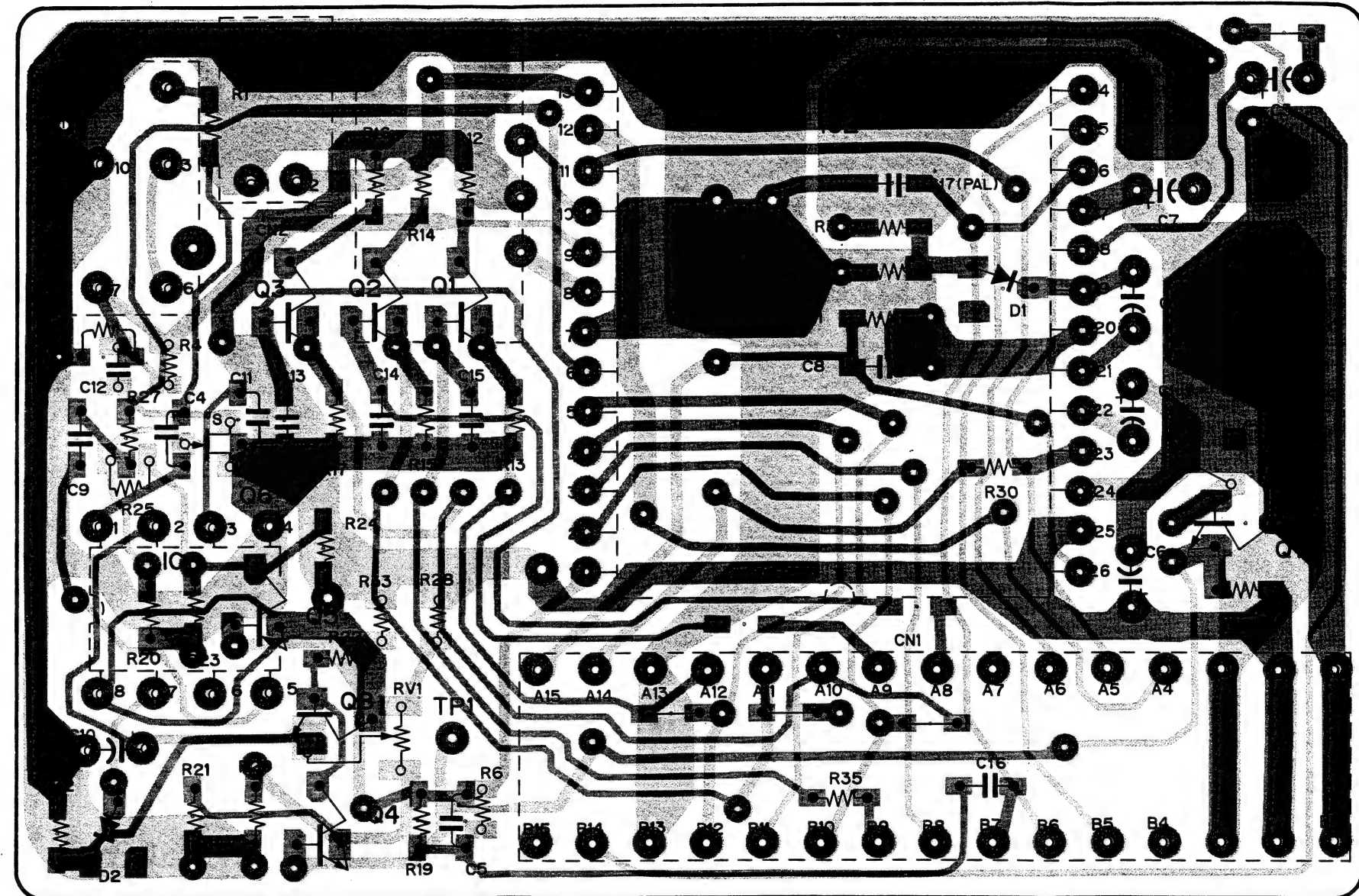
DXC-101/101P/102/102P

DXC-101/101P/102/102P

EN-40

EN-40 BOARD

SERIAL NO.	
DXC-101 (J)	50181 to 51290
DXC-101 (UC)	10221 to 11180
DXC-101P (EK)	10061 to 12080
DXC-102 (J)	10021 to 10470
DXC-102 (UC)	10031 to 10660
DXC-102P (EK)	10011 to 11070



— SOLDERING SIDE —

EN-40 BOARD

1-617-215-13

XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UC, J)
DXC-102P (EK)

EN-40

DXC-101/101P/102/102P

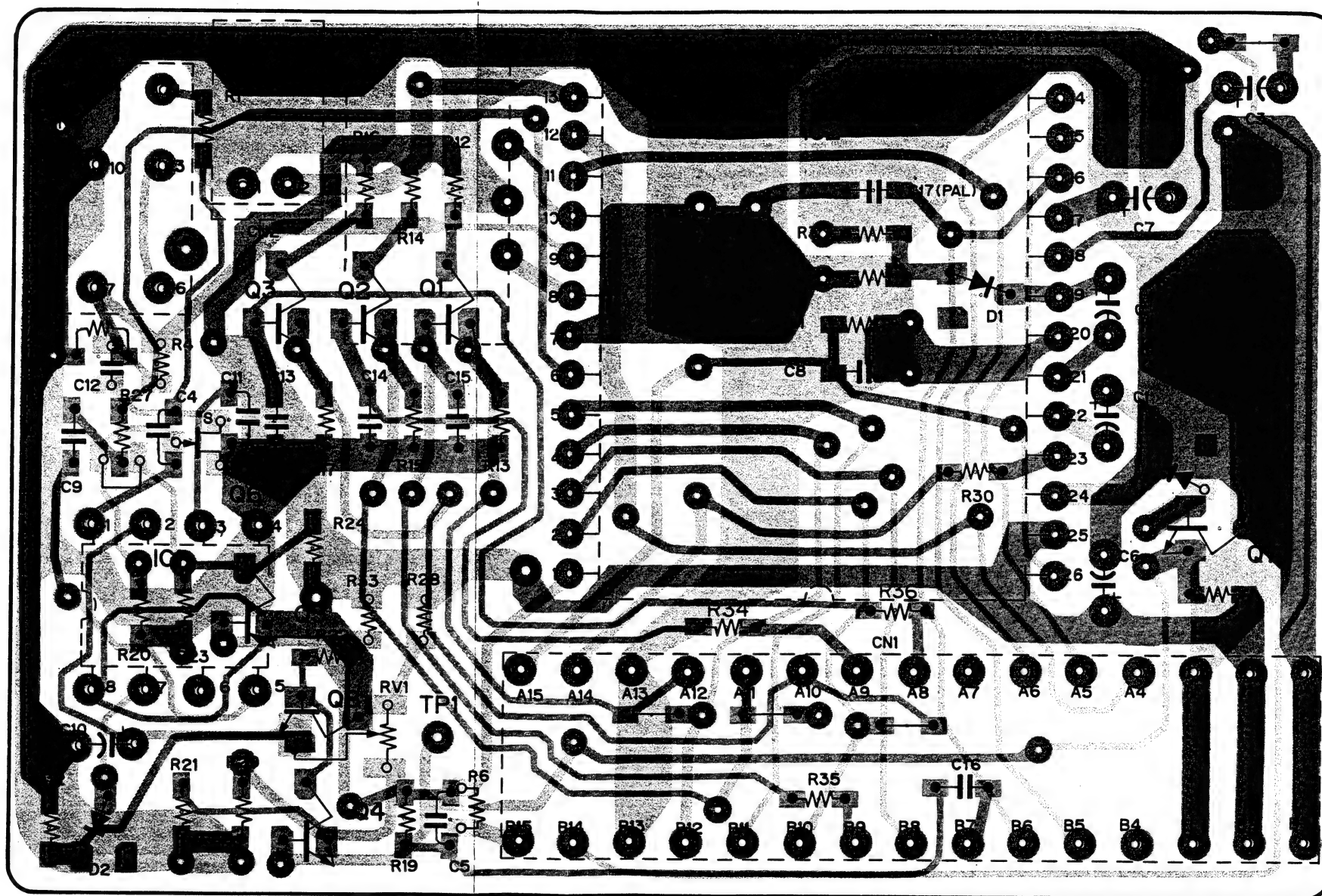
DXC-101/101P/102/102P

EN-40

EN-40 BOARD

SERIAL NO.

DXC-101 (J) 51291 and higher
 DXC-101 (UC) 11181 and higher
 DXC-101P (EK) 12081 and higher
 DXC-102 (J) 10471 and higher
 DXC-102 (UC) 10661 and higher
 DXC-102P (EK) 11071 and higher



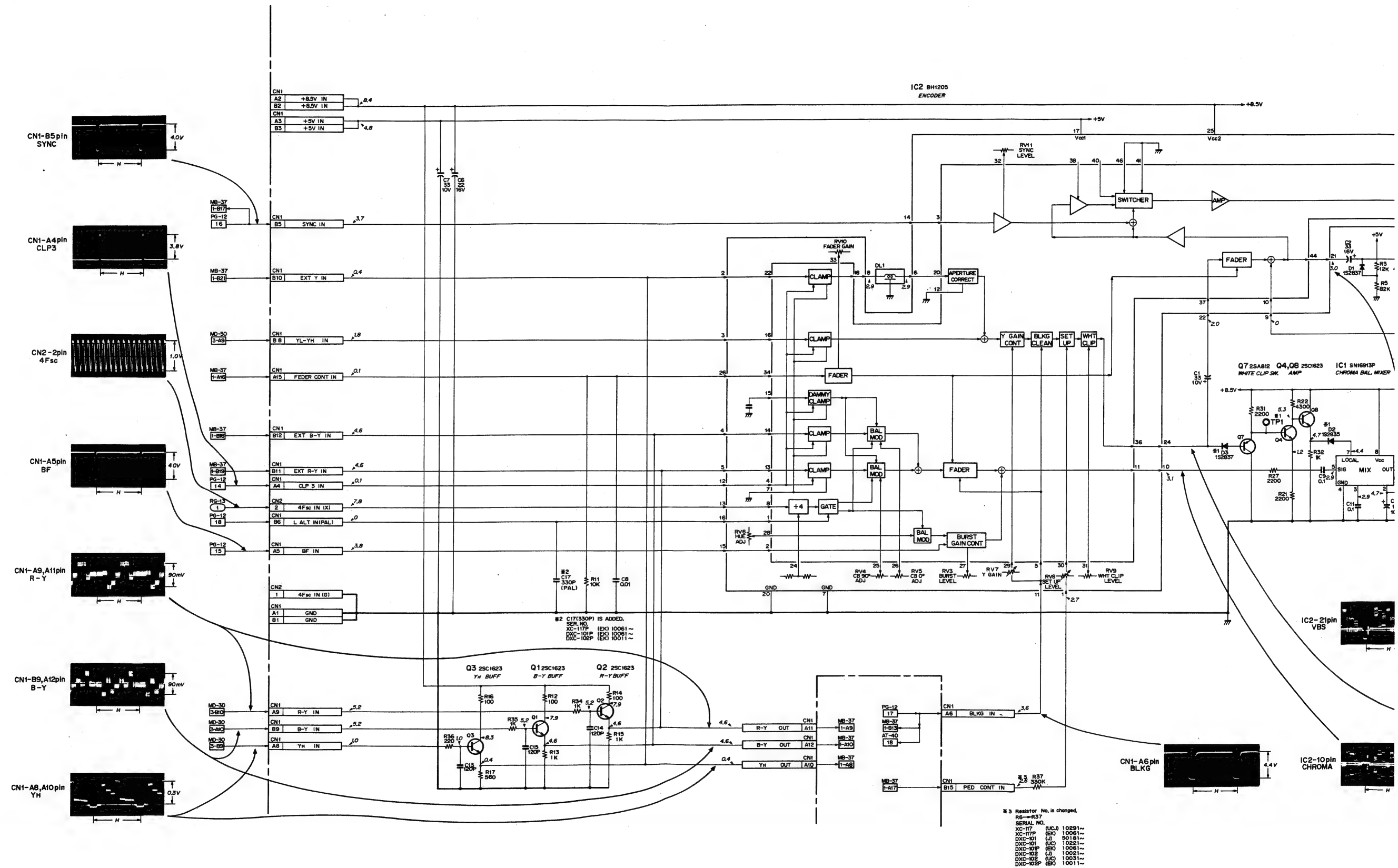
— SOLDERING SIDE —

EN-40 BOARD

1-617-215-14

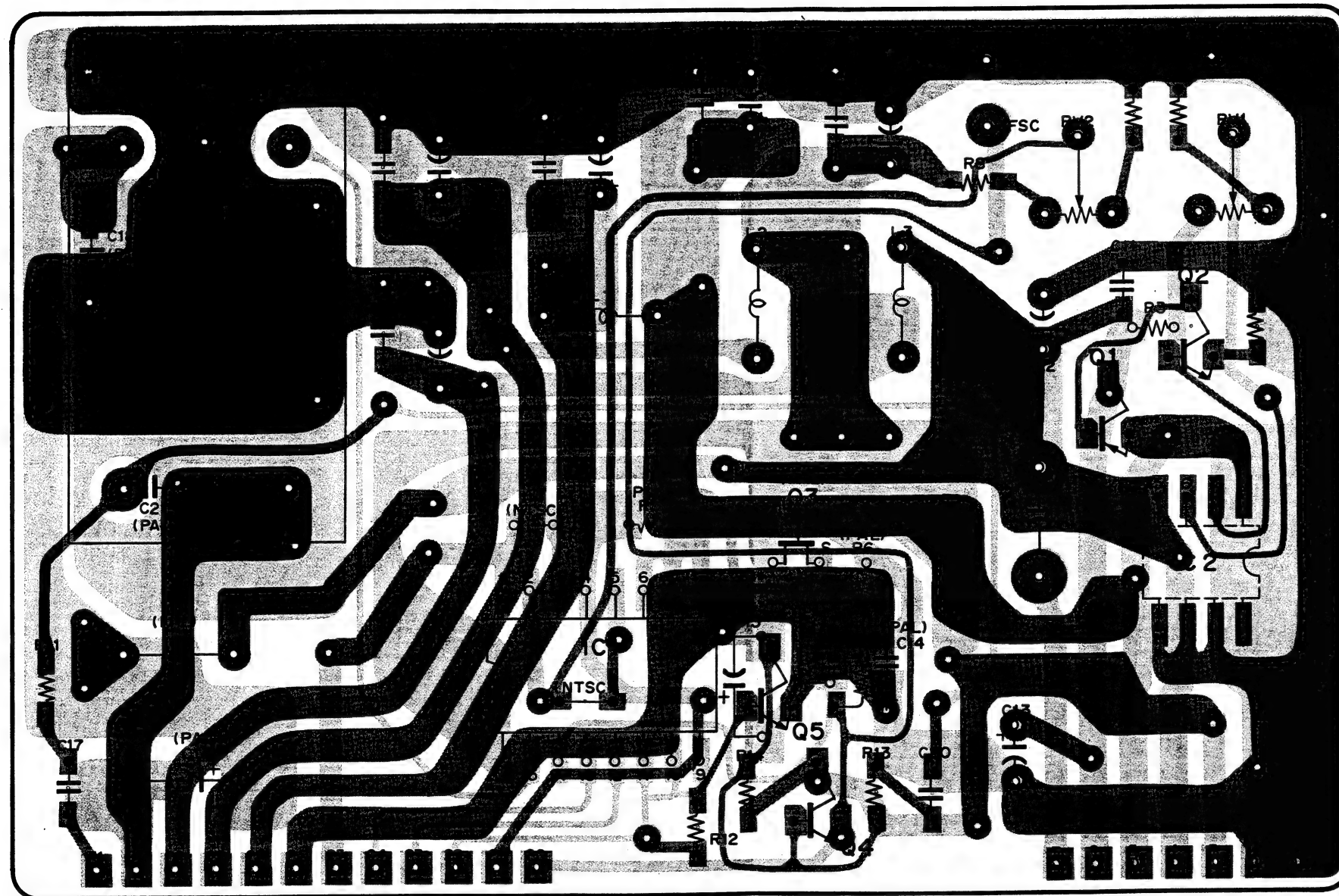
XC-117 (UC,J)
 XC-117P (EK)
 DXC-101 (UC,J)
 DXC-101P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

EN-40 BOARD (ENCODER)



RG-13 BOARD

SERIAL NO.	
DXC-101 (J)	Up to 50430
DXC-101 (UC)	Up to 10220
DXC-101P (EK)	Up to 10260
DXC-102 (J)	Up to 10190
DXC-102 (UC)	Up to 10180
DXC-102P (EK)	Up to 10310



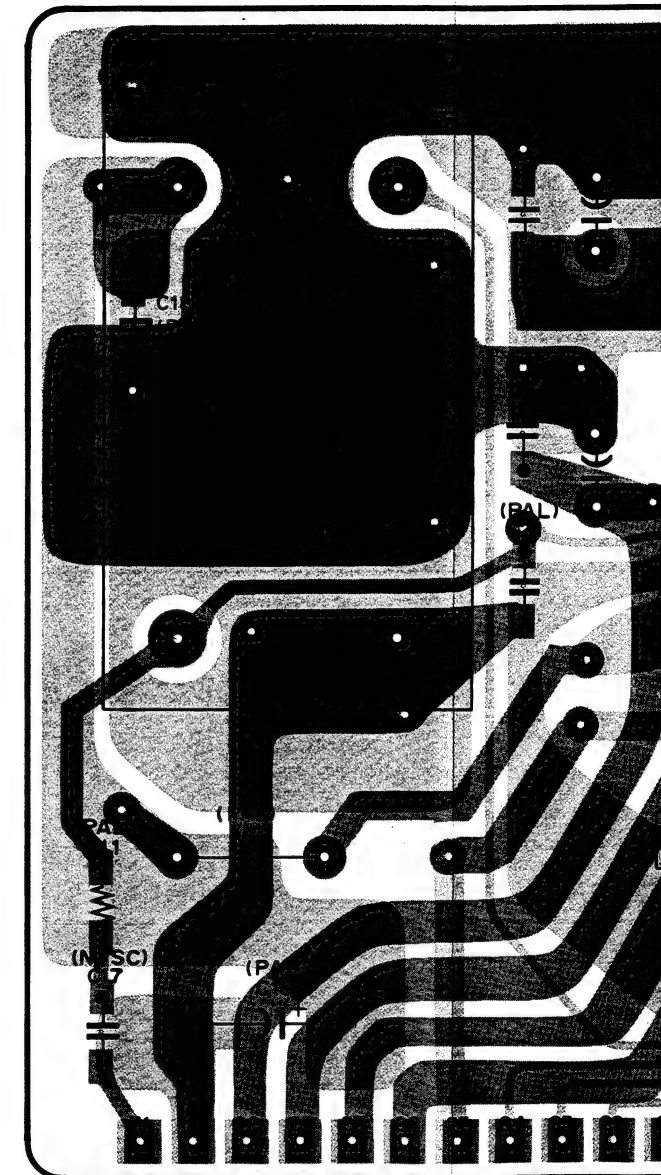
-SOLDERING SIDE-

RG-13 BOARD

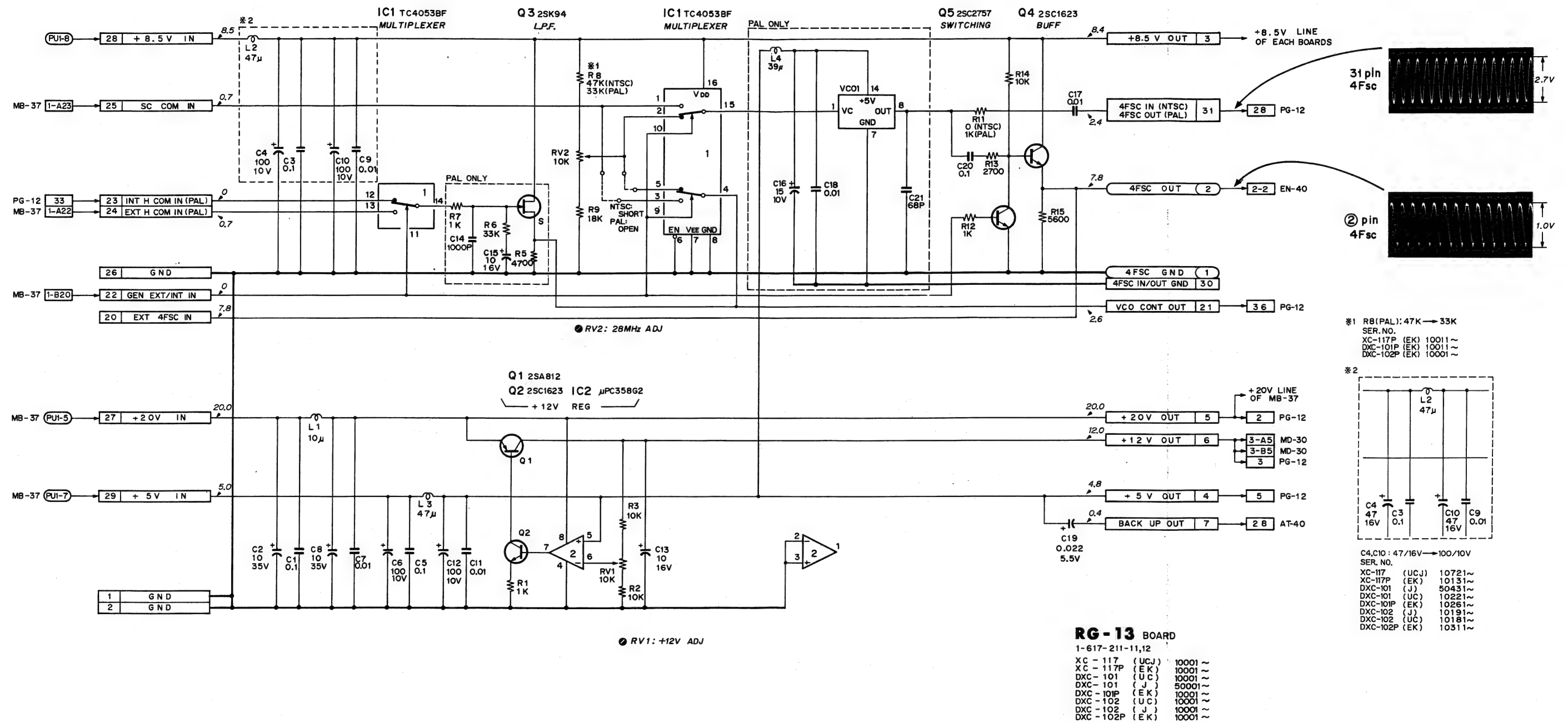
1-617-211-11

XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

SERIAL NO.	
DXC-101 (J)	50431 and higher
DXC-101 (UC)	10221 and higher
DXC-101P (EK)	10261 and higher
DXC-102 (J)	10191 and higher
DXC-102 (UC)	10181 and higher
DXC-102P (EK)	10311 and higher



RG-13 BOARD



SG-38

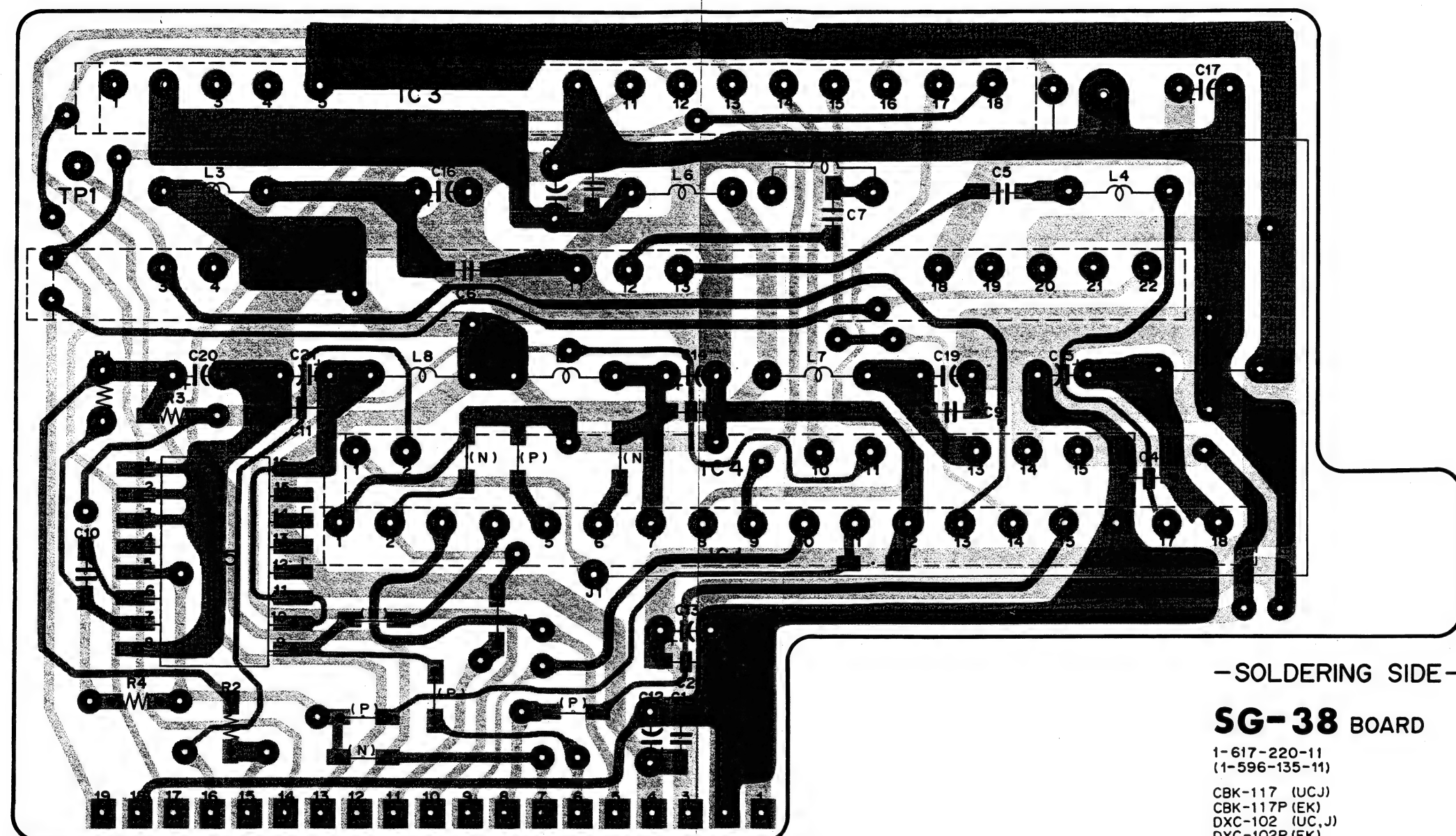
DXC-102/102P

DXC-102/102P

SG-38

SG-38 BOARD

SERIAL NO.
DXC-102 (J) Up to 11190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310



—SOLDERING SIDE—

SG-38 BOARD

1-617-220-11
(1-596-135-11)

CBK-117 (UCJ)
CBK-117P (EK)
DXC-102 (UC, J)
DXC-102P (EK)

SG-38

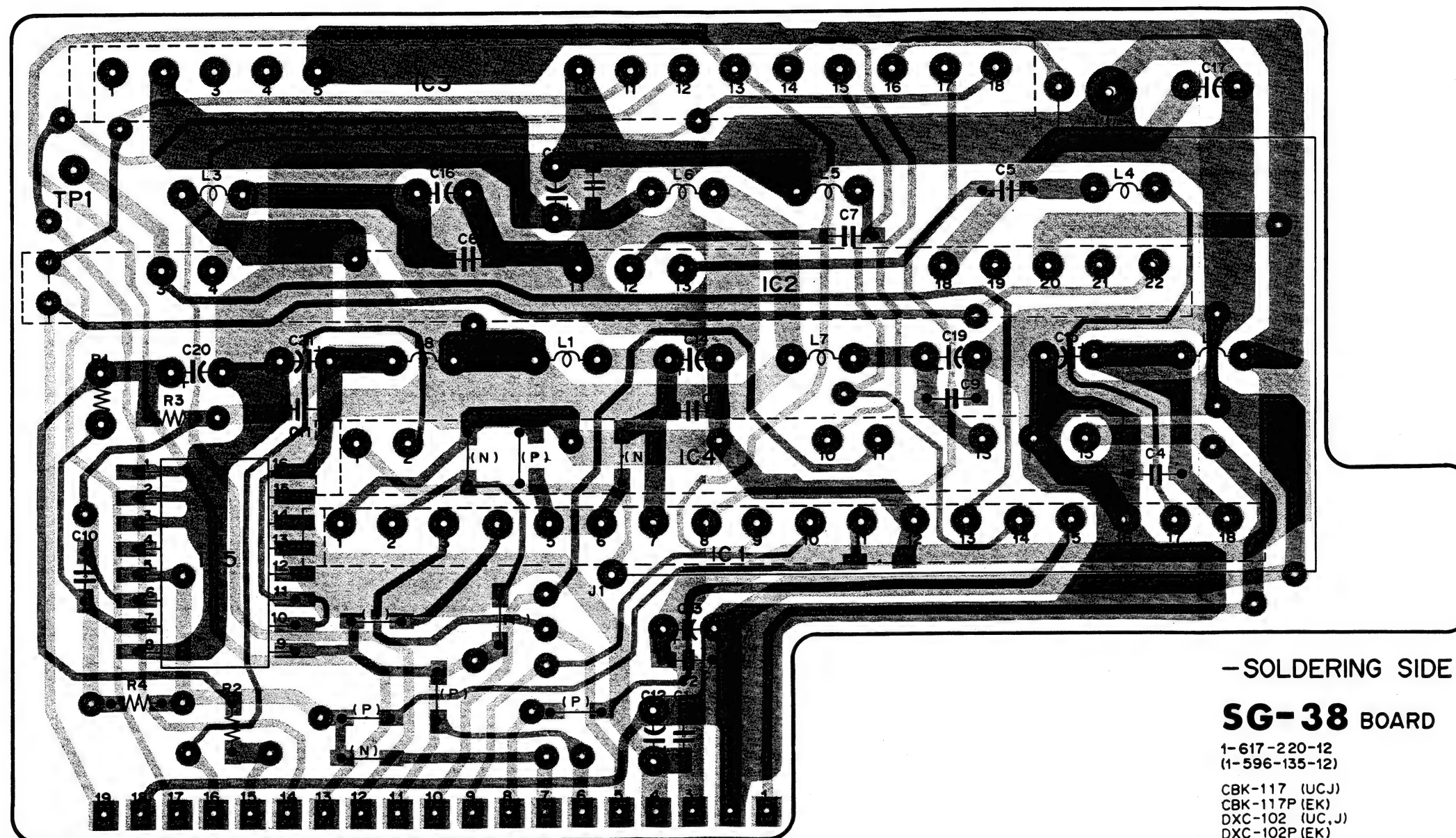
DXC-102/102P

DXC-102/102P

SG-38

SG-38 BOARD

SERIAL NO.
 DXC-102 (J) 10191 to 10470
 DXC-102 (UC) 10181 to 10660
 DXC-102P (EK) 10311 to 11070



—SOLDERING SIDE—

SG-38 BOARD

1-617-220-12
 (1-596-135-12)

CBK-117 (UCJ)
 CBK-117P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

SG-38

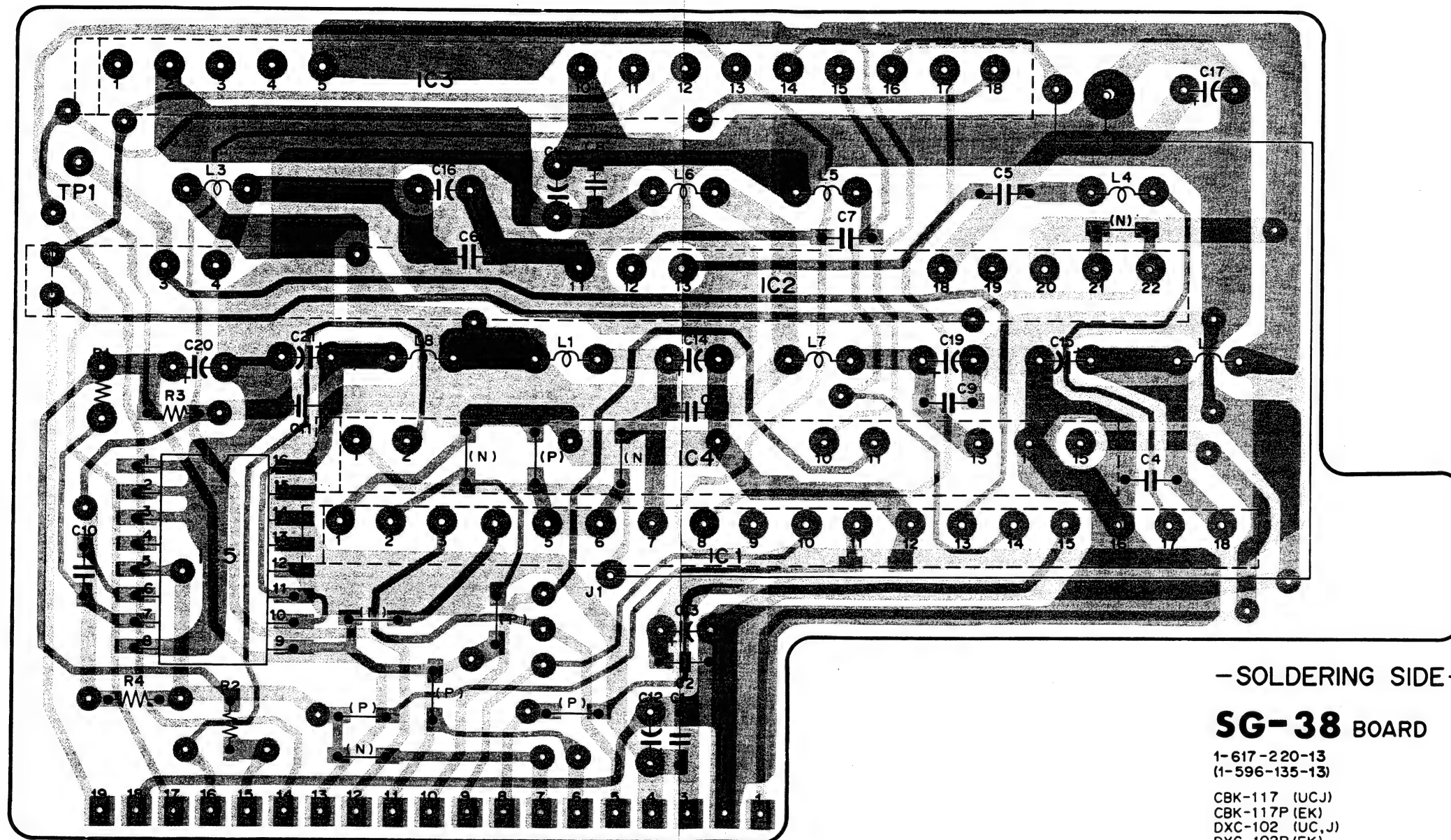
DXC-102/102P

DXC-102/102P

SG-38

SG-38 BOARD

SERIAL NO.
 DXC-102 (J) 10471 and higher
 DXC-102 (UC) 10661 and higher
 DXC-102P (EK) 11071 and higher

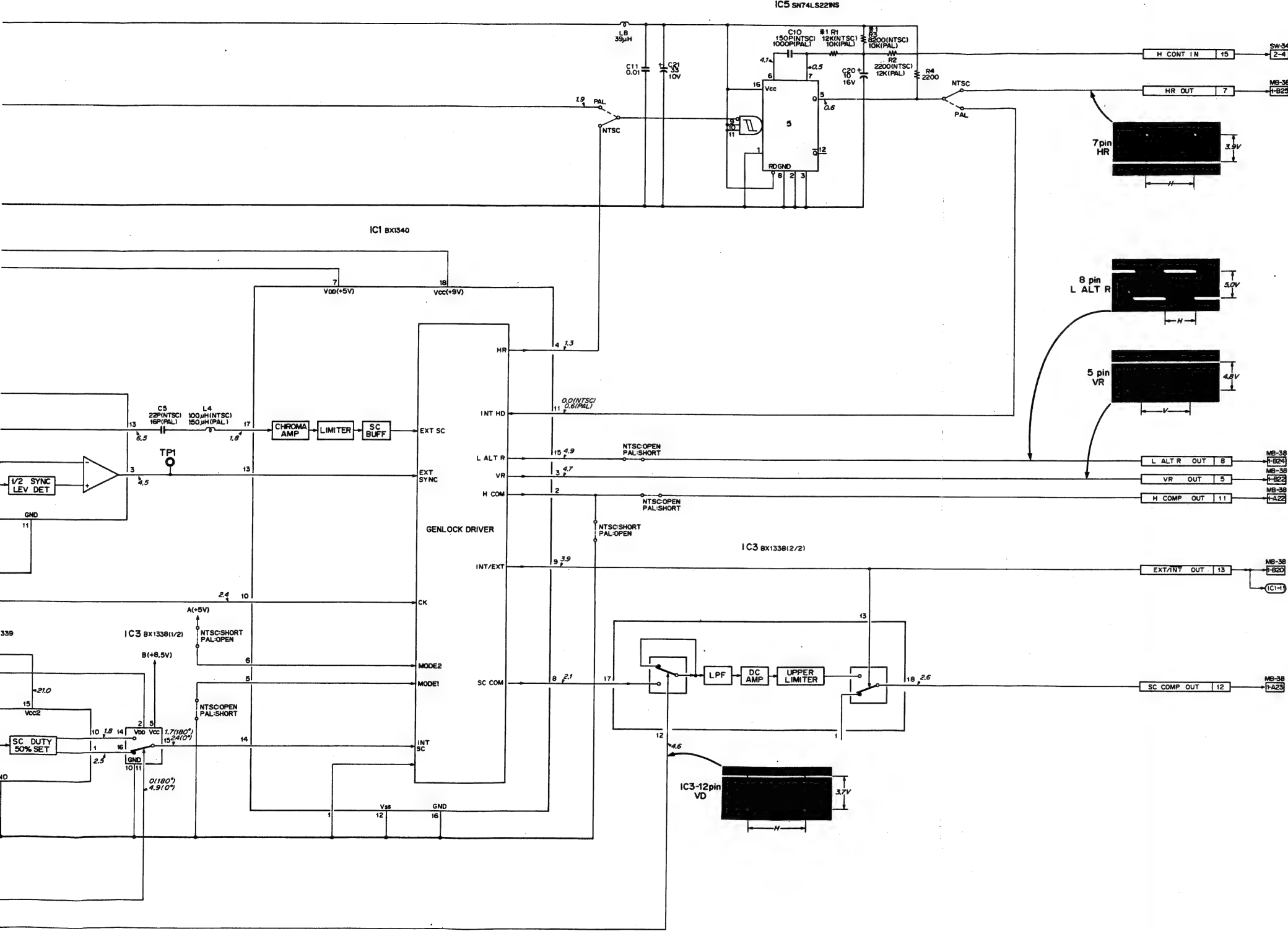


-SOLDERING SIDE-

SG-38 BOARD

1-617-220-13
 (1-596-135-13)

CBK-117 (UCJ)
 CBK-117P (EK)
 DXC-102 (UC, J)
 DXC-102P (EK)



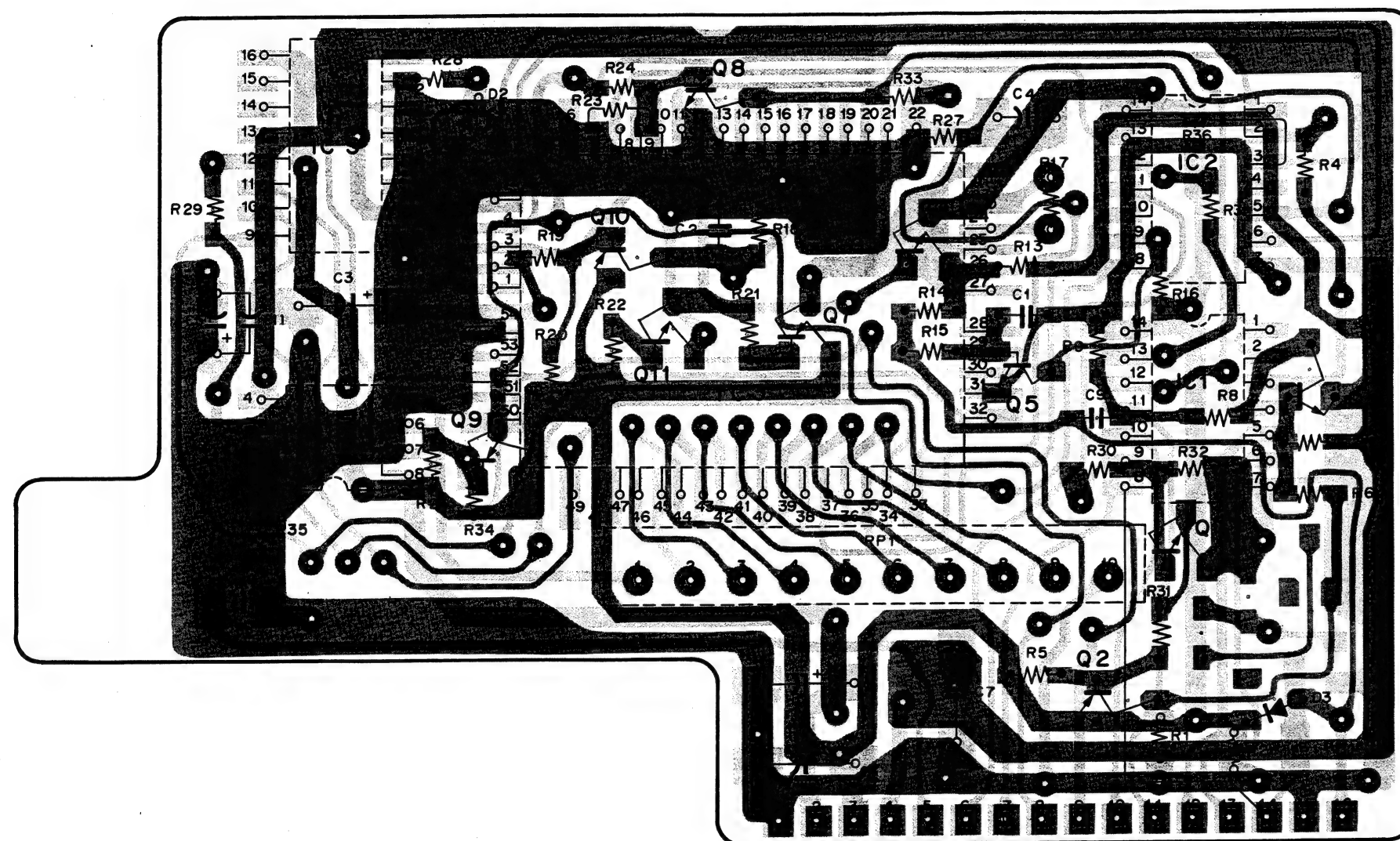
#1
R1(NTSC): 8200 → 12K
R3(NTSC): 10K → 8200
CBK-117 (UCJ) 10026 ~
DXC-102 (J) 10031 ~
DXC-102 (UC) 10031 ~
#2
C17: 100/16V → 100/10V
CBK-117 (UCJ) 10031 ~
CBK-117P (EK) 10031 ~
DXC-102 (J) 10191 ~
DXC-102 (UC) 10181 ~
DXC-102P (EK) 10311 ~

SG-38 BOARD
1-817-220-11,12,13
CBK-117 (UCJ) 10001 ~
CBK-117P (EK) 10001 ~
DXC-102 (J) 10001 ~
DXC-102 (UC) 10001 ~
DXC-102P (EK) 10001 ~

- 注意:
- DC電圧はデジタル電圧計による値。
 - 波形写真はGENLOCK IN端子よりカラーバー信号を入力する。
- NOTE:
- All voltage are dc, measured with a digital voltmeter (input resistance 10 MΩ).
 - All waveforms are taken in condition below.
 - Supply a color bar signal to the GENLOCK terminal.

RM-32 BOARD

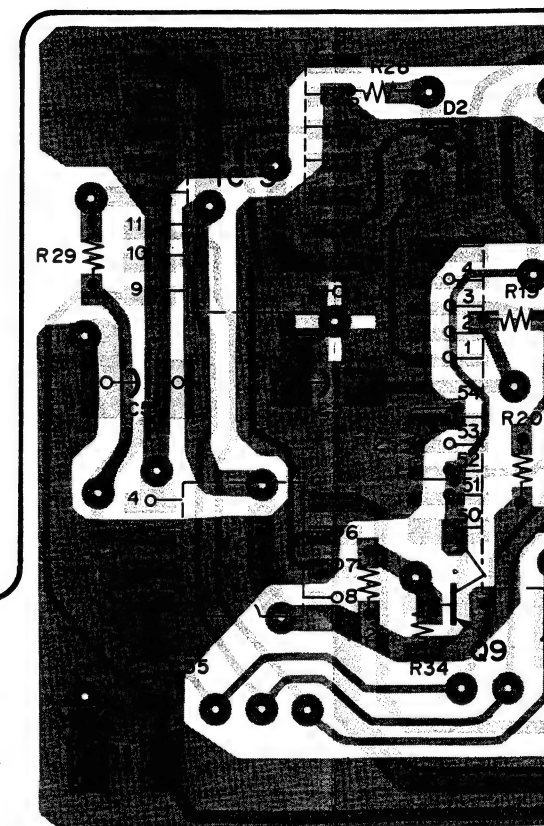
SERIAL NO.
 DXC-102 (J) Up to 10190
 DXC-102 (UC) Up to 10180
 DXC-102P (EK) Up to 10310



—SOLDERING SIDE—

RM-32 BOARD

1-617-219-11
 CBK-117 (UCJ)
 CBK-117P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)



SERIAL NO.
 DXC-102 (J) 10191 and higher
 DXC-102 (UC) 10181 and higher
 DXC-102P (EK) 10311 and higher

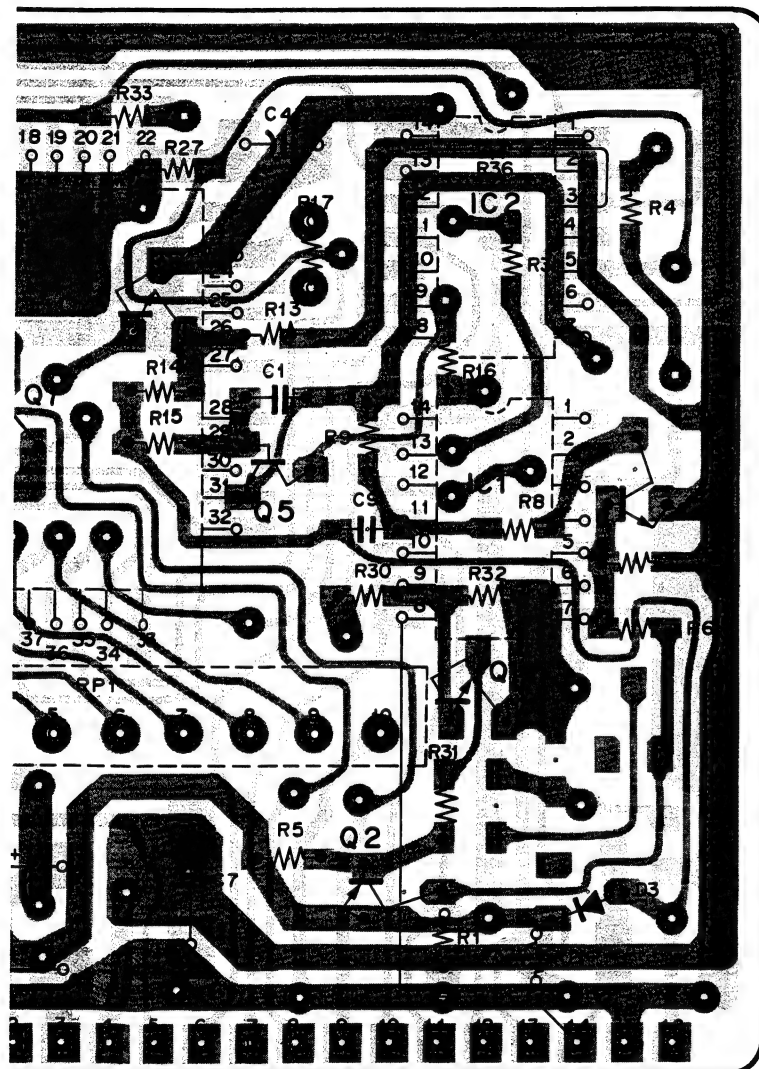
RM-32

DXC-102/102P

DXC-102/102P

RM-32

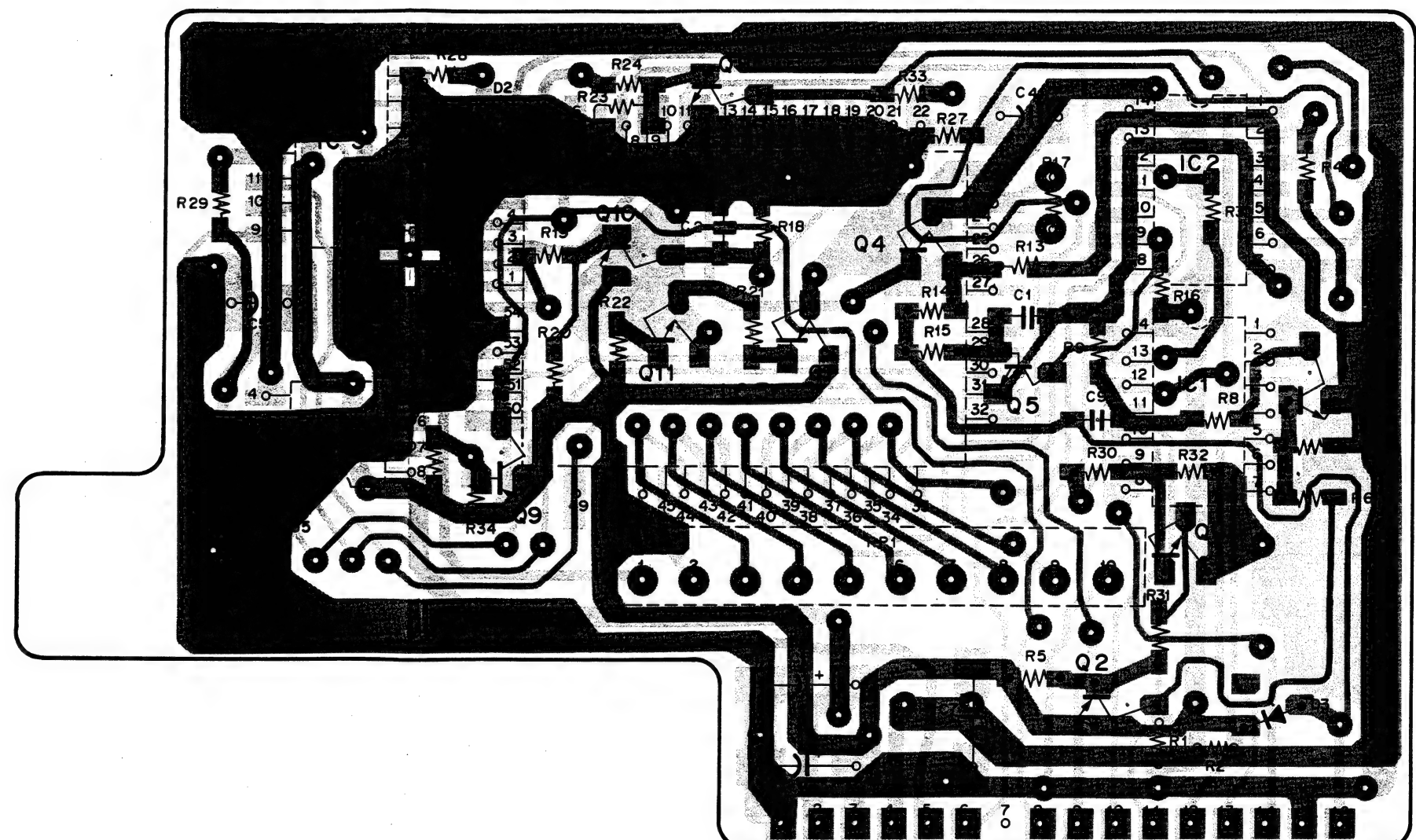
SERIAL NO.
DXC-102 (J) 10191 and higher
DXC-102 (UC) 10181 and higher
DXC-102P (EK) 10311 and higher



—SOLDERING SIDE—

RM-32 BOARD

1-617-219-11
CBK-117 (UCJ)
CBK-117P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

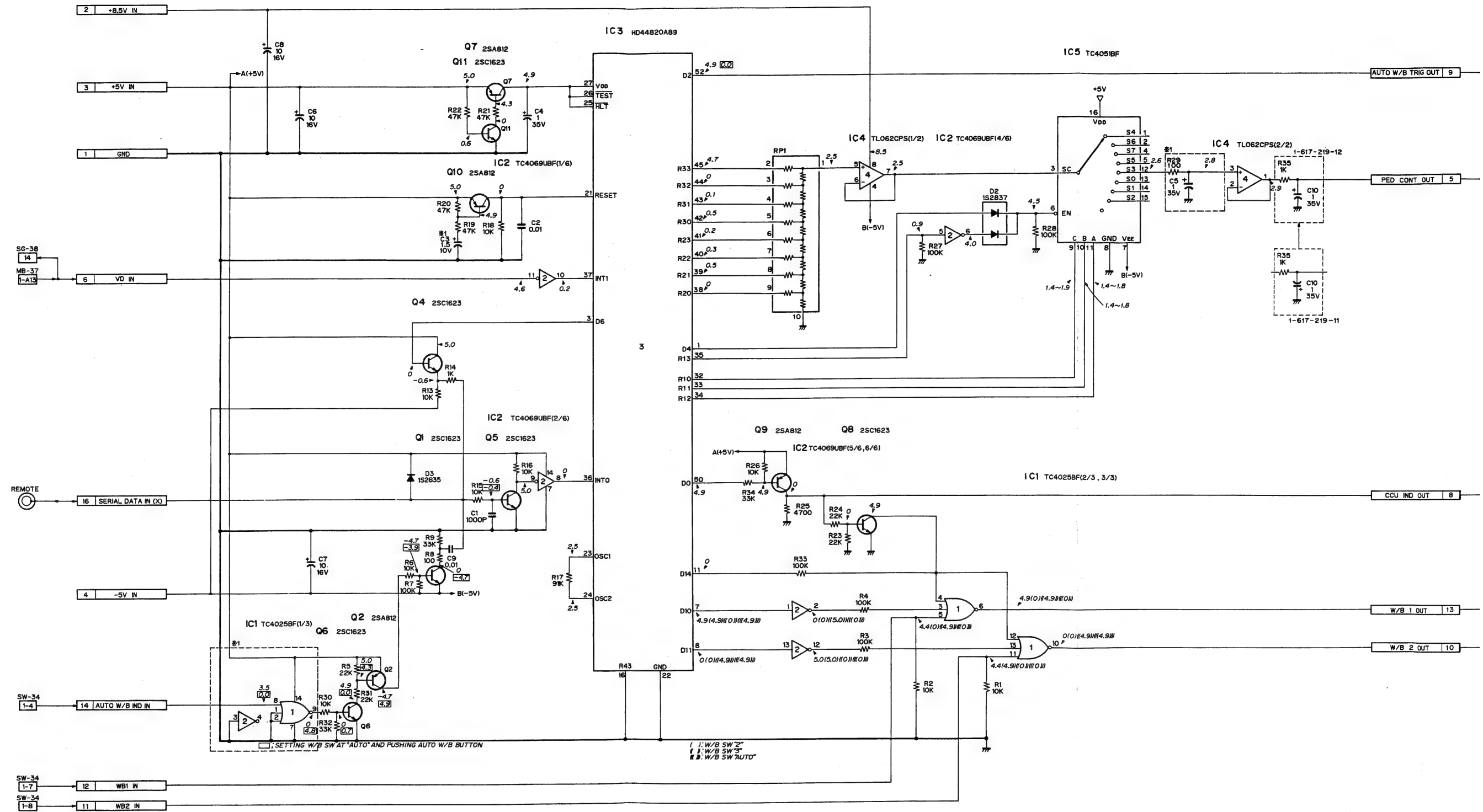


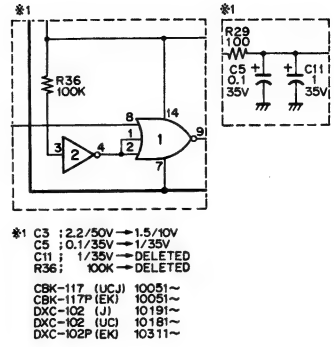
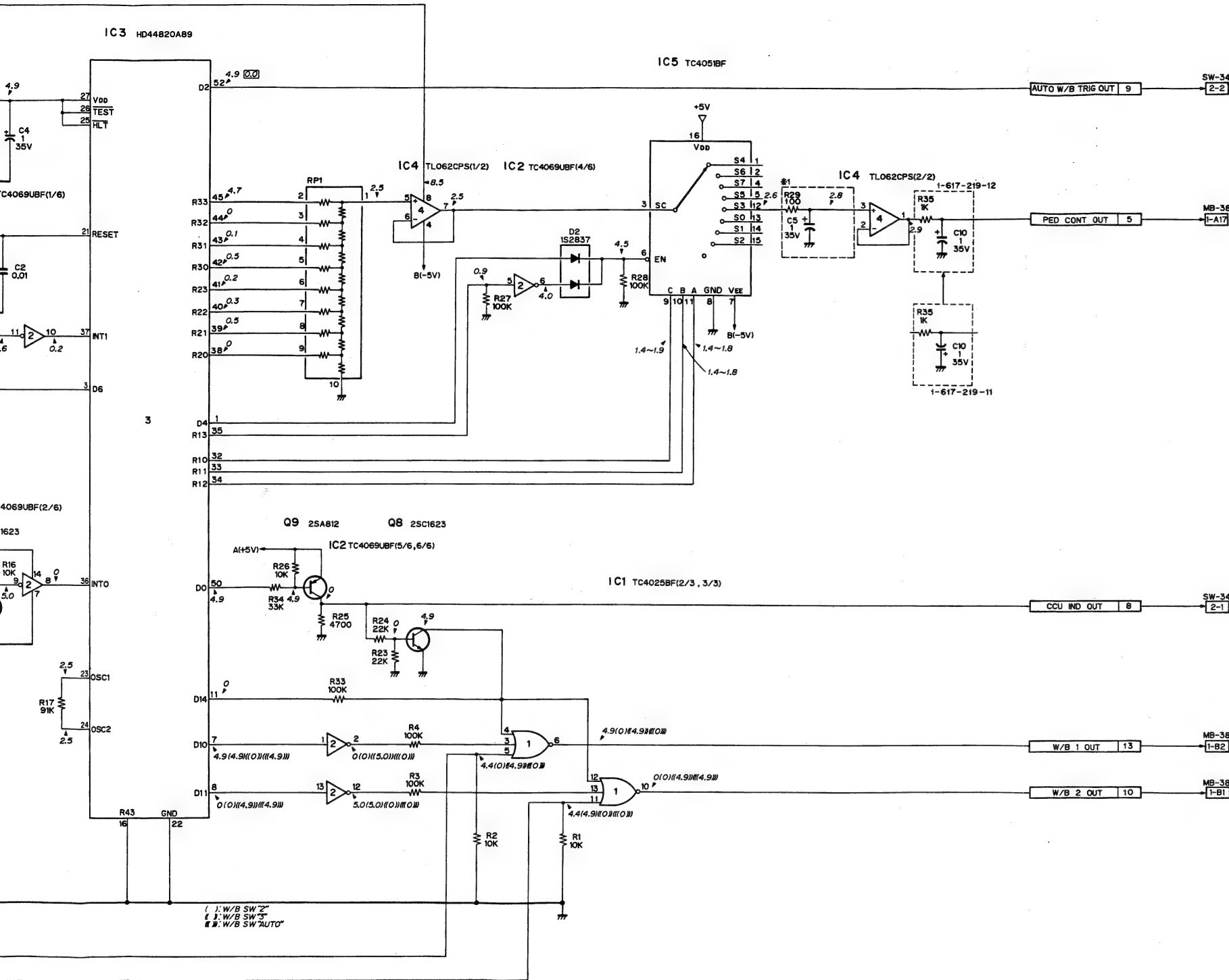
—SOLDERING SIDE—

RM-32 BOARD

1-617-219-12
CBK-117 (UCJ)
CBK-117P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

RM-32 BOARD





注意：
DC電圧は下記条件による値。
●デジタル電圧計で測定。
●REMOTE端子にカメラアダプターCMA-10を接続。
CMA-10セッティング;
PEDESTAL:メカニカルセンター
WHITE BAL: "1"位置

NOTE:
All voltage are taken in condition below.
●Digital voltmeter.
●Connect REMOTE terminal to camera adaptor
CMA-10/10CE.
CMA-10/10CE setting;
PEDESTAL: mechanicalcenter
WHITE BAL: "1" position.

RM-32 BOARD
1-617-219-11,12
CBK-117(UCJ) 10001~
CBK-117P(EK) 10001~
DXC-102(J) 10001~
DXC-102(UC) 10001~
DXC-102P(EK) 10001~

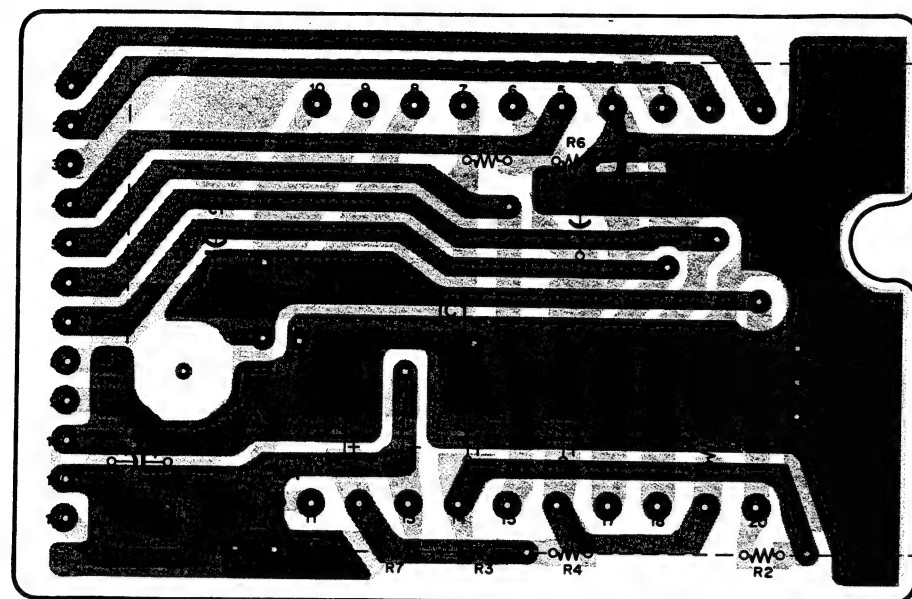
MB-37,BI-3,CN-39,SW-33,DC-28,LE-47

DXC-101/101P

DXC-101/101P

MB-37,BI-3,CN-39,SW-33,DC-28,LE-47

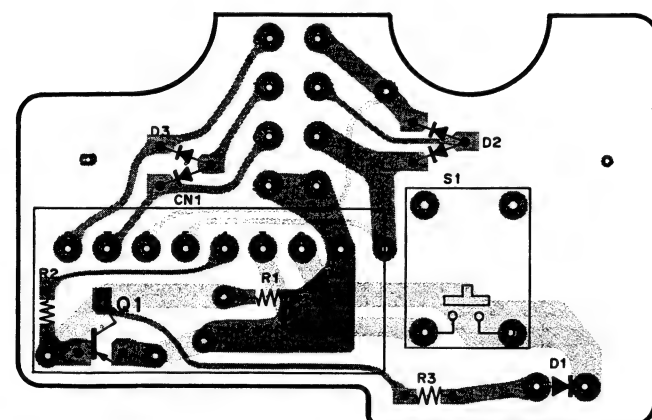
SERIAL NO.
DXC-101 (J) Up to 50180
DXC-101 (UC) Up to 10220
DXC-101P (EK) Up to 10060



— SOLDERING SIDE —

BI-3 BOARD

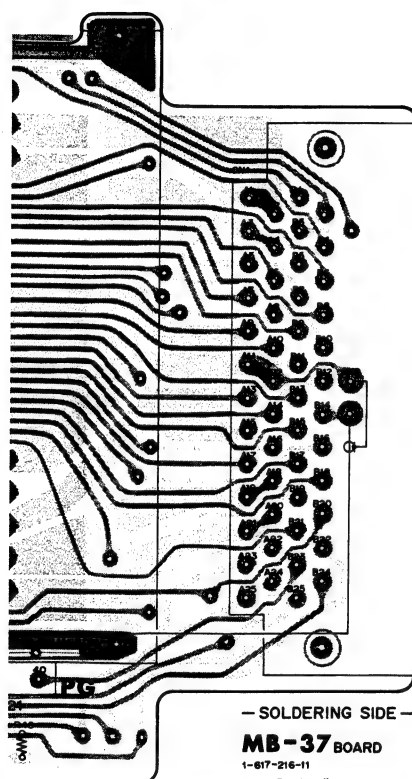
1-617-209-11
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)



— SOLDERING SIDE —

SW-33 BOARD

1-617-218-11
DXC-101 (UC, J)
DXC-101P (EK)

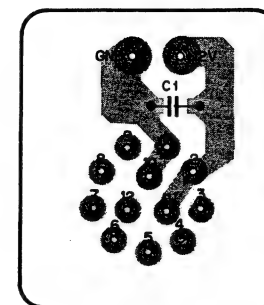


— SOLDERING SIDE —

MB-37 BOARD

1-617-216-11
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UCJ)
DXC-102P (EK)

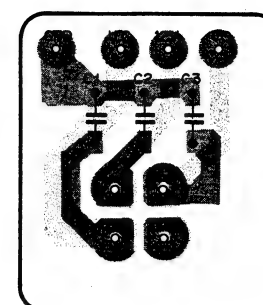
SERIAL NO.
DXC-101(J) Up to 50330
DXC-101(UC) Up to 10220
DXC-101P(EK) Up to 10060



— SOLDERING SIDE —

DC-28 BOARD

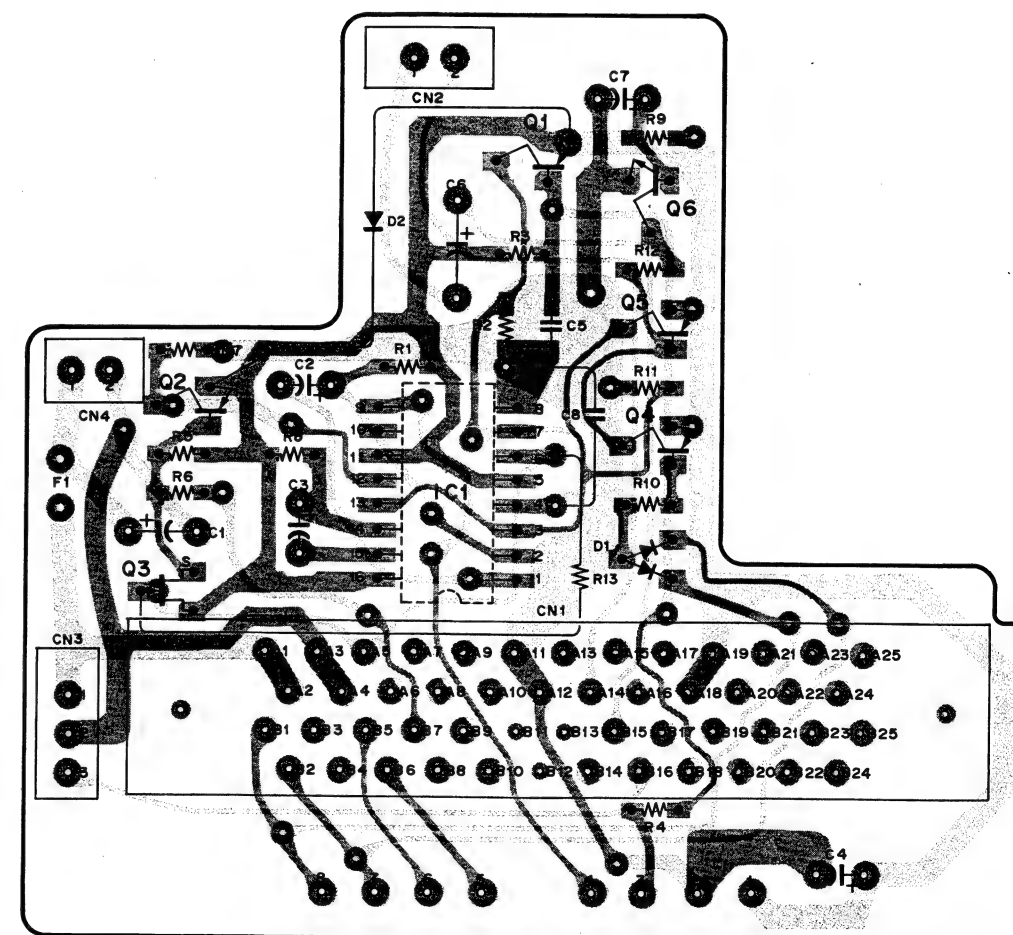
1-617-768-11
DXC-101 (UC, J)
DXC-101P (EK)



— SOLDERING SIDE —

LE-47 BOARD

1-617-767-11
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UC, J)
DXC-102P (EK)



— SOLDERING SIDE —

CN-39 BOARD

DXC-101 (UC, J)
DXC-101P (EK)

6-49(a)

6-50(a)

DXC-101/102/101P/102P (J, UC, EK)

MB37, BI-3, SW-39, SW-33, DC-28 LE-47A

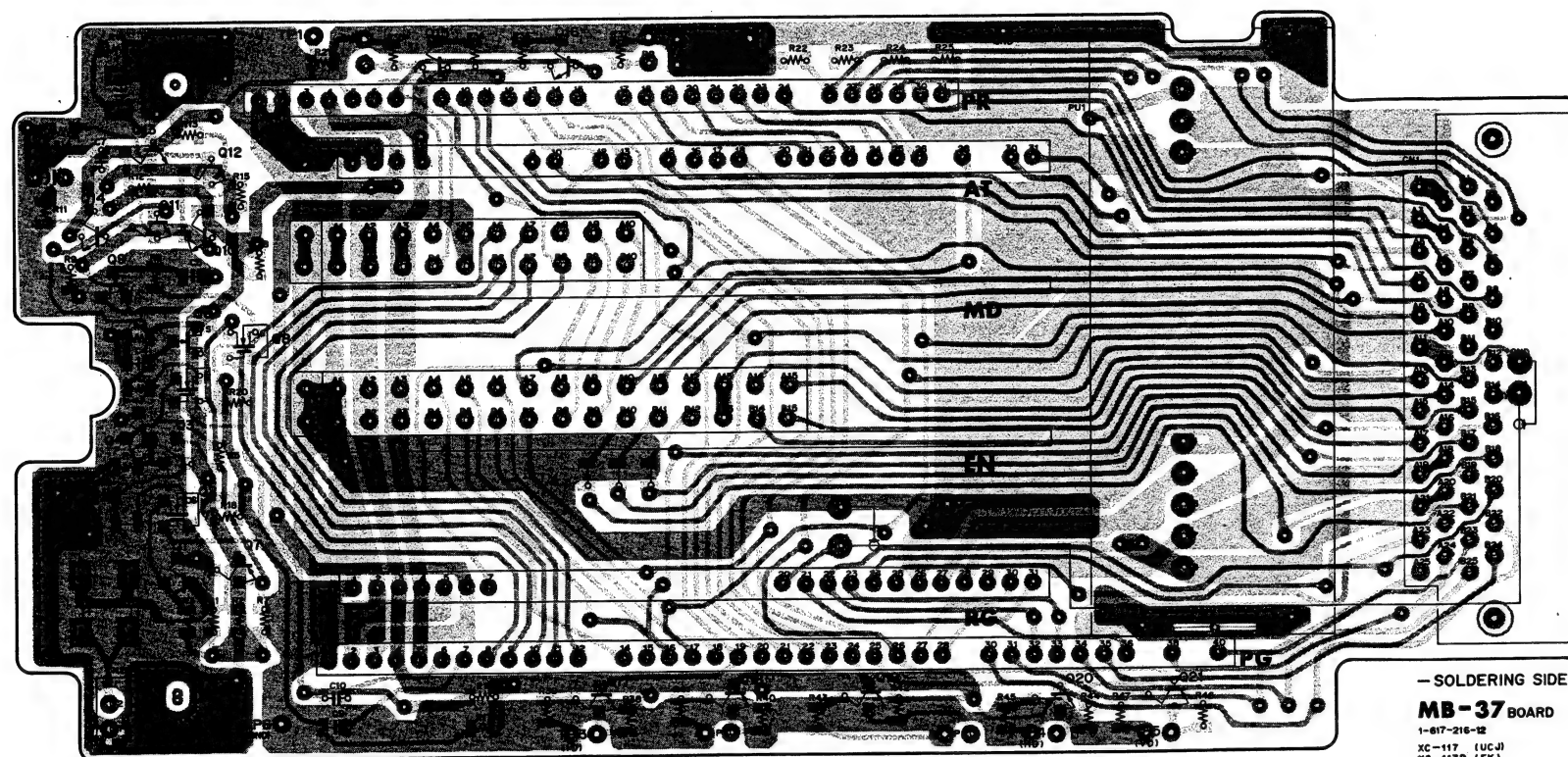
DXC-101/101P

DXC-101/101P

MB37, BI-3, SW-39, SW-33, DC-28 LE-47A

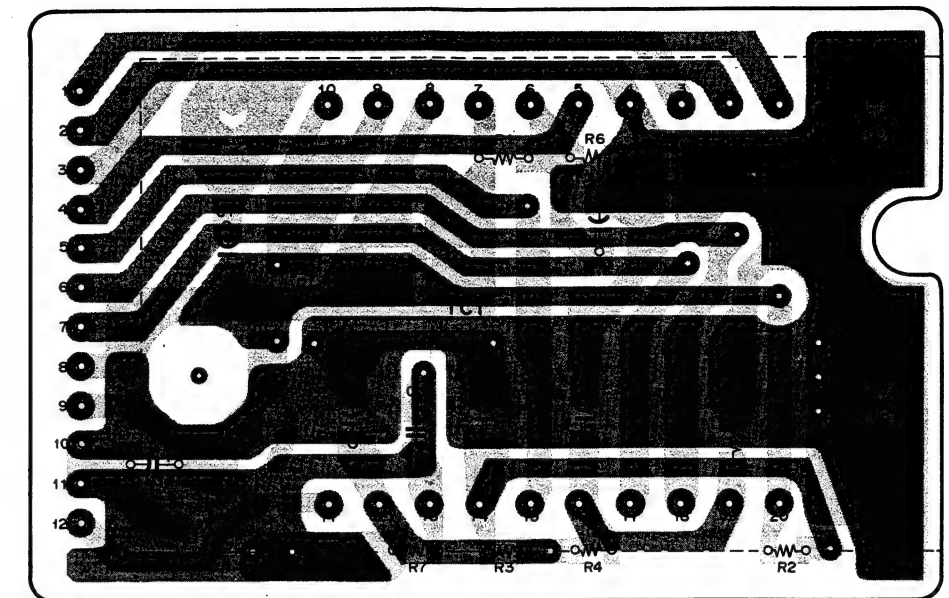
MB-37 BOARD
BI-3 BOARD
CN-39 BOARD
SW-33 BOARD
DC-28 BOARD
LE-47A BOARD

SERIAL NO.
DXC-101 (J) 50431 to 50610
DXC-101 (UC) 10221 to 10630
DXC-101P (EK) 10261 to 10580

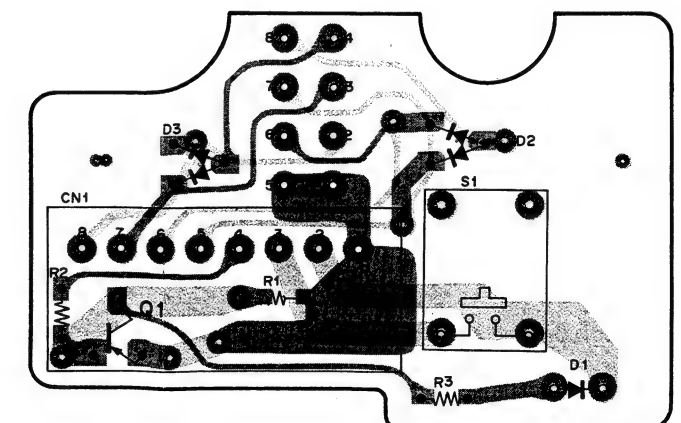


— SOLDERING SIDE —
MB-37 BOARD
1-617-216-12
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UCJ)
DXC-102P (EK)

SERIAL NO.
DXC-101 (J) 50181 and higher
DXC-101 (UC) 10221 and higher
DXC-101P (EK) 10061 and higher

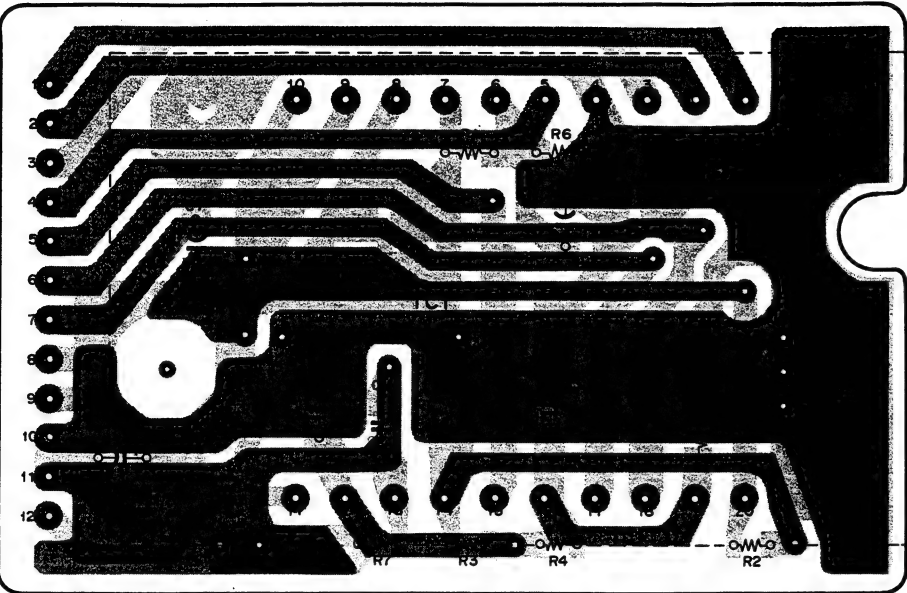


— SOLDERING SIDE —
BI-3 BOARD
1-617-209-12
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UCJ)
DXC-102P (EK)

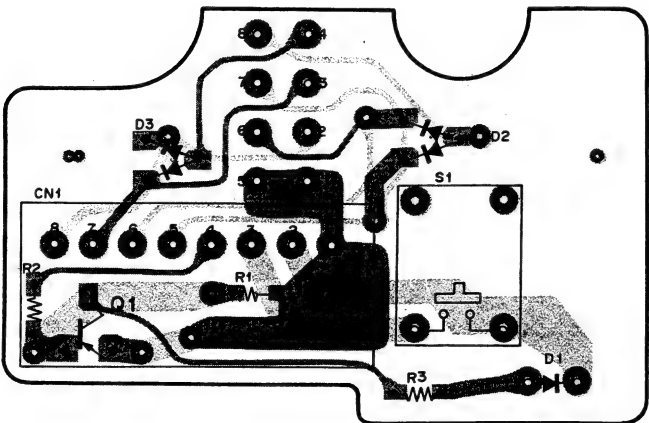


— SOLDERING SIDE —
SW-33 BOARD
1-617-218-12
DXC-101 (UC, J)
DXC-101P (EK)

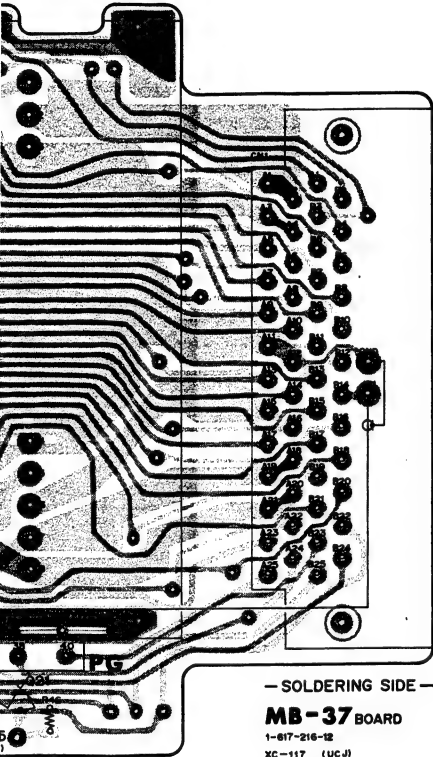
SERIAL NO.
DXC-101 (J) 50181 and higher
DXC-101 (UC) 10221 and higher
DXC-101P (EK) 10061 and higher



— SOLDERING SIDE —
BI-3 BOARD
1-617-209-12
XC-117 (UC,J)
XC-117P (EK)
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

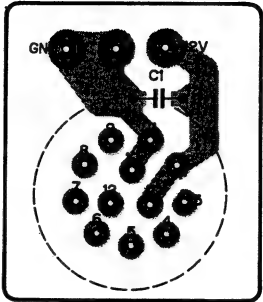


— SOLDERING SIDE —
SW-33 BOARD
1- 617 - 218 - 12
DXC-101 (UC,J)
DXC-101P (EK)

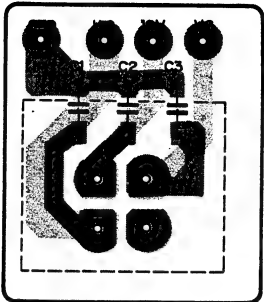


— SOLDERING SIDE —
MB-37 BOARD
1-617-216-12
XC-117 (UC,J)
XC-117P (EK)
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

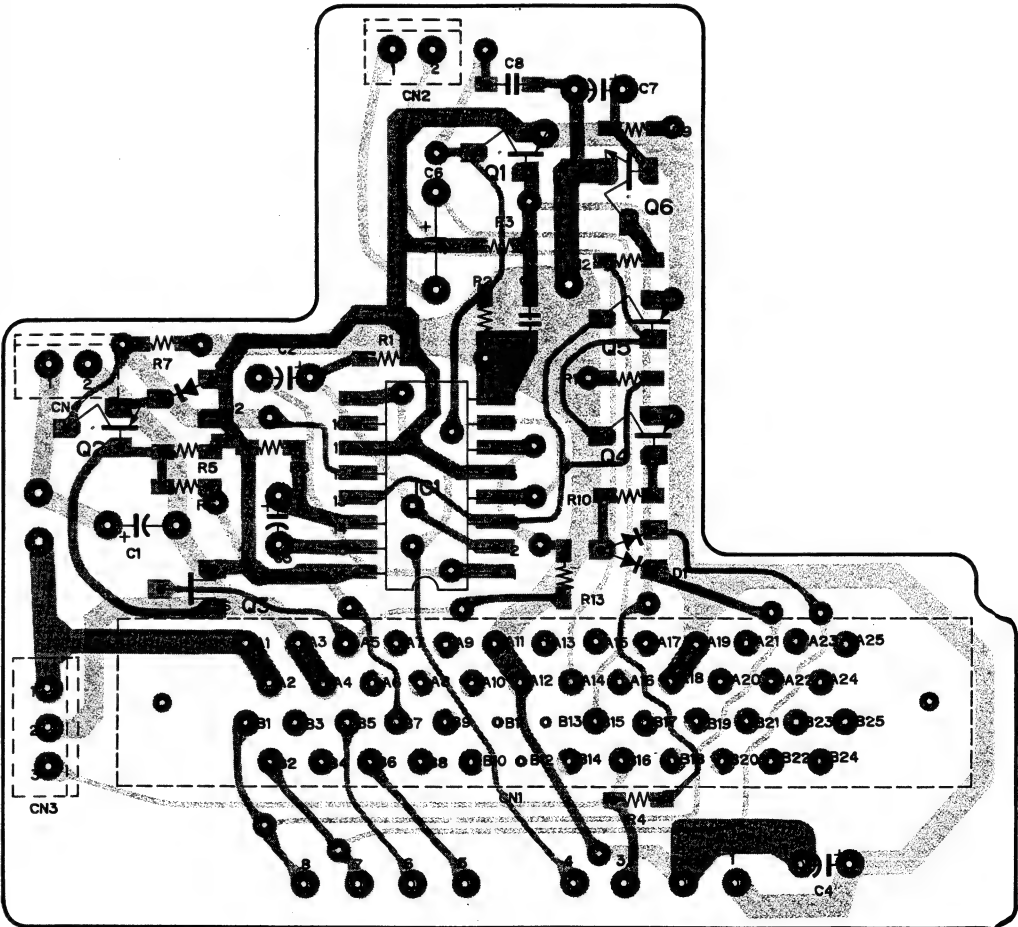
SERIAL NO.
DXC-101 (J) 50331 and higher
DXC-101 (UC) 10221 and higher
DXC-101P (EK) 10061 and higher



— SOLDERING SIDE —
DC-28 BOARD
1-617-768-12
DXC-101 (UC,J)
DXC-101P (EK)

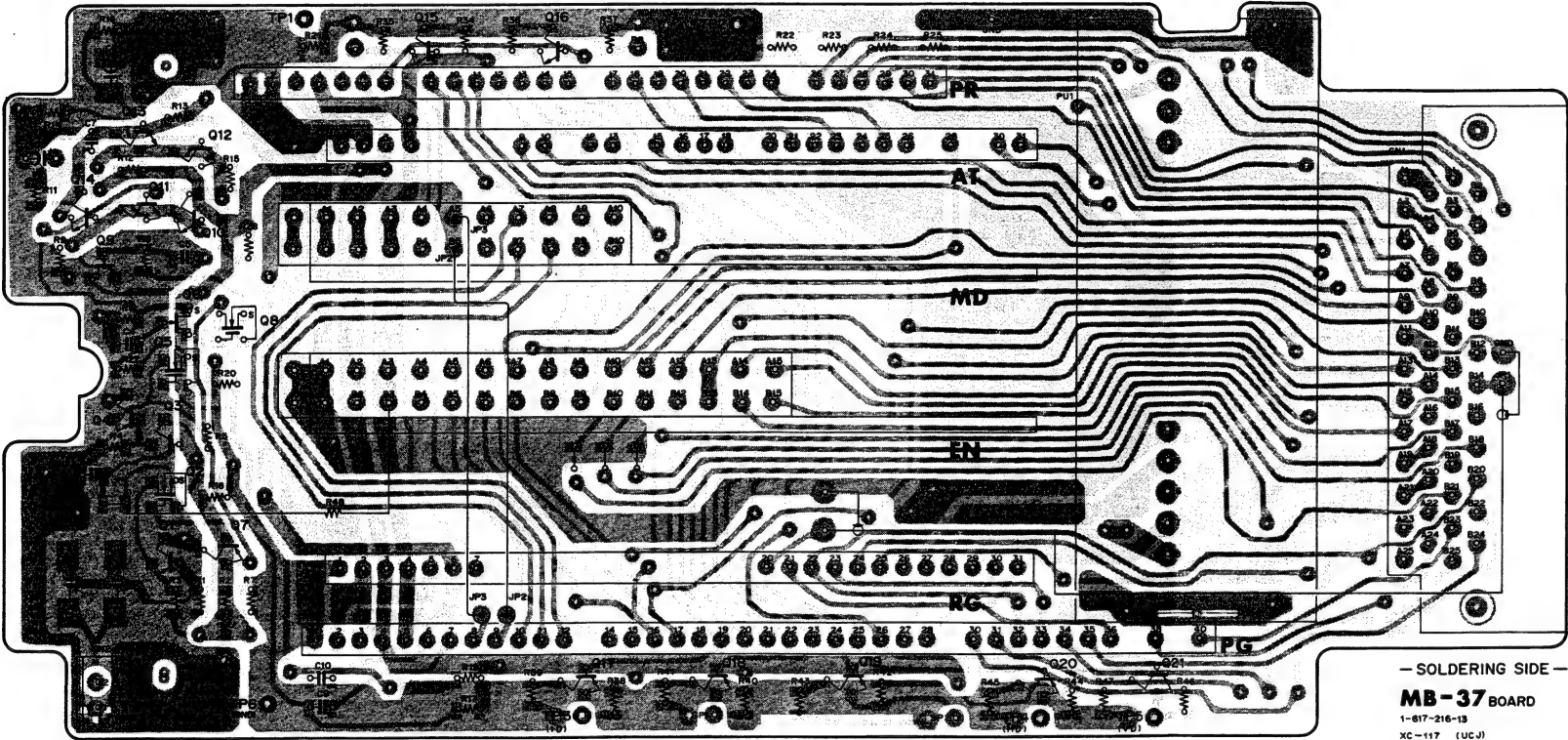


— SOLDERING SIDE —
LE-47A BOARD
1-617-768-12
DXC-101 (UC,J)
DXC-101P (EK)

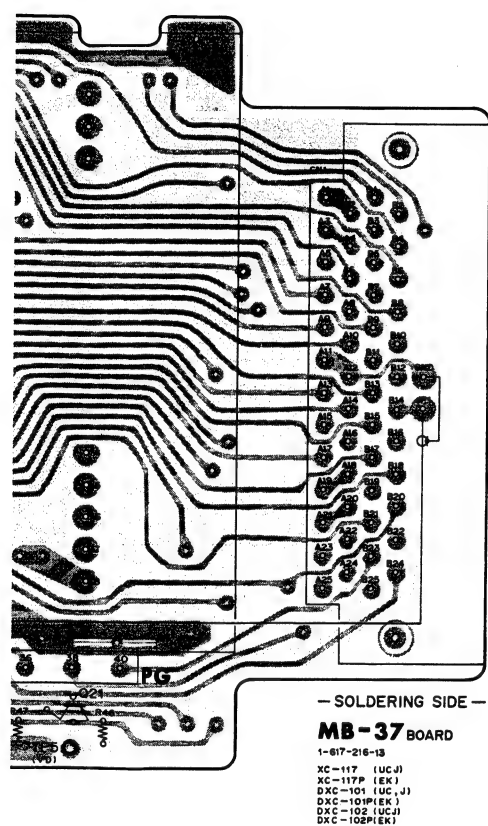


MB-37 BOARD

SERIAL NO.
DXC-101 (J) 50611 and higher
DXC-101 (UC) 10631 and higher
DXC-101P (EK) 10581 and higher



— SOLDERING SIDE —
MB-37 BOARD
1-617-216-13
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC, J)
DXC-101P (EK)
DXC-102 (UCJ)
DXC-102P (EK)



DXC-101/101P FRAME

MB-37 BOARD

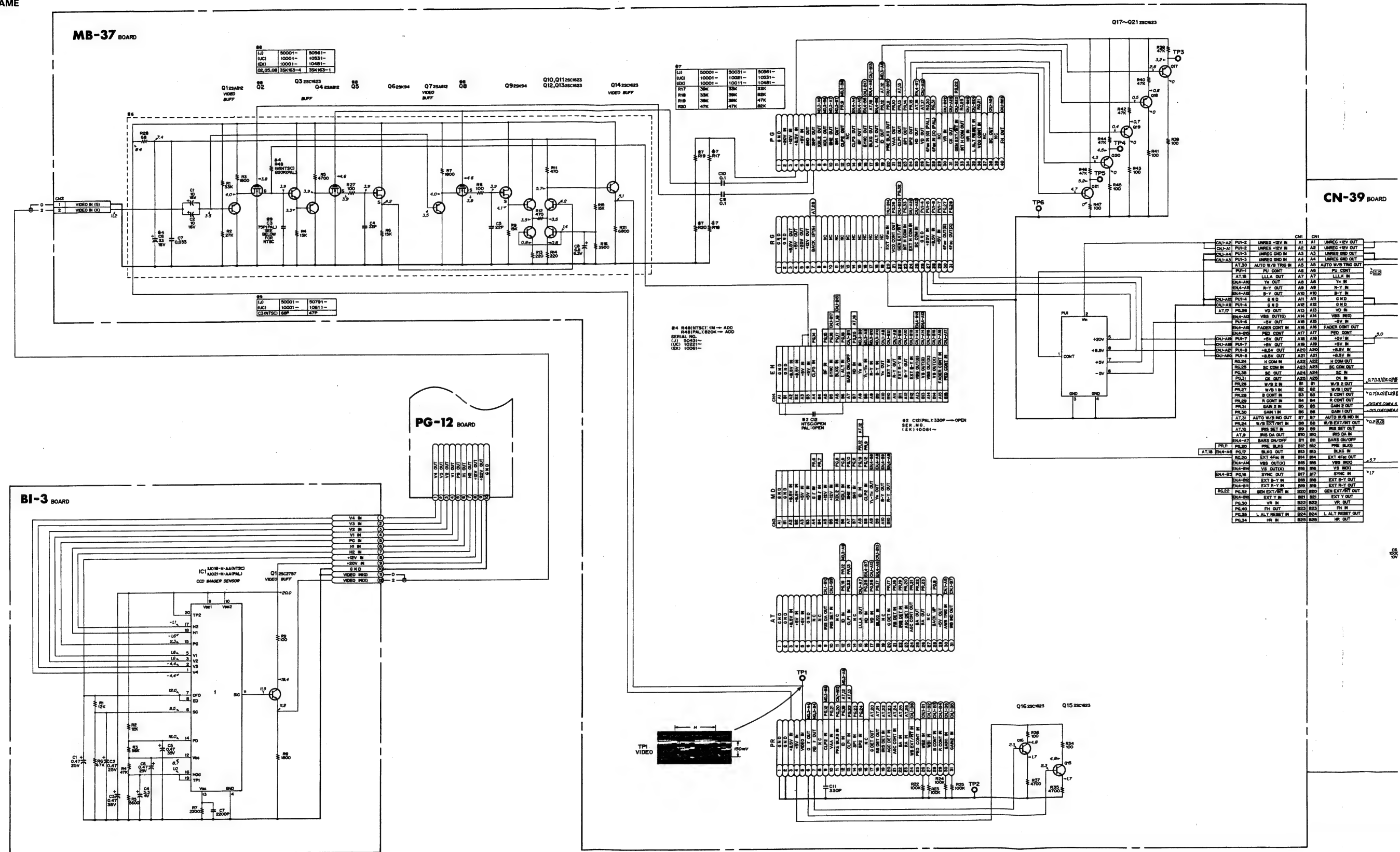
BI-3 BOARD

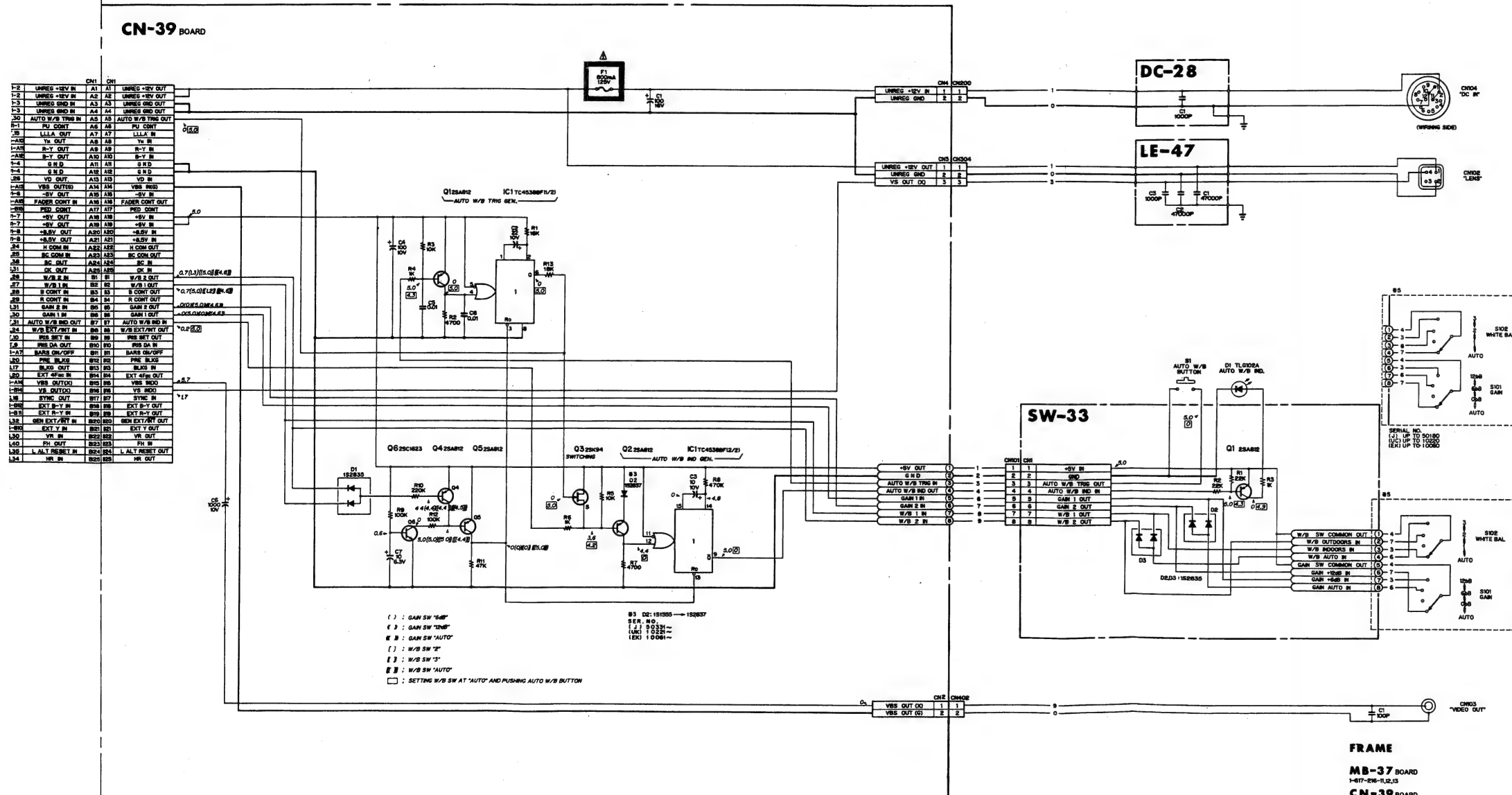
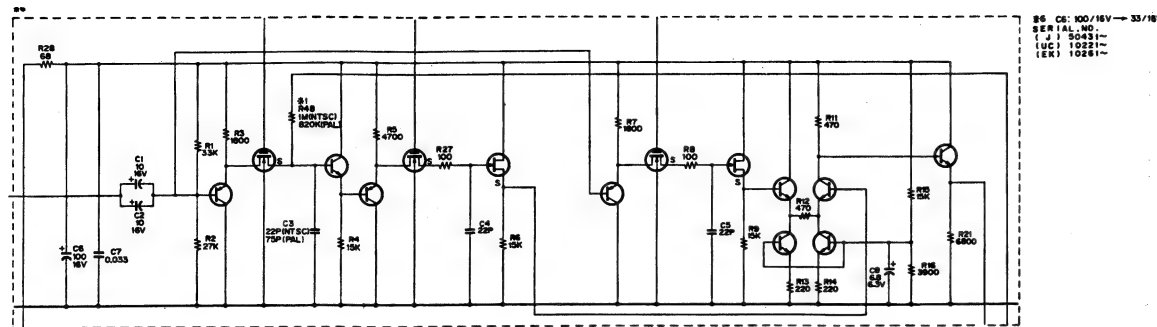
CN-39 BOARD

SW-33 BOARD

DC-28 BOARD

LE-47 BOARD





注意:

- DC電圧はデジタル電圧計による値。
- 波形写真は下記条件で撮影。
 - MB-37基板、TP1にてカラーバーの白部分が150mVp-pになる様レンズアイリスをセットする。
(F≒4、波形モニターで100IRE)
 - WHITE BALスイッチ←1(3200°K)位置
 - GAINスイッチ→0dB位置
- △印及び で囲まれた部品は安全性を維持するために重要な部品です。従って交換する時は必ず指定の部品を使って下さい。

NOTE:

- All voltage are dc, measured with a digital voltmeter (input resistance 10 MΩ).
- All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box.
Adjust lens iris so that a white level at TP1/MB-37 board is 150 mV. [F≒4, White level on the waveform monitor is 100 IRE (700 mV for PAL)]
 - Set camera WHITE BAL switch to "1 (3200°K)".
 - Set camera GAIN switch to "0 dB".

- The shaded and △ marked components are critical to safety.
Replace only with same components as specified.

MB-37,MB-38,BI-3,SG-110,SW-34,LE-47

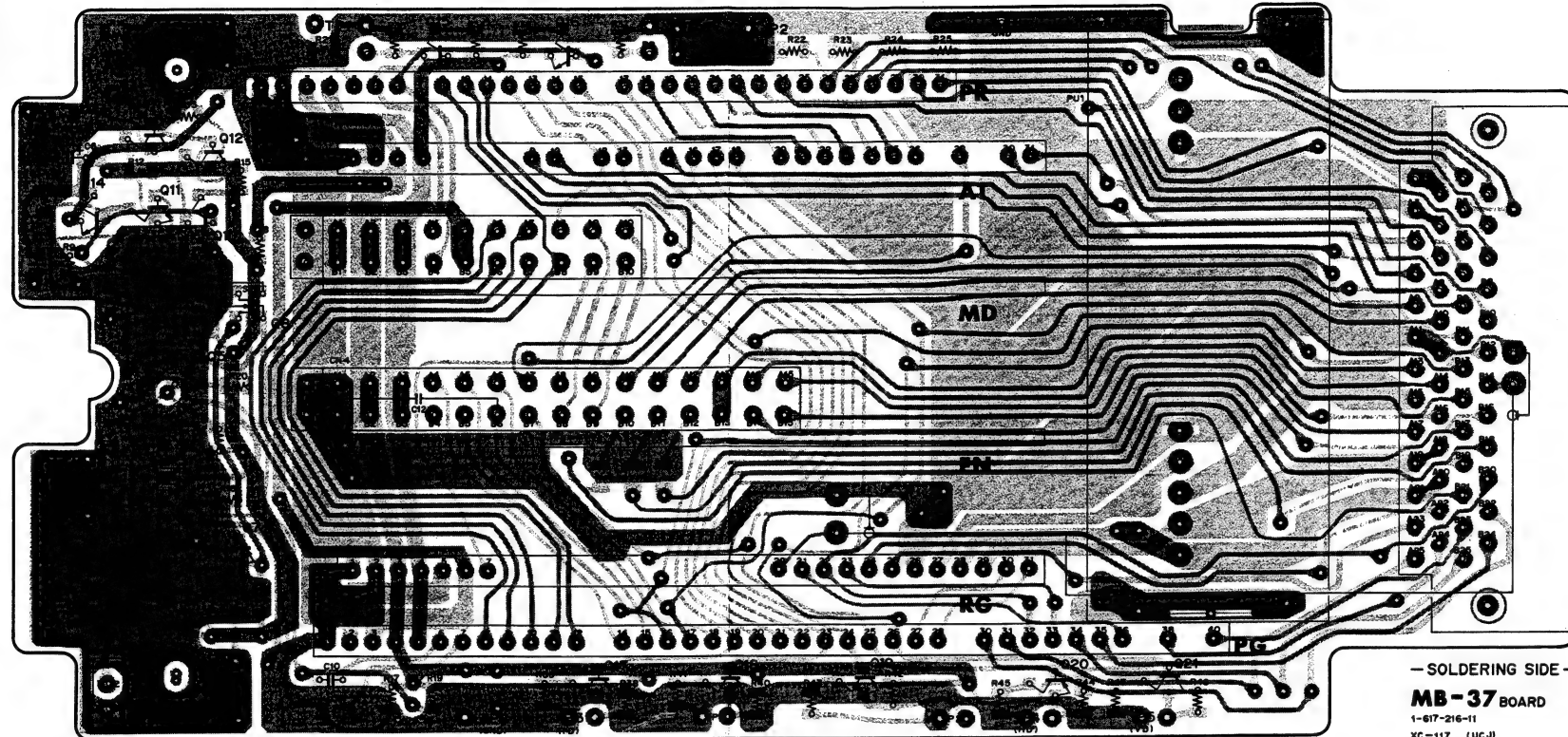
DXC-102/102P

DXC-102/102P

MB-37,MB-38,BI-3,SG-110,SW-34,LE-47

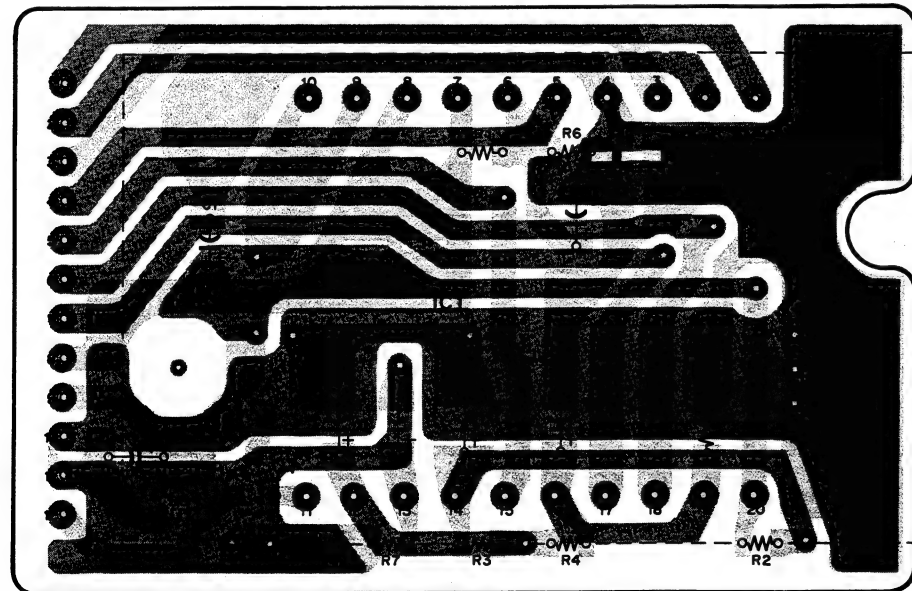
MB-37 BOARD
MB-38 BOARD
BI-3 BOARD
SG-110 BOARD
SW-34 BOARD
LE-47 BOARD

SERIAL NO.
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310

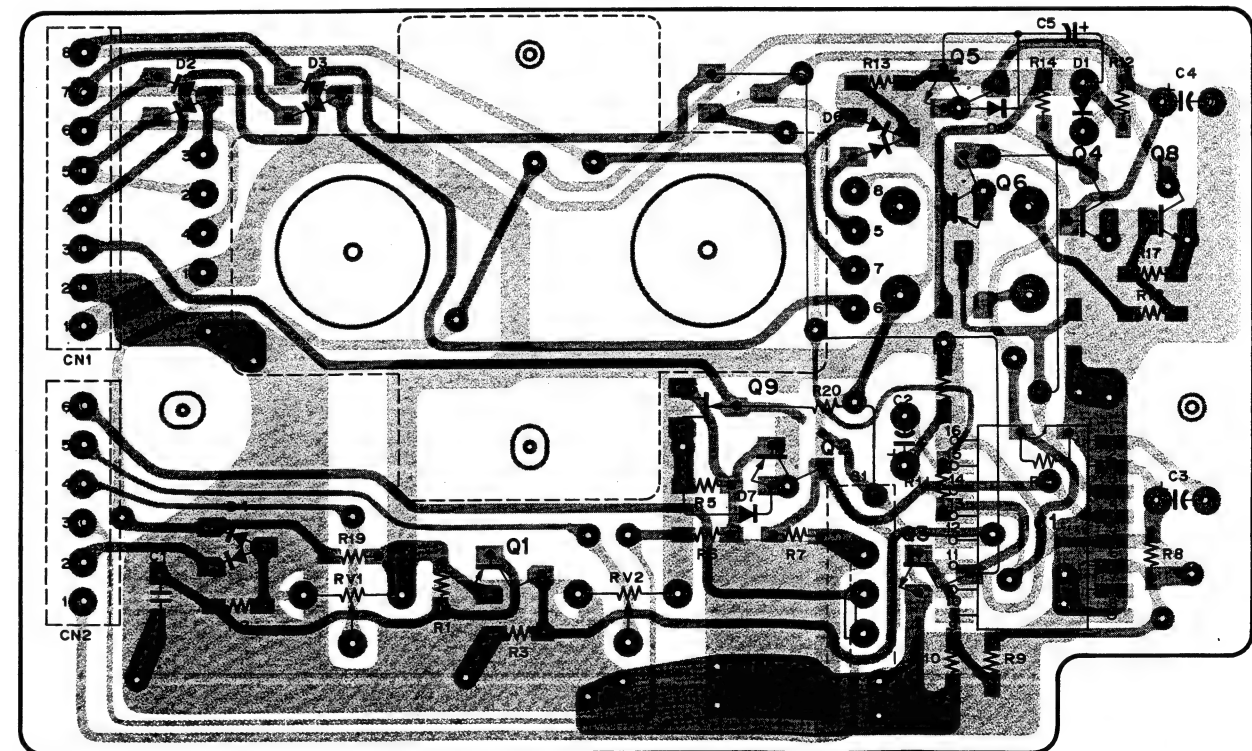


SERIAL NO.
DXC-102 (J) Up to 10020
DXC-102 (UC) Up to 10030
DXC-102P (EK) Up to 10010

SERIAL NO.
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310

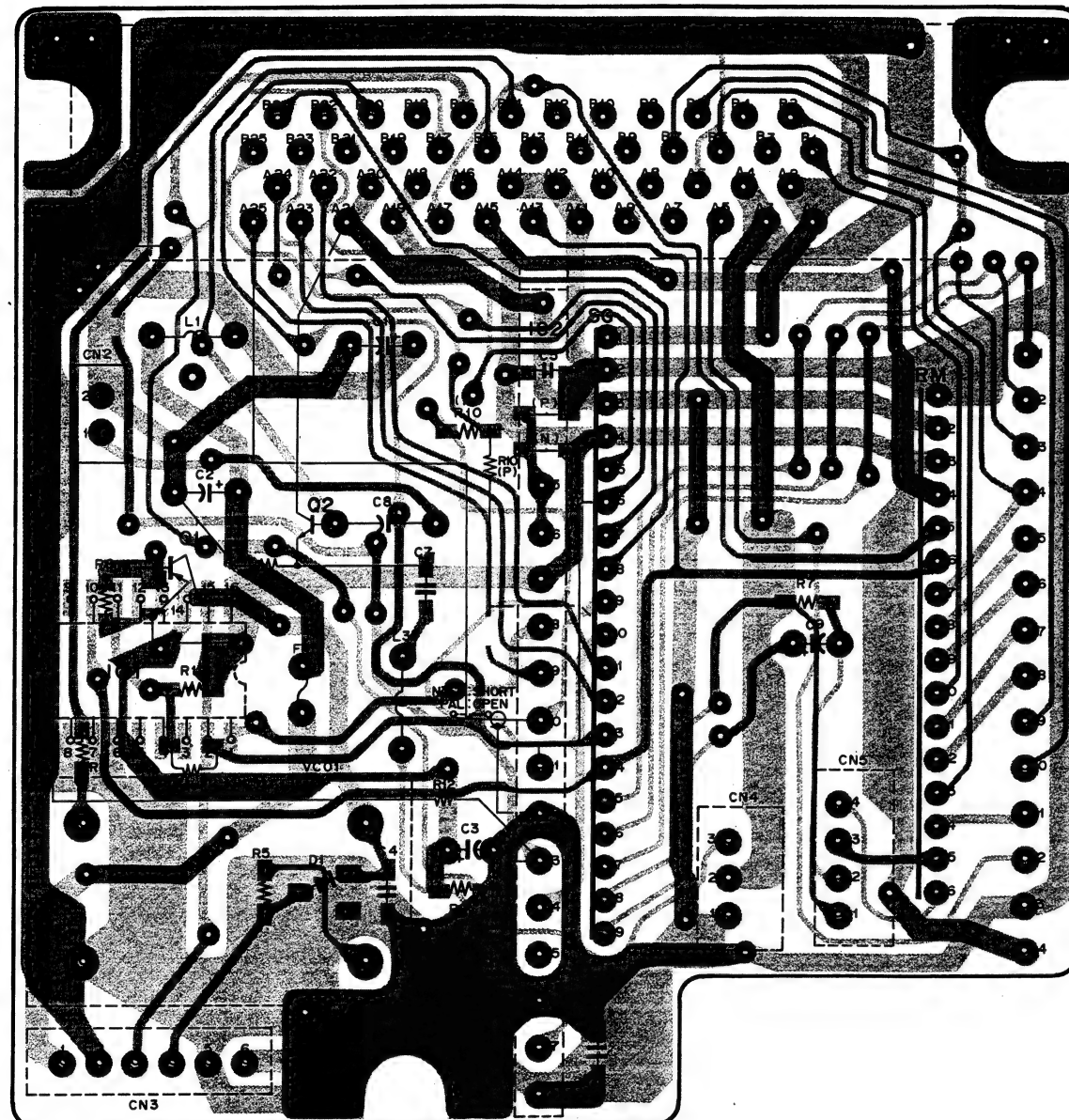


6-55 (a)



6-56(a)

SERIAL NO.
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310

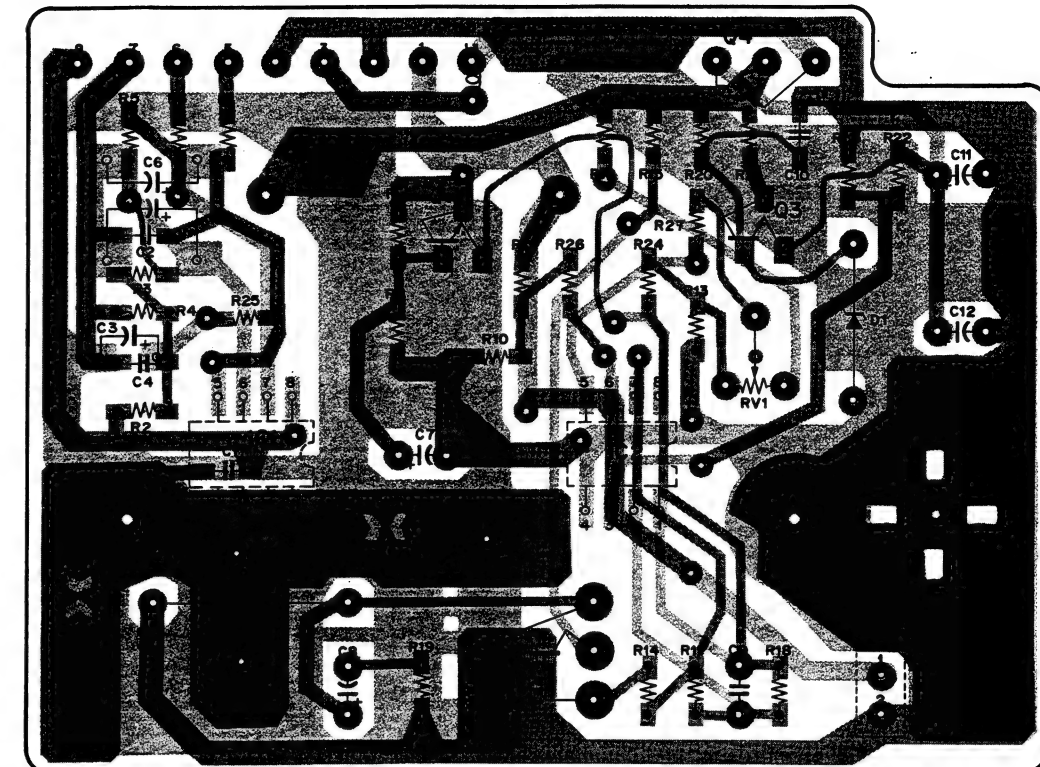


—SOLDERING SIDE—

MB-38 BOARD

1-617-213-11
CBK-117 (UC,J)
CBK-117P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

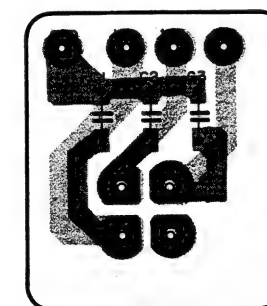
6-57(a)



—SOLDERING SIDE—

SG-110 BOARD

1-617-222-11
CBK-117 (UC,J)
CBK-117P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

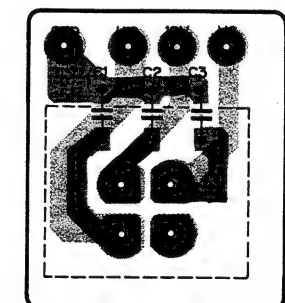


—SOLDERING SIDE—

LE-47 BOARD

1-617-767-11
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

SERIAL NO.
DXC-102(J) Up to 10020
DXC-102(UC) Up to 10030
DXC-102P(EK) Up to 10010



—SOLDERING SIDE—

LE-47B BOARD

1-617-768-21
DXC-102 (UC,J)
DXC-102P(EK)

SERIAL NO.
DXC-102(J) 10021 and higher
DXC-102(UC) 10031 and higher
DXC-102P(EK) 10011 and higher

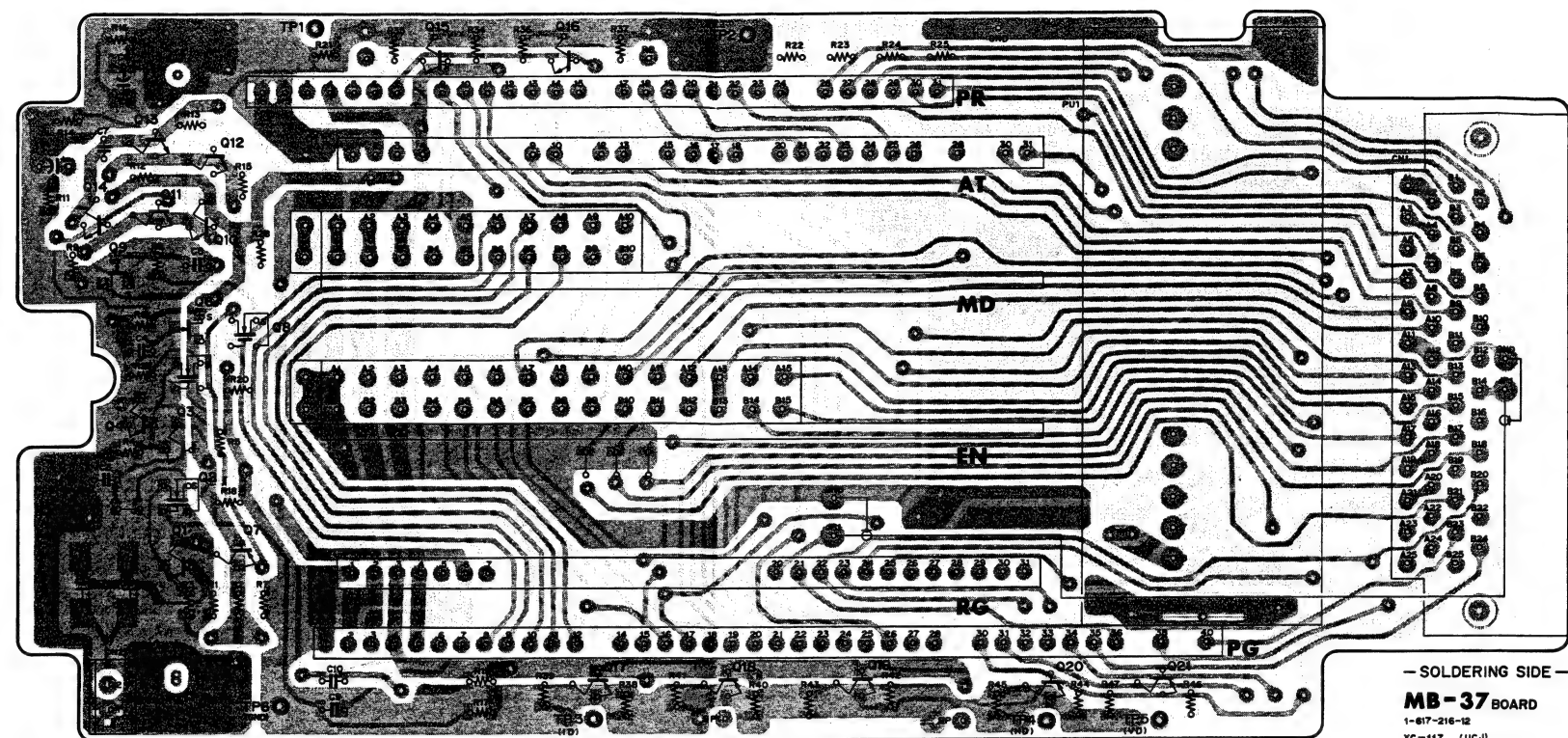
6-58(a)

DXC-101/102/101P/102P (J, UC, EK)

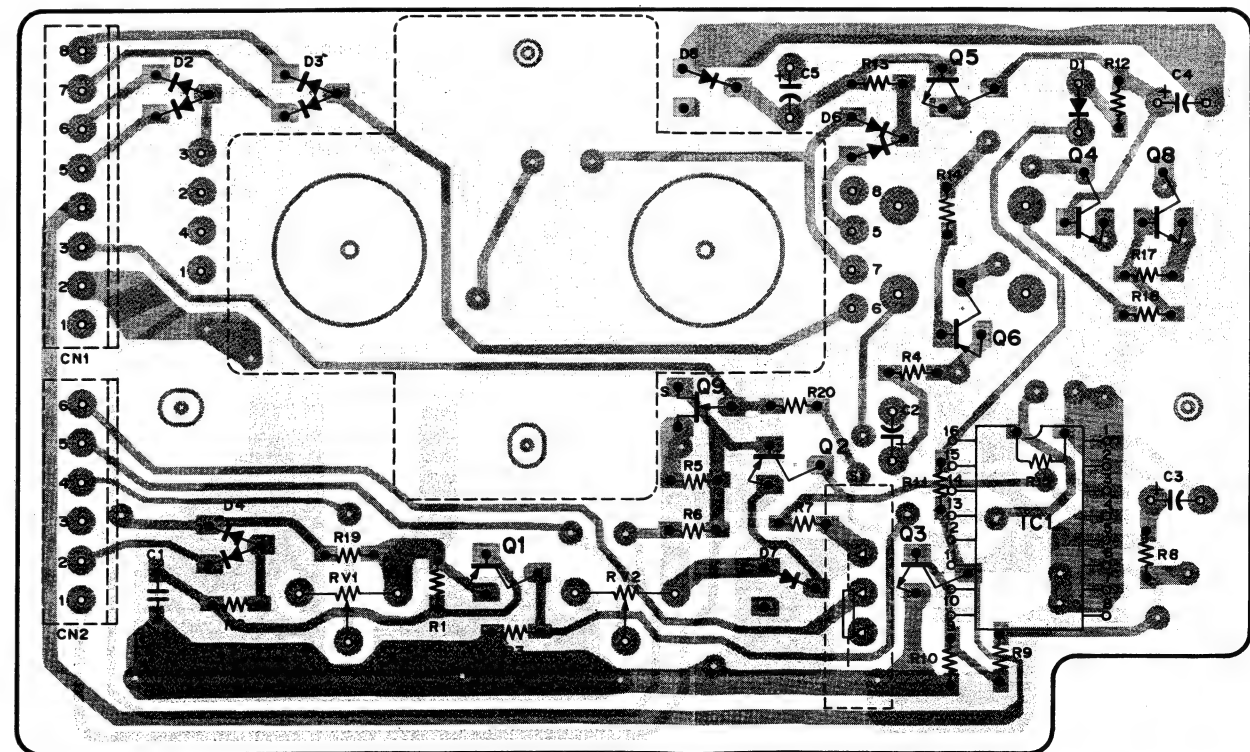
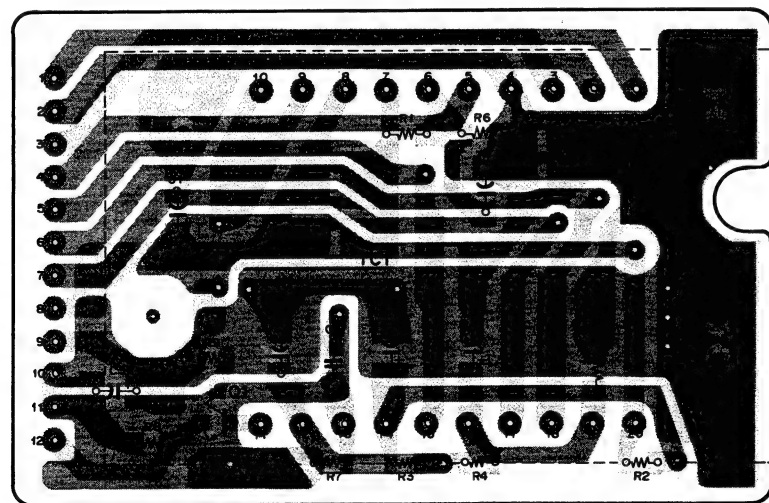
MB-37 BOARD
 MB-38 BOARD
 BI-3 BOARD
 SW-34 BOARD

SERIAL NO.
 DXC-102 (J) 10191 to 10300
 DXC-102 (UC) 10181 to 10410
 DXC-102P (EK) 10311 to 10570

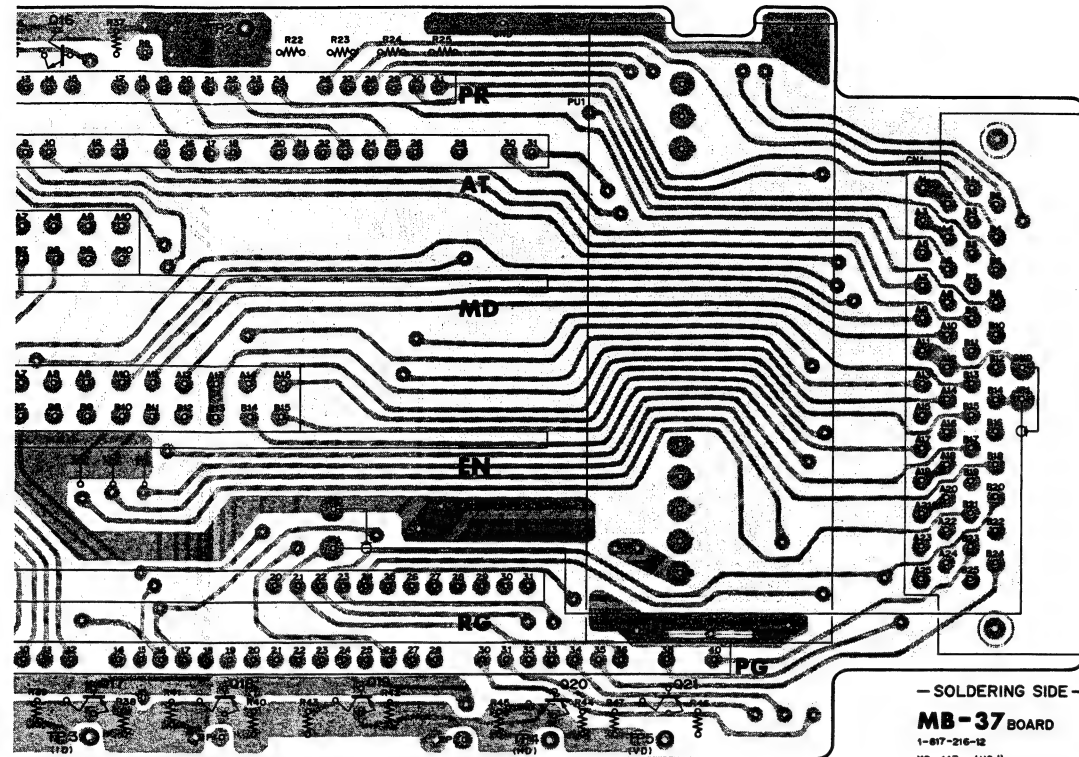
DXC-102 (J) 10021 and higher
 DXC-102 (UC) 10031 and higher
 DXC-102P (EK) 10011 and higher



SERIAL NO.
 DXC-102 (J) 10191 and higher
 DXC-102 (UC) 10181 and higher
 DXC-102P (EK) 10311 and higher

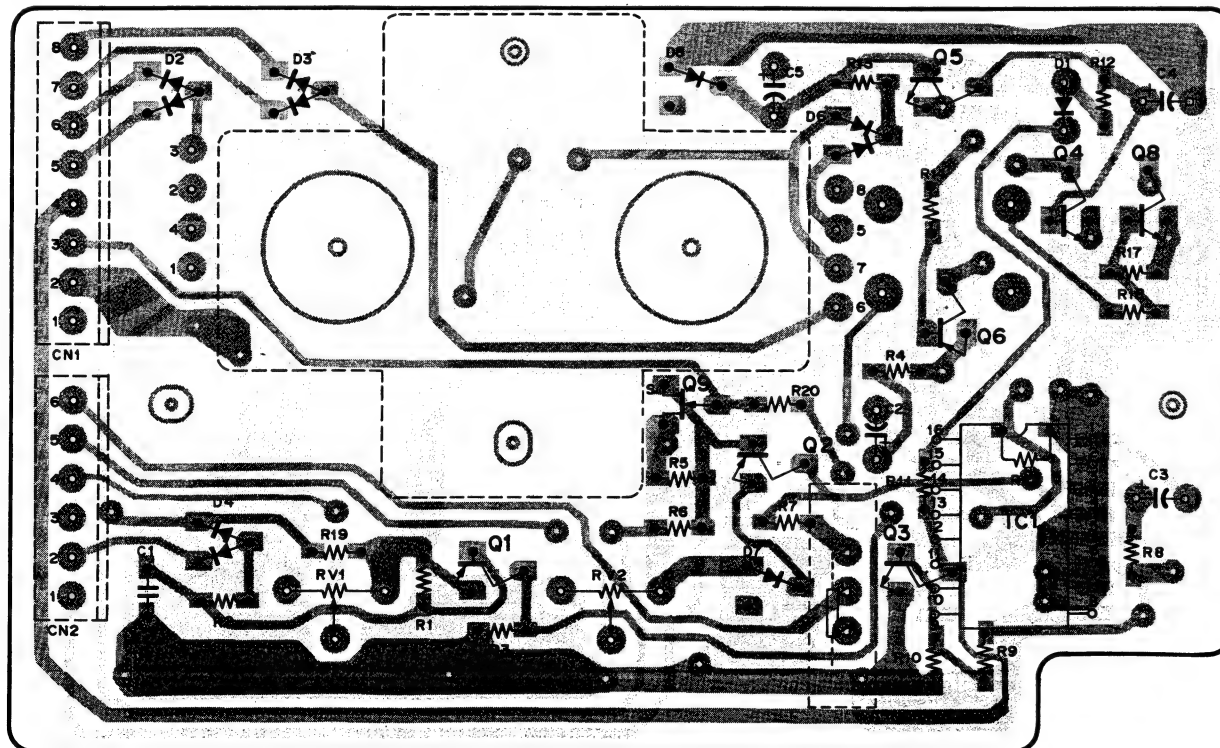


— SOLDERING SIDE —
SW-34 BOARD
 1-617-223-12
 DXC-102 (UC,J)
 DXC-102P (EK)



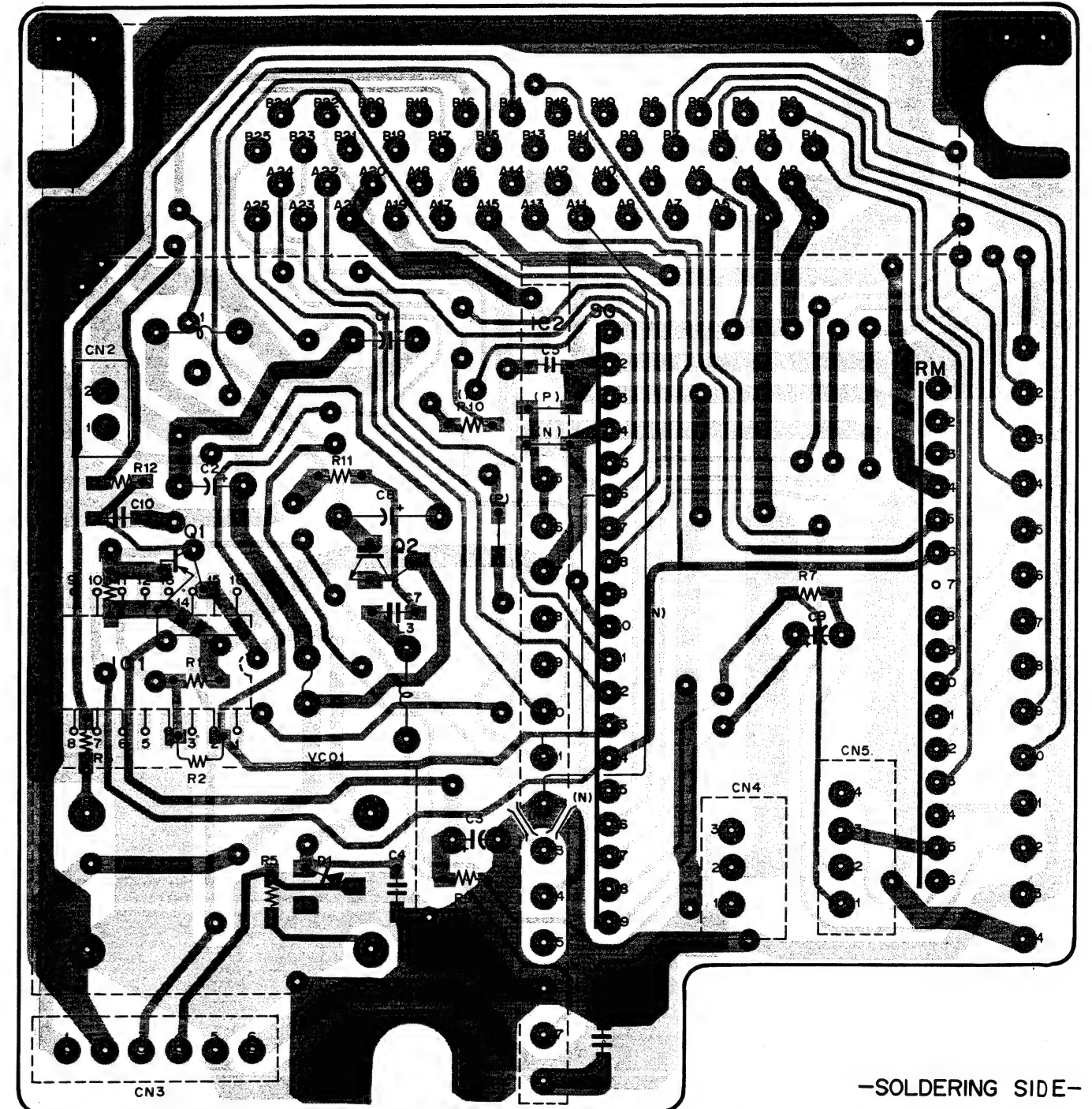
—SOLDERING SIDE—
MB-37 BOARD
 1-617-216-12
 XC-117 (UC,J)
 XC-117P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)
 DXC-102P (EK)

SERIAL NO.
 DXC-102 (J) 10191 and higher
 DXC-102 (UC) 10181 and higher
 DXC-102P (EK) 10311 and higher



—SOLDERING SIDE—
SW-34 BOARD
 1-617-223-12
 DXC-102 (UC,J)
 DXC-102P (EK)

6-57(b)



—SOLDERING SIDE—
MB-38 BOARD
 1-617-213-12
 CBK-117 (UC,J)
 CBK-117P (EK)
 DXC-102 (UC,J)
 DXC-102P (EK)

6-58(b)

MB-37, MB-38

DXC-102/102P

DXC-102/102P

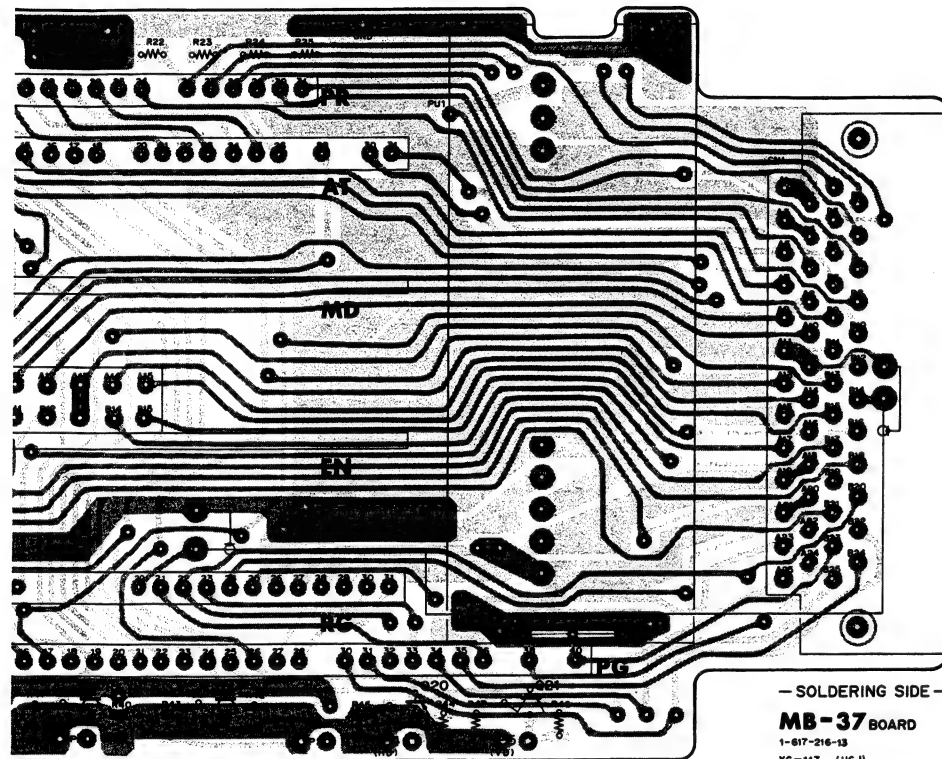
MB-37, MB-38

SERIAL NO.

DXC-102 (J) 10471 and higher

DXC-102 (UC) 10661 and higher

DXC-102P (EK) 11071 and higher



—SOLDERING SIDE—

MB-37 BOARD

1-617-216-13

XC-117 (UC)

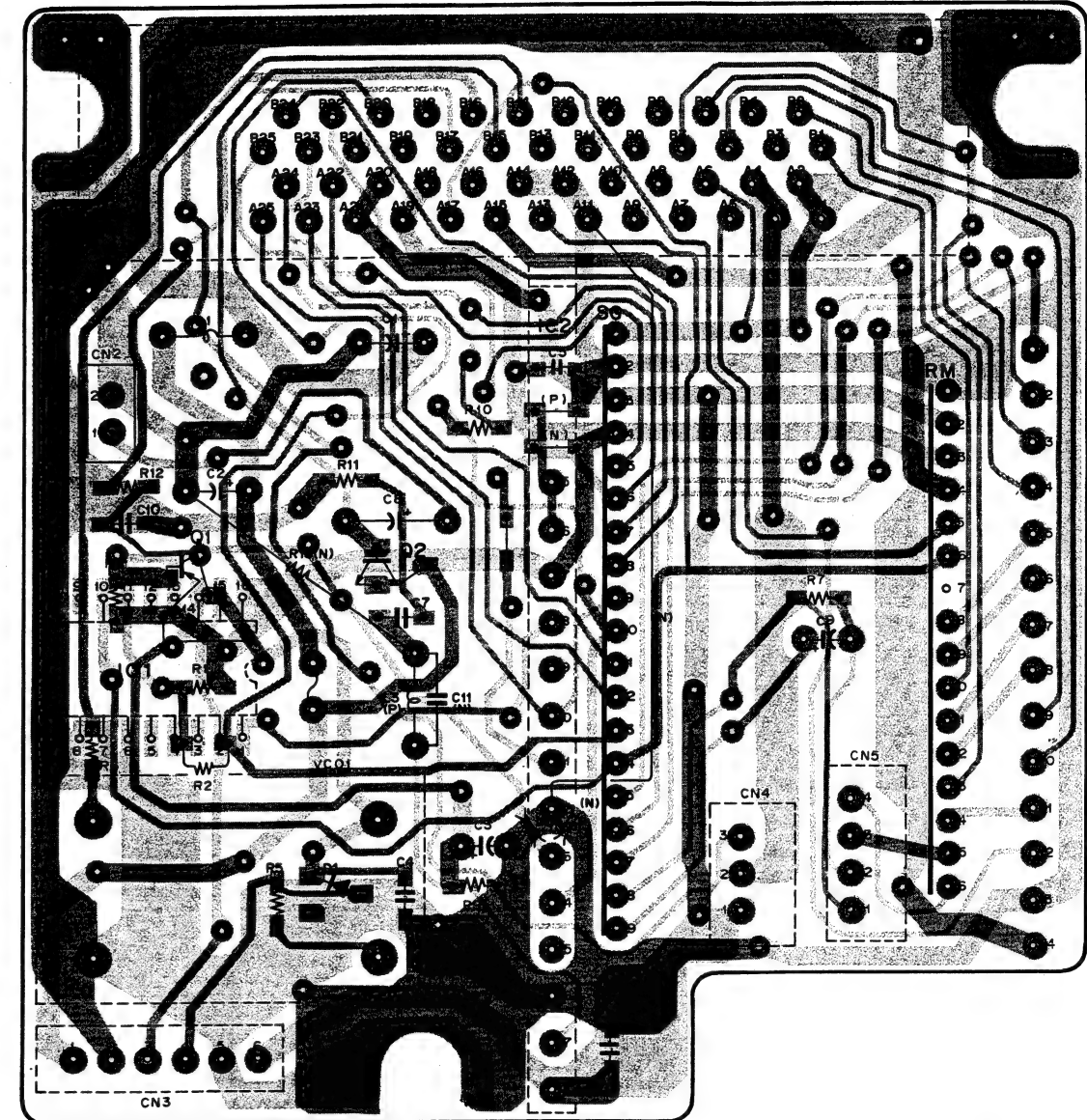
XC-117P (EK)

DXC-101 (UC, J)

DXC-101P (EK)

DXC-102 (UC, J)

DXC-102P (EK)



—SOLDERING SIDE—

MB-38 BOARD

1-617-213-13

CBK-117 (UC, J)

CBK-117P (EK)

DXC-102 (UC, J)

DXC-102P (EK)

DXC-102/102P FRAME

MB-37 BOARD

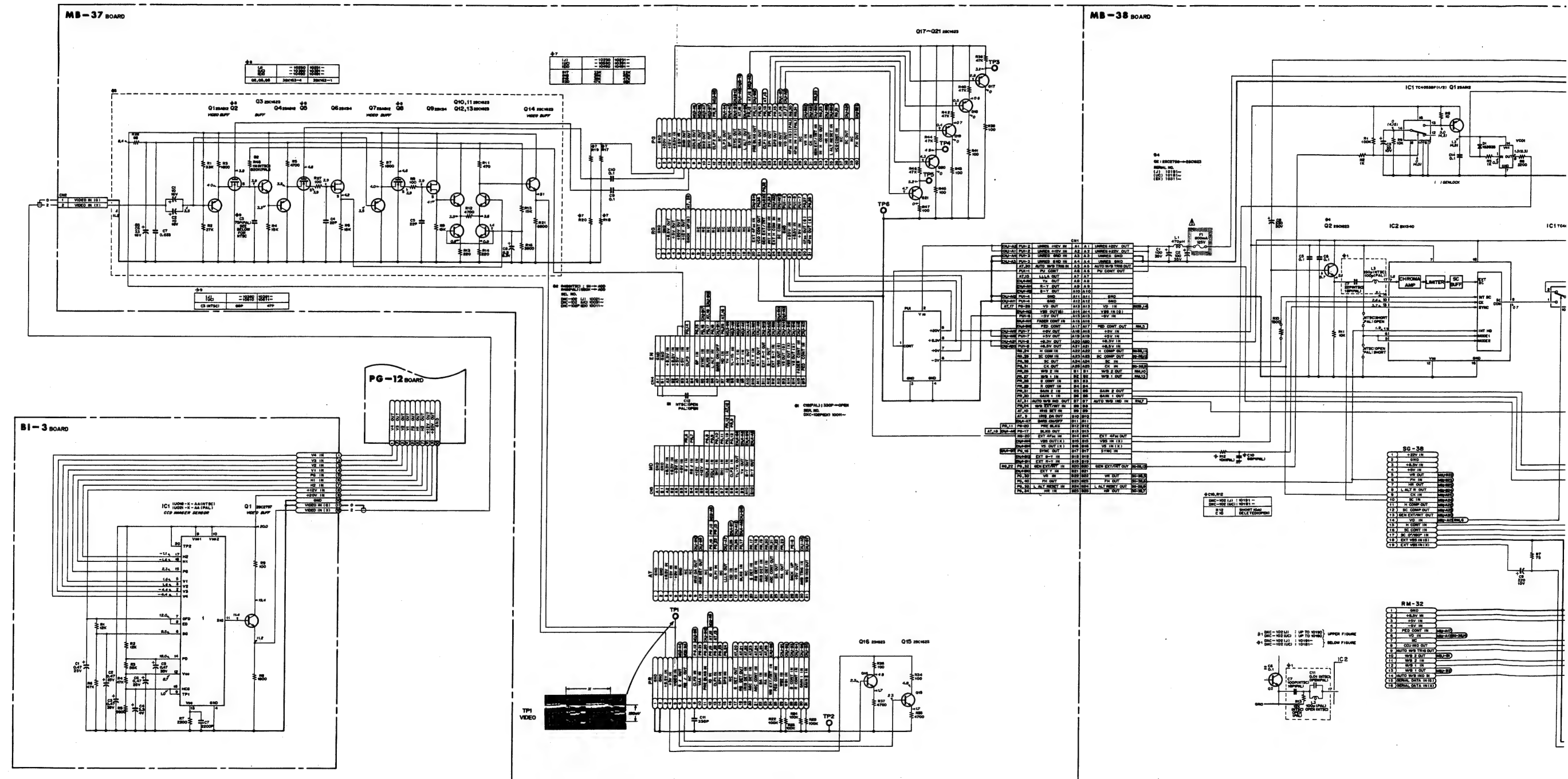
MB-38 BOARD

BI-3 BOARD

SG-110 BOARD

SW-34 BOARD

LE-47 BOARD



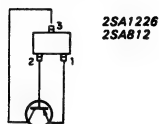
SECTION 7

SEMICONDUCTOR PIN ASSIGNMENTS

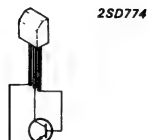
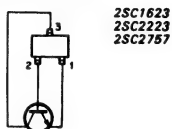
NOTE: The circuit diagram of IC is obtained from the IC data book published by the manufacturer.

7-1. TRANSISTOR

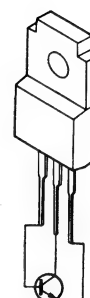
TOP VIEW (SCALE 4/1)



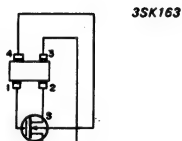
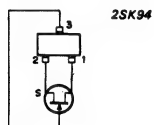
TOP VIEW (SCALE 4/1)



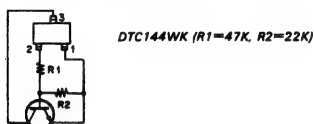
2SD1406



TOP VIEW (SCALE 4/1)

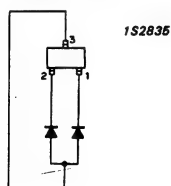


TOP VIEW (SCALE 4/1)

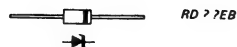
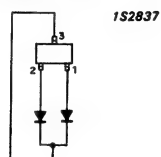


7-2. DIODE

TOP VIEW (SCALE 4/1)

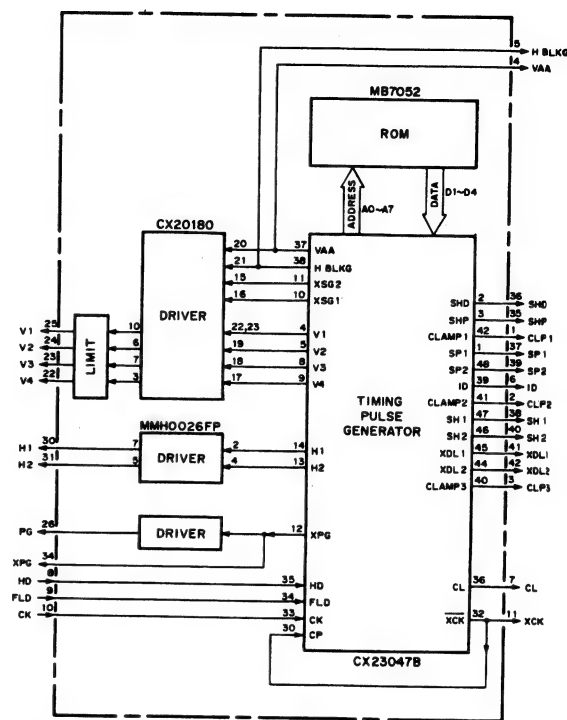
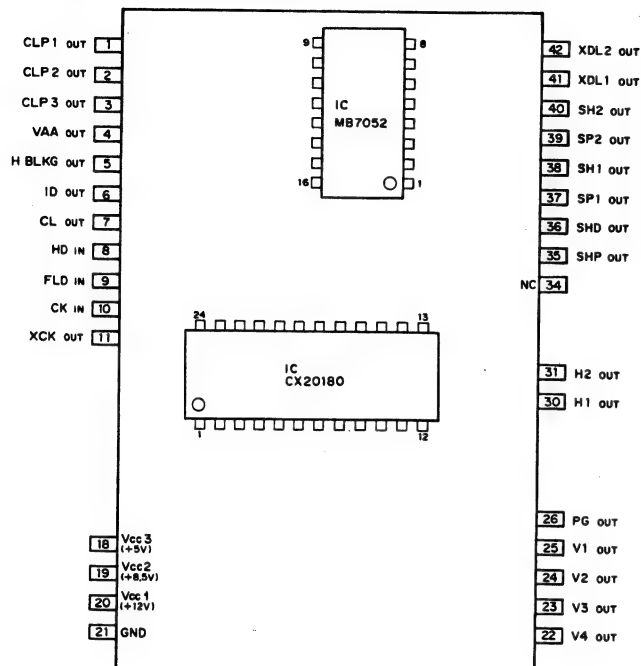


TOP VIEW (SCALE 4/1)

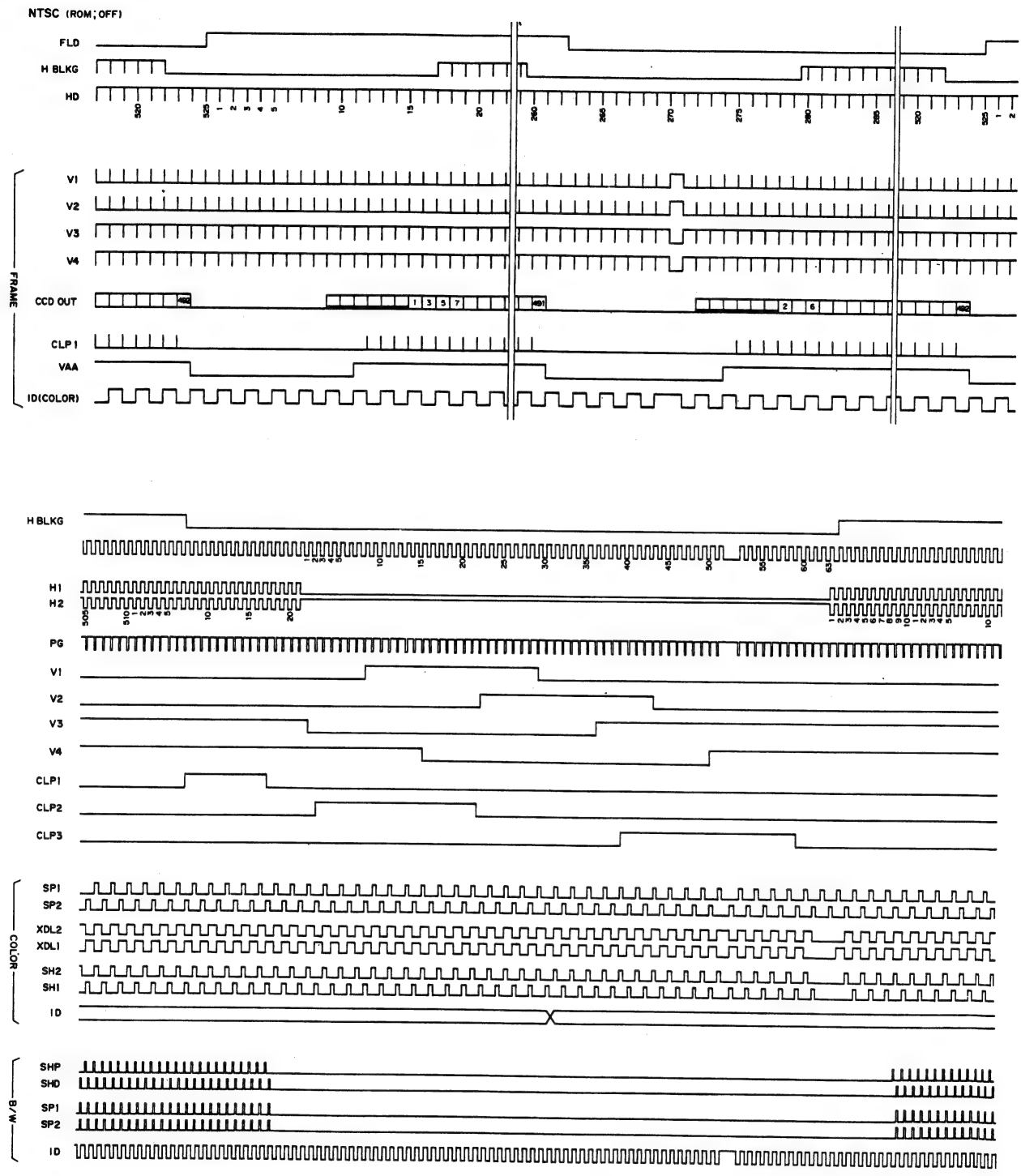


7-3. IC

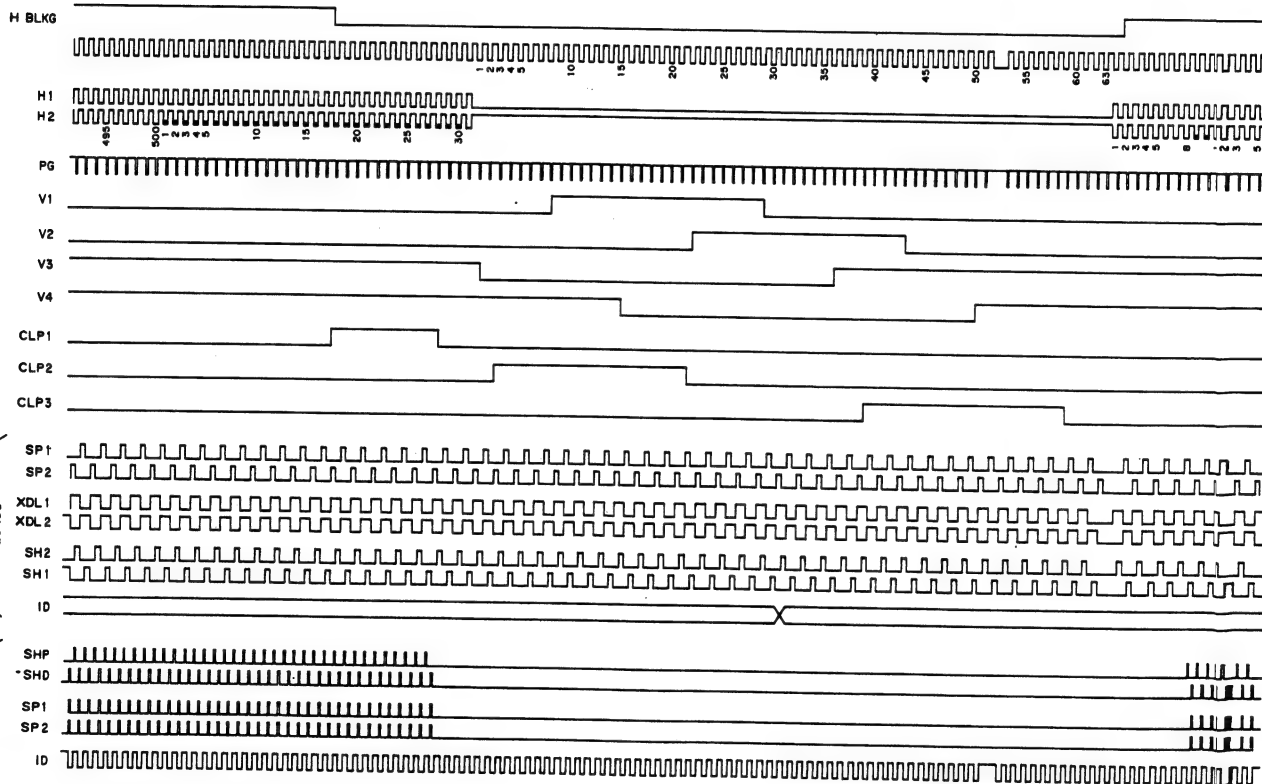
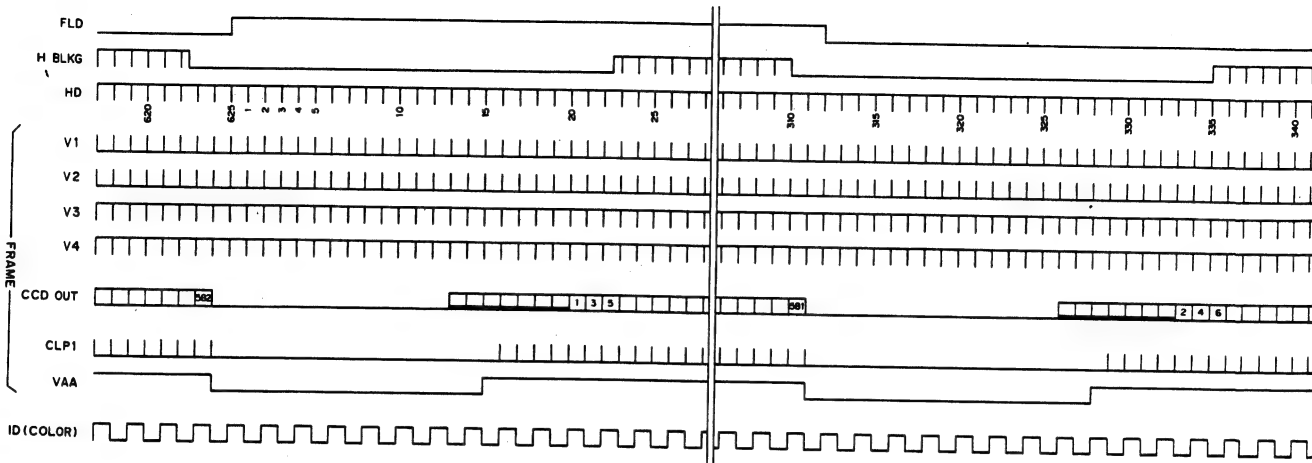
BH1203 (SONY)
C MOS-TIMING PULSE GENERATOR FOR CCD CAMERA
— TOP VIEW —



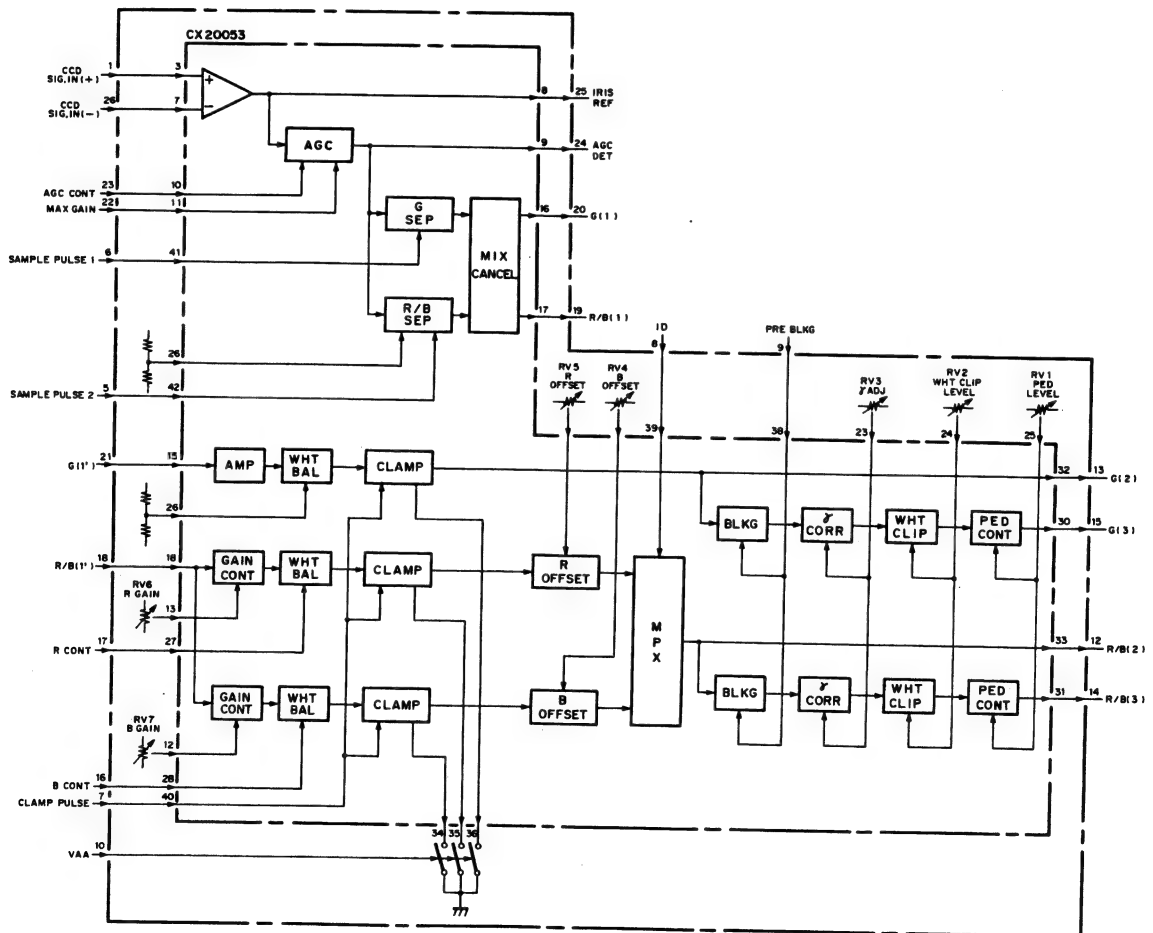
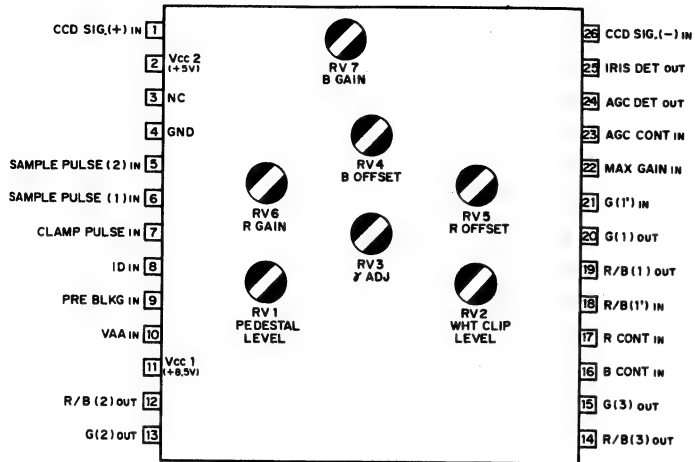
Note; 1. NTSC/PAL MODE IS SELECTED BY ROM DATA.
2. FREQUENCY OF CK, NTSC; 28.6364 MHz
PAL; 28.3750 MHz



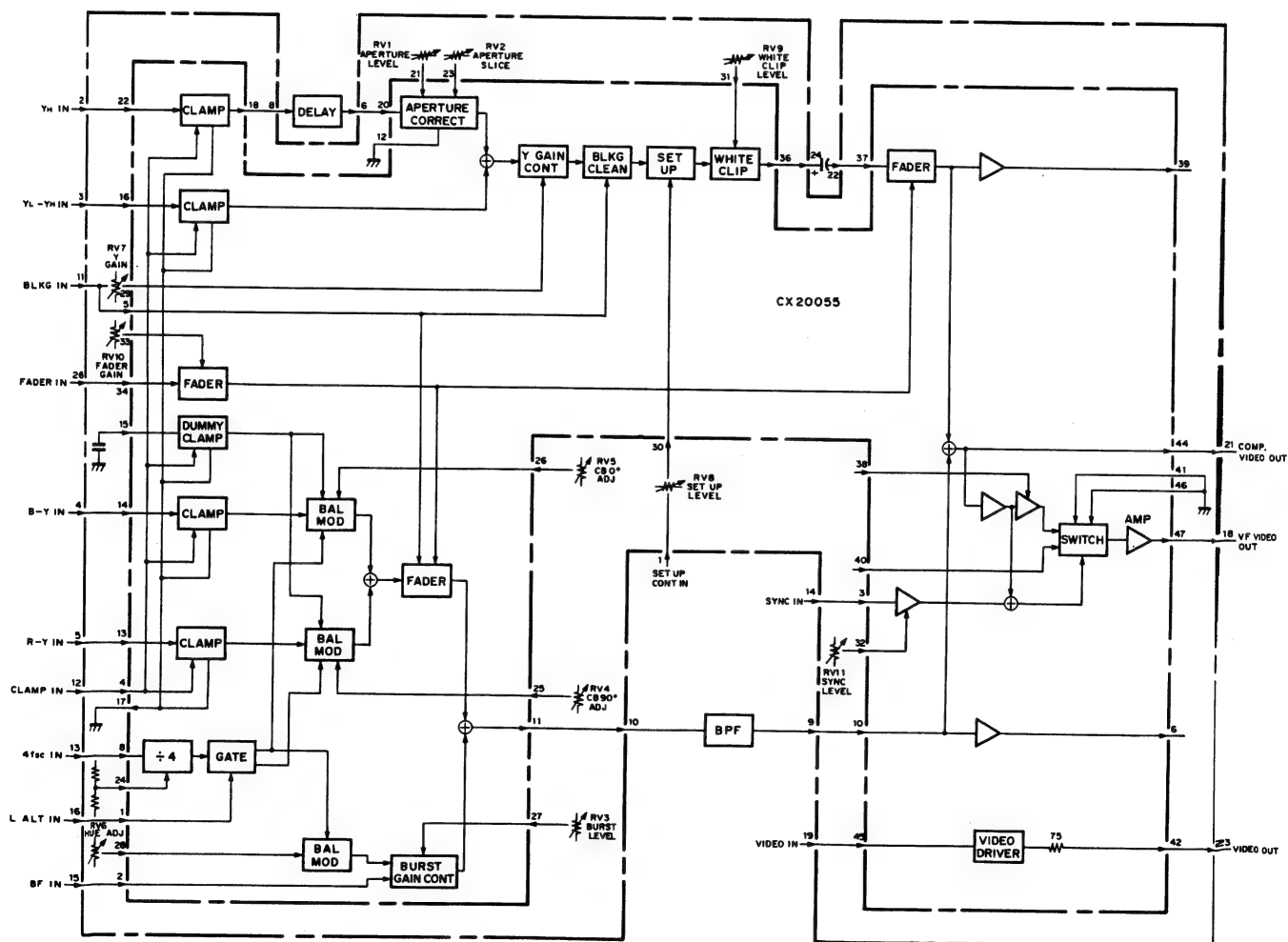
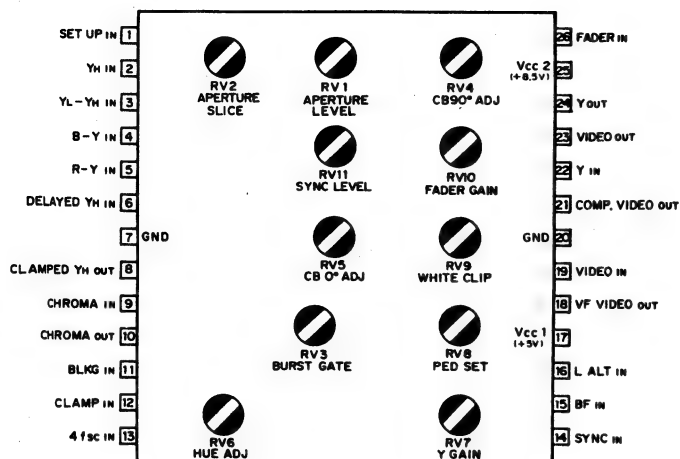
PAL (ROM; OFF)



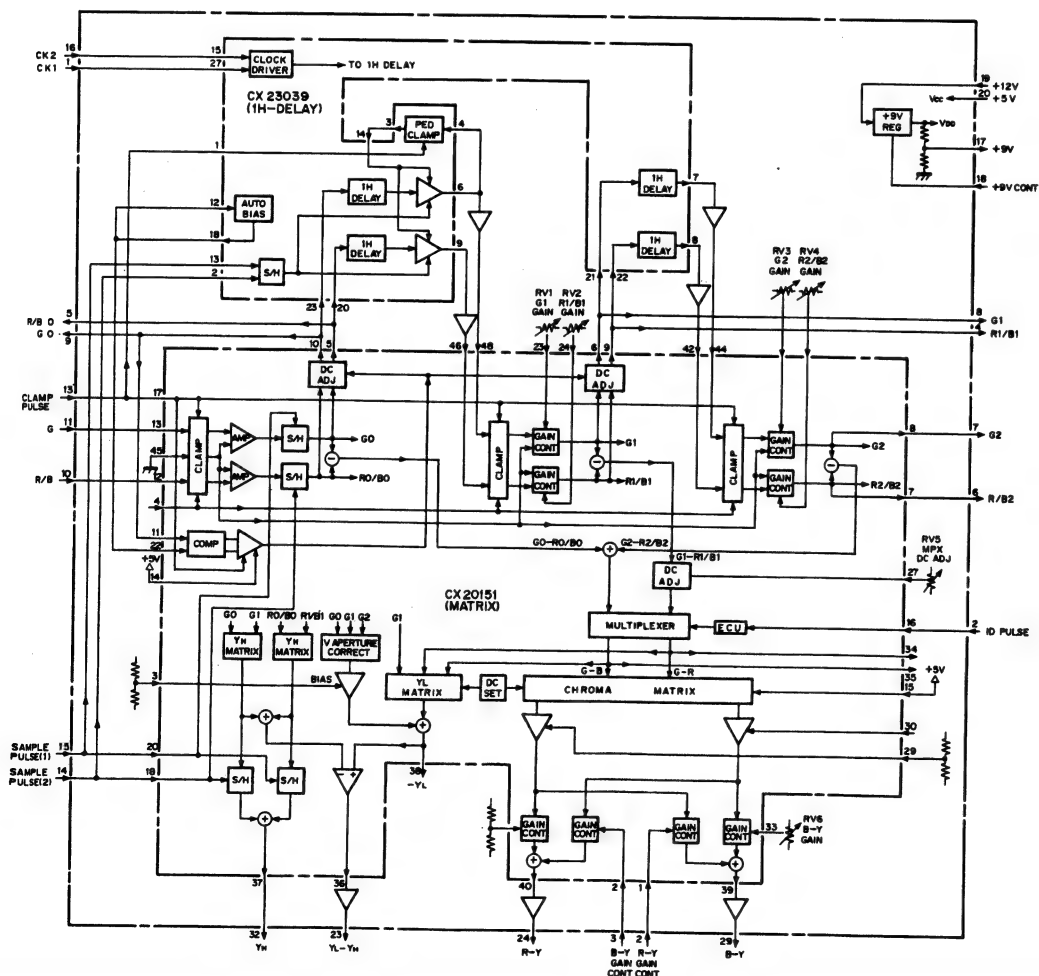
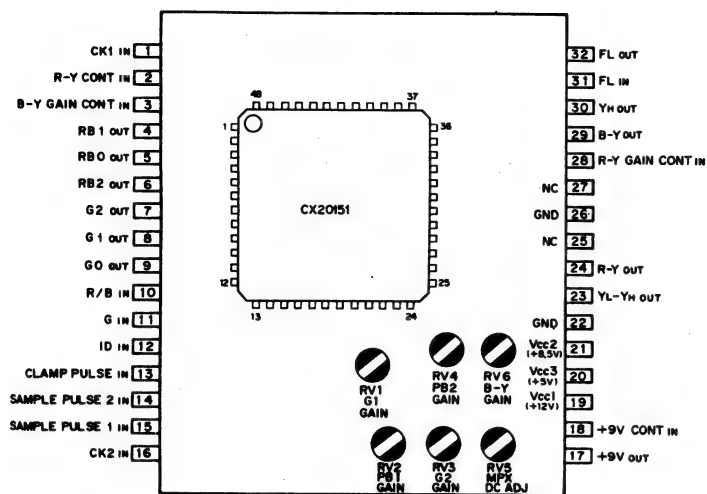
BH1204 (SONY)
VIDEO SIGNAL PROCESSOR FOR CCD COLOR CAMERA
— TOP VIEW —



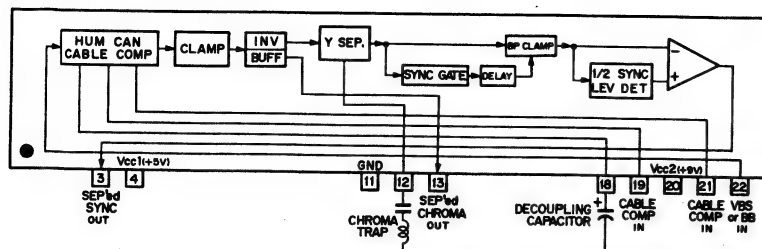
BH1205 (SONY)
ENCODER FOR COLOR CAMERA
— TOP VIEW —



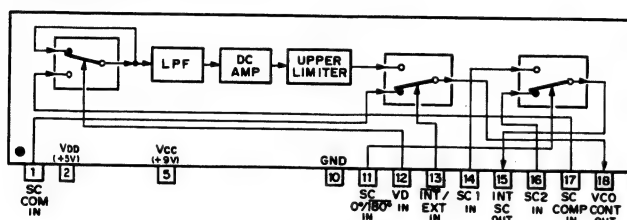
BH1206 (SONY)
YH/YL-YH/R-Y/B-Y GENERATOR FOR COLOR CAMERA
— TOP VIEW —



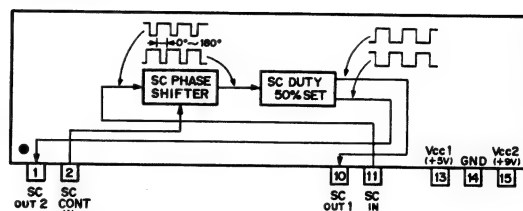
BX1337 (SONY)
SYNC SEPARATOR
 — REAR VIEW —



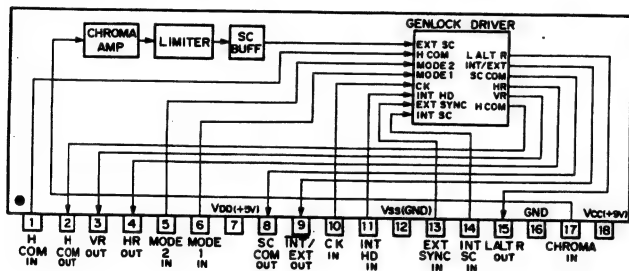
BX1338 (SONY)
APC AMPLIFIER AND SC 0°/180° SELECTOR
 — REAR VIEW —



BX1339 (SONY)
BX1339A (SONY)
SC PHASE SHIFTER
 — REAR VIEW —



BX1340 (SONY)
SC LIMITER AND GENLOCK DRIVER
 — REAR VIEW —

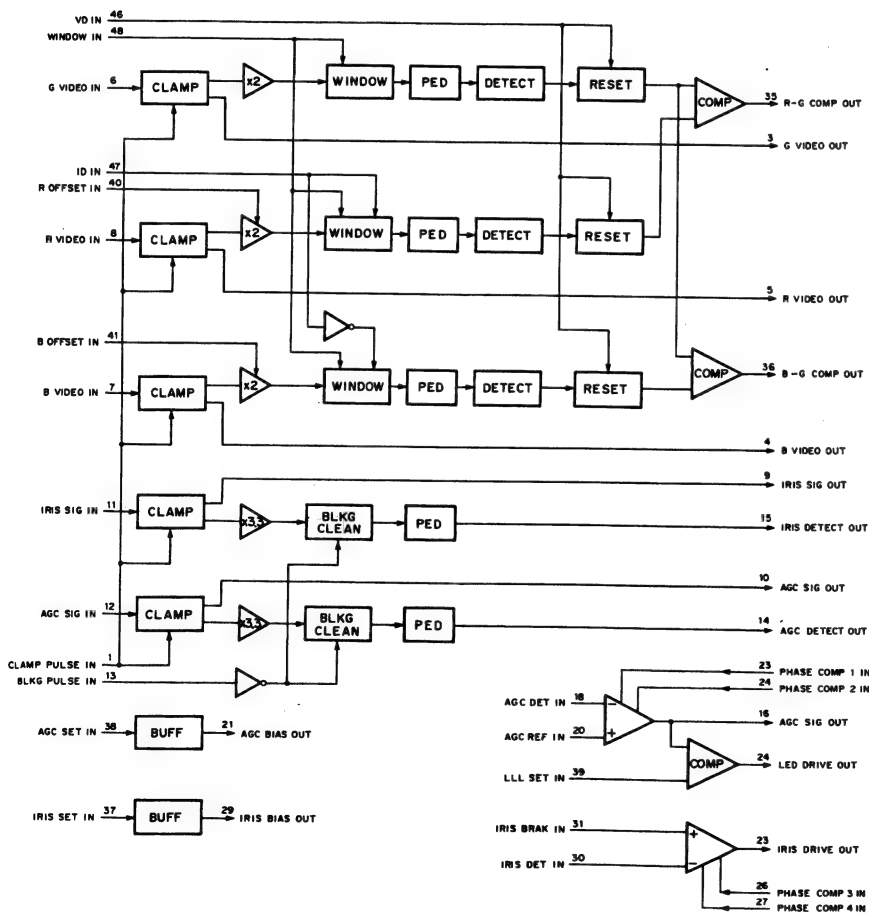
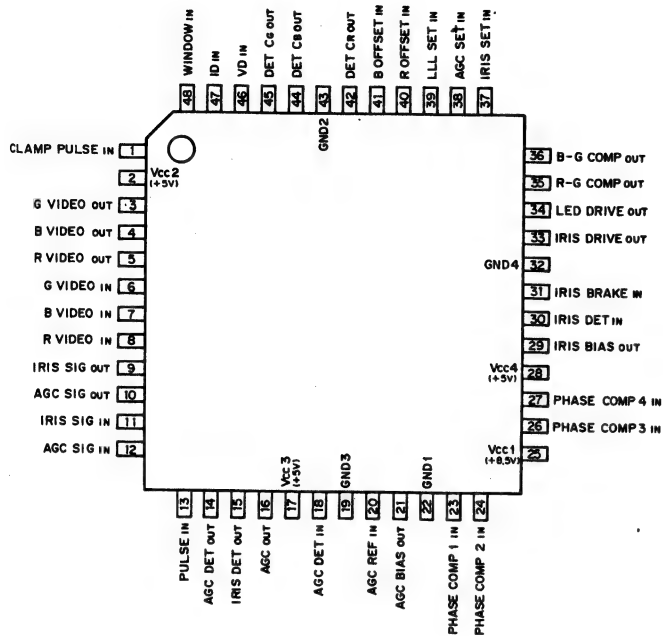


MODE SELECTION

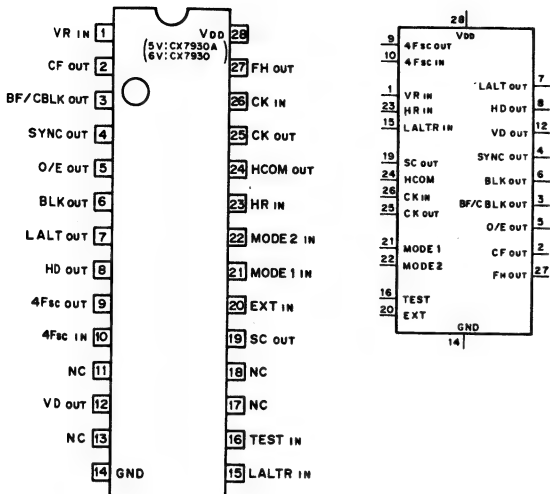
MODE 1	MODE 2	MODE
1	1	NTSC
0	0	PAL

0; LOW LEVEL
 1; HIGH LEVEL

CX20056 (SONY)
 AUTO IRIS, AUTO WHITE BALANCE AND AGC CONTROL FOR COLOR CAMERA
 — TOP VIEW —



CX7930-1 (SONY) FLAT PACKAGE
C-MOS SYNC GENERATOR (NTSC, PAL-M, PAL, SECAM)
— TOP VIEW —



O/E: ODD/EVEN FIELD
CF: COLOR FRAME PULSE
HCOM: H COMPARATOR

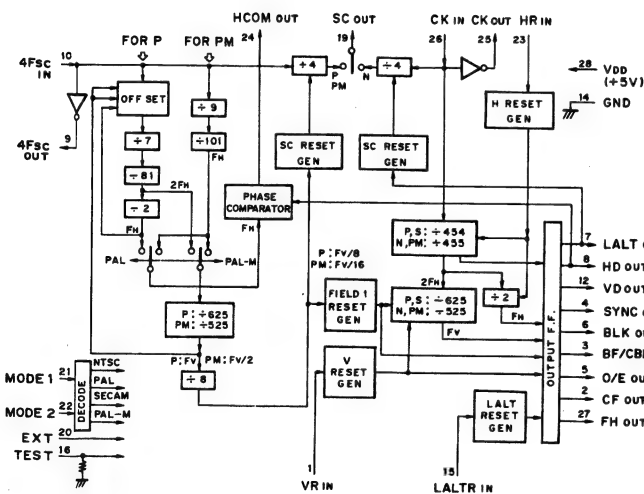
SYSTEM	4Fsc	CLOCK
NTSC	910 Fh	910 Fh
PAL	1135 Fh + 2Fv	908 Fh
PALM	909 Fh	910 Fh
SECAM		908 Fh

INPUTS	MODE1	MODE2	SYSTEM
0	0	0	NTSC
0	1	0	SECAM
1	0	1	PALM
1	1	1	PAL

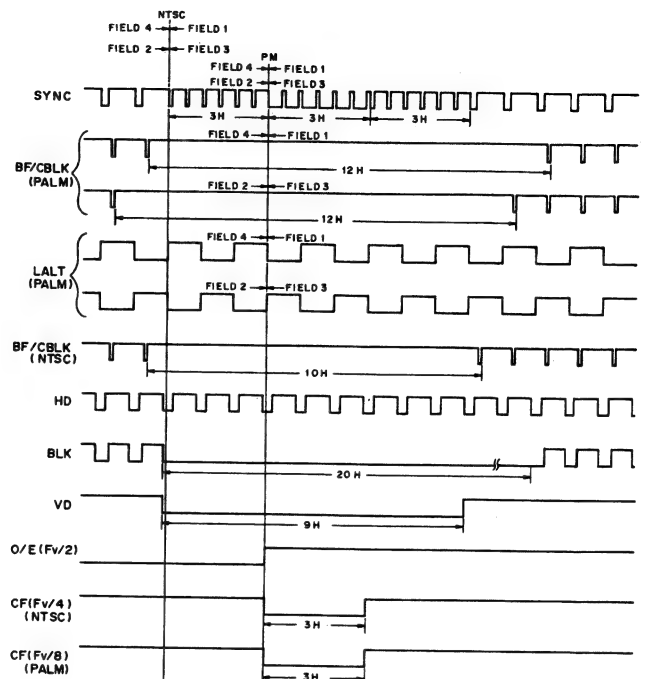
INPUTS	EXT	TEST	FUNCTION
0	0	0	INTERNAL
0	1	0	INVALID
1	0	1	EXT
1	1	1	TEST

0: LOW LEVEL (GND)
1: HIGH LEVEL (VDD)

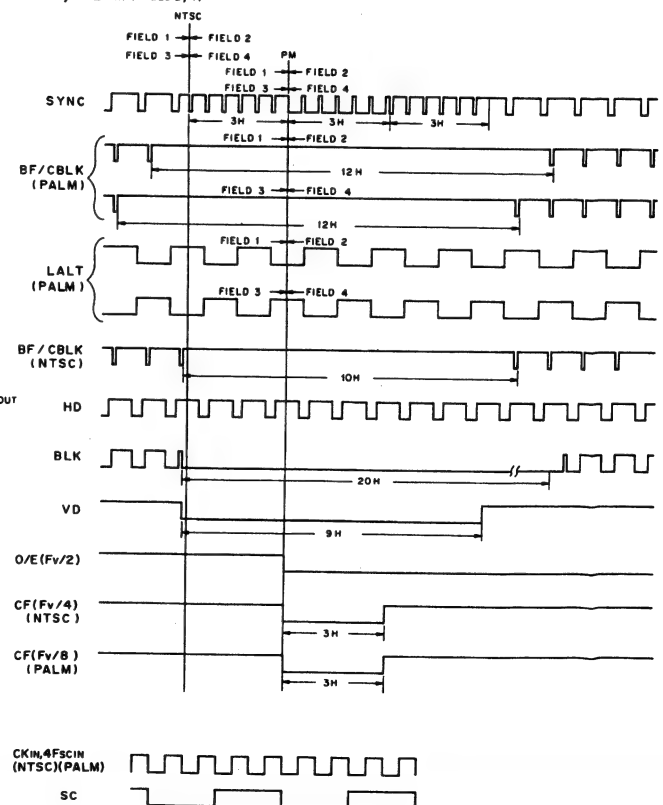
TEST '0': OPEN
(INTERNALLY PULLED DOWN)



NTSC, PAL-M (FIELD 1,3)



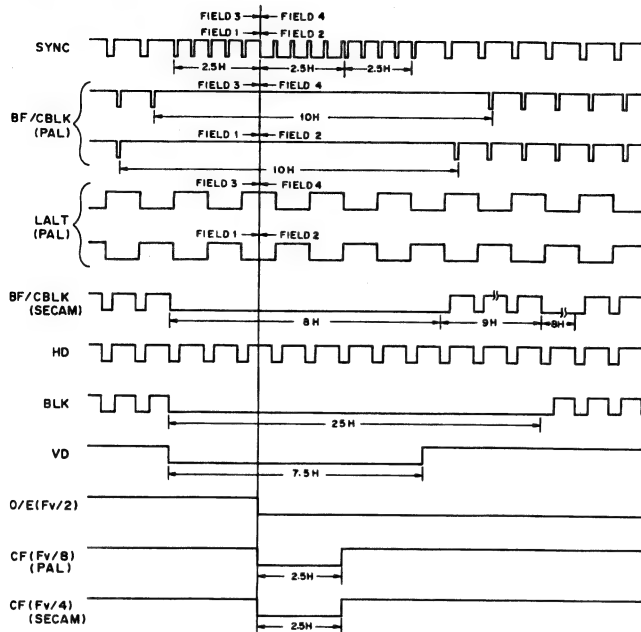
NTSC, PAL-M (FIELD 2,4)



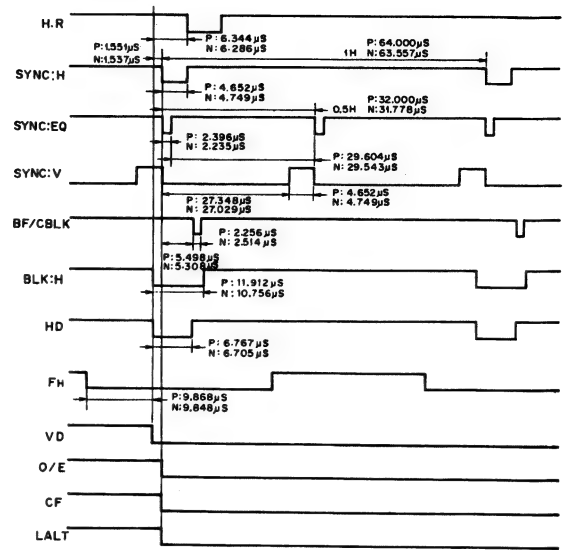
CKIN, 4FSCIN (NTSC)(PALM)

SC

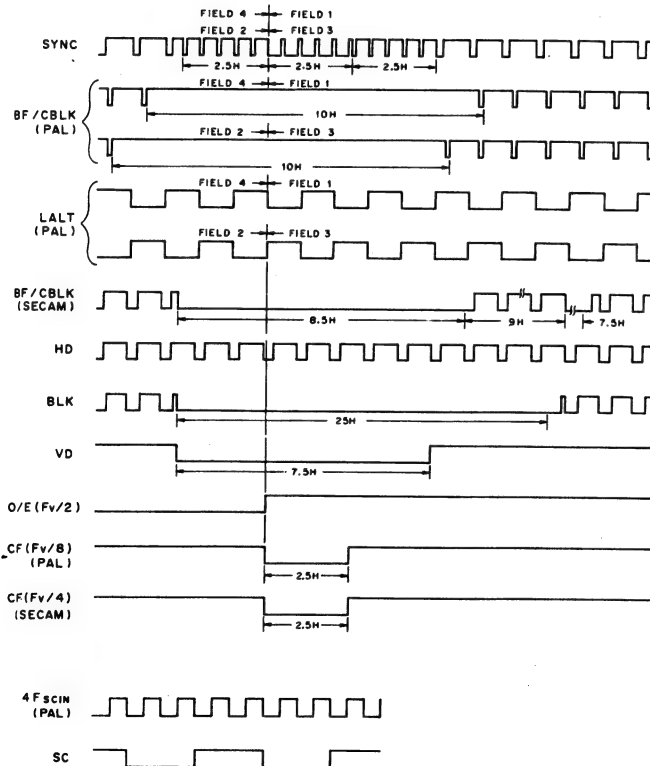
PAL, SECAM (FIELD 4,2)



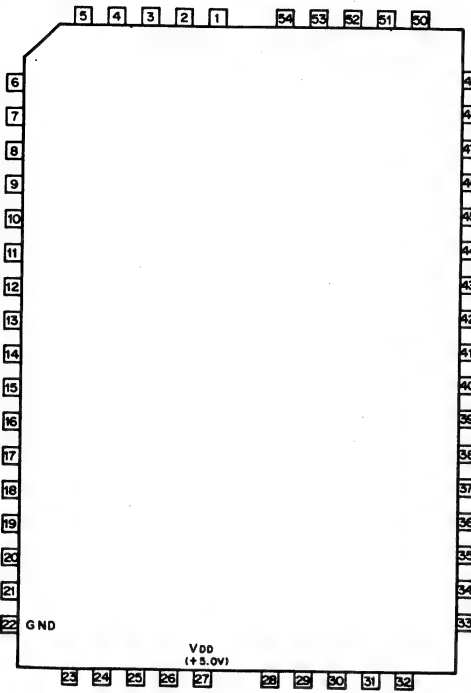
P: PAL, SECAM
N: NTSC, PALM



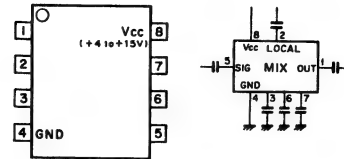
PAL, SECAM (FIELD 1,3)



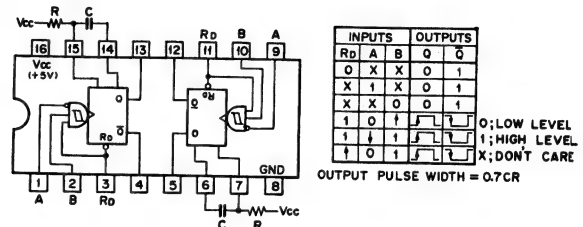
HD44820A89 (HITACHI) FLAT PACKAGE
C-MOS 4-BIT MICROPROCESSOR
— TOP VIEW —



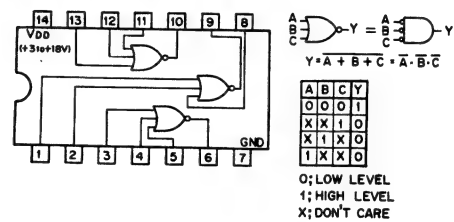
SN16913P (TI)
BALANCED MIXER
— TOP VIEW —



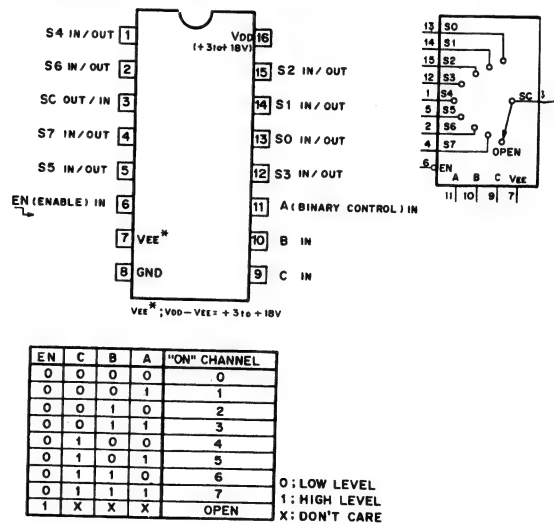
SN74LS221NS (TI) FLAT PACKAGE
TTL MONOSTABLE MULTIVIBRATOR WITH SCHMITT TRIGGER INPUT
— TOP VIEW —



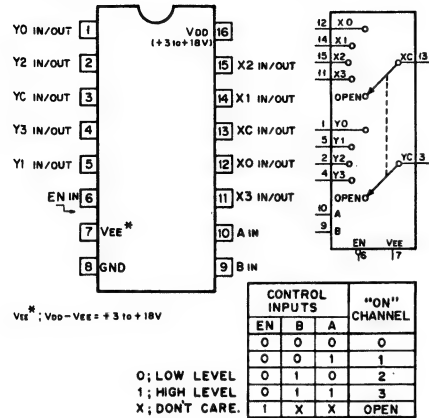
TC4025BF (TOSHIBA) FLAT PACKAGE
C-MOS 3-INPUT NOR GATE
— TOP VIEW —



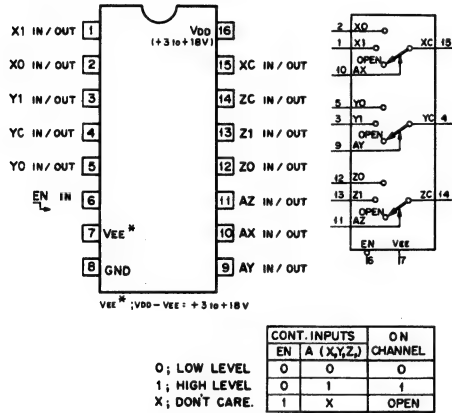
TC4051BF (TOSHIBA) FLAT PACKAGE
C-MOS 8-CHANNEL MULTIPLEXER/DEMULTIPLEXER
— TOP VIEW —



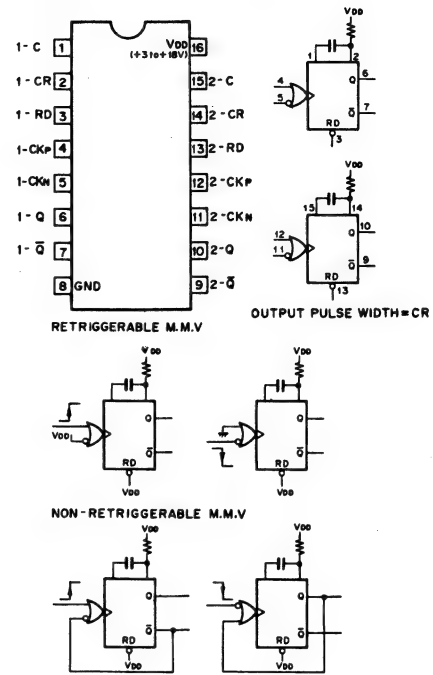
TC4052BF (TOSHIBA) FLAT PACKAGE
C-MOS 4-CHANNEL MULTIPLEXER/DEMULTIPLEXER
— TOP VIEW —



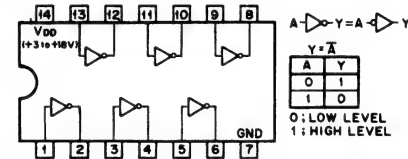
TC4053BF (TOSHIBA) FLAT PACKAGE
C-MOS 2-CHANNEL MULTIPLEXER/DEMULTIPLEXER
— TOP VIEW —



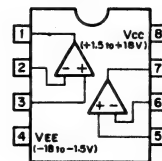
TC4538BF (TOSHIBA) FLAT PACKAGE
C-MOS DUAL RETRIGGERABLE/NON-RETRIGGERABLE
MONOSTABLE MULTIVIBRATOR
— TOP VIEW —



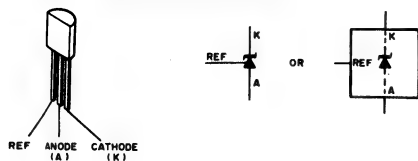
TC4069UBF (TOSHIBA) FLAT PACKAGE
C-MOS INVERTER
— TOP VIEW —



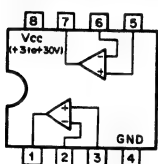
TL062CPS (TI) FLAT PACKAGE
OPERATIONAL AMPLIFIER
(JFET INPUT)
— TOP VIEW —



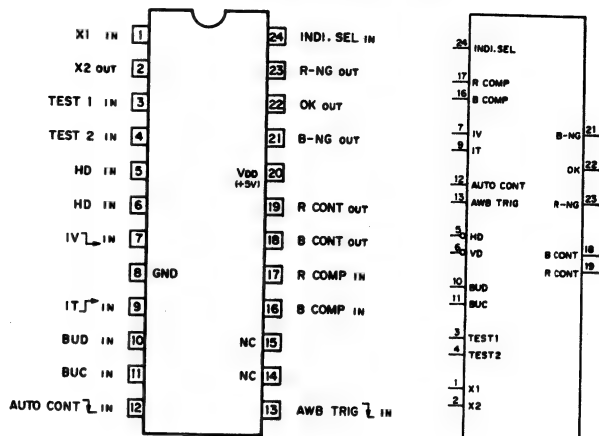
TL431CLP (TI)
TL431CLPB (TI)
ADJUSTABLE PRECISION SHUNT REGULATOR



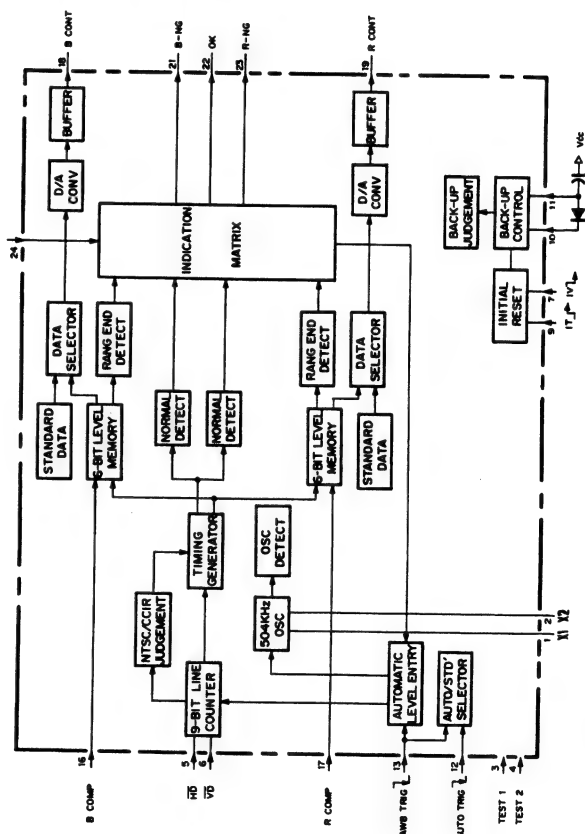
uPC358G2 (NEC) FLAT PACKAGE
DUAL OPERATIONAL AMPLIFIERS
— TOP VIEW —



uPD6107G (NEC)
C-MOS AUTOMATIC WHITE BALANCE CONTROLLER FOR COLOR CAMERA
— TOP VIEW —




IV : INITIAL RESET VOLTAGE
IT : INITIAL RESET TIME CONSTANT
BUD : BACK-UP DIODE
BUC : BACK-UP CAPACITOR



SECTION 8 SPARE PARTS

8-1. PARTS INFORMATION

1. Safety Related Component Warning

Components identified by shading marked with  on the schematic diagrams, exploded views and electrical spare parts list are critical to safe operation. Replace these components with Sony parts whose parts numbers appear as shown in this manual or in service bulletins and service manual supplements published by Sony.

2. Replacement Parts supplied from Sony Parts Center will sometimes have different shape and outside view from the parts which actually in use. This is due to "accommodating the improved parts and/or engineering changes" or "standardization of genuine parts."

- This manual's exploded views and electrical spare parts lists are indicating the parts numbers of "the standardized genuine parts at present".
- Regarding engineering parts changes in our engineering department, refer Sony service bulletins and service manual supplements.

3. Printed Components in Bold-Face type on the exploded views and electrical spare parts list are normally stocked for replacement purposes. The remaining parts are not normally required for routine service work. Orders for parts not shown in Bold-Face type will be processed, but allow for additional delivery time.

4. Item with no part number and/or no description are not stocked because they are seldom required for routine service.

5. Abbreviation

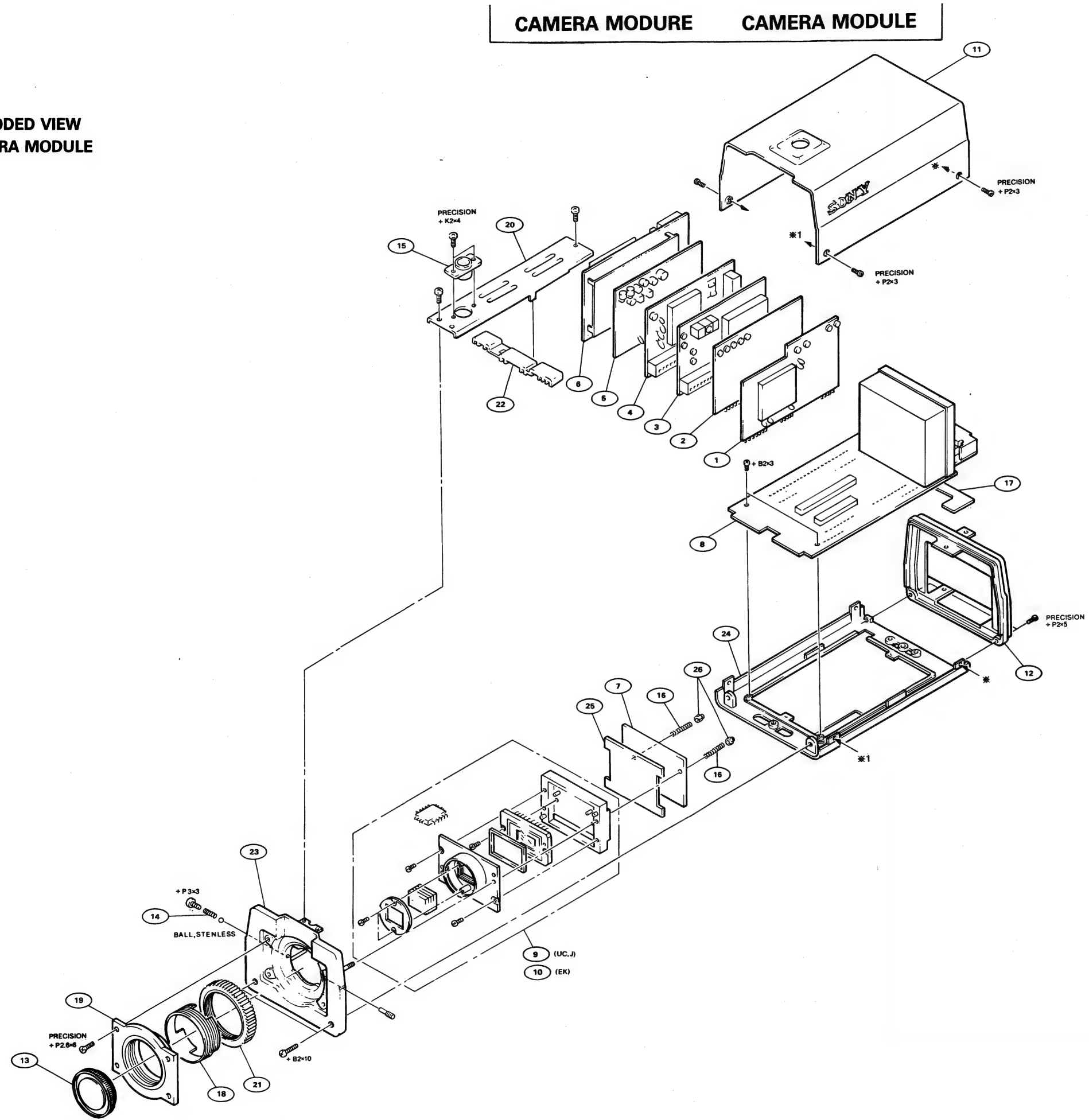
REF. NO.	DESCRIPTION	REF. NO.	DESCRIPTION	REF. NO.	DESCRIPTION
C	CAPACITOR	F	FUSE	Q	TRANSISTOR
CN	CONNECTOR	FL	FILTER	R	RESISTOR
D	DIODE	IC	IC	RV	VARIABLE RESISTOR
DL	DELAY LINE	L	INDUCTOR	S	SWITCH
				X	OSCILLATOR

All capacitors are in micro farads unless otherwise specified.

All inductors are in micro henries unless otherwise specified.

All resistors are in ohms.

8-2. EXPLODED VIEW
CAMERA MODULE



DXC-101/102/101P/102P (UC, EK)

8-3

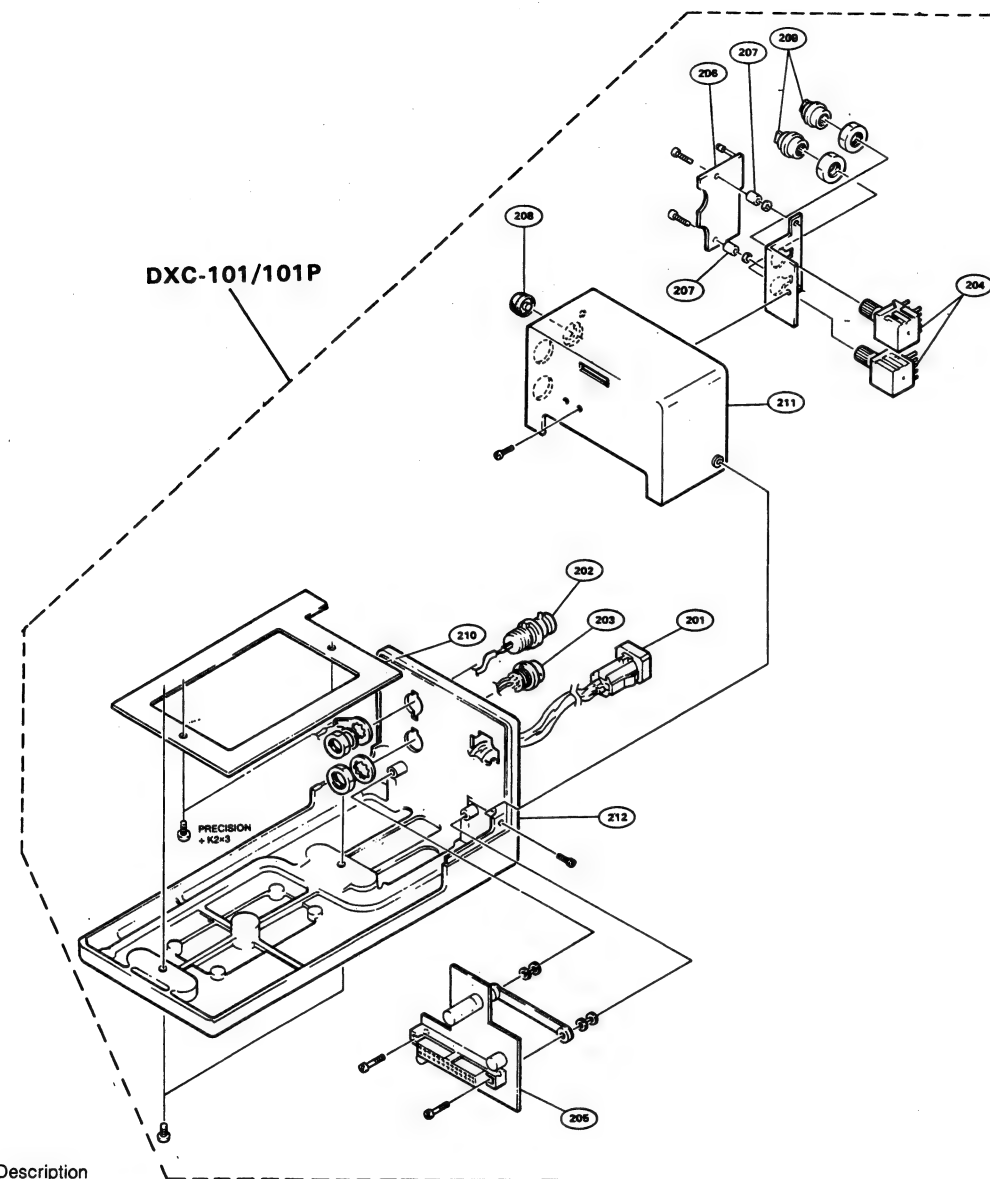
CAMERA MODURE

CAMERA MODULE

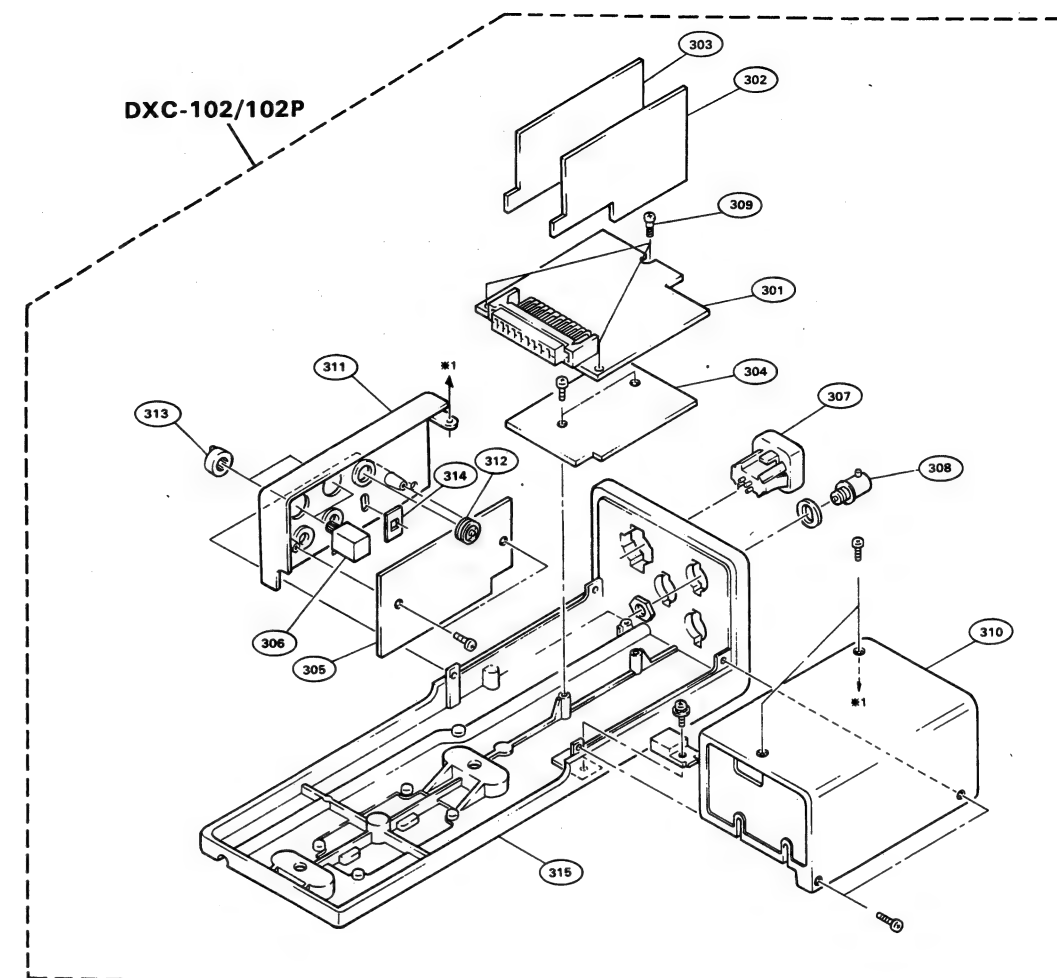
No.	Parts No.	Description
1	A-7513-323-A	MOUNTED CIRCUIT BORAD "RP-72"
2	A-7513-324-A	MOUNTED CIRCUIT BORAD "AT-40"
3	A-7513-325-A	MOUNTED CIRCUIT BORAD "MD-30" (UC, J)
	A-7513-326-A	MOUNTED CIRCUIT BORAD "MD-30" (EK)
4	A-7513-327-A	MOUNTED CIRCUIT BORAD "EN-40" (UC, J)
	A-7513-328-A	MOUNTED CIRCUIT BORAD "EN-40" (EK)
5	A-7513-329-A	MOUNTED CIRCUIT BORAD "RG-13" (UC, J)
	A-7513-330-A	MOUNTED CIRCUIT BORAD "RG-13" (EK)
6	A-7513-331-A	MOUNTED CIRCUIT BORAD "PG-12" (UC, J)
	A-7513-332-A	MOUNTED CIRCUIT BORAD "PG-12" (EK)
7	A-7520-231-A	MOUNTED CIRCUIT BORAD "BI-3"
8	A-7520-233-A	MOUNTED CIRCUIT BORAD "MB-37" (UC, J)
	A-7520-234-A	MOUNTED CIRCUIT BORAD "MB-37" (EK)
9	A-7560-026-A	CCD BLOCK ASSY (UC, J)
10	A-7560-027-A	CCD BLOCK ASSY (EK)
11	X-3698-801-1	COVER ASSY
12	X-3698-802-1	PANEL ASSY, REAR
13	2-042-385-00	CAP, C MOUNT
14	3-563-463-00	SPRING, COMPRESSION
15	3-670-518-01	SCREW, TRIPOD
16	3-698-802-01	SPRING, COMPRESSION
17	3-698-805-02	SHEET, INSULATING, MB
18	3-698-810-01	RING, SLIDE
19	3-698-811-01	MOUNT, LENS
20	3-698-813-02	SPAN
21	3-698-814-01	RING, ADJUSTMENT
22	3-698-819-01	HOLDER, PC BOARD
23	3-698-840-01	PANEL, FRONT
24	3-698-842-01	CHASSIS
25	3-698-806-02	SHEET, INSULATING, CCD HOLDER
26	3-698-829-01	NUT

8-4

ADAPTOR ASSY



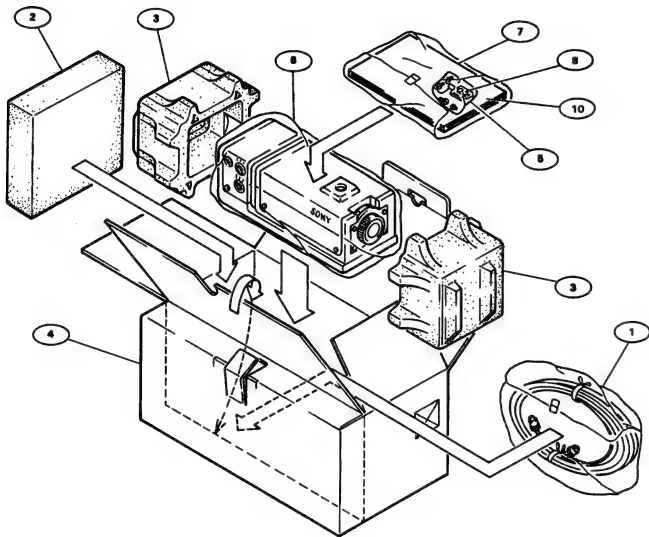
No.	Parts No.	Description
201	1-563-113-11	RECEPTACLE, LENS
202	1-561-781-21	RECEPTACLE, BNC
203	1-562-381-00	RECEPTACLE, 12P
204	1-570-505-11	ROTARY, SWITCH
205	1-617-217-11	PRINTED CIRCUIT BOARD "CN-39"
206	1-617-218-11	PRINTED CIRCUIT BOARD "SW-33"
207	3-569-418-01	GUAIDE, BOTTON
208	3-676-244-01	COVER, SWITCH
209	3-698-809-01	KNOB
210	3-698-834-01	PLATE, CHASSIS
211	3-698-837-01	COVER(A), ADAPTOR
212	3-698-843-02	ADAPTOR (A)



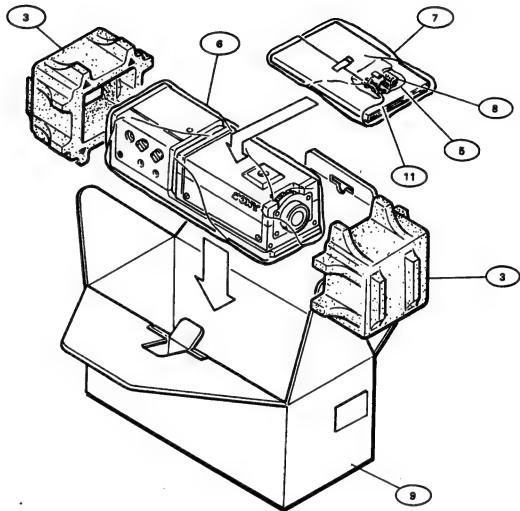
No.	Part No.	Description
301	A-7513-329-A	MOUNTED CIRCUIT BORAD "MB-38" (UC)
	A-7513-350-A	MOUNTED CIRCUIT BOARD "MB-38" (EK)
302	A-7513-351-A	MOUNTED CIRCUIT BORAD "RM-32"
303	A-7513-352-A	MOUNTED CIRCUIT BORAD "SG-38" (UC)
	A-7513-353-A	MOUNTED CIRCUIT BOARD "SG-38" (EK)
304	A-7513-354-A	MOUNTED CIRCUIT BORAD "SG-110"
305	A-7513-355-A	MOUNTED CIRCUIT BORAD "SW-34"
306	1-570-505-11	ROTARY, SWITCH
307	1-563-113-11	CONNECTOR, LENS
308	1-561-781-11	BNC, CONNECTOR
309	3-312-161-00	SCREW, STEP, PRECISION
310	3-698-863-01	COVER,ADAPTOR(R)
311	3-698-864-02	COVER,ADAPTOR(L)
312	3-676-244-01	COVER, SW
313	3-689-809-01	KNOB
314	3-680-604-11	PLATE, BLIND
315	3-698-865-01	ADAPTOR (B)

8-3. PACKING MATERIAL AND ACCESSORIES

DXC-101/101P



DXC-102/102P



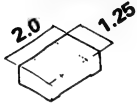
No.	Parts No.	Description
1	1-557-668-12	CABLE, DC 4P
	1-560-246-11	RECEPTACLE 4P
	1-562-356-00	RECEPTACLE 12P
2	3-698-847-01	SPACER (DXC-101/P)
3	3-698-850-01	CUSHION
4	3-698-851-01	CARTON INDIVIDUAL (UC)
	3-698-851-11	CARTON INDIVIDUAL (EK)
5	3-701-613-00	BAG, POLYETHYLENE (STOPPER, SCREW)
6	3-701-626-00	BAG, POLYETHYLENE (DXC-101/P)
	3-701-631-01	BAG, POLYETHYLENE (DXC-102/P)
7	3-701-626-00	BAG, POLYETHYLENE (PRINTED MATTER)
8	3-698-830-01	STOPER
	7-621-772-00	SCREW + B2 x 3
9	3-698-854-01	CARTON INDIVIDUAL (UC)
	3-698-854-11	CARTON INDIVIDUAL (EK)
10	3-760-863-11	MANUAL, INSTRUCTION (DXC-101/P)
	3-760-863-31	MANUAL, INSTRUCTION (DXC-101/P)
	3-760-863-41	MANUAL, INSTRUCTION (EK) (DXC-101/P)
11	3-760-924-11	MANUAL, INSTRUCTION (DXC-102/P)
	3-760-924-31	MANUAL, INSTRUCTION (DXC-102/P)
	3-760-924-41	MANUAL, INSTRUCTION (DXC-102/P)

8-4. ELECTRICAL PARTS LIST

RESISTOR

Parts that are not listed in the "reference numbers order list" are shown in following table.
Reference numbers are omitted.

CHIP RESISTOR



±5% 1/10W
0Ω through 3.3MΩ

Parts No. 1-216-□□□-00

Value	Parts No. - □□□ -	Value	Parts No. - □□□ -	Value	Parts No. - □□□ -	Value	Parts No. - □□□ -	Value	Parts No. - □□□ -
0Ω	295	30	012	910	048	30	084	910	120
1Ω	—	33Ω	013	1kΩ	049	33kΩ	085	1MΩ	121
1.1	—	36	014	1.1	050	36	086	1.1	122
1.2	—	39	015	1.2	051	39	087	1.2	123
1.3	—	43	016	1.3	052	43	088	1.3	124
1.5	—	47	017	1.5	053	47	089	1.5	125
1.6	—	51	018	1.6	054	51	090	1.6	126
1.8	—	56	019	1.8	055	56	091	1.8	127
2	—	62	020	2	056	62	092	2	128
2.2	298	68	021	2.2	057	68	093	2.2	129
2.4	301	75	022	2.4	058	75	094	2.4	130
2.7	302	82	023	2.7	059	82	095	2.7	131
3	303	91	024	3	060	91	096	3	132
3.3	304	100Ω	025	3.3	061	100kΩ	097	3.3	133
3.6	305	110	026	3.6	062	110	098		
3.9	306	120	027	3.9	063	120	099		
4.3	307	130	028	4.3	064	130	100		
4.7	308	150	029	4.7	065	150	101		
5.1	297	160	030	5.1	066	160	102		
5.6	309	180	031	5.6	067	180	103		
6.2	310	200	032	6.2	068	200	104		
6.8	311	220	033	6.8	069	220	105		
7.5	312	240	034	7.5	070	240kΩ	106		
8.2	313	270	035	8.2	071	270	107		
9.1	314	300	036	9.1	072	300	108		
10Ω	001	330	037	10kΩ	073	330	109		
11	002	360	038	11	074	360	110		
12	003	390	039	12	075	390	111		
13	004	430	040	13	076	430	112		
15	005	470	041	15	077	470	113		
16	006	510	042	16	078	510	114		
18	007	560	043	18	079	560	115		
20	008	620	044	20	080	620	116		
22	009	680	045	22	081	680	117		
24	010	750	046	24	082	750	118		
27	011	820	047	27	083	820	119		

Ref. No.	Part No.	Description
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AT-40 BOARD

A-7513-324-A	MOUNTED CIRCUIT BOARD	"AT-40"
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C1	1-135-091-00	TANTALUM CHIP 1 10% 16V
C2	1-135-096-21	TANTALUM CHIP 4.7 10% 10V
C4	1-135-095-21	TANTALUM CHIP 1.5 10% 10V
C5	1-135-097-00	TANTALUM CHIP 15 10% 10V
C6	1-135-072-21	TANTALUM CHIP 0.22 10% 35V
C7	1-135-096-21	TANTALUM CHIP 4.7 10% 10V
C8	1-163-038-00	CERAMIC CHIP 0.1 25V
C9	1-135-096-21	TANTALUM CHIP 4.7 10% 10V
C10	1-163-038-00	CERAMIC CHIP 0.1 25V
C11	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C12	1-163-038-00	CERAMIC CHIP 0.1 25V
C13	1-163-038-00	CERAMIC CHIP 0.1 25V
C14	1-163-038-00	CERAMIC CHIP 0.1 25V
C15	1-163-038-00	CERAMIC CHIP 0.1 25V
C16	1-163-038-00	CERAMIC CHIP 0.1 25V
C17	1-135-096-21	TANTALUM CHIP 4.7 10% 10V
C18	1-135-093-21	TANTALUM CHIP 10 20% 16V
C19	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C20	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C21	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C22	1-163-038-00	CERAMIC CHIP 0.1 25V
C23	1-163-251-00	CERAMIC CHIP 100PF 5% 50V
C24	1-163-038-00	CERAMIC CHIP 0.1 25V
C27	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C28	1-135-070-00	TANTALUM CHIP 0.1 20% 35V

D3	8-719-100-03	1S2835
D4	8-719-100-05	1S2837

IC1	8-759-908-12	CX20056: SONY
IC2	8-759-103-03	μPD6107G: NEC

Ref. No.	Part No.	Description
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Q1	8-729-901-04	DTA114EK
Q2	8-729-100-66	2SC1623
Q6	8-729-100-76	2SA812
Q7	8-729-100-76	2SA812
Q8	8-729-100-66	2SC1623

Q9	8-729-100-76	2SA812
Q10	8-729-100-76	2SA812
Q11	8-729-100-76	2SA812
Q12	8-729-100-66	2SC1623
Q13	8-729-100-66	2SC1623

Q15	8-729-900-00	DTA144WK
Q16	8-729-901-03	DTC144WK

R58	1-249-437-11	CARBON 47K 5% 1/6W
(UC: DXC-101 S/N Up to 10220 DXC-102 S/N Up to 10180 EK: DXC-101P S/N Up to 10260 DXC-102P S/N Up to 10310)		
1-216-089-00 CHIP 47K 5% 1/10W		
(UC: DXC-101 S/N 10221 AND HIGHER DXC-102 S/N 10181 AND HIGHER EK: DXC-101P S/N 10261 AND HIGHER DXC-102P S/N 10311 AND HIGHER)		

RV1	1-230-871-21	METAL 22K
RV2	1-230-870-21	METAL 10K
RV3	1-230-870-21	METAL 10K
RV4	1-230-868-21	METAL 2.2K
RV5	1-230-870-21	METAL 10K

Ref. No. Part No. Description

BI-3 BOARD

A-7520-231-A MOUNTED CIRCUIT BOARD "BI-3"

C1	1-135-083-00	TANTALUM CHIP 0.47 10% 25V
C2	1-135-083-00	TANTALUM CHIP 0.47 10% 25V
C3	1-135-074-21	TANTALUM CHIP 0.47 10% 35V
C4	1-135-103-00	TANTALUM CHIP 3.3 10% 4V
C5	1-135-074-21	TANTALUM CHIP 0.47 10% 35V
C6	1-135-083-00	TANTALUM CHIP 0.47 10% 25V
C7	1-163-013-00	CERAMIC CHIP 0.0022 10% 50V

Q1 8-729-175-73 2SC2757

Ref. No. Part No. Description

EN-40 BOARD

A-7513-327-A MOUNTED CIRCUIT BOARD
"EN-40" (UC,J)
A-7513-328-A MOUNTED CIRCUIT BOARD
"EN-40" (EK)

C1	1-131-380-00	TANTALUM 33 10% 10V
C2	1-131-374-00	TANTALUM 33 10% 16V
C3	1-124-225-00	ELECT 100 20% 6.3V
C4	1-163-038-00	CERAMIC CHIP 0.1 25V
C5	1-163-097-00	CERAMIC CHIP 15PF 5% 50V
C6	1-131-373-00	TANTALUM 22 10% 16V
C7	1-131-380-00	TANTALUM 33 10% 10V
C8	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C9	1-163-038-00	CERAMIC CHIP 0.1 25V
C10	1-131-377-00	TANTALUM 10 10% 10V
C11	1-163-038-00	CERAMIC CHIP 0.1 25V
C12	1-163-038-00	CERAMIC CHIP 0.1 25V
C13	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
C14	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
C15	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
C16	1-163-038-00	CERAMIC CHIP 0.1 25V

C17 1-163-129-00 CERAMIC CHIP 330PF 5% 50V(EK)
(DXC-101P S/N 10061 AND HIGHER)
(DXC-102P S/N 10011 AND HIGHER)

CN1	1-561-770-00	RECEPTACLE, 30P MALE
CN2	1-564-012-00	RECEPTACLE, 2P MALE

D1	8-719-100-05	1S2837
D2	8-719-104-24	1S2835
D3	8-719-100-05	1S2837

DL1 1-415-463-11 150nS

Ref. No.	Part No.	Description
FL1	1-235-277-00	BAND PASS 3.58MHz (UC,J)
FL1	1-235-439-11	BAND PASS 4.43MHz (EK)

IC1	8-759-969-13	SN16913P: TI
IC2	1-807-384-11	BH1205: SONY

Q1	8-729-100-66	2SC1623
Q2	8-729-100-66	2SC1623
Q3	8-729-100-66	2SC1623
Q4	8-729-100-66	2SC1623
Q5	8-729-100-76	2SA812
Q6	8-729-109-44	2SK94
Q7	8-729-100-76	2SA812
Q8	8-729-100-66	2SC1623

RV1	1-230-868-11	METAL 2.2 K
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LE-47 BOARD

1-617-767-11	PRINTED CIRCUIT BOARD "LE-47A" (DXC-101/101P)
1-617-767-21	PRINTED CIRCUIT BOARD "LE-47B" (DXC-102/102P)

C1	1-163-035-00	CERAMIC CHIP 0.047 50V
C2	1-163-035-00	CERAMIC CHIP 0.047 50V
C3	1-163-141-00	CERAMIC CHIP 0.001 5% 50V

Ref. No.	Part No.	Description
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MB-37 BOARD

A-7520-233-A	MOUNTED CIRCUIT BOARD "MB-37" (UC,J)
A-7520-234-A	MOUNTED CIRCUIT BOARD "MB-37" (EK)

C1	1-135-093-21	TANTALUM CHIP 10 10% 16V
C2	1-135-093-21	TANTALUM CHIP 10 10% 16V
C3	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (UC) (DXC-101 S/N Up to 11180) (DXC-102 S/N Up to 10710)
	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (UC) (DXC-101 S/N 11181 AND HIGHER) (DXC-102 S/N 10711 AND HIGHER)
	1-163-248-11	CERAMIC CHIP 75PF 5% 50V (EK)
C4	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
C5	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
C6	1-131-374-00	ELECT 33 10% 16V
C7	1-163-034-00	CERAMIC CHIP 0.033 50V
C8	1-135-100-21	TANTALUM CHIP 6.8 10% 6.3V
C9	1-163-038-00	CERAMIC CHIP 0.1 25V
C10	1-163-038-00	CERAMIC CHIP 0.1 25V
C11	1-102-112-00	CERAMIC 330PF 10% 50V
C12	1-102-112-00	CERAMIC 330PF 10% 50V (EK)

CN1	1-564-851-11	RECEPTACLE, 50P MALE
CN2	1-564-001-11	RECEPTACLE, 2P MALE
	1-562-147-11	PLUG HOUSING 2P
	1-564-026-00	PLUG CONTACT
CN3	1-564-862-11	RECEPTACLE, 20P MALE
CN4	1-564-867-11	RECEPTACLE, 30P MALE
CN5	1-564-858-11	RECEPTACLE, 2P MALE
CN6	1-564-858-11	RECEPTACLE, 2P MALE
CN7	1-562-372-00	RECEPTACLE, 2P FEMALE
CN8	1-562-372-00	RECEPTACLE, 2P FEMALE

PU1	1-464-580-11	CONVERTER, DC-DC UNIT
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Ref. No.	Part No.	Description
Q1	8-729-100-76	2SA812
Q2	8-769-401-84	3SK163-4
	(UC: DXC-101 S/N Up to 10220	
	DXC-102 S/N Up to 10030	
	EK: DXC-101P S/N Up to 10060	
	DXC-102P S/N Up to 10010)	
	8-769-401-67	3SK163-1
	(UC: DXC-101 S/N 10221 AND HIGHER	
	DXC-102 S/N 10031 AND HIGHER	
	EK: DXC-101P S/N 10061 AND HIGHER	
	DXC-102P S/N 10011 AND HIGHER)	
Q3	8-729-100-66	2SC1623
Q4	8-729-100-76	2SA812
Q5	8-769-401-84	3SK163-4
	(UC: DXC-101 S/N Up to 10220	
	DXC-102 S/N Up to 10030	
	EK: DXC-101P S/N Up to 10060	
	DXC-102P S/N Up to 10010)	
	8-769-401-67	3SK163-1
	(UC: DXC-101 S/N 10221 AND HIGHER	
	DXC-102 S/N 10031 AND HIGHER	
	EK: DXC-101P S/N 10061 AND HIGHER	
	DXC-102P S/N 10011 AND HIGHER)	
Q6	8-729-109-44	2SK94
Q7	8-729-100-76	2SA812
Q8	8-769-401-84	3SK163-4
	(UC: DXC-101 S/N Up to 10220	
	DXC-102 S/N Up to 10030	
	EK: DXC-101P S/N Up to 10060	
	DXC-102P S/N Up to 10010)	
	8-769-401-67	3SK163-1
	(UC: DXC-101 S/N 10221 AND HIGHER	
	DXC-102 S/N 10031 AND HIGHER	
	EK: DXC-101P S/N 10061 AND HIGHER	
	DXC-102P S/N 10011 AND HIGHER)	
Q9	8-729-109-44	2SK94
Q10	8-729-100-66	2SC1623
Q11	8-729-100-66	2SC1623
Q12	8-729-100-66	2SC1623
Q13	8-729-100-66	2SC1623
Q14	8-729-100-66	2SC1623
Q15	8-729-100-66	2SC1623
Q16	8-729-100-66	2SC1623
Q17	8-729-100-76	2SA812
Q18	8-729-100-76	2SA812
Q19	8-729-100-76	2SA812
Q20	8-729-100-76	2SA812
Q21	8-729-100-76	2SA812
R48	1-215-493-00	CARBON 1M 5% 1/4W (UC)
	(DXC-101 S/N 10221 AND HIGHER	
	DXC-102 S/N 10031 AND HIGHER)	
R48	1-215-491-00	CARBON 820K 5% 1/4W (EK)
	(DXC-101P S/N 10061 AND HIGHER	
	DXC-102P S/N 10011 AND HIGHER)	

Ref. No. Part No. Description

MD-30 BOARD

A-7513-325-A	MOUNTED CIRCUIT BOARD
	"MD-30" (UC,J)
A-7513-326-A	MOUNTED CIRCUIT BOARD
	"MD-30" (EK)
C1	1-131-375-00 TANTALUM 4.7 10% 10V
C2	1-131-374-00 TANTALUM 33 10% 16V
C3	1-163-038-00 CERAMIC CHIP 0.1 25V
C4	1-163-101-00 CERAMIC CHIP 22PF 5% 50V
C5	1-163-101-00 CERAMIC CHIP 22PF 5% 50V
C6	1-163-101-00 CERAMIC CHIP 22PF 5% 50V
C7	1-163-101-00 CERAMIC CHIP 22PF 5% 50V
C8	1-163-101-00 CERAMIC CHIP 22PF 5% 50V
C9	1-131-357-00 TANTALUM 4.7 10% 25V
C10	1-163-101-00 CERAMIC 22PF 5% 50V
C11	1-163-038-00 CERAMIC CHIP 0.1 25V
CN1	1-563-114-11 RECEPTACLE, 20P MALE
FL1	1-235-394-11 LOW PASS 4.773MHZ (UC,J)
FL1	1-235-442-11 LOW PASS 0-25MHZ (EK)
IC1	8-759-908-15 TL431CLP: TI
IC2	1-807-385-11 BH1206: SONY
L1	1-408-399-00 MICRO 1.5
L2	1-408-409-00 MICRO 10
Q1	8-729-100-66 2SC1623
Q2	8-729-100-76 2SA812
Q3	8-729-100-66 2SC1623
Q4	8-729-100-66 2SC1623
Q5	8-729-102-76 2SA812
Q6	8-729-100-66 2SC1623
Q7	8-729-100-66 2SC1623
Q8	8-729-100-66 2SC1623
Q9	8-729-100-66 2SC1623
Q10	8-729-100-66 2SC1623
RV1	1-230-870-21 METAL 10K
RV2	1-230-870-21 METAL 10K
RV3	1-230-870-21 METAL 10K
RV4	1-230-870-21 METAL 10K
RV5	1-230-870-21 METAL 10K

Ref. No. Part No. Description

PR-72 BOARD

A-7513-323-A MOUNTED CIRCUIT BOARD
"PR-72"

C1	1-131-371-00	TANTALUM 10 10% 16V
C2	1-163-038-00	CERAMIC CHIP 0.1 25V
C3	1-163-038-00	CERAMIC CHIP 0.1 25V
C4	1-131-380-00	TANTALUM 33 10% 10V
C5	1-163-085-00	CERAMIC CHIP 2PF ± 0.25 PF 50V
C6	1-163-218-11	CERAMIC CHIP 1.5PF ± 0.25 PF 50V
C7	1-163-090-00	CERAMIC CHIP 7PF ± 0.25 PF 50V
C8	1-163-038-00	CERAMIC CHIP 0.1 25V
C9	1-131-347-00	TANTALUM 1 10% 35V
C10	1-163-038-00	CERAMIC CHIP 0.1 25V
C11	1-163-038-00	CERAMIC CHIP 0.1 25V
C12	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
C13	1-131-371-00	TANTALUM 10 10% 16V
C14	1-131-371-00	TANTALUM 10 10% 16V
C15	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
C16	1-135-101-21	TANTALUM CHIP 22 10% 6.3V (UC: DXC-101 S/N Up to 10120 DXC-102 S/N Up to 10180 EK: DXC-101P S/N Up to 10260 DXC-102P S/N Up to 10310)
C17	1-163-255-00	CERAMIC CHIP 150PF 5% 50V
C18	1-163-102-00	CERAMIC CHIP 24PF 5% 50V
C19	1-163-085-00	CERAMIC CHIP 2PF ± 0.25 PF 50V
C20	1-135-099-00	TANTALUM CHIP 2.2 10% 6.3V (UC: DXC-101 S/N Up to 10830 DXC-102 S/N Up to 10610 EK: DXC-101P S/N Up to 11080 DXC-102P S/N Up to 10920)
	1-135-101-21	TANTALUM CHIP 22 10% 6.3V (UC: DXC-101 S/N 10831 AND HIGHER DXC-102 S/N 10611 AND HIGHER EK: DXC-101P S/N 11081 AND HIGHER DXC-102P S/N 10921 AND HIGHER)
C21	1-124-444-00	ELECT 220 20% 6.3V (UC: DXC-101 S/N Up to 10830 DXC-102 S/N Up to 10610 EK: DXC-101P S/N Up to 11080 DXC-102P S/N Up to 10920)
C22	1-135-076-21	TANTALUM CHIP 1 10% 35V (UC: DXC-101 S/N 10831 AND HIGHER DXC-102 S/N 10611 AND HIGHER EK: DXC-101P S/N 11081 AND HIGHER DXC-102P S/N 10921 AND HIGHER)

Ref. No. Part No. Description

C24	1-163-125-00	CERAMIC CHIP 220PF 5% 50V (UC: DXC-101 S/N 10831 AND HIGHER DXC-102 S/N 10611 AND HIGHER EK: DXC-101P S/N 11081 AND HIGHER DXC-102P S/N 10921 AND HIGHER)
C25	1-163-129-00	CERAMIC CHIP 330PF 5% 50V (UC: DXC-101 S/N 10831 AND HIGHER DXC-102 S/N 10611 AND HIGHER EK: DXC-101P S/N 11081 AND HIGHER DXC-102P S/N 10921 AND HIGHER)
D1	8-719-100-05	1S2837
IC1	8-759-201-00	TC4052BF: TOSHIBA
IC2	8-759-201-00	TC4052BF: TOSHIBA
IC3	8-759-100-94	μ PC358G2: NEC
IC4	1-807-383-13	BH1204: SONY
Q1	8-729-100-66	2SC1623
Q2	8-729-100-66	2SC1623
Q3	8-729-100-66	2SC1623
Q4	8-729-109-44	2SK94
Q5	8-729-109-44	2SK94
Q6	8-729-100-66	2SC1623
Q7	8-729-100-66	2SC1623
Q8	8-729-100-66	2SC1623
Q9	8-729-100-66	2SC1623
Q10	8-729-100-66	2SC1623
Q11	8-729-100-66	2SC1623
Q12	8-729-109-44	2SK94
Q13	8-729-100-66	2SC1623
Q14	8-729-100-66	2SC1623 (UC: DXC-101 S/N 10221 AND HIGHER DXC-102 S/N 10181 AND HIGHER EK: DXC-101P S/N 10261 AND HIGHER DXC-102P S/N 10311 AND HIGHER)
R12	1-214-590-00	METAL 24K 1% 1/8W
R13	1-214-589-00	METAL 22K 1% 1/8W
R14	1-214-584-00	METAL 13K 1% 1/8W
R15	1-214-585-00	METAL 15K 1% 1/8W
R18	1-214-584-00	METAL 13K 1% 1/8W
R19	1-214-585-00	METAL 15K 1% 1/8W
R20	1-214-584-00	METAL 13K 1% 1/8W
R21	1-214-586-00	METAL 16K 1% 1/8W
RV1	1-230-870-21	METAL 10K
RV2	1-230-870-21	METAL 10K
RV3	1-230-870-21	METAL 10K
RV4	1-230-870-21	METAL 10K
RV5	1-230-870-21	METAL 10K
RV6	1-230-871-21	METAL 22K

Ref. No.	Part No.	Description
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PG-12 BOARD

A-7513-331-A	MOUNTED CIRCUIT BOARD	"PG-12" (UC,J)
A-7513-332-A	MOUNTED CIRCUIT BOARD	"PG-12" (EK)

C1	1-163-093-00	CERAMIC CHIP 10PF 5% 50V (UC,J)
C1	1-163-241-11	CERAMIC CHIP 39PF 5% 50V (EK)
C2	1-163-097-00	CERAMIC CHIP 15PF 5% 50V (UC,J)
C2	1-163-099-00	CERAMIC CHIP 18PF 5% 50V (EK)
C3	1-163-093-00	CERAMIC CHIP 10PF 5% 50V
C4	1-163-093-00	CERAMIC CHIP 10PF 5% 50V
C5	1-163-093-00	CERAMIC CHIP 10PF 5% 50V
C6	1-163-093-00	CERAMIC CHIP 10PF 5% 50V
C7	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C8	1-163-093-00	CERAMIC CHIP 10PF 5% 50V
C9	1-163-119-00	CERAMIC CHIP 120PF 10% 50V (UC,J)
C9	1-163-247-00	CERAMIC CHIP 68PF 5% 50V (EK)
C10	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (UC,J)
C10	1-163-111-00	CERAMIC CHIP 56PF 5% 50V (EK)
C11	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C12	1-163-251-00	CERAMIC CHIP 100PF 5% 50V
C13	1-163-038-00	CERAMIC CHIP 0.1 25V
C14	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C15	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C16	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C17	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C18	1-163-105-00	CERAMIC CHIP 33PF 5% 50V (UC,J)
C19	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (EK)
C20	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C21	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C22	1-163-038-00	CERAMIC CHIP 0.1 25V
C23	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C24	1-135-091-00	TANTALUM CHIP 1 10% 16V
C25	1-131-379-00	TANTALUM 22 10% 10V
C26	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C27	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C28	1-163-109-00	CERAMIC CHIP 47PF 5% 50V
C29	1-163-087-00	CERAMIC CHIP 4PF 0.25PF 50V (EK)
		(DXC-101P S/N Up to 12080)
		(DXC-102P S/N Up to 11070)
	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (EK)
		(DXC-101P S/N 12081 AND HIGHER)
		(DXC-102P S/N 11071 AND HIGHER)
C30	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (EK)
C31	1-163-105-00	CERAMIC CHIP 33PF 5% 50V
C32	1-163-105-00	CERAMIC CHIP 33PF 5% 50V
C33	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (UC,J)
C34	1-163-034-00	CERAMIC CHIP 0.033 50V
C35	1-135-093-21	TANTALUM CHIP 10 10% 16V
C36	1-131-345-00	TANTALUM CHIP 0.47 1% 35V
C38	1-163-263-00	CERAMIC CHIP 330PF 5% 50V
C39	1-163-038-00	CERAMIC CHIP 0.1 25V
C40	1-161-021-11	CERAMIC 0.047 10% 25V (EK)

Ref. No.	Part No.	Description
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D1	8-719-100-05	1S2837
D2	8-719-100-05	1S2837
D3	8-719-100-05	1S2837
D4	8-719-100-03	1S2835

IC1	8-757-930-02	CX7930-1: SONY
IC2	1-807-382-11	BH1203: SONY

L1	1-408-399-00	MICRO 1.5
L2	1-408-399-00	MICRO 1.5
L3	1-408-728-21	CHIP 1

Q1	8-729-100-66	2SC1623
Q2	8-729-100-76	2SA812
Q3	8-729-122-63	2SA1226
Q4	8-729-102-06	2SC2223

R35	1-249-405-11	CARBON 100 1/4W (EK)
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VCO1	1-567-549-11	28.63636MHz (UC,J)
VCO1	1-567-550-11	28.375MHz (EK)

Ref. No.	Part No.	Description
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RG-13 BOARD

A-7513-329-A	MOUNTED CIRCUIT BOARD
	"RG-13" (UC,J)
A-7513-330-A	MOUNTED CIRCUIT BOARD
	"RG-13" (EK)

C1	1-163-038-00	CERAMIC CHIP 0.1 25V
C2	1-124-247-00	ELECT 10 20% 35V
C3	1-163-038-00	CERAMIC CHIP 0.1 25V
C4	1-124-236-00	ELECT 47 20% 16V
		(UC: DXC-101 S/N Up to 10220 DXC-102 S/N Up to 10180 EK: DXC-101P S/N Up to 10260 DXC-102P S/N Up to 10310)
	1-124-584-00	ELECT 100 20% 10V
		(UC: DXC-101 S/N 10221 AND HIGHER DXC-102 S/N 10181 AND HIGHER EK: DXC-101P S/N 10261 AND HIGHER DXC-102P S/N 10311 AND HIGHER)
C5	1-163-038-00	CERAMIC CHIP 0.1 25V
C6	1-124-584-00	ELECT 100 20% 10V
C7	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C8	1-124-247-00	ELECT 10 20% 35V
C9	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C10	1-124-236-00	ELECT 47 20% 16V
		(UC: DXC-101 S/N Up to 10220 DXC-102 S/N Up to 10180 EK: DXC-101P S/N Up to 10260 DXC-102P S/N Up to 10310)
	1-124-584-00	ELECT 100 20% 10V
		(UC: DXC-101 S/N 10221 AND HIGHER DXC-102 S/N 10181 AND HIGHER EK: DXC-101P S/N 10261 AND HIGHER DXC-102P S/N 10311 AND HIGHER)
C11	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C12	1-124-584-00	ELECT 100 20% 10V
C13	1-131-371-00	TANTALUM 10 10% 16V
C14	1-163-141-00	CERAMIC CHIP 0.001 5% 50V (EK)
C15	1-135-093-21	TANTALUM CHIP 10 10% 16V (EK)
C16	1-135-097-21	TANTALUM CHIP 15 10% 10V (EK)
C17	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C18	1-163-021-00	CERAMIC CHIP 0.01 10% 50V (EK)
C19	1-125-373-11	DOUBLE LAYERS 0.022 5.5V
C20	1-163-038-00	CERAMIC CHIP 0.1 25V
C21	1-163-113-00	CERAMIC CHIP 68PF 5% 50V (EK)

IC1	8-759-200-81	TC4053BF: TOSHIBA
IC2	8-759-200-94	μPC358G2: NEC

Ref. No.	Part No.	Description
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L1	1-408-409-00	MICRO 10
L2	1-408-417-21	MICRO 47
L3	1-408-417-21	MICRO 47
L4	1-408-416-00	MICRO 39 (EK)

Q1	8-729-100-76	2SA812
Q2	8-729-100-66	2SC1623
Q3	8-729-109-44	2SK94 (EK)
Q4	8-729-100-66	2SC1623
Q5	8-729-175-73	2SC2757

RV1	1-228-395-11	METAL 10K (UC,J)
RV1	1-228-395-00	METAL 10K (EK)
RV2	1-228-395-11	METAL 10K (UC,J)
RV2	1-228-395-00	METAL 10K (EK)

VC01	1-527-585-00	17.734475MHz (EK)
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FRAME

A-7560-026-A	CCD ASSY (UC,J)
A-7560-027-A	CCD ASSY (EK)

FIXTURE

J-6028-450-A	EXTENTION BOARD "EX-97"
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Ref. No.	Part No.	Description
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CN-39 BOARD

1-617-217-11	PRINTED CIRCUIT BOARD
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"CN-39"

C1	1-124-143-00	ELECT 100 20% 16V
C2	1-131-379-00	TANTALUM 22 10% 10V
C3	1-131-377-00	TANTALUM 10 10% 10V
C4	1-124-139-00	ELECT 100 20% 10V
C5	1-163-021-00	CERAMIC CHIP 0.01 10% 50V

C6	1-124-473-11	ELECT 1000 20% 10V
C7	1-131-383-00	TANTALUM 10 10% 6.3V
C8	1-161-013-11	CERAMIC 0.01 10% 25V
		(UC: DXC-101 S/N Up to 10220 EK: DXC-101P S/N Up to 10060)
C8	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
		(UC: DXC-101 S/N 10221 AND HIGHER EK: DXC-101P S/N 10061 AND HIGHER)

CN1	1-562-715-11	RECEPTACLE, 50P FEMALE
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D1	8-719-100-03	1S2835
D2	8-719-100-05	1S2837

F1	1-532-721-11	GLASS, TUBE 0.8A 125V
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IC1	8-759-200-90	TC4538BF: TOSHIBA
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Q1	8-729-100-76	2SA812
Q2	8-729-100-76	2SA812
Q3	8-729-109-44	2SK94
Q4	8-729-100-76	2SA812
Q5	8-729-100-76	2SA812
Q6	8-729-100-66	2SC1623

Ref. No.	Part No.	Description
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DC-28 BOARD

1-617-768-12	PRINTED CIRCUIT BOARD "DC-28"
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C1	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
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SW-33 BOARD

1-617-218-11	PRINTED CIRCUIT BOARD "SW-33"
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CN1	1-564-018-11	RECEPTACLE, 8P MALE
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D1	8-719-800-33	TLG102A
D2	8-719-100-03	1S2835
D3	8-719-100-03	1S2835

Q1	8-729-100-76	2SA812
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S1	1-553-856-00	KEY BOARD
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FRAME

C1	1-102-106-00	CERAMIC 100PF 10% 50V
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CN101	1-562-153-11	PLUG HOUSING 8P
	1-564-026-00	PLUG CONTACT
CN102	1-563-113-11	RECEPTACLE, 4P MALE
CN103	1-561-781-21	RECEPTACLE, BNC
CN104	1-562-381-00	RECEPTACLE, 12P MALE
CN200	1-562-147-11	PLUG HOUSING 2P
CN304	1-562-148-11	PLUG HOUSING 3P
	1-564-026-00	PLUG CONTACT
CN402	1-562-147-11	PLUG HOUSING 2P
	1-564-026-00	PLUG CONTACT

S101	1-570-505-11	ROTARY
S102	1-570-505-11	ROTARY

Ref. No. Part No. Description

MB-38 BOARD

△A-7513-349-A MOUNTED CIRCUIT BOARD
"MB-38" (UC,J)

△A-7513-350-A MOUNTED CIRCUIT BOARD
"MB-38" (EK)

C1	1-124-121-00	ELECT 100 20% 35V
C2	1-124-121-00	ELECT 100 20% 35V
C3	1-131-380-00	TANTALUM 33 10% 10V
C4	1-163-038-00	CERAMIC CHIP 0.1 25V
C5	1-163-038-00	CERAMIC CHIP 0.1 25V
C6	1-163-038-00	CERAMIC CHIP 0.1 25V
C7	1-163-117-00	CERAMIC CHIP 100PF 5% 50V (UC,J)
C7	1-163-099-00	CERAMIC CHIP 18PF 5% 50V (EK)
C8	1-124-912-11	ELECT 330 20% 50V
C9	1-124-140-00	ELECT 220 20% 10V
C10	1-163-113-00	CERAMIC CHIP 68PF 5% 50V (EK) (EK: DXC-102P S/N 10311 AND HIGHER)
C11	1-161-051-00	CERAMIC 0.01 10% 25V (UC,J)
CN1	1-564-853-11	RECEPTACLE, 50P MALE
CN2	1-564-001-00	RECEPTACLE, 2P MALE
	1-562-147-11	PLUG HOUSING 2P
	1-564-026-00	PLUG CONTACT
CN3	1-564-005-00	RECEPTACLE, 6P MALE
	1-562-151-11	PLUG HOUSING 6P
	1-564-026-00	PUG CONTACT
CN4	1-564-002-00	RECEPTACLE, 3P MALE
CN5	1-564-003-00	RECEPTACLE, 4P MALE

D1 8-719-100-03 1S2835

△ F1 1-532-721-11 GLASS TUBE 0.8A 125V

IC1 8-759-200-81 TC4053BF: TOSHIBA
IC2 8-741-134-00 BX1340: SONY

L1 1-421-843-11 MICRO 470
L3 1-408-423-00 MICRO 150 (UC,J)
L3 1-408-421-00 MICRO 100 (EK)

Q1 8-729-100-76 2SA812
Q2 8-729-178-55 2SC2785-E
(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)
8-729-271-22 2SC1623
(UC: DXC-102 S/N 10181 AND HIGHER
EK: DXC-102P S/N 10310 AND HIGHER)

R11 1-247-855-11 CARBON 10 5% 1/6W

VCO1 1-527-478-00 14.31818MHz (UC,J)
VCO1 1-527-585-00 17.734475MHz (EK)

DXC-102/102P (UC, EK)

Ref. No. Part No. Description

RM-32 BOARD

A-7513-351-A MOUNTED CIRCUIT BOARD "RM-32"

C1 1-163-141-00 CERAMIC CHIP 0.001 5% 50V
C2 1-163-021-00 CERAMIC CHIP 0.01 10% 50V
C3 1-131-361-21 TANTALUM 2.2 20V

(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)
1-135-095-00 TANTALUM CHIP 1.5 10% 10V
(UC: DXC-102 S/N 10181 AND HIGHER
EK: DXC-102P S/N 10311 AND HIGHER)

C4 1-135-076-21 TANTALUM CHIP 1 10% 35V
C5 1-135-070-00 TANTALUM CHIP 0.1 10% 35V
(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)

1-135-076-21 TANTALUM CHIP 1 10% 35V
(UC: DXC-102 S/N 10181 AND HIGHER
EK: DXC-102P S/N 10311 AND HIGHER)

C6 1-135-093-21 TANTALUM CHIP 10 10% 16V
C7 1-135-093-21 TANTALUM CHIP 10 10% 16V
C8 1-135-093-21 TANTALUM CHIP 10 10% 16V
C9 1-163-021-00 CERAMIC CHIP 0.01 10% 50V
C10 1-135-076-21 TANTALUM CHIP 1 10% 35V
C11 1-131-347-21 TANTALUM CHIP 1 35V

(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)

D1 8-719-100-05 1S2837
(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)
D2 8-719-100-05 1S2837
D3 8-719-100-03 1S2835

IC1 8-759-200-75 TC4025BF: TOSHIBA
IC2 8-759-200-82 TC4069UBF: TOSHIBA
IC3 8-759-300-40 HD44820A89: HITACHI
IC4 8-759-906-53 TL062CPS: TI
IC5 8-759-200-99 TC4051BF: TOSHIBA

Q1 8-729-100-66 2SC1623
Q2 8-729-100-76 2SA812
Q3 8-729-100-66 2SC1623
(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)

Q4 8-729-100-66 2SC1623
Q5 8-729-100-66 2SC1623
Q6 8-729-100-66 2SC1623
Q7 8-729-100-76 2SA812
Q8 8-729-100-66 2SC1623
Q9 8-729-100-76 2SA812
Q10 8-729-100-76 2SA812
Q11 8-729-100-66 2SC1623

R17 1-215-829-11 METAL 91K 1% 1/8W

R36 1-247-879-51 CARBON 100K 5% 1/6W
(UC: DXC-102 S/N Up to 10180
EK: DXC-102P S/N Up to 10310)

RP1 1-231-387-00 25K

Ref. No. Part No. Description

SG-38 BOARD

A-7513-352-A MOUNTED CIRCUIT BOARD
"SG-38" (UC,J)
A-7513-353-A MOUNTED CIRCUIT BOARD
"SG-38" (EK)

C1	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C2	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C3	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C4	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C5	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (UC,J)
C5	1-163-099-00	CERAMIC CHIP 18PF 5% 50V (EK)
C6	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C7	1-163-111-00	CERAMIC CHIP 56PF 5% 50V (UC,J)
C7	1-163-107-00	CERAMIC CHIP 39PF 5% 50V (EK)
C8	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C9	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C10	1-163-255-00	CERAMIC CHIP 150PF 5% 50V (UC,J)
C10	1-163-141-00	CERAMIC CHIP 0.001 5% 50V (EK)
C11	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C12	1-131-380-00	TANTALUM 33 10% 10V
C13	1-131-380-00	TANTALUM 33 10% 10V
C14	1-131-380-00	TANTALUM 33 10% 10V
C15	1-131-380-00	TANTALUM 33 10% 10V
C16	1-131-380-00	TANTALUM 33 10% 10V
C17	1-124-139-00	ELECT 100 20% 10V
C18	1-131-380-00	TANTALUM 33 10% 10V
C19	1-131-380-00	TANTALUM 33 10% 10V
C20	1-123-617-00	ELECT 10 20% 16V
C21	1-131-380-00	TANTALUM 33 10% 10V
IC1	8-741-134-00	BX1340: SONY
IC2	8-741-133-70	BX1337: SONY
IC3	8-741-133-80	BX1338: SONY
IC4	8-741-133-91	BX1339A: SONY
IC5	8-759-907-81	SN74LS221NS: TI
L1	1-408-124-00	MICRO 39
L2	1-408-124-00	MICRO 39
L3	1-408-124-00	MICRO 39
L4	1-408-423-00	MICRO 150 (UC,J)
L4	1-408-123-00	MICRO 100 (EK)
L5	1-408-124-00	MICRO 39 (UC,J)
L5	1-408-123-00	MICRO 33 (EK)
L6	1-408-124-00	MICRO 39
L7	1-408-124-00	MICRO 39
L8	1-408-124-00	MICRO 39
R1	1-214-583-00	METAL 12K 1% 1/8W (UC,J)
R1	1-214-581-00	METAL 10K 1% 1/8W (EK)

Ref. No. Part No. Description

SG-110 BOARD

A-7513-354-A MOUNTED CIRCUIT BOARD "SG-110"

C1	1-163-038-00	CERAMIC CHIP 0.1 25V
C2	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C3	1-135-091-00	TANTALUM CHIP 1 10% 16V
C4	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C5	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
C6	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
C7	1-131-353-00	TANTALUM 10 10% 35V
C8	1-131-367-00	TANTALUM 22 10% 20V
C9	1-124-282-00	ELECT 22 20% 25V
C10	1-163-038-00	CERAMIC CHIP 0.1 25V
C11	1-124-248-00	ELECT 22 20% 35V
C12	1-124-248-00	ELECT 22 20% 35V
CN1	1-564-012-00	RECEPTACLE, 2P MALE
D1	8-719-100-89	RD24EB1
IC1	8-759-100-94	μPC358G2: NEC
IC2	8-759-100-94	μPC358G2: NEC
Q1	8-729-100-66	2SC1623
Q2	8-729-177-43	2SD774
Q3	8-729-100-66	2SC1623
Q4	8-729-201-78	2SD1406
R11	1-244-813-00	CARBON 3.3 5% 1/2W
R16	1-247-714-00	CARBON 1.2K 5% 1/4W
RV1	1-228-457-00	METAL 2K
L1	1-408-074-11	MICRO 56

Ref. No.	Part No.	Description
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SW-34 BOARD

A-7513-355-A	MOUNTED CIRCUIT BOARD "SW-34"
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C1	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C2	1-131-379-00	TANTALUM 22 10% 10V
C3	1-131-377-00	TANTALUM 10 10% 10V
C4	1-131-385-00	TAMTALUM 22 10% 6.3V
C5	1-131-341-21	TAMTALUM 0.1 10% 35V

CN1	1-564-007-00	RECEPTACLE, 8P
CN2	1-564-005-00	RECEPTACLE, 6P

D1	8-719-800-33	TLG102A
D2	8-719-100-03	1S2835
D3	8-719-100-03	1S2835
D4	8-719-100-03	1S2835
D5	8-719-100-03	1S2835
		(UC: DXC-102 S/N Up to 10180)
		(EK: DXC-102P S/N Up to 10310)
D6	8-719-100-05	1S2837
D7	8-719-815-55	1S1555
		(UC: DXC-102 S/N Up to 10180)
		(EK: DXC-102P S/N Up to 10310)
	8-719-100-05	1S2837
		(UC: DXC-102 S/N 10181 AND HIGHER)
		(EK: DXC-102P S/N 10311 AND HIGHER)
D8	8-719-815-55	1S1555
		(UC: DXC-102 S/N Up to 10180)
		(EK: DXC-102P S/N Up to 10310)
	8-719-100-05	1S2837
		(UC: DXC-102 S/N 10181 AND HIGHER)
		(EK: DXC-102P S/N 10311 AND HIGHER)

IC1	8-759-200-90	TC4538BF: TOSHIBA
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Q1	8-729-100-76	2SA812
Q2	8-729-100-76	2SA812
Q3	8-729-100-66	2SC1623
Q4	8-729-100-66	2SC1623
Q5	8-729-100-66	2SC1623
Q6	8-729-100-76	2SA812
Q7	8-729-100-76	2SA812
		(UC: DXC-102 S/N Up to 10180)
		(EK: DXC-102P S/N Up to 10310)
Q8	8-729-100-66	2SC1623
Q9	8-729-109-44	2SK94

Ref. No.	Part No.	Description
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R20	1-247-861-11	CARBON 18K 5% 1/6W
		(UC: DXC-102 S/N Up to 10180)
		(EK: DXC-102P S/N Up to 10310)

RV1	1-224-940-00	METAL 10K
RV2	1-224-940-00	METAL 10K

S1	1-554-165-00	SLIDE
S2	1-553-856-00	KEY BOARD

FRAME

CN101	1-561-781-11	RECEPTACLE BNC "DCIN/VIDEO OUT"
CN102	1-563-113-11	RECEPTACLE "LENS"
CN103	1-561-781-11	RECEPTACLE "GENLOCK"
CN104	1-561-781-11	RECEPTACLE "REMOTE"

S101	1-570-505-11	ROTARY "GAIN"
S102	1-570-505-11	ROTARY "WHITE BAL"

C1	1-102-106-21	CERAMIC 100PF 10% 50V
C2	1-102-106-21	CERAMIC 100PF 10% 50V
C3	1-102-106-21	CERAMIC 100PF 10% 50V

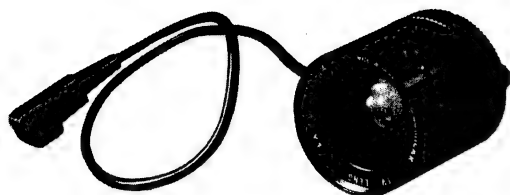
FIXTURE

J-6080-058-A	LB-140 FILTER
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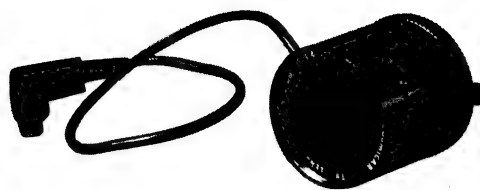
J-6029-590-A	LB-200 FILTER
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AUTO IRIS LENS

VCL-08Y/16Y



VCL-08Y



VCL-16Y

SPECIFICATIONS

Mount	C-mount
Focal length	VCL-08Y: 8 mm (1/3 inches) VCL-16Y: 16 mm (5/8 inches)
Maximum aperture ratio	1:1.4
Iris range	F1.4 to F360 (effective value)
Auto iris range	30 to 100,000 lux
Minimum focus distance	VCL-08Y: 0.2 m (75/16 inches) VCL-16Y: 0.5 m (193/4 inches)
Image size	11 mm dia. (7/16 inches)
Front thread	43 mm dia., 0.75 mm-pitch
Power requirements	12 V DC
Operating temperature	0°C to 40°C (32°F to 104°F)
Dimensions	VCL-08Y: Approx. 46.5 mm dia. x 51.1 mm long (17/8 inches dia. x 2 1/8 inches) VCL-16Y: Approx. 46.5 mm dia. x 46.7 mm long (17/8 inches dia. x 1 7/8 inches)
Weight	VCL-08Y: Approx. 170 g (6 oz) VCL-16Y: Approx. 140 g (5 oz)
Accessories supplied	Lens cap (1) Dust cap (1)

SONY
SERVICE MANUAL

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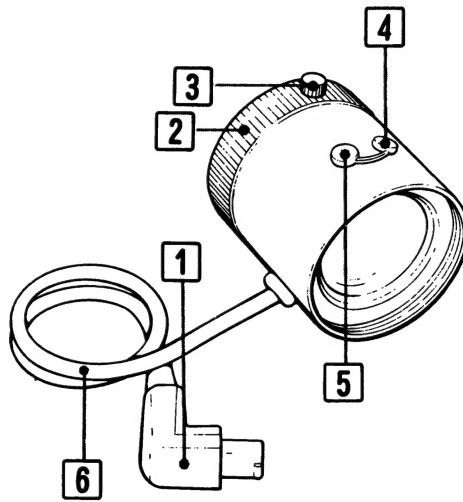
SECTION 1

GENERAL DESCRIPTION

1-1. PARTS IDENTIFICATION

(See illustration A.)

A Refer to "PARTS IDENTIFICATION".
Se reporter à "IDENTIFICATION DES ORGANES".
Siehe „BEZEICHNUNG DER TEILE“.



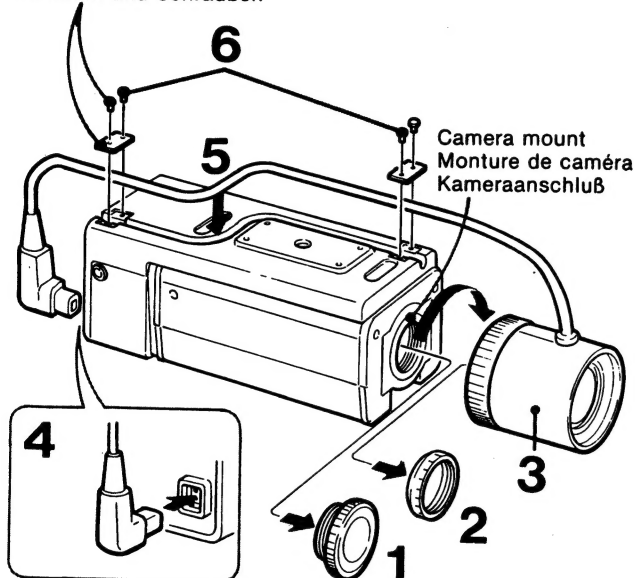
- | | |
|--|---|
| <p>1 Lens connector (4-pin)
Connect to the LENS connector on the camera. The video camera sends a signal for automatic iris adjustment to the lens.</p> <p>2 Focus ring (See "FOCUSING".)</p> <p>3 Focus ring fixing screw
Fixes the focus ring after focusing. (See "FOCUSING".)</p> | <p>4 LEVEL adjustment control
Adjusts the lens sensitivity. (See "SENSITIVITY ADJUSTMENT".)</p> <p>5 ALC (Automatic Light Control) adjustment control
Determines the video signal level measuring system of the lens. (See "ALC ADJUSTMENT".)</p> <p>6 Lens cord</p> |
|--|---|

1-2. ATTACHING THE LENS TO THE CAMERA (See illustration [B].)

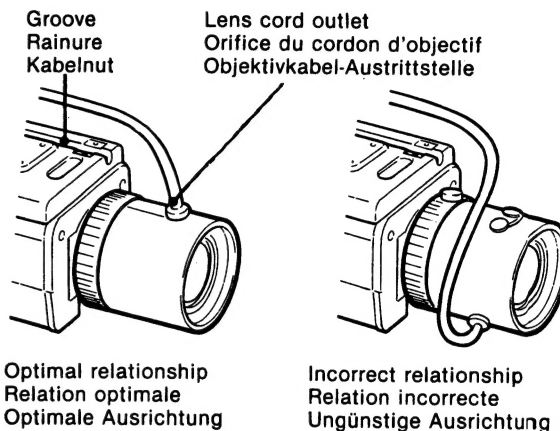
- 1 Remove the lens mount cap of the camera.
- 2 Remove the lens dust cap.
- 3 Align the lens with the camera's lens mount and secure it by turning it clockwise.
- 4 Connect the lens cord to the LENS connector of the camera. (If the lens mounting position is not appropriate for connecting, see "Adjustment of the lens mounting position" below.)
- 5 Thread the lens cord through the groove of the camera.
- 6 Fasten the lens cord with the plates and screws (supplied with the camera) (at two points on the DXC-101 series camera, and at three points on the DXC-102 series camera).

B

Plate and screws
Plaquette et vis
Plättchen und Schrauben



Adjustment of the lens mounting position (See illustration [C].)
After the lens is attached to the camera (in step 3 above), if the relationship between the lens cord outlet and camera groove is not appropriate, make the following adjustment.

C

- 1 Unplug the lens cord from the camera, and loosen the lens by turning it counterclockwise one full rotation.
- 2 Turn the lens clockwise or counterclockwise to the desired position by pushing it toward the camera firmly to release the clutch inside the lens.
- 3 Tighten the lens by turning it clockwise without pushing it in.

If the lens is not fixed at the desired position, repeat the above steps 1 to 3. When it is fixed at the desired position, proceed to step 4 in "ATTACHING THE LENS TO THE CAMERA".

To remove the lens

Reverse the procedure described in "ATTACHING THE LENS TO THE CAMERA".

1-3. FOCUSING

- 1 Remove the lens cap and loosen the focus ring fixing screw.
- 2 Watch the monitor screen, and focus by adjusting the focus ring.
- 3 Tighten the focus ring fixing screw to fix the focus ring. The focus ring setting will remain stable, even if the camera is subjected to vibration.

1-4. SENSITIVITY ADJUSTMENT

(See illustration [D].)

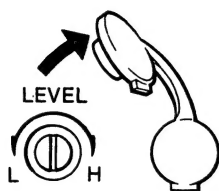
Since the lens sensitivity has been adjusted at the factory, it is not necessary for you to readjust it. If the picture is too dark, however, or if the picture's highlights are extremely overexposed, remove the cap and adjust the LEVEL adjustment control with a screwdriver to improve the picture quality.

If the control is turned

toward L: The picture becomes darker.

toward H: The picture becomes brighter.

[D]



1-5. ALC ADJUSTMENT (See illustration [E].)

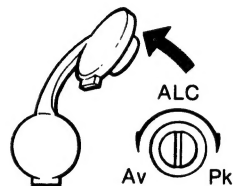
The ALC adjustment control sets the reference signal level for auto iris control at a level within a range between the average brightness level of the entire image and the level of the brightest part of the image. Since the ALC adjustment has been preset at the factory, usually no further adjustment is required. However, when shooting an image which includes a luminous body (such as a fluorescent lamp) that might cause an overexposed picture, remove the cap and adjust the ALC adjustment control as follows:

If the control is turned

toward Av: The picture becomes brighter and the picture's highlights become more overexposed.

toward Pk: The picture becomes darker and the picture's highlights become less overexposed.

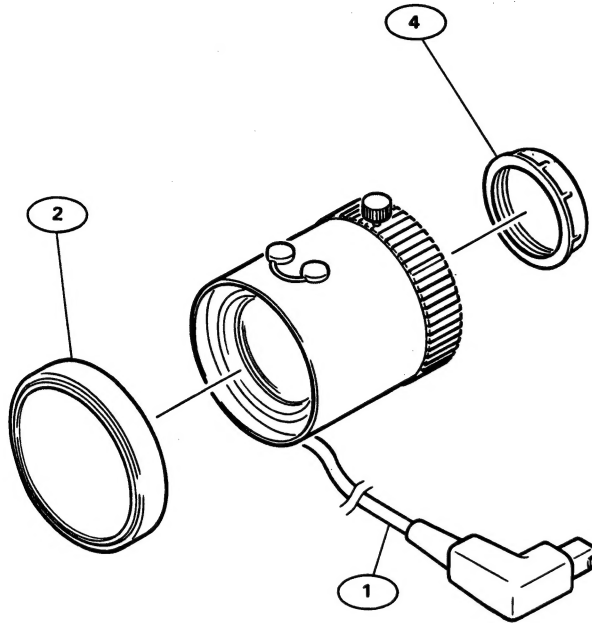
[E]



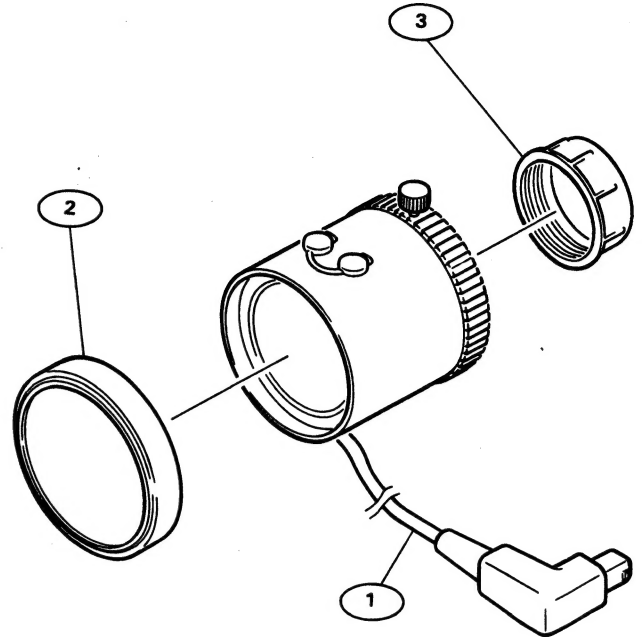
SECTION 2 SPARE PARTS

2-1. EXPLODED VIEW

VCL-08Y



VCL-16Y



No.	Parts No.	Description
1	1-558-489-11	CABLE WITH CONNECTOR
2	3-706-842-01	CAP, LENS
3	3-706-843-01	CAP, DUST (VCL-16Y)
4	3-707-254-01	CAP, DUST (VCL-08Y)

PACKING MATERIAL

3-760-960-02 MANUAL, INSTRUCTION
(UC, EK)